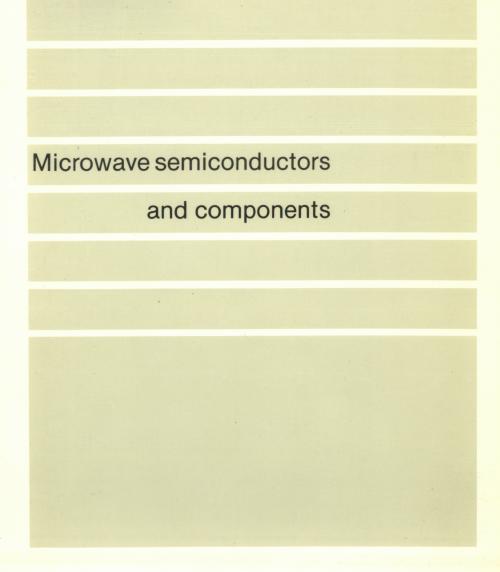


Electron tubes

Part 11 October 1982



CONTENTS

GENERAL SECTION	Α	PRESENTED STREETED STREETED ST
GUNN, IMPATT AND NOISE DIODES	В	COMMENSOR COMMENSOR STREET, COMMENSOR COM
MIXER AND DETECTOR DIODES	C	CONTRACTOR CONTRA
BACKWARD DIODES	D	Characteristics Characteristic
MULTIPLIER VARACTOR DIODES	E	entropy and the second
TUNING VARACTOR DIODES		
LIMITER VARACTOR DIODES	G	
SILICON BIPOLAR TRANSISTORS	Н	
GALLIUM ARSENIDE FET TRANSISTORS	J	
OSCILLATORS	K	
MIXER AND DETECTOR MODULES	L	=
DOPPLER MODULES AND VEHICLE DETECTORS	M	=
CIRCULATORS AND ISOLATORS	N	
MISCELLANEOUS	Р	
INDEX		



DATA HANDBOOK SYSTEM

Our Data Handbook System is a comprehensive source of information on electronic components, sub-assemblies and materials; it is made up of four series of handbooks each comprising several parts.

ELECTRON TUBES

BLUE

SEMICONDUCTORS

RED

INTEGRATED CIRCUITS

PURPLE

COMPONENTS AND MATERIALS

GREEN

The several parts contain all pertinent data available at the time of publication, and each is revised and reissued periodically.

Where ratings or specifications differ from those published in the preceding edition they are pointed out by arrows. Where application information is given it is advisory and does not form part of the product specification.

If you need confirmation that the published data about any of our products are the latest available, please contact our representative. He is at your service and will be glad to answer your inquiries.

This information is furnished for guidance, and with no guarantee as to its accuracy or completeness; its publication conveys no licence under any patent or other right, nor does the publisher assume liability for any consequence of its use; specifications and availability of goods mentioned in it are subject to change without notice; it is not to be reproduced in any way, in whole or in part without the written consent of the publisher.

ELECTRON TUBES (BLUE SERIES)

The blue series of data handbooks is comprised of the following parts:

- T1 Tubes for r.f. heating
- T2 Transmitting tubes for communications
- T3 Klystrons, travelling-wave tubes, microwave diodes
- ET3 Special Quality tubes, miscellaneous devices (will not be reprinted)
- T4 Magnetrons
- T5 Cathode-ray tubes
 Instrument tubes, monitor and display tubes, C.R. tubes for special applications
- T6 Geiger-Müller tubes
- T7 Gas-filled tubes

Segment indicator tubes, indicator tubes, dry reed contact units, thyratrons, industrial rectifying tubes, ignitrons, high-voltage rectifying tubes, associated accessories

T8 Picture tubes and components

Colour TV picture tubes, black and white TV picture tubes, colour monitor tubes for data graphic display, monochrome monitor tubes for data graphic display, components for colour television, components for black and white television and monochrome data graphic display

T9 Photo and electron multipliers

Photomultiplier tubes, phototubes, single channel electron multipliers, channel electron multiplier plates

- T10 Camera tubes and accessories, image intensifiers
- T11 Microwave components and assemblies

SEMICONDUCTORS (RED SERIES)

The red series of data handbooks is comprised of the following parts:

S1	$\begin{array}{l} \textbf{Diodes} \\ \textbf{Small-signal germanium diodes, small-signal silicon diodes, voltage regulator diodes} (< 1,5 \text{ W}), \\ \textbf{voltage reference diodes, tuner diodes, rectifier diodes} \end{array}$
S2	Power diodes, thyristors, triacs Rectifier diodes, voltage regulator diodes (> 1,5 W), rectifier stacks, thyristors, triacs
S3	Small-signal transistors
S4	Low-frequency power transistors and hybrid IC modules
S5	Field-effect transistors
S6	R.F. power transistors and modules
S7	Microminiature semiconductors for hybrid circuits
S8	Devices for optoelectronics Photosensitive diodes and transistors, light-emitting diodes, displays, photocouplers, infrared sensitive devices, photoconductive devices.
S9	Taken into handbook T11 of the blue series
S10	Wideband transistors and wideband hybrid IC modules

INTEGRATED CIRCUITS (PURPLE SERIES)

The purple series of data handbooks is comprised of the following parts:

IC1	Bipolar ICs for radio and audio equipment
IC2	Bipolar ICs for video equipment
IC3	ICs for digital systems in radio, audio and video equipment
IC4	Digital integrated circuits LOCMOS HE4000B family
IC5	Digital integrated circuits — ECL ECL10 000 (GX family), ECL100 000 (HX family), dedicated design
IC6	Professional analogue integrated circuits
IC7	Signetics bipolar memories
IC8	Signetics analogue circuits
IC9	Signetics TTL logic

IC9

COMPONENTS AND MATERIALS (GREEN SERIES)

The green series of data handbooks is comprised of the following parts:

C1	Assemblies for industrial use PLC modules, PC20 modules, HNIL FZ/30 series, NORbits 60-, 61-, 90-series, input devices, hybrid ICs, peripheral devices
C2	FM tuners, television tuners, video modulators, surface acoustic wave filters
С3	Loudspeakers
C4	Ferroxcube potcores, square cores and cross cores
C 5	Ferroxcube for power, audio/video and accelerators
C6	Electric motors and accessories Permanent magnet synchronous motors, stepping motors, direct current motors
C7	Variable capacitors*
C8	Variable mains transformers
C9	Piezoelectric quartz devices Quartz crystal units, temperature compensated crystal oscillators, compact integrated oscillators, quartz crystal cuts for temperature measurements
C10	Connectors
C11	Non-linear resistors Voltage dependent resistors (VDR), light dependent resistors (LDR), negative temperature coefficient thermistors (NTC), positive temperature coefficient thermistors (PTC)
C12	Variable resistors and test switches
C13	Fixed resistors
C14	Electrolytic and solid capacitors
C15	Film capacitors, ceramic capacitors*
C16	Piezoelectric ceramics, permanent magnet materials

^{*} C7 is in preparation. Retain C15 05-80 for information on variable capacitors until C7 becomes available.



GENERAL SECTION A





MICROWAVE SEMICONDUCTORS GENERAL EXPLANATORY NOTES

TYPE NOMENCLATURE

Microwave semiconductor devices are registered with Pro-Electron.

The type nomenclature of a discrete device or, in certain cases, of a range of devices, consists of three letters followed by a serial number. The serial number normally consists of two figures, but a suffix letter is added where variants or a series occur.

The first letter indicates the semiconductor material used:

A - germanium

B - silicon

C - compound materials, such as gallium arsenide

The second letter indicates the general function of the device:

A - detection diode, mixer diode

E - backward diode

F - r.f. transistor

L – power r.f. transistor

X - multiplier diode such as varactor or step recovery diode

The third letter forms part of the serial number.

A suffix letter R after the complete type number denotes the reverse polarity version of a diode (body cathode) where applicable. A normal polarity version (body anode) has no suffix letter.

Subscripts for quantity symbols

A, a anode terminal

BR breakdown

F. f forward

I, i input

J, j junction

K, k cathode

O, o open-circuit, output

R, r resistive, reverse, repetitive

S, s series, source

Z, z impedance



ELECTRICAL PARAMETERS

	Device	Associated circuit
Resistance	r	R
Reactance	x	X
Impedance	Z	z
Admittance	У	Y
Conductance	g	G
Susceptance	b	В
Mututal inductance	m	M
Inductance	 I	L
Capacitance	,	-
Frequency limits	С	С
Trapandy mind	f max.	
Bandwidth	f min.	
	Δf	В
Noise factor		N

Symbols for microwave semiconductor devices

η	efficiency
В	bandwidth
c_d	diode capacitance
c_j	junction capacitance
c_{\min}	diode capacitance at breakdown voltage
Co	diode capacitance at zero bias
C_{p}	parasitic (parallel) capacitance
C_s	stray capacitance
c_{tot}	total capacitance
f	operating frequency
f_{co}	varactor diode cut-off frequency
ł	current
^l dc	bias current
i.f.	intermediate frequency
۱F	d.c. foward current
^I FM	peak forward current
IR	continuous (d.c.) reverse leakage current
$L_{\mathbf{c}}$	conversion loss
L_S	series inductance
M	figure of merit
N_f	flicker noise
N_{if}	noise figure at intermediate frequency

Microwave semiconductors General Explanatory Notes

GENERAL

overall noise figure N_{o} noise temperature ratio N_r input r.f. power Pin output r.f. power Pout total power dissipated within the device P_{tot} r.f. load resistance R_{L} spreading resistance R_s thermal resistance Rth current sensitivity Si tangential sensitivity S_{ts} ambient temperature Tamb case temperature T_{case} heatsink temperature at device interface with device Ths junction temperature T_i storage temperature Tstg pulse duration t_{p} storage time t_s transition time t_{tr} voltage ٧

V_{(BR)R} V_F

 V_{BR}

d.c. forward voltage

breakdown voltage

 V_{R}

d.c. reverse voltage voltage standing wave ratio

v.s.w.r. Z_{if}

intermediate frequency impedance

 Z_{rf}

radio frequency impedance

reverse breakdown voltage

 Z_V $1/_f$

video impedance flicker noise



RATING SYSTEMS

The rating systems described are those recommended by the International Electrotechnical Commission (IEC) in its Publication 134.

DEFINITIONS OF TERMS USED

Electronic device. An electronic tube or valve, transistor or other semiconductor device.

Note

This definition excludes inductors, capacitors, resistors and similar components.

Characteristic. A characteristic is an inherent and measurable property of a device. Such a property may be electrical, mechanical, thermal, hydraulic, electro-magnetic, or nuclear, and can be expressed as a value for stated or recognized conditions. A characteristic may also be a set of related values, usually shown in graphical form.

Bogey electronic device. An electronic device whose characteristics nave the published nominal values for the type. A bogey electronic device for any particular application can be obtained by considering only those characteristics which are directly related to the application.

Rating. A value which establishes either a limiting capability or a limiting condition for an electronic device. It is determined for specified values of environment and operation, and may be stated in any suitable terms.

Note

Limiting conditions may be either maxima or minima.

Rating system. The set of principles upon which ratings are established and which determine their interpretation.

Note

The rating system indicates the division of responsibility between the device manufacturer and the circuit designer, with the object of ensuring that the working conditions do not exceed the ratings.

ABSOLUTE MAXIMUM RATING SYSTEM

Absolute maximum ratings are limiting values of operating and environmental conditions applicable to any electronic device of a specified type as defined by its published data, which should not be exceeded under the worst probable conditions.

These values are chosen by the device manufacturer to provide acceptable serviceability of the device, taking no responsibility for equipment variations, environmental variations, and the effects of changes in operating conditions due to variations in the characteristics of the device under consideration and of all other electronic devices in the equipment.

The equipment manufacturer should design so that, initially and throughout life, no absolute maximum value for the intended service is exceeded with any device under the worst probable operating conditions with respect to supply voltage variation, equipment component variation, equipment control adjustment, load variations, signal variation, environmental conditions, and variations in characteristics of the device under consideration and of all other electronic devices in the equipment.

October 1977



DESIGN MAXIMUM RATING SYSTEM

Design maximum ratings are limiting values of operating and environmental conditions applicable to a bogey electronic device of a specified type as defined by its published data, and should not be exceeded under the worst probable conditions.

These values are chosen by the device manufacturer to provide acceptable serviceability of the device, taking responsibility for the effects of changes in operating conditions due to variations in the characteristics of the electronic device under consideration.

The equipment manufacturer should design so that, initially and throughout life, no design maximum value for the intended service is exceeded with a bogey device under the worst probable operating conditions with respect to supply voltage variation, equipment component variation, variation in characteristics of all other devices in the equipment, equipment control adjustment, load variation, signal variation and environmental conditions.

DESIGN CENTRE RATING SYSTEM

Design centre ratings are limiting values of operating and environmental conditions applicable to a bogey electronic device of a specified type as defined by its published data, and should not be exceeded under normal conditions.

These values are chosen by the device manufacturer to provide acceptable serviceability of the device in average applications, taking responsibility for normal changes in operating conditions due to rated supply voltage variation, equipment component variation, equipment control adjustment, load variation, signal variation, environmental conditions, and variations in the characteristics of all electronic devices.

The equipment manufacturer should design so that, initially, no design centre value for the intended service is exceeded with a bogey electronic device in equipment operating at the stated normal supply voltage.

GUNN, IMPATT AND NOISE DIODES B



SILICON AVALANCHE NOISE DIODE

Epitaxial, silicon planar, broadband noise generator. This is a current controlled device operated at avalanche breakdown and is effective from less than 10 Hz to above J-band. Applications include built-in test equipment (BITE) for surveillance, tracking and weather radars, microwave links, direction finding, p.c.m. systems and noise modulators for electronic countermeasures. It conforms to the environmental requirements of BS9300 where applicable and can be supplied to NATO stock No. 5691-99-038-3893.

QUICK REFERENCE DATA

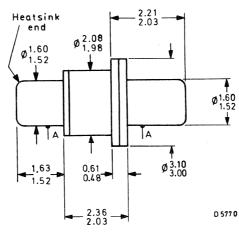
Frequency range		<10 Hz to >18	GHz
Avalanche voltage	min.	17	V
, transmitted	max.	22	V
Recommended operating current range		0.5 to 40	mΑ
Broadband excess noise ratio (figs. 1 and 3)	typ.	34	dB

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to BS3934 SO-86 and to SOD-31

Dimensions in mm



A = concentricity tolerance = ± 0.13



Normal operation with reverse bias, i.e. heatsink end positive.



RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stg}	-55 t	o +150	οс
Mounting base temperature	T _{mb}	max.	80	οС
Reverse current	^I R	max.	40	mA
Total power dissipation	P _{tot}	max.	1.0	w
CHARACTERISTICS (T _{mb} = 25 °C)				
Broadband excess noise ratio (figs. 1 and 3)		typ.	34	dB
Reverse breakdown voltage at $I_R = 5 \text{ mA}$	V _{BR(R)}	min.	17	V
Junction capacitance at $V_R = 6 V$, $f = 1 MHz$	Ci	min.	0.4	рF
	,	max.	0.8	рF
Reverse current at V _R = 6 V	^I R	max.	0.1	μΑ
Reverse slope resistance at $I_R = 40 \text{ mA}$, $f = 1 \text{ kHz}$ (note 1)	R _{slope}	max.	60	Ω
$\frac{R_1}{R_{40}}$ at $I_R = 1$ mA and 40 mA, $f = 1$ kHz (note 1)		max.	2.5	
Stray capacitance	Cs	typ.	0.2	рF
Series inductance	L _s .	typ.	650	рг На
	-8	Cyp.	030	ЬΠ

Notes

1. R_{slope} is the reverse slope resistance and $\frac{R_1}{R_{40}}$ is the ratio of the reverse slope resistance at 1 mA and

 $40\ mA$, measured at 1 kHz. This ratio is included in the characteristics to eliminate spurious effects in the noise output/current characteristic.

The reverse slope resistance consists of the space charge resistance R_{SC} , the spreading resistance R_{Sp} and the 'thermal resistance' R_{th} , i.e.

$$R_{slope} = R_{sc} + R_{sp} + R_{th}$$

where:

 $\rm R_{SC}$ is approximately 10 Ω at 10 to 40 mA and 19 Ω at 1 mA

 $R_{\mbox{\footnotesize{sp}}}$ is approximately 1 Ω

 $R_{\mbox{\scriptsize th}}$ is the effective resistance due to isothermal heating in the device when operated with an infinite heatsink. Above 10 MHz, $R_{\mbox{\scriptsize th}}$ may be neglected.

- The location of the top cap should be a hole of diameter 1.8 to 2.2 mm, bearing on flange with a force not exceeding 10 N.
- 3. Other encapsulations may be made available on request.



APPLICATION INFORMATION

The device, as characterised, is operated in a 50 Ω characteristic impedance measurement system. When used as a noise source in an on-off mode, the device, when off, should appear to be 50 Ω . Since it has a large reflection coefficient when zero biased or biased just below avalanche breakdown, sufficient attenuation is required to provide a reasonable match to 50 Ω . For the broadest operating frequency range, an attenuator of approximately 14 dB with a v.s.w.r. of <1.2:1 is recommended. This will reduce the available excess noise by 14 dB. Higher excess noise may be obtained, but over a reduced operating frequency range, in a balanced configuration with low noise directional couplers (e.g. a 3 dB quadrature coupler), or fed into a broadband ferrite isolator (or terminated circulator) which would reduce the available excess noise by approximately 1 dB.

Temperature and excess noise relationship

Excess noise dB	Noise temperature ^O K	1 Hz bandwidth dBm	1 MHz bandwidth dBm
+100	2.9 x 10 ¹²	-74	-14
+90	2.9 × 10 ¹	-84	-24
+80	2.9×10^{10}	94	-34
+70	2.9×10^9	-104	-44
+60	2.9 × 10 ⁸	-114	-54
+50	2.9×10^{7}	-124	64
+40	2.9×10^{6}	-134	-74
+30	2.9 × 10 ⁵	-144	-84
+20	2.9 × 10 ⁴	-154	-94
+10	2.9×10^{3}	164	-104
0	2.9×10^{2}	-174	-114

The device may be pulse operated with a rise time of <<0.5 μs

The device should be operated from a constant current source, however, good results may be achieved using a 28 V supply and typically a metal film or wirewound 1.6 $k\Omega$ resistor in series with the noise diode, with suitable power supply decoupling.

In some applications, current profiling with time may be useful, i.e. linear excess noise ratio as a function of log bias current as shown in fig.1. This may be used for receiver sensitivity measurement on a P.P.I. display.





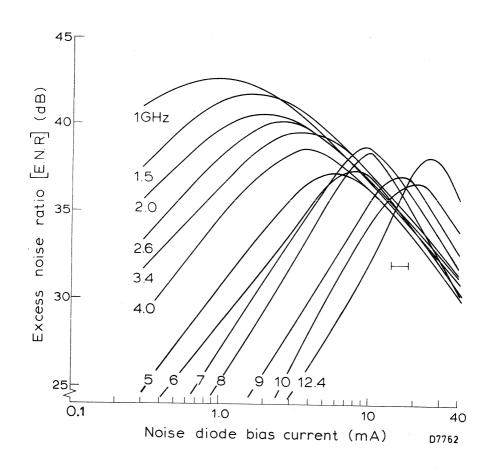
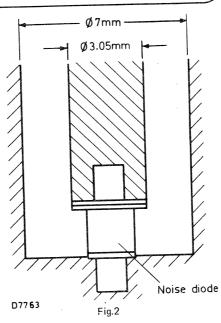


Fig.1

Typical excess noise ratio as a function of avalanche current with frequency as a parameter. Device mounted in a 50 Ω 7 mm coaxial line as shown in Fig.2



Device mounted in a 50 Ω 7 mm coaxial line

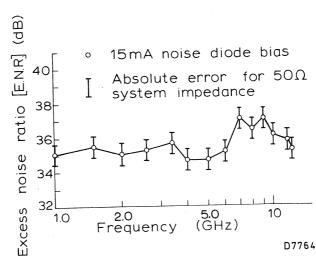


Fig.3

Typical broadband noise performance for an avalanche current of 15 mA with device mounted as shown in Fig.2



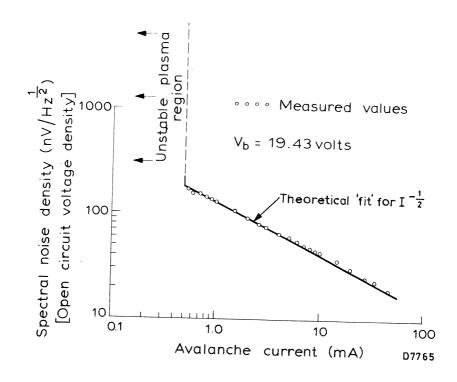


Fig.4

Typical broadband noise density measured over a 1 kHz to 10 kHz bandwidth.

SILICON IMPATT DIODE

A high efficiency silicon Impatt diode for the generation of c.w. power at microwave frequencies. It conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

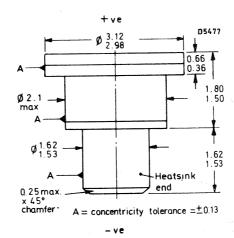
Operating frequency	f		8.0 to 10	GHz
Output power, T _{hs} = 35 °C	Pout	typ.	600	mW
Operating current		typ.	135	mA
Operating voltage		typ.	91	V

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS—MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Confroms to SOD-45

Dimensions in mm



Devices may be selected to suit customers' specific requirements

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T _{stg}		-55 to	+175	оС
Junction to heatsink temperature diff.	T _j – T _{hs}	max.		165	oC
Total power dissipation (note 1)	P _{tot}	max.	200 - R _{th j}	- T _{hs} -hs	W
THERMAL RESISTANCE					
Thermal resistance from junction to heatsink	R _{th j-hs}	max.		15	°C/W
CHARACTERISTICS (T _{hs} = 25 °C)		min.	typ.	max.	
Reverse breakdown voltage I _R = 1.0 mA	V _{(BR)R}	65	75	85	V
Reverse current V _R = 50 V	I _R		_	10	μΑ
Total capacitance $V(BR)R = -5 V$	C _T	_	0.9	_	pF
TYPICAL OSCILLATOR PERFORMANCE					
Operating current (note 2)			135		mA
Operating voltage			91		V
Frequency (note 3)	f	8.0		10	GHz
Output power (notes 2, 4, 5 and 6)	Pout	500	600	-	mW
Efficiency	η	_	5.0		%

Notes

1. The maximum junction temperature is 200 °C, therefore care must be taken to ensure that

$$P_{tot max.} \le \frac{200 - T_{hs}}{R_{th j-hs}}$$
 W

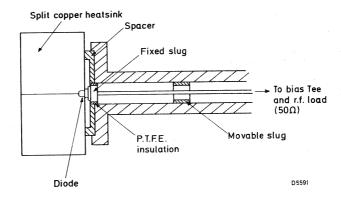
where $P_{tot} = P_{in} - P_{out}$

Ths = temperature of heatsink at interface with device

R_{th j-hs} = thermal resistance from junction to heatsink in which device is clamped.

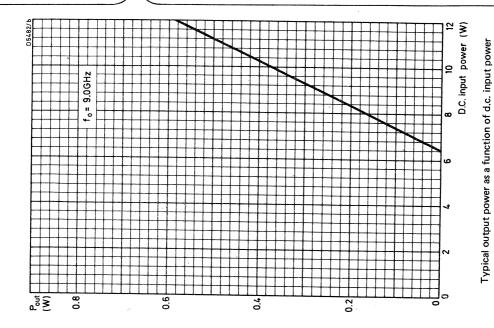
- 2. The bias supply should be current regulated to within 1% and care should be taken to avoid transient current surges which could cause burn-out. The bias circuit should be arranged to present a high impedance at d.c. to v.h.f. frequencies. This will help to prevent oscillation in the bias circuit and noisy operation. Particular care should be taken to minimise stray capacitances across the diode. The maximum power supply requirements are 115 V and 160 mA
- 3. The frequency is governed by the choice of cavity to which the device is coupled.
- 4. The polarity of the device must be strictly observed when applying bias, (see outline drawing).
- 5. The output power is normally measured in a coaxial cavity near to centre band frequency.

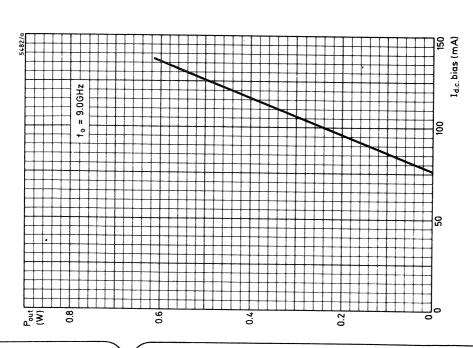
- Ξ
- 6. The heatsink end of the device should be held in a collet or equivalent clamping system to ensure minimum thermal resistance in the path to the mounting base. This in turn must be coupled to an adequate heatsink. Alternatively, direct soldering, using a low melting point solder, or an electrically conductive single loaded epoxy, such as Epotek H40, may be used.
- 7. This device may be used as a negative resistance amplifier.



Coaxial test oscillator cavity







Typical output power as a function of bias current

SILICON IMPATT DIODE

A high efficiency silicon Impatt diode for the generation of c.w. power at microwave frequencies. It conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

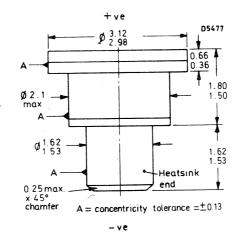
Operating frequency	f		10 to 12	GHz
Output power, T _{hs} = 35 °C	P _{out}	typ.	450	mW
Operating current		typ.	120	mΑ
Operating voltage		typ.	80	V
000000000000000000000000000000000000000				

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — ${\tt MICROWAVE}$ SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-45

Dimensions in mm



Devices may be selected to suit customers' specific requirements.

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stg}	-55 to +175			οС
Junction to heatsink temperature diff.	T _j –T _{hs}	max.		165	οС
Total power dissipation (note 1)	P _{tot}	max.	-	T _{hs} th j-hs	W
THERMAL RESISTANCE					
Thermal resistance from junction to heatsink	R _{th j-hs}	max.		19	oC/W
CHARACTERISTICS (Ths = 25 °C)					
		min.	typ.	max.	
Reverse breakdown voltage					
I _R = 1.0 mA	$V_{(BR)R}$	55	65	75	V
Reverse current V _R = 45 V					
Total capacitance	^I R		_	10	μΑ
V(BR)R = -5 V	c_{T}	_	0.85	-	рF
TYPICAL OSCILLATOR PERFORMANCE					
Operating current (note 2)		_	120		mA
Operating voltage			80		V
Frequency (note 3)	f	10	_	12	GHz
Output power (notes 2,4,5 and 6)	P _{out}	400	450		mW
Efficiency	η	_	5.0	_	%

Notes

1. The maximum junction temperature is 200 °C, therefore care must be taken to ensure that

$$P_{tot} \, \text{max.} \leqslant \frac{200 - T_{hs}}{R_{th\cdot j \text{-} hs}} \quad \text{W,} \quad$$

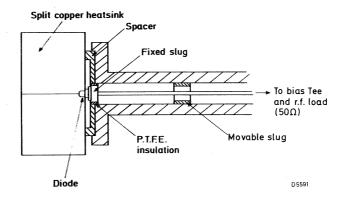
where $P_{tot} = P_{in} - P_{out}$

 T_{hs} = temperature of heatsink at interface with device

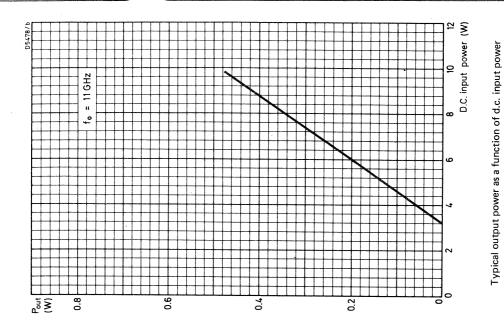
 R_{th} j-hs = thermal resistance from junction to heatsink in which device is clamped.

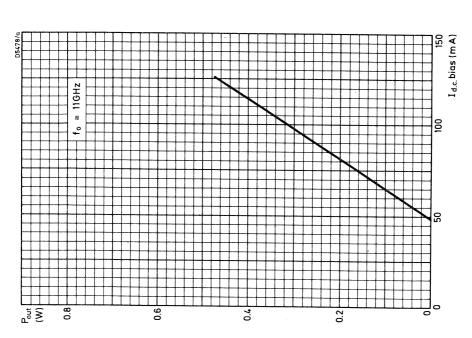
- 2. The bias supply should be current regulated to within 1% and care should be taken to avoid transient current surges which could cause burn-out. The bias circuit should be arranged to present a high impedance at d.c. to v.h.f. frequencies. This will help to prevent oscillation in the bias circuit and noisy operation. Particular care should be taken to minimise stray capacitances across the diode. The maximum power supply requirements are 105 V and 170 mA
- 3. The frequency is governed by the choice of cavity to which the device is coupled.
- 4. The polarity of the device must be strictly observed when applying bias, (see outline drawing).
- 5. The output power is normally measured in a coaxial cavity near to centre band frequency.

- 6. The heatsink end of the device should be held in a collet or equivalent clamping system to ensure minimum thermal resistance in the path to the mounting base. This in turn must be coupled to an adequate heatsink. Alternatively, direct soldering, using a low melting point solder, or an electrically conductive single loaded epoxy, such as Epotek H40, may be used.
- 7. This device may be used as a negative resistance amplifier.



Coaxial test oscillator cavity





Typical output power as a function of bias current

SILICON IMPATT DIODE

A high efficiency silicon Impatt diode for the generation of c.w. power at microwave frequencies. It conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

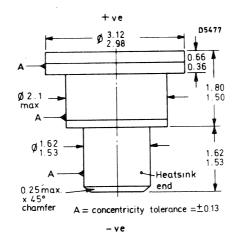
Operating frequency	f		12 to 14	GHz
Output power, T _{hs} = 35 °C	P _{out}	typ.	370	mW
Operating current		typ.	120	mΑ
Operating voltage		typ.	70	V

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-45

Dimensions in mm



Devices may be selected to suit customers' specific requirements.

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stg}	55 to +175			οс
Junction to heatsink temperature diff.	T _i - T _{hs}	max.		165	oC .
Total power dissipation (note 1)	P _{tot}	max.	200 R _{th}	– T _{hs} j-hs	W
THERMAL RESISTANCE					
Thermal resistance from junction to heatsink	R _{th j-hs}	max.		24	°C/W
CHARACTERISTICS (Ths = 25 °C)					
		min.	typ.	max.	
Reverse breakdown voltage I _R = 1.0 mA	V _{(BR)R}	50	55	60	V
Reverse current $V_R = 40 \text{ V}$	I _R			10	μΑ
Total capacitance $V_{(BR)R} = -5 V$	c _T	-	0.75		pF
TYPICAL OSCILLATOR PERFORMANCE					
Operating current (note 2)			120		mΑ
Operating voltage		_	70	_	V
Frequency (note 3)	f	12	_	14	GHz
Output power (notes 2, 4, 5 and 6)	Pout	300	370	_	mW
Efficiency	η	_	4.5	_	%

Notes

1. The maximum junction temperature is 200 $^{\rm o}$ C, therefore care must be taken to ensure that

$$P_{\mbox{tot max.}} \leqslant \frac{200 - T_{\mbox{hs}}}{R_{\mbox{th j-hs}}} \ \ \mbox{W},$$

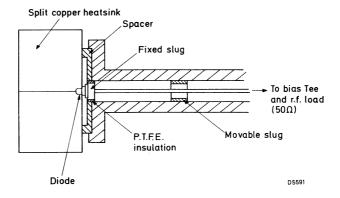
where $P_{tot} = P_{in} - P_{out}$

T_{hs} = temperature of heatsink at interface with device

Rth j-hs = thermal resistance from junction to heatsink in which device is clamped.

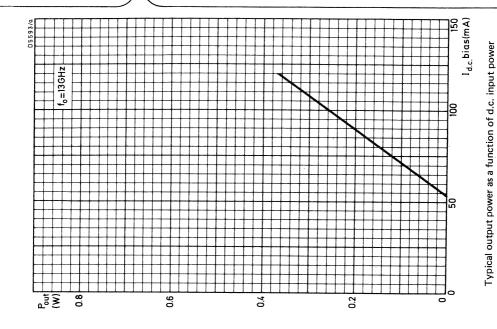
- 2. The bias supply should be current regulated to within 1% and care should be taken to avoid transient current surges which could cause burn-out. The bias circuit should be arranged to present a high impedance at d.c. to v.h.f. frequencies. This will help to prevent oscillation in the bias circuit and noisy operation. Particular care should be taken to minimise stray capacitances across the diode. The maximum power supply requirements are 90 V and 150 mA
- 3. The frequency is governed by the choice of cavity to which the device is coupled.
- 4. The polarity of the device must be strictly observed when applying bias, (see outline drawing).
- 5. The output power is normally measured in a coaxial cavity near to centre band frequency.

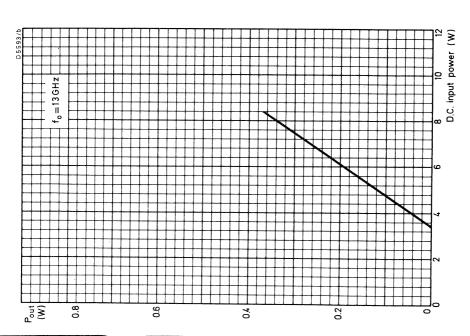
- 6. The heatsink end of the device should be held in a collet or equivalent clamping system to ensure minimum thermal resistance in the path to the mounting base. This in turn must be coupled to an adequate heatsink. Alternatively, direct soldering, using a low melting point solder, or an electrically conductive single loaded epoxy, such as Epotek H40, may be used.
- 7. This device may be used as a negative resistance amplifier.



Coaxial test oscillator cavity







Typical output power as a function of bias current

SILICON IMPATT DIODE

A high efficiency silicon Impatt diode for the generation of c.w. power at microwave frequencies. It conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

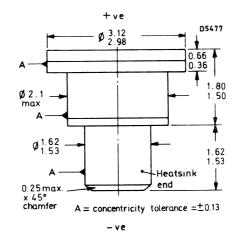
Operating frequency			6.0 to 8.0	GHz
Output power, T _{hs} = 35 °C	P _{out}	typ.	750	mW
Operating current		typ.	125	mΑ
Operating voltage		typ.	120	V

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-45

Dimensions in mm



Devices may be selected to suit customers' specific requirements, including alternative packages.



Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stg}		55 to	+175	οС
Junction temperature	Tj	max.		200	οС
Junction to heatsink temperature diff.	$T_j^{'} - T_{hs}$			165	οС
Total power dissipation (note 1)	P _{tot}	max.	$\frac{200}{R_{th}}$	– T _{hs} j-hs	w
THERMAL RESISTANCE					
Thermal resistance from junction to heatsink	R _{th j-hs}	max.		14	°C/W
CHARACTERISTICS (Ths = 25 °C)					
Reverse breakdown voltage	V(BR)R	min. 85	typ. 100	max. 115	V
Reverse current V _R = 70 V	I _R		<u> </u>	10	μΑ
Total capacitance V(BR)R = 75 V	С _Т	_	0.97	_	pF
TYPICAL OSCILLATOR PERFORMANCE					
Operating current (note 2)			125	_	mA
Operating voltage		_	120		V
Frequency (note 3)	f .	6.0		8.0	GHz
Output power (notes 2, 4, 5 and 6)	Pout	650	750	_	mW
Efficiency	η		5.0	_	%

Notes

1. The maximum junction temperature is 200 °C, therefore care must be taken to ensure that

$$P_{tot} \; \text{max.} \leqslant \frac{200 - T_{hs}}{R_{th} \; i\text{-}hs} \quad \text{W,}$$

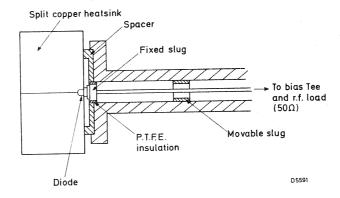
where $P_{tot} = P_{in} - P_{out}$

Ths = temperature of heatsink at interface with device

R_{th j-hs} = thermal resistance from junction to heatsink in which device is clamped.

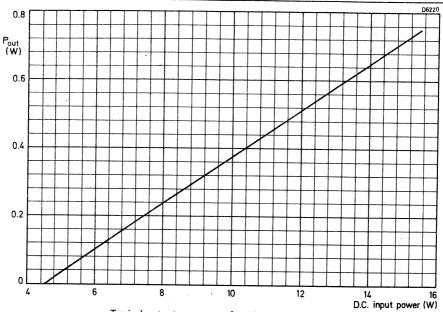
- 2. The bias supply should be current regulated to within 1% and care should be taken to avoid transient current surges which could cause burn-out. The bias circuit should be arranged to present a high impedance at d.c. to v.h.f. frequencies. This will help to prevent oscillation in the bias circuit and noisy operation. Particular care should be taken to minimise stray capacitances across the diode. The maximum power supply requirements are 140 V and 180 mA.
- 3. The frequency is governed by the choice of cavity to which the device is coupled.
- 4. The polarity of the device must be strictly observed when applying bias, (see outline drawing).
- 5. The output power is normally measured in a coaxial cavity near to centre band frequency.

- 6. The heatsink end of the device should be held in a collet or equivalent clamping system to ensure minimum thermal resistance in the path to the mounting base. This in turn must be coupled to an adequate heatsink. Alternatively, direct soldering, using a low melting point solder, or an electrically conductive single loaded epoxy, such as Epotek H40, may be used.
- 7. This device may be used as a negative resistance amplifier.

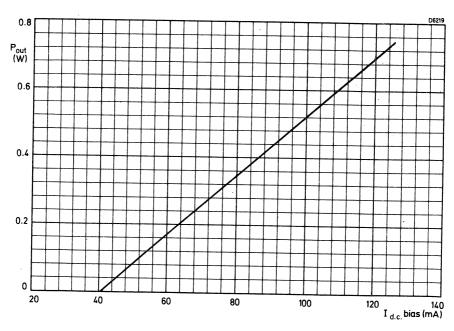


Coaxial test oscillator cavity





Typical output power as a function of d.c. input power



Typical output power as a function of bias current

GUNN EFFECT DEVICES

Gallium arsenide bulk effect devices employing the Gunn effect to produce c.w. oscillations at microwave frequencies. Each device is encapsulated in a standard microwave package and conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

Operating frequency range		f		8.0 to 12	GHz
Operating voltage		٧	typ.	7.0	٧
Total power dissipation, T _n	_{nb} = 70 °C	P _{tot}	max.	1.0	W
Output power CXY11A CXY11B CXY11C		P _{out}	min.	5.0 10 15	mW mW mW

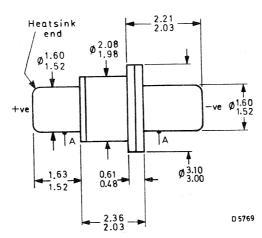
Unless otherwise stated, data is applicable to all types.

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-31

Dimensions in mm



A = concentricity tolerance = ± 0.13

Complete oscillators using these devices are available Devices may be selected to suit customers' specific requirements.



Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range		T_{stg}		-55	to +150	οС
Mounting base temperature range		T _{mb}		-4	0 to +70	оС
Operating voltage (note 1)		V	max.		7.5	V
Operating voltage for less than 1 m	ıs	V	max.		9.0	V
Total power dissipation, $T_{mb} = 70$	o C	P_{tot}	max.		1.0	W
CHARACTERISTICS (T _{amb} = 25	oC)					
			min.	typ.	max.	
Bias current, V = 7.0 V (note 1)		l _{dc}	-	120	150	mA
Operating frequency (note 2)		f	8.0	9.5	12	GHz
Output power, $V = 7.0 V$ (note 3)						
	CXY11A	Pout	5.0	8.0		mW
	CXY11B		10	12	-	mW
	CXY11C		15	20	_	mW
A.M. noise to output power ratio (note 4)		-90	-100		dB

- Bias must be applied in such a way that the mounting base (heatsink end) of the device is always
 positive. Reversing the polarity may cause permanent damage. Care should be taken to protect
 the device from transients. An 8.2 V voltage regulator diode to shunt the power supply is
 recommended for this purpose.
- 2. The frequency is governed by the choice of cavity to which the device is coupled.
- 3. The output power is normally measured in a coaxial cavity at a frequency of 9.5 GHz. Other centre frequencies may be supplied at 8.5, 10.5 and 11.5 GHz by suffixing the type number e.g. CXY11B/10.5 specifies a diode giving 10 mW min. at 10.5 GHz. See the table below. Diodes with these other centre frequencies will not necessarily oscillate over the whole 8 to 12 GHz range. The bias may be optimized to give maximum output power within the V max. and Ptot max. ratings.
- A.M. noise is measured in a 1 Hz to 1 kHz bandwidth with the diode mounted in a CL8630 oscillator.
- 5. It is important to ensure good thermal contact between the device and the mounting base, which in turn should be coupled to an adequate heatsink.
- The power supply should be low impedance, voltage regulated and capable of supplying approximately 1.5 times the normal current, to initiate oscillation.

Minimum output		Test fr	requency (GHz)	
power (mW)	wer (mW) 8.5 9.5		10.5	11.5
5	CXY11A/8.5	CXY11A	CXY11A/10.5	CXY11A/11.5
10	CXY11B/8.5	CXY11B	CXY11B/10.5	CXY11B/11.5
15	CXY11C/8.5	CXY11C	CXY11C/10.5	CXY11C/11.5



GUNN EFFECT DEVICES

Gallium arsenide bulk effect devices employing the Gunn effect to produce c.w. oscillations at microwave frequencies. Each device is encapsulated in a standard microwave package and conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

Operating frequency	y range	f		12 to 18	GHz
Operating voltage		V	typ.	7.0	V
Total power dissipa	tion, T _{mb} = 70 °C	P_{tot}	max.	1.0	W
Output power	CXY14A CXY14B	P _{out}	min.	5.0 10	mW mW
	CXY14C			15	mW

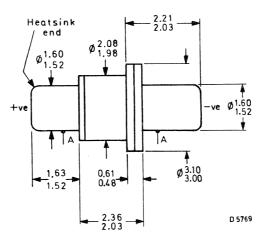
Unless otherwise stated, data is applicable to all types.

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-31

Dimensions in mm



A = concentricity tolerance = ± 0.13



Limiting values in accordance with the Absolute Maximum System (IEC134)

TATE OF THE PARTY NAMED IN
STATE OF THE PARTY
REAL PROPERTY.
A CONTRACTOR OF THE PARTY OF TH
200 miles (24)
and made and

Storage temperature range		T_{stg}		-55	5 to +150	o oc
Mounting base temperature range		T _{mb}		_4	10 to +70	o oc
Operating voltage		V	max.		7.5	5 V
Operating voltage for less than 1 ms		V	max.		9.0) V
Total power dissipation, $T_{mb} = 70 {}^{\circ}\text{C}$		P_{tot}	max.		1.0) W
CHARACTERISTICS (T _{amb} = 25 °C)						
			min.	typ.	max.	
Bias current, V = 7.0 V (note 1)		Idc		120	145	mΑ
Operating frequency (note 2)		f	12	14	18	GHz
Output power, $V = 7.0 V$ (note 3)	CXY14A	P_{out}	5.0	8.0	_	mW
	CXY14B		10	12	_	mW
	CXY14C		15	20	_	mW

- Bias must be applied in such a way that the mounting base (heatsink end) of the device is always
 positive. Reversing the polarity may cause permanent damage. Care should be taken to protect the
 device from transients. An 8.2 V voltage regulator diode to shunt the power supply is recommended
 for this purpose.
- 2. The frequency is governed by the choice of cavity to which the device is coupled.
- The output power is normally measured in a coaxial cavity at approximately centre-band frequency. The bias may be optimized to give maximum output power within the V max. and P_{tot} max. ratings.
- 4. It is important to ensure good thermal contact between the device and the mounting base, which in turn should be coupled to an adequate heatsink.
- 5. The power supply should be low impedance, voltage regulated and capable of supplying approximately 1.5 times the normal current, to initiate oscillation.

GUNN EFFECT DEVICE

Gallium arsenide bulk effect device employing the Gunn effect to produce c.w. oscillations at microwave frequencies. Each device is encapsulated in a standard microwave package and conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

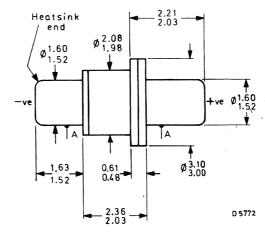
Operating frequency range	f		8.0 to 12	GHz
Operating voltage (note 2)	V		8.0 to 12	V
Total power dissipation, T _{mb} = 70 °C	P_{tot}	max.	6.0	W
Output power, f = 9.5 GHz	P _{out}	min.	100	mW

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-31

Dimensions in mm



A = concentricity tolerance = ± 0.13

All dimensions in mm



Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stg}		−55 to	+150	оС
Mounting base temperature range	T_{mb}		-40	to +70	оС
Operating voltage (note 1)	V	max.		12	V
Operating voltage for less than 1 ms	V	max.		14	V
Total power dissipation, $T_{mb} = 70 {}^{\circ}\text{C}$	P_{tot}	max.		6.0	W
CHARACTERISTICS (T _{amb} = 25 °C)					
		min.	typ.	max.	
Bias current (notes 1 and 2)	^I dc	-	450	750	mΑ
Threshold current		-	_	1.0	Α
Operating frequency (note 3)	f	8.0	9.5	12	GHz
Output power (note 2)	Pout	100	150		mW

- Bias must be applied in such a way that the mounting base (heatsink end) of the device is always negative. Reversing the polarity may cause permanent damage. Care should be taken to protect the device from transients.
- Each device is measured for maximum output power at 9.5 GHz in a coaxial test cavity. The bias
 is optimized for this maximum within the V max. and P_{tot} max. ratings. The operating voltage
 and corresponding current are quoted for this condition on a test record supplied with each device.
- 3. The frequency is governed by the choice of cavity to which the device is coupled.
- 4. The heatsink end of the device should be held in a collet or equivalent clamping system to ensure minimum thermal resistance in the path to the mounting base. This in turn must be coupled to an adequate heatsink. Alternatively, direct soldering, using a low melting point solder, or an electrically conductive single loaded epoxy, such as Epotek H40, may be used.
- 5. The power supply should be low impedance, voltage regulated and capable of supplying approximately 1.5 times the normal current, to initiate oscillation.

GUNN EFFECT DEVICE

Gallium arsenide bulk effect device employing the Gunn effect to prduce c.w. oscillations at microwave frequencies. Each device is encapsulated in a standard microwave package and conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

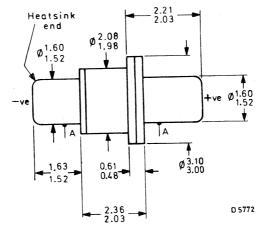
Operating frequency range	f		8.0 to 12	GHz
Operating voltage (note 2)	V		8.0 to 12	V
Total power dissipation, $T_{mb} = 70 ^{\circ}\text{C}$	P _{tot}	max.	6.0	W
Output power, f = 9.5 GHz	Pout	min.	200	mW

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — ${\tt MICROWAVE}$ SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-31

Dimensions in mm



A = concentricity tolerance = ± 0.13



Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stg}		55	to +150	°C
Mounting base temperature range	T _{mb}			0 to +70	°C
Operating voltage (note 1)	V	max.		12	V
Operating voltage for less than 1 ms	V	max.		14	V
Total power dissipation, T _{mb} = 70 °C	P_{tot}	max.		6.0	w
CHARACTERISTICS (T _{amb} = 25 °C)					
		min.	typ.	max.	
Bias current (notes 1 and 2)	^l dc		450	750	mA
Threshold current		*****		1.0	Α .
Operating frequency (note 3)	f	8.0	9.5	12	GHz
Output power (note 2)	Pout	200	250	_	mW

- Bias must be applied in such a way that the mounting base (heatsink end) of the device is always negative. Reversing the polarity may cause permanent damage. Care should be taken to protect the device from transients.
- Each device is measured for maximum output power at 9.5 GHz in a coaxial test cavity. The bias
 is optimized for this maximum within the V max. and P_{tot} max. ratings. The operating voltage
 and corresponding current are quoted for this condition on a test record supplied with each device.
- 3. The frequency is governed by the choice of cavity to which the device is coupled.
- 4. The heatsink end of the device should be held in a collet or equivalent clampling system to ensure minimum thermal resistance in the path to the mounting base. This in turn must be coupled to an adequate heatsink. Alternatively, direct soldering, using a low melting point solder, or an electrically conductive single loaded epoxy, such as Epotek H40, may be used.
- The power supply should be low impedance, voltage regulated and capable of supplying approximately 1.5 times the normal current, to initiate oscillation.

GUNN EFFECT DEVICE

Gallium arsenide bulk effect n+ sandwich device employing the Gunn effect to produce c.w. oscillations at microwave frequencies. Each device is encapsulated in a standard microwave package and conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

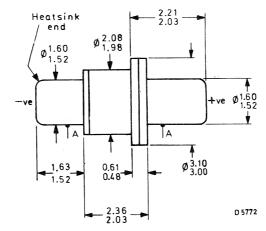
Operating frequency range	f		8.0 to 12	GHz
Operating voltage (note 2)	V		8.0 to 12	V
Total power dissipation, $T_{mb} = 70$ °C	P _{tot}	max.	7.5	W
Output power, f = 9.5 GHz	P _{out}	min.	300	mW .

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-31

Dimensions in mm



A = concentricity tolerance = ± 0.13

Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stg}		-55	to +150	°C
Mounting base temperature range	T _{mb}			0 to +70	°C
Operating voltage (note 1)	V	max.		12	V
Operating voltage for less than 1 ms	V	max.		14	V
Total power dissipation, T _{mb} = 70 °C	P_{tot}	max.		7.5	W
CHARACTERISTICS (T _{amb} = 25 °C)					
		min.	typ.	max.	
Bias current (notes 1 and 2)	l _{dc}		650	950	mΑ
Threshold current		_	mon.	1.2	Α
Operating frequency (note 3)	f	8.0	9.5	12	GHz
Output power (note 2)	Pout	300	325		mW

- Bias must be applied in such a way that the mounting base (heatsink end) of the device is always negative. Reversing the polarity may cause permanent damage. Care should be taken to protect the device from transients.
- Each device is measured for maximum output power at 9.5 GHz in a coaxial test cavity. The bias
 is optimized for this maximum within the V max. and P_{tot} max. ratings. The operating voltage
 and corresponding current are quoted for this condition on a test record supplied with each device.
- 3. The frequency is governed by the choice of cavity to which the device is coupled.
- 4. The heatsink end of the device should be held in a collect or equivalent clampling system to ensure maximum thermal resistance in the path to the mounting base. This in turn must be coupled to an adequate heatsink. Alternatively, direct soldering, using a low melting point solder, or an electrically conductive single loaded epoxy, such as Epotek H40, may be used.
- The power supply should be low impedance, voltage regulated and capable of supplying approximately 1.5 times the normal current, to initiate oscillation.

GUNN EFFECT DEVICE

Gallium arsenide bulk effect device employing the Gunn effect to produce c.w. oscillations at microwave frequencies. Each device is encapsulated in a standard microwave package and conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

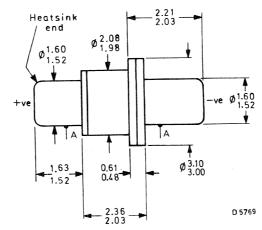
Operating frequency range	f		8.0 to 12	GHz
Operating voltage	٧	typ.	8.0	V
Total power dissipation, $T_{mb} = 70$ °C	P _{tot}	max.	2.5	W
Output power, f = 9.5 GHz	Pout	typ.	50	mW

This data must be read in conjunction with GENERAL SAFERY RECOMMENDATIONS — ${\tt MICROWAVE}$ SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-31

Dimensions in mm



A = concentricity tolerance = ± 0.13



Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stg}		-55	to +150	οС
Mounting base temperature range	T _{mb}		4	0 to +70	οс
Operating voltage (note 1)	V	max.		10	V
Operating voltage for less than 1 ms	V	max.		12	v
Total power dissipation, T _{mb} = 70 °C	P_{tot}	max.		2.5	w
CHARACTERISTICS (T _{amb} = 25 °C)					
		min.	typ.	max.	
Bias current, V = 9.5 V	l _{dc}	_	210	265	mΑ
Operating frequency (note 2)	f	8.0		12	GHz
Output power (note 3)	Pout	40	50		mW

- The heatsink end is positive. Bias must be applied in such a way that the mounting base (heatsink end) of the device is always positive. Reversal of the polarity will cause permanent damage. Care should be taken to protect the device from transients. An 11 V voltage regulator diode to shunt the power supply is recommended for this purpose.
- 2. The frequency is governed by the choice of cavity to which the device is coupled.
- The output power is normally measured in a coaxial cavity at approximately centre-band frequency. The bias may be optimized to give maximum output power within the limits of V max. and P_{tot} max.
- 4. The heatsink end of the device should be held in a collet or similar clamping system to ensure minimum thermal resistance in the path to the mounting base. This in turn must be coupled to an adequate heatsink. Alternatively, direct soldering, using a low melting point solder, or an electrically conductive single loaded epoxy, such as Epotek H40, may be used.
- The power supply should be low impedance, voltage regulated and be capable of supplying 1.5 times the normal current, to initiate oscillation.

GUNN EFFECT DEVICES

Gallium arsenide bulk effect devices employing the Gunn effect to produce c.w. oscillations at microwave frequencies. They are encapsulated in metal-ceramic packages suitable for mounting in various types of cavity. The device will oscillate in Q-band (Ka-band), the actual frequency being determined by the type of cavity.

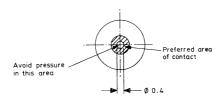
OUICK REFERENCE DATA

	f		30 to 38	GH:
	V	typ.	3.5	V
	1	typ.	0.8	Α
CXY24A CXY24B	P _{out}	min.	25 50	mW mW
		CXY24A Pout	I typ. CXY24A Pout min.	V typ. 3.5 I typ. 0.8 CXY24A P _{out} min. 25

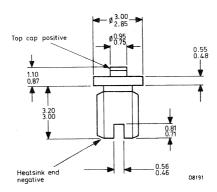
This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to MO-75



Dimensions in mm





Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stq}		-55 t	to +150	οС
Operational stud temperature (note 1)	T _{stud}	max.		70	оС
Transient supply voltage (note 2)		max.		6.0	V
Continuous supply voltage	V	max.		note 3	
Input power (note 3)	Pin	max.		4.0	W
CHARACTERISTICS (T _{amb} = 25 °C)					
		min.	typ.	max.	
Operating voltage (notes 2 and 3)	V	_	3.5	5.0	V
Operating current (note 4)	I _{dc}		0.8	1.1	Α
Threshold current		_	_	1.6	Α
Operating frequency (note 5)	f	30	34	38	GHz
Output power (note 6) CXY24A CXY24B	P _{out}	25 50	30 60	_	mW mW

- 1. Good thermal conductivity is essential between the heatsink **e**nd of the device and the cavity.
- Bias must be applied in such a way that the heatsink end of the device is always negative.
 Reversing the polarity may cause permanent damage. Care should be taken to protect the device against transient voltages.
- Each device is supplied with a maximum supply voltage recommendation for continuous operation, within the limits of operating voltage and input power specified above.
- The power supply should be low impedance, voltage regulated and capable of supplying current in excess of the threshold current.
- 5. The frequency is governed by the choice of cavity to which the device is coupled.
- Output power is normally measured in a waveguide cavity at a frequency of 34 GHz, at a voltage not exceeding the maximum recommended supply voltage (note 2) and at a stud temperature of 25 °C.



MIXER AND DETECTOR DIODES

C



MICROWAVE MIXER/DETECTOR DIODES

Silicon Schottky barrier beam-lead diodes for use as low noise mixer or low level detector in hybrid integrated circuits.

The production process ensures exceptionally uniform characteristics and very low parasitic capacitance.

Matched pairs are available as 2-BAS22, 2-BAS23, 2-BAS24 and 2-BAS25. These are produced as adjacent pairs on the wafer, to ensure very accurate matching.

QUICK REFERENCE DATA

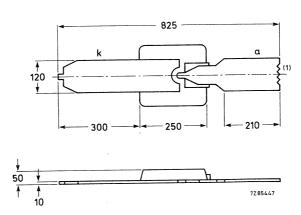
Frequency range	f		1 to 18	GHz
Noise figure	N_{o}	typ.	5.7	dB
Tangential sensitivity	S_{ts}	typ.	-55	dBm

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — ${\tt MICROWAVE}$ SEMICONDUCTORS

MECHANICAL DATA

Dimensions in μm

Fig.1



(1) Identification

one notch = BAS22 two notches = BAS23 three notches = BAS24 four notches = BAS25

The maximum lead pulling forces should not exceed 20 mN

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Continuous reverse voltage	BAS22 BAS23 to 25	V _R	max. max.	3.5 4.0	V
Non-repetitive peak forward current ($t \le 1s$)		IFSN	nax.	150	mA
Storage temperature		T _{stq}	•	to +150	οС
Junction temperature		Ti	max.	150	оС
Soldering temperature (t_{sld} < 10 s)		T _{sld}	max.	230	oC
CHARACTERISTICS					
$T_{amb} = 25 {}^{\circ}C$	BAS22 B	AS23	BAS24	BAS25	
Reverse breakdown voltage					

Lead inductance	L _s	typ.	0.1	0.1	0.1	0.1	nΗ
Series resistance	rs	typ.	12	8	6	4.5	Ω
Parasitic capacitance	c_p	typ.	0. 0 3	0.04	0.05	0.07	рF
Total capacitance (note 1) V _R = 0.5 V; f = 1 MHz	C_{tot}	> <	0. 0 8 0.12	0.12 0.16	0.16 0.20	0.24 0.32	pF pF
Forward voltage I _F = 1 mA	V _F	<	0.55	0.50	0.50	0.50	٧
$I_R = 10 \mu\text{A}$	V(BR)	R >	3.5	4.0	4.0	4.0	V

Frequency range	f		1 to 18	GHz
Noise figure (note 2)	N_{o}	typ.	5.7	dB
Intermediate frequency impedance	z_{if}		200 to 400	Ω
Tangential sensitivity (note 3)	s_{ts}	typ.	–55	dBm

- 1. The two devices of a matched pair have a capacitance difference \leq 0.01 pF.
- 2. S.S.B. operation, measured at 9.375 GHz, local oscillator power 1 mW including N_{if} = 1.5 dB, f_{if} = 30 MHz.
- 3. Measured at 9.375 GHz with 2 MHz video bandwidth and 50 μ A forward bias current.

HANDLING INSTRUCTIONS

The beam lead diodes require careful and considerate handling during inspection, testing, and assembly so that they will not be mechanically or electrically damaged. The diodes are very small. Magnification is necessary to view them inside the shipping container.

The diodes are shipped in a flat, plastic container. The inside bottom surface of the container is coated with a thin layer of silicone to which the diodes adhere. They are covered with anti-static silk. A vacuum pickup is recommended for removing them from the container. This should be done under 20 x magnification for accurate positioning of the tip on the die

A beam lead diode can be destroyed electrically by a static discharge through the diode. Hence, they must be handled so that static discharges cannot occur.

If a vacuum pickup is not used, it is recommended that a wooden toothpick or sharpened Q-tip dipped in alcohol be used as a handling probe. A diode will adhere to the end of the wooden probe without danger of mechanically or electrically damaging the diode. It can then be placed where required.

BONDING RECOMMENDATIONS

Beam lead devices are silicon chips with coplanar plated gold tabs that extend parallel to the top surface of the chip. The leads are mounted by thermocompression bonding to the substrate metallization. The bonding is accomplished by placing the device face down with the tabs resting flat on the pad area and using heated wedge (and/or substrate) or parallel-gap (spot-welding) techniques.

The heated wedge may be continuously heated, as in most standard equipment, or it may be pulse resistance heated where a high current, short duration pulse is used to raise the wedge to the required temperature. In the spot-welding operation, current is passed through the substrate metallization and the device lead. Most of the heat is generated at the interface between the two, where the bond is formed.

The major advantage of pulse heating is that it generates only localized heating in the vicinity of the bond. The electrodes (or wedge) can be placed on the device lead while the bond area is cold, and maintain a constant force through the heating and cooling cycle.

OPERATING NOTES

Care must be taken when making measurements that the precautions described in the operating notes are observed and that test equipment does not introduce transients.

- 1. The diode has a low junction capacitance and may be damaged by transients of very short duration. It is therefore recommended that soldering irons are isolated from the mains supply when making soldered connections to the diode.
- 2. Precautions similar to those required for CMOS devices are necessary namely:
 - (a) Earthed wrist straps should be worn.
 - (b) Table tops or other working surfaces should be conductive and earthed.
 - (c) Anti-static clothing should be worn.
 - (d) To prevent the development of damaging transient voltages, the device should not be inserted or removed from the user's circuit with the d.c. power applied.



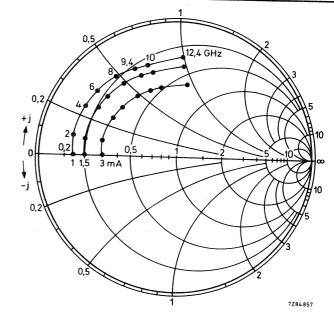


Fig.2 Admittance characteristics. Typical values; self bias

BAS23; 2-BAS23

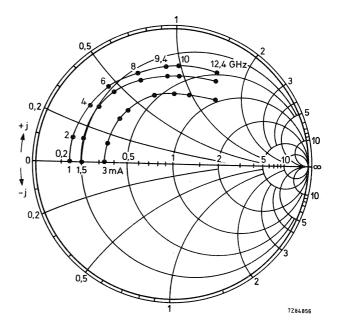


Fig.3 Admittance characteristics. Typical values; self bias.



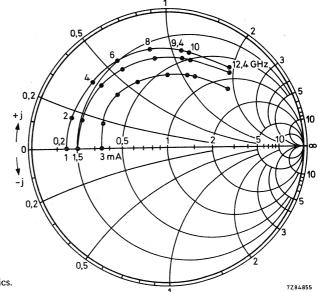


Fig.4 Admittance characteristics. Typical values; self bias.

BAS25; 2-BAS25

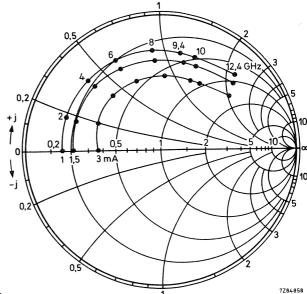


Fig.5 Admittance characteristics. Typical values; self bias.



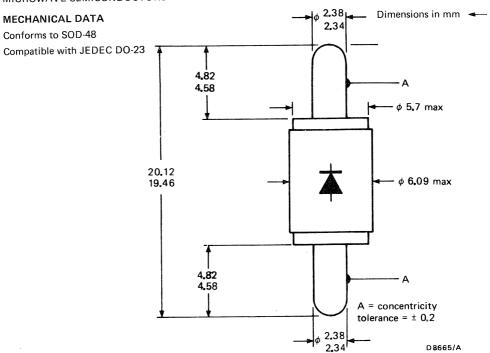
X-BAND MIXER/DETECTOR DIODE

Silicon Schottky barrier diode in DO-23 outline specially designed for use in Doppler radar systems and intruder alarms where low 1/f noise and high sensitivity are required. May be used for both mixer and detector applications. This device is a direct replacement for the BAV46 and has an all-bonded structure capable of withstanding higher shock levels and wide temperature excursions during operation and storage.

QUICK REFERENCE DATA

Mixer mode			
Voltage output for -90 dBm input power at X-band	typ.	40	μV
1/f noise in the bandwidth 1 Hz to 1 kHz from carrier	typ.	1.0	μV
Detector mode			
Tangential sensitivity in bandwidth 0 to 2 MHz	typ.	-55	dBm

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS



Terminal identification: diode symbol indicates polarity

Accessory: collet type 56321 (see page 4) converts BAS46 to JEDEC DO-22 outline.





' RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Storage temperature range	T_{stg}	-55 to +125		оС
Ambient temperature range for operation	T _{amb}	55 1	to +125	οС
_Ŕeverse voltage	VR	max.	2	V
Forward current	1F	max.	10	mA
CHARACTERISTICS (T _{amb} = 25 °C)				
Forward voltage at I _F = 1 mA	V_{F}	typ.	0.5	V
Reverse current at V _R = 2 V	IR	max.	2	μΑ
Mixer mode				
Voltage output at X-band (notes 1 and 2)	V_{o}	min.	15	μV
1	V_{o}	typ.	40	μV
¹ / _f noise (note 3)	Nf	typ.	1.0	μV
	N _f	max.	2.0	μV
Detector mode				
Tangential sensitivity (note 4)	S _{ts}	min.	-52	dBm
	Sts	typ.	-55	dBm
Video impedance (note 5)	Z_V	typ.	850	Ω

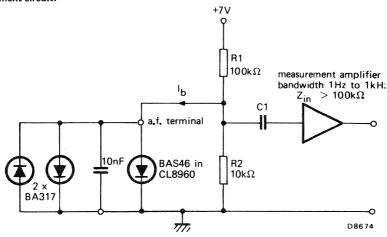
Notes

- 1. Mixer operated with d.c. bias of 35 μ A and r.f. bias of -18 dBm, giving a total bias of 42 μ A.
- 2. Measurement made using CL8960 doppler radar module, output power 10 mW (typ.). The input power to the mixer of -90 dBm is a signal 100 dB down on the output power from a typical CL8960 with signal + noise at 18 dB (min.)

A return signal, 100 dB down on radiated power, is equivalent to that achieved from a man target of radar cross-section 1.0 $\rm m^2$ at a range of 15 m when operating the CL8960 with a 5 dB antenna.

3. Other encapsulations may be made available on request.

Measurement circuit:



- N.B. a) The current I_b should be approximately 35 μ A with the Gunn device disconnected and approximately 42 μ A with the Gunn device operational and the antenna operating into free space, using the mounting recommended in the CL8960 data.
 - The coupling capacitor C₁ should have a small impedance compared with Z_{in}. See measurement circuit above.
- 3. Noise measured in the bandwidth 1 Hz to 1 kHz from carrier with a d.c. bias of 50 μ A.
- 4. Bandwidth 0 to 2 MHz and a forward bias of 50 μ A.
- 5. Measured with a forward bias of 50 μ A.

OPERATING NOTES

Care must be taken when making measurements that the precautions described in the operating notes are observed and that test equipment does not introduce transients.

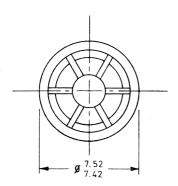
- The diode has a low junction capacitance and may be damaged by transients of very short duration. It is therefore recommended that soldering irons are isolated from the mains supply when making soldered connections to the diode.
- 2. Precautions similar to those required for CMOS devices are necessary namely:
 - (a) Earthed wrist straps should be worn.
 - (b) Table tops or other working surfaces should be conductive and earthed.
 - (c) Anti-static clothing should be worn.
 - (d) To prevent the development of damaging transient voltages, the device should not be inserted or removed from the user's circuit with the d.c. power applied.
- 3. It is recommended that the user incorporates a diode protection circuit. A suitable circuit consists of two BA317 diodes connected in parallel but with one diode reversed, together with a parallel 10 nF capacitor. This circuit should be connected in close proximity to the diode terminals and has been found to afford a suitable degree of protection.
- 4. A d.c. bias level of at least 30 μ A must be maintained to ensure adequate mixer performance.

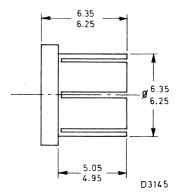


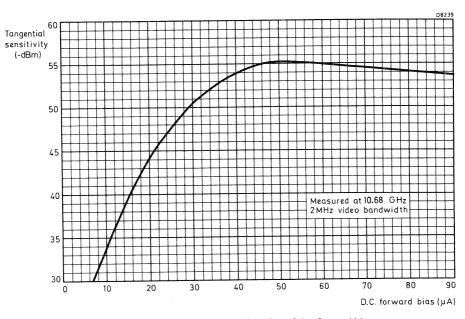
COLLET 56321

Dimensions in mm

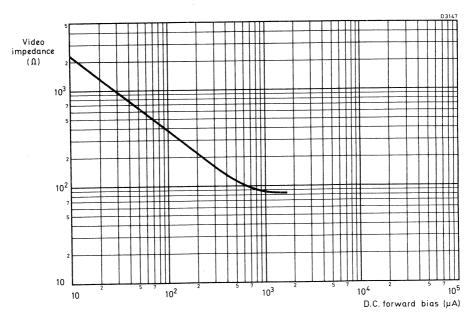








Typical tangential sensitivity as a function of d.c. forward bias.



Typical video impedance as a function of d.c. forward bias





MICROWAVE MIXER/DETECTOR DIODE

Silicon Schottky barrier diode for use as a low level detector or as a low noise mixer at microwave frequencies. The diode is plastic encapsulated with ribbon leads suitable for mounting in stripline circuitry and conforms to the environmental requirements of BS9300 where applicable. Available as a matched pair 2/BAT10 M.

QUICK REFERENCE DATA

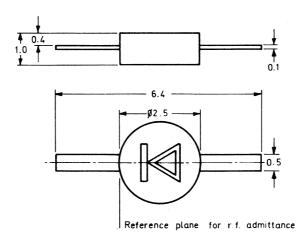
Frequency range		1 to 12	GHz
Mixer: Noise figure in X-band	typ.	7.0	dB
Detector: Tangential sensitivity in X-band with 100 μA bias	typ.	-50	dBm
Current sensitivity in X-band with 50 μA bias	typ	5.0	$\mu A/\mu W$

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to MO-28

Dimensions in mm



D3108

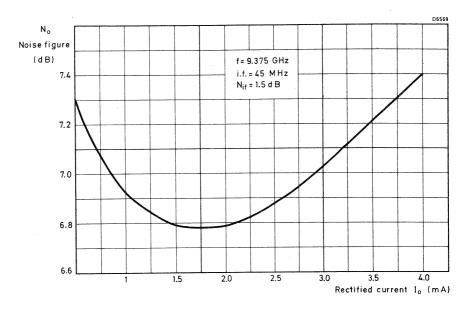


Limiting values in accordance with the Absolute Maximum System (IEC134)

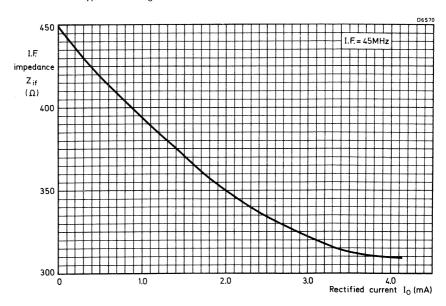
Storage temperature range			-55 to	+150	oC
Ambient temperature range			−55 to	+150	oC
Peak pulsed r.f. input power at 9.375 GHz, 0.5 μs	pulse length	max.		1.0	W
Burn out (multiple r.f. spike, $\Delta N_0 = 1$ dB)		max.		20 0.2	nJ erg
CHARACTERISTICS (T _{amb} = 25 °C)					
Mixer			typ.	max.	
Noise figure (note 1)	No		7.0	7.5	dB
Voltage standing wave ratio (note 2)	v.s.w.r.		_	2:1	
Intermediate frequency impedance (note 3)	Z _{if}		_	500	Ω
Detector					
Tangential sensitivity (note 4)	S _{ts}		-50	_	dBm
Current sensitivity (note 5)	s _i		5.0	_	$\mu A/\mu W$
Voltage standing wave ratio (note 6)	v.s.w.r.			5:1	
Video impedance (note 7)	z_{v}		600	-	Ω
Noise	1/f		12	17	dB

- 1. Measured in a 50 Ω test mount at f = 9.375 GHz, rectified current = 2.0 mA, load resistance = 20 Ω , i.f. = 45 MHz and i.f. noise figure = 1.5 dB. BS9300.
- 2. Measured with respect to 50 Ω at f = 9.375 GHz, rectified current = 2.0 mA and load resistance = 10 Ω . BS9300.
- 3. Measured in a 50 Ω test mount at f = 9.375 GHz, rectified current = 2.0 mA, load resistance = 20 Ω and i.f. = 45 MHz. BS9300.
- 4. Measured at f = 9.375 GHz with 2.0 MHz bandwidth and 100 μ A bias.
- 5. Measured at f = 9.375 GHz at an input power of 1.0 μ W and 50 μ A bias.
- 6. Measured with respect to 50 Ω at f = 9.375 GHz, 100 μ A bias and c.w. input less than 2.0 μ W. BS9300.
- 7. D.C. measurement with 1.0 mV max. and 50 μ A bias.
- 8. Other encapsulations may be made available on request.
- 9. Matched pairs of diodes are available to customer specifications.

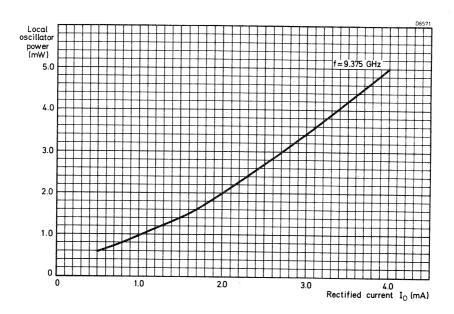




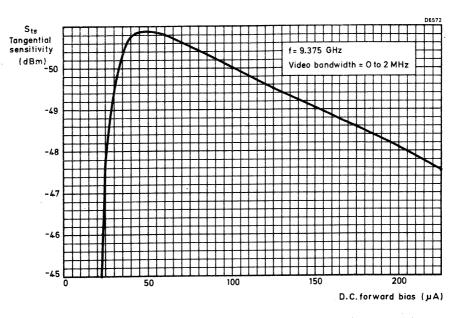
Typical noise figure as a function of rectified current (as a mixer)



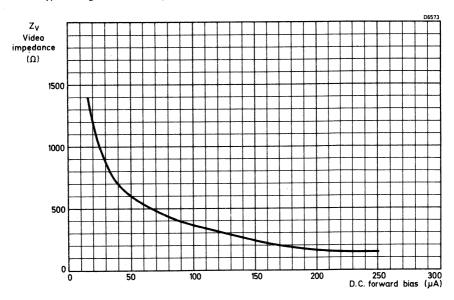
Typical i.f. impedance as a function of rectified current (as a mixer)



Typical local oscillator power as a function of rectified current (as a mixer)

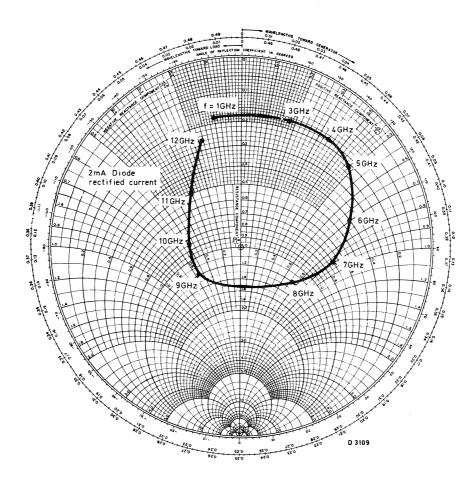


Typical tangential sensitivity as a function of d.c. forward bias current (as a detector)



Typical video impedance as a function of d.c. forward bias current (as a detector)





Typical admittance as a function of frequency

Silicon Schottky barrier low noise mixer diode mounted in a L.I.D. type envelope. Primarily intended for hybrid integrated circuit applications in X-band. It conforms to the environmental requirements of BS9300 where applicable. Available as a matched pair 2/BAT11M.

QUICK REFERENCE DATA

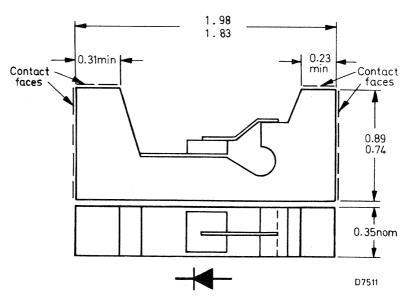
Frequency range		up to 12	GHz
Noise figure in X-band	typ.	6.5	dB

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm

Conforms to MO-27



Contact faces are gold plated, 5 μ m over 1.27 μ m of nickel.

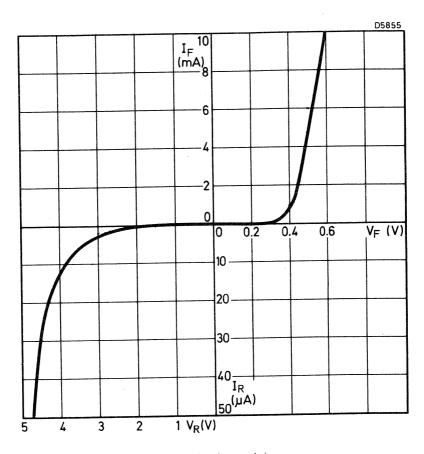
Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stg}		-55 to +	150	oC
Ambient temperature range	Tamb		-55 to +	-150	oC
Burn-out (r.f. spike)		max.		20 0.2	nJ erg
Burn-out (multiple d.c. spike)		max.		30	nJ
CHARACTERISTICS (T _{amb} = 25 °C)					
•		min.	typ.	max.	

Dynamic					
Noise figure (note 1)	N_{o}	_	6.5	7.0	dB
Voltage standing wave ratio	v.s.w.r.	_		2:1	
Intermediate frequency impedance (note 3)	z_{if}	280	320	380	Ω
Operating frequency range	f	_		12	GHz

Notes

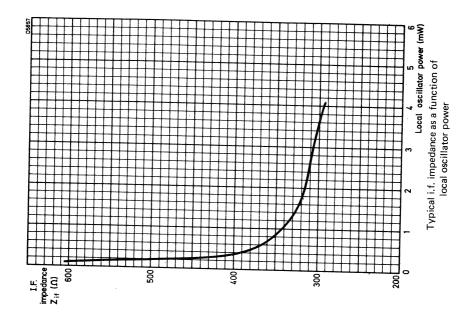
- 1. Measured at 9.375 GHz \pm 0.1 GHz, 1.5 mA rectified current, R_L = 15 Ω . N_O includes N_{if} = 1.5 dB with 45 MHz intermediate frequency. BS9300, method 1406.
- 2. Measured at 9.375 GHz \pm 0.1 GHz, 1.5 mA rectified current, R_L = 15 Ω . BS9300, method 1409.
- 3. Measured at 9.375 GHz \pm 0.1 GHz, 1.5 mA rectified current, R_L = 15 Ω , intermediate frequency 45 MHz.BS9300 method 1405,
- 4. Maximum out of balance for a matched pair:
 - a) 0.1 mA rectified current.
 - b) R.F. admittance 1.5:1 with other diode normalized to 50 Ω .
- 5. The diode may be mounted on microstrip, using conventional thermocompression or micro-gap bonding techniques. Alternatively, the application of a single loaded epoxy, such as Epotek H40, may be used, followed by polymerisation at 150 °C for 15 minutes. The force applied to the L.I.D. must not exceed 147 mN (15 gf).
- 6. Devices may be specially selected with the r.f. impedance measured at a customer's specific frequency in the range 8.4 to 12 GHz.
- 7. Other encapsulations may be made available on request.
- 8. The diode is available, on request, with a protective coating of gel around the mechanically sensitive part of the device.

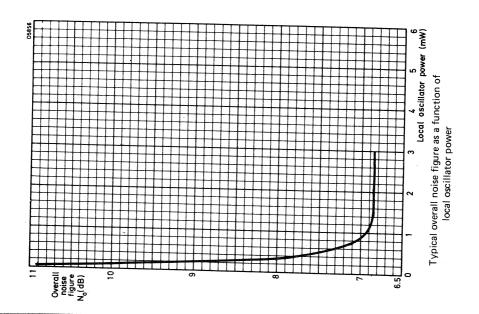


Typical d.c. characteristic









Subminiature silicon Schottky barrier mixer diode for use at Q-band (Ka-band) frequencies. Where applicable, this device conforms to the environmental requirements of BS9300. It can be supplied to NATO stock No. 5691-99-038-0540.

QUICK REFERENCE DATA

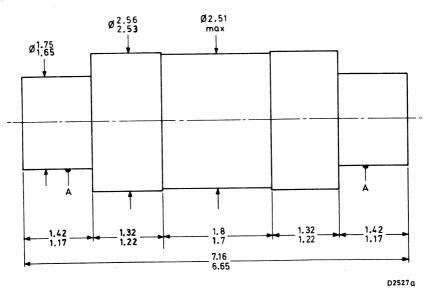
		00 : 10	011-
Frequency range		26 to 40	GHz
Noise figure	typ.	8.5	dB
110,00			

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm

Conforms to SOD-42



 $AA = concentricity tolerance = \pm 0.15$

The cathode (positive) is marked red.

The cathode indicates the electrode which becomes positive in an a.c. rectifier circuit.

Limiting values in accordance with the Absolute Maximum System (IEC134)

Burn-ou	ıt
---------	----

R.F. spike	max.	0.04	ora
Peak pulse power ($t_p = 0.2 \mu s$)	max.	0.04	erg
reak pulse power (tp = 0.2 μs)	max.	0.5	W
The late against the second se			

The devices are 100% burn-out screened to the above specifications at 34 GHz.

Temperature

Storage temperature	T _{sta}	-55 to +100	οс
Ambient temperature	T _{amb}	-55 to +100	°C

- CHARACTERISTICS T

lo.	may	2.0	^
•			μΑ
'F	*******	2.0	mA
No	typ.	8.5 10	dB dB
La			· dB
<u>-</u> C	typ.	5.5	· ub
Nr		1 6 - 1	
'		1.0.1	
	typ.	1.4:1	
v.s.w.r.	max.	2.0:1	
_	typ.	900	Ω
∠if	700	to 1100	Ω
	IR IF No Lc Nr v.s.w.r.	No typ. max. Lc typ. Nr v.s.w.r. typ. max.	N _O typ. 8.5 max. 10 L _C typ. 5.5 N _r 1.6:1 v.s.w.r. typ. 1.4:1 max. 2.0:1

f

GHz

26 to 40

MATCHED PAIRS

Operating frequency range

The diodes can be supplied in matched pairs under the type number 2/BAT38M. The diodes are matched to $\pm 10\%$ on rectified current and within 150 Ω i.f. impedance.

^{*} Standard test holder.



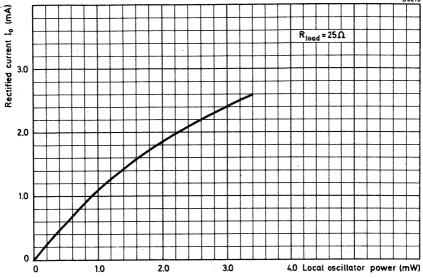


Fig.2 Typical rectified current as a function of local oscillator power at 34.86 GHz

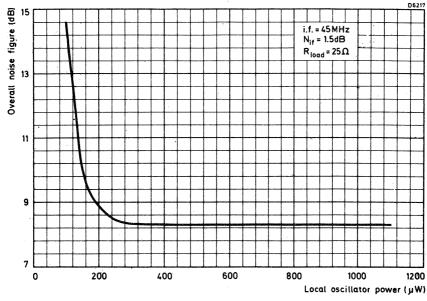


Fig.3 Typical overall noise figure as a function of local oscillator power at 34.86 GHz



Subminiature silicon reversible Schottky barrier diode primarily intended for low noise mixer applications in X-band. It is intended as a retrofit for AAY39 and CV7762. Available as a matched pair as 2/BAT39M. Can be supplied to NATO stock No. 5961-99-037-5207.

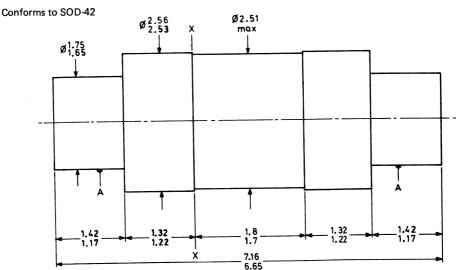
QUICK REFERENCE DATA

Operating frequency range		1.0 to 18	GHz	
Noise figure at X-band	typ.	6.0	dB	

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm



XX = reference plane

All dimensions in mm

D2527 a

 $AA = concentricity tolerance = \pm 0.15$

Terminal identification:

The BAT39 is colour coded as follows:

That is: the positive end (cathode) is marked red and the negative end (anode) is marked blue. The positive end indicates the electrode which becomes positive in an a.c. rectifier circuit.

ACCESSORIES

WG16 holders to fit these diodes are available in the U.K. from Marconi Instruments Ltd., (Sanders Division), Gunnels Wood Road, Stevenage, Herts.



Limiting values in accordance with the Absolute Maximum System (IEC134)

T	21	nı	۱۵	ra	tı.	re
	7 I	11	,,	ıα	ιu	: 0

romporataro					
Storage temperature range		T_{stg}	55	to +100	οс
Ambient temperature range		T _{amb}		to +100	οС
Burn-out (f = 9.375 GHz)					
•					
Multiple d.c. spike		ma	ax.	0.1	erg
Multiple r.f. spike (spike width at half peak power = 2μ	ıs)	ma	ax.	0.05	erg
Peak pulse power					
$f = 9.375 \text{ GHz}, t_p = 1.0 \ \mu\text{s}$		ma	ıx.	0.5	w
CHARACTERISTICS (T _{amb} = 25 °C)					
		min.	typ.	max.	
Reverse current V _R = 0.5 V	۱ _R			2.0	μA
Forward current $V_F = 0.5 V$	۱F		7.0	_	mA
Overall noise figure					
f = 9.375 GHz, R_L = 15 Ω , rectified current = 1.0 mA, N_O includes N_{if} = 1.5 dB. BS9300, method 1406	N				
	No	5.5	6.0	6.5	dB
Conversion loss	L_{c}	M7004	4.2	_	dB
Noise temperature ratio					
I.F. = 45 MHz. BS9300, method 1407	N_r		1.1:1		
Voltage standing wave ratio					
F = 9.375 GHz, R _L = 15 Ω , rectified current = 1.0 mA. BS9300, method 1409					
Measured in standard test holder	v.s.w.r.	_	1.4:1 : 2	2.0:1	
Intermediate frequency impedance					
f = 9.375 GHz, R _L = 15 Ω , rectified current = 1.0 mA. BS9300, method 1405	Z _{if}	250	_	450	Ω
Opposition for	•				
Operating frequency range	f	1.0	-	18	GHz

OPERATING NOTE

Optimum performance is obtained when the local oscillator drive is adjusted to give a diode rectified current of 1.0 mA and the load resistance is restricted to 100 Ω max.

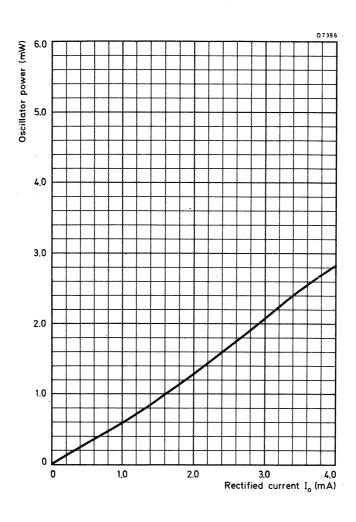
NOTE

Matched pairs of diodes are available to customer specifications.

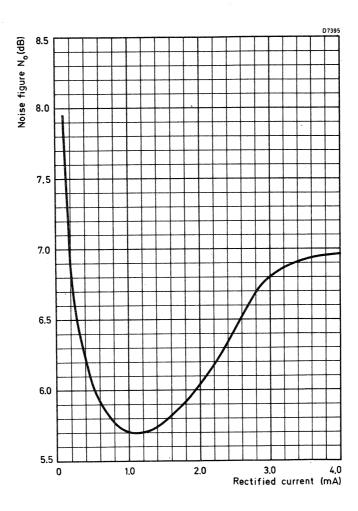


APPLICATION INFORMATION				
Mixer performance at other than Test Radio Frequency				
Measured overall noise figure $f=16.5~GHz$, $N_{\dot{1}\dot{f}}=1.5~dB$, i.f. = 45 MHz $f=3.0~GHz$, $N_{\dot{1}\dot{f}}=1.5~dB$, i.f. = 45 MHz $f=9.5~GHz$, i.f. = 3.0 kHz	N _o N _o N _o	typ. typ. typ.	7.0 5.5 29	dB dB dB
Signal/flicker noise at 9.5 GHz				
Measured at 2.0 kHz from carrier in a 70 Hz bandwidth		typ.	131	dB
Detector performance Tangential sensitivity at 9.375 GHz, 1 kHz to 1 MHz video bandwidth, I_F (bias) = 50 μ A (BS9300/1411)	S _{ts}	typ.	– 52	dBm
A.C. video impedance				
I_E (bias) = 50 μ A (BS9300/1403)	Z_r	typ.	800	Ω



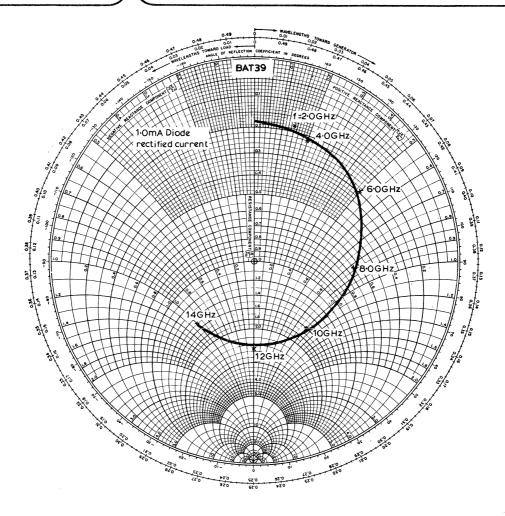


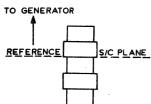
Typical rectified current as a function of local oscillator power



Typical noise figure as a function of rectified current







Typical r.f. admittance as a function of radio frequency Admittance with respect of 1/50 mho. Measured in 50Ω coaxial line.

Coaxial silicon Schottky barrier diodes for use in pre-tuned X-band low noise mixer circuits. They are intended for use as low noise retrofits at X-band frequencies for coaxial mixer diodes types AAY50, AAY50R etc. The two types have identical dimensions and characteristics but the polarity is reversed. Available as a matched pair as 2/BAT50MR. The pair are intended for use in balanced mixer circuits and conform to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

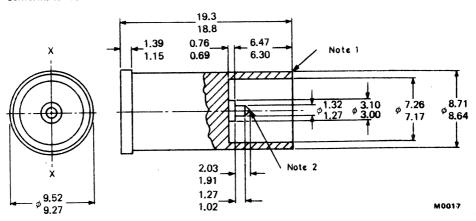
Operating frequency		max.	12	GHz
Noise figure		typ.	6.2	dB

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm

Conforms to MO-74



Terminal identification

BAT50 Pin cathode BAT50R Pin anode Body (red spot) anode Body (green spot) cathode

ACCESSORIES

Holders to fit these coaxial diodes are available in the U.K. from Marconi Instruments (Sanders Division) Gunnels Wood Rd., Stevenage, Herts.



Note 1 The device is designed to make contact on this open face.

Note 2 Cone tapers to a radius of 0.13 mm nominal.

Limiting values in accordance with the Absolute Maximum System (IEC134)

Temperature

: omperatore				
Storage temperature range	T_{stg}		-55 to +100	оС
Ambient temperature range	T _{amb}		-55 to +100	оС
Burn-out				
R.F. spike		max.	0.2	erg
Peak pulse power ($t_p = 0.5 \mu s$)		max.	1.0	W
CHARACTERISTICS (T _{amb} = 25 °C)				
 Reverse current (V _R = 0.5 V)	IR	max.	2.0	μΑ
 Forward current (V _F = 0.5 V)	I _E	min.	2.0	mA
Overall noise figure (note 1) f = 9.375 GHz, rectified current = 1.0 mA, R_L = 15 Ω , N_O includes N_{if} = 1.5 dB	No	typ. max.	6.2 6.8	dB dB
Conversion loss	L _c		4.4	dB
Noise temperature ratio 1.F. = 45 MHz	Nr		1.1:1	
 Voltage standing wave ratio (notes 1 and 2) f = $9375 \pm 10\%$ MHz, rectified current 1.0 mA R _L = 15Ω , N _O includes N _{if} = $1.5 dB$	v.s.w.r.	typ.	1.4:1	
ii Taran ay		max.	2.0:1	
Intermediate frequency impedance	Z _{if}	min. max.	300 500	$\Omega \ \Omega$
Operating frequency range	f	max.	12	GHz

Notes

- 1. Measured in standard holder (K1007, Issue 3, Section 8B3.3.1/2).
- 2. The nominal rectifier admittance at a plane 7.01 mm inside the body from the open end is

$$\frac{1}{83.5} + \frac{j}{350}$$
 mho

OPERATING NOTE

These devices will exhibit their inherent improved noise figure performance over the frequency range 1.0 to 12 GHz, but are not recommended for use as direct replacements in pre-tuned mounts designed for the AAY50 type coaxial diode, at other than X-band frequencies.

APPLICATION INFORMATION

Signal/Flicker noise ratio f = 9.5 GHz. Measured at 2 kHz from carrier in 70 Hz bandwidth		typ.	131	dB
Detector performance				
Tangential sensitivity, f = 9.375 GHz, video bandwidth = 1.0 MHz, I _F (bias) = 50 μ A video impedance, I _F (bias) = 50 μ A	S _t Z _v	typ. typ.	-52 800	dBm Ω

NOTE

Matched pairs of diodes are available to customer specifications.



3



The BAT51 and BAT51R form a reverse pair of mixer diodes for use in balanced mixer circuits at J-band (Ku-band). They are of silicon Schottky barrier construction and are intended as retrofits for AAY51 and AAY51R, (CV7776 and CV7777). They are packaged in the standard coaxial outline for this band, similar to 1N78 types. The encapsulation is hermetically sealed and cadmium plated. The diodes conform to the environmental requirements of BS9300 where applicable and are available as a matched pair as 2/BAT51MR, (CV7778). Can be supplied to NATO stock Nos. 5961-99-037-5472 (BAT51), 5961-99-037-5473 (BAT51R) and 5961-99-037-5474 (2/BAT51MR).

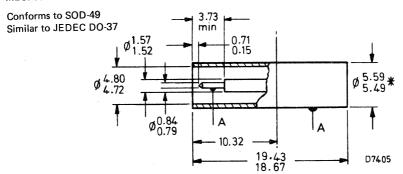
QUICK REFERENCE DATA

		10 +- 10	CII-
Frequency range		12 to 18	GHz
	tum	7.0	dB
Noise figure	typ.	7.0	ab
3			

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm



A = concentricity tolerance = ± 0.35

*These limits apply only to the 10.32 dimension

Terminal identification

cathode BAT51 Pin Body (red) anode

BAT51R

Pin

anode

Body (green) cathode



1

BAT51R

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

perature

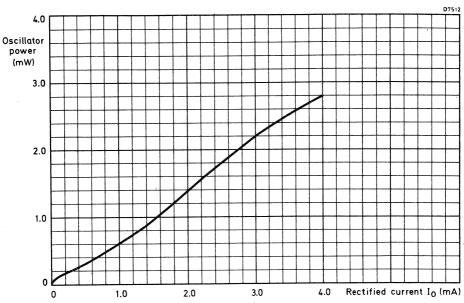
Storage temperature range	T _{stq}		-55 to +100	οс
Ambient temperature range	T _{am}		-55 to +100	°C
Burn out				
f = 9.375 GHz, multiple r.f. spike, spike width at half peak power = 2 ns		max.	0.05	ora
Peak pulse power		arti	0.03	erg
$f = 9.375 \text{ GHz}, t_p = 1.0 \mu\text{s}$		max.	0.5	w
CHARACTERISTICS (T _{amb} = 25 °C)				
 ► Reverse current V _R = 0.5 V	^I R	max.	2.0	μΑ
 Forward current V _F = 0.5 V	۱ _F	min.	2.0	mΑ
Overall noise figure f = 13.5 GHz,				
${ m N_O}$ includes ${ m N_{if}}$ = 1.5 dB Measured in JAN 201 holder. BS9300, method 1406	No	typ. max.	7.0 7.5	dB dB
Conversion loss	LC		5.2	dB
Noise temperature ratio I.F. = 45 MHz. BS9300, method 1407	N _r		1.1:1	
 Voltage standing wave ratiof = 13.5 GHz, rectified current = 0.9 mA		typ. max.	1.5:1 2.0:1	
Intermediate frequency impedance	Z _{if}	min. typ. max.	250 350 450	Ω Ω
Operating frequency range	f		12 to 18	GHz

GHz

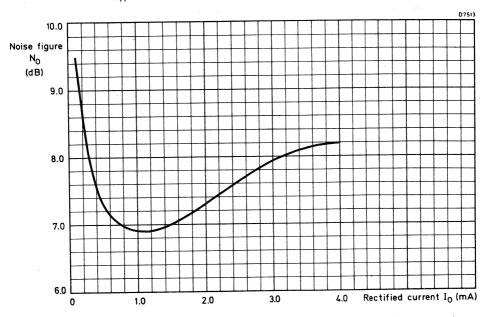
As a matched pair

Maximum unbalance conditions, $Z_{if} = 25 \Omega$, rectified current 0.1 mA.





Typical rectified current as a function of local oscillator power



Typical noise figure as a function of rectified current



The BAT52 and BAT52R form a reverse pair of mixer diodes for use in balanced mixer circuits at J-band (Ku band). The diodes are of silicon Schottky barrier construction and are intended as retrofits for AAY52 and AAY52R. They are packaged in the standard coaxial outline for this band, similar to IN78 types. The encapsulation is hermetically sealed and cadmium plated. The devices conform to the environmental requirements of BS9300 where applicable. Available as a matched pair as 2/BAT52MR.

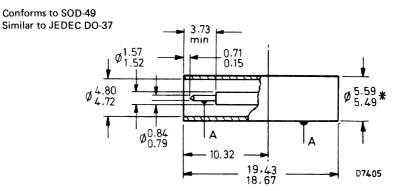
QUICK REFERENCE DATA

Frequency range	12 to 18	GHz
Noise figure	8.0	dB

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm



A = concentricity tolerance = ± 0.35

Terminal identification

BAT52

Pin

Body (red)

cathode anode

BAT52R

Pin

Body (green)

anode cathode

^{*}These limits apply only to the 10.32 dimension

BAT52 BAT52R

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

Temperature				
Storage temperature range	T_{stg}		-55 to +100	oC
Ambient temperature range	T_{amb}		-55 to +100	oC
Burn-out				
f = 9.375 GHz, multiple r.f. spike, spike width at half peak power = 2 ns		max.	0.05	erg
Peak pulse power $f = 9.375 \text{ GHz}, t_p = 1.0 \mu \text{s}$		max.	0.5	W
CHARACTERISTICS (T _{amb} = 25 °C)				
 Reverse current V _R = 0.5 V	^I R	max.	2.0	μA
 Forward current V _F = 0.5 V	۱F	min.	2.0	mA
Overall noise figure f = 13.5 GHz,				
${ m N}_{ m O}$ includes ${ m N}_{ m if}$ = 1.5 dB Measured in JAN 201 holder. BS9300, method 1406	No	typ. max.	8.0 8.5	dB dB
Conversion loss	$L_{\mathbf{C}}$		5.2	dB
Noise temperature ratio I.F. = 45 MHz. BS9300, method 1407	N _r		1.1:1	
 -Voltage standing wave ratio f = 13.5 GHz, rectified current = 0.9 mA		typ. max.	1.5:1 2.0:1	
Intermediate frequency impedance	Z _{if}	min. typ. max.	250 350 450	Ω Ω
Operating frequency range	f		12 to 18	GHz

As a matched pair

Maximum unbalance conditions, Z_{if} = 25 Ω , rectified current 0.1 mA.



Coaxial Schottky barrier diodes for use in pre-tuned X- and S-band low noise mixer circuits. The diodes are suitable as replacements for most British coaxial point contact types in these bands, for example, GEM3, GEM4, CV7108, CV7109, CV2154 and CV2155. They conform to the environmental requirements of BS9300 where applicable. Available as a matched pair as 2/BAV22MR.

QUICK REFERENCE DATA

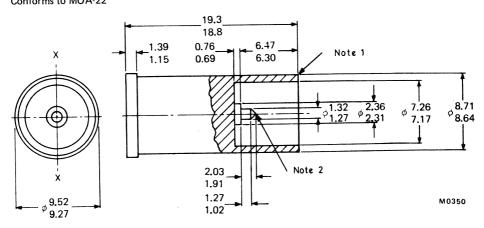
Operating frequency	max.	12	GHz
Noise figure at X-band	typ.	7.0	dB
at S-band	typ.	6.0	dB

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm

Similar to BS3934 SO-26 Conforms to MOA-22



Terminal identification

BAV22 Pin Body (red spot) cathode anode BAV22R

Pin

anode

Body (green spot) cathode

ACCESSORIES

Holders to fit these coaxial diodes are available in the U.K. from Marconi Instruments.

Note 1 The device is designed to make contact on this open face.

Note 2 Cone tapers to a radius of 0.13 mm nominal.



BAV22 BAV22R

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

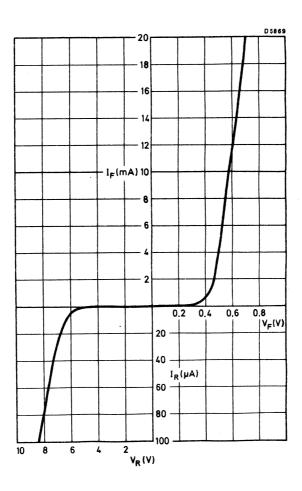
Temperature

•				
Storage temperature range	T_{stg}	-5	5 to +100	οС
Ambient temperature range	T _{amb}	-5	5 to +100	оС
Burn-out				
Multiple r.f. spikes, $\triangle N_0 = 1 \text{ dB}$		max.	0.2	erg
Peak pulse power, f = 9.375 GHz, t_p = 0.5 μ s		max.	1.0	w
CHARACTERISTICS (T _{amb} = 25 °C)				
Reverse current V _R = 2.0 V	I _R	max.	2.0	μΑ
Forward current V _F = 0.5 V	l _E	typ.	4.0	mA
Overall noise figure f = 9.375 GHz, rectified current = 1.0 mA,	•			
$R_L = 15 \Omega$, N_O includes $N_{if} = 1.5 dB$, with i.f. = 45 MHz. BS9300, method 1406.	No	typ. max.	7.0 7.5	dB dB
f = 3.0 GHz	$N_{\mathbf{o}}$	typ.	6.0	dB
Voltage standing wave ratio f = 9375 \pm 10% MHz, rectified current 1.0 mA R $_{L}$ = 15 Ω using CV2154 holder. BS9300, method 1409.	v.s.w.r.	typ. max.	1.4:1 2.0:1	
Intermediated frequency impedance f = 9.375 GHz, rectified current 1.0 mA R $_{L}$ = 15 Ω , i.f. = 45 MHz. BS9300, method 1406.		min. max.	300 550	Ω
Operating frequency range	f	max.	12	GHz

NOTE

Matched pairs of diodes are available to customer specifications.

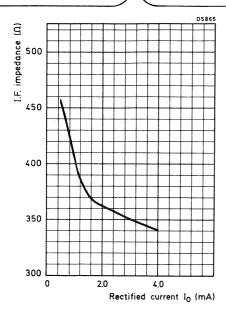




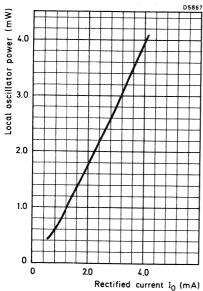
Typical d.c. characteristic



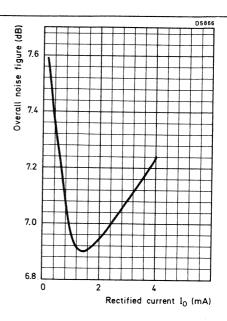




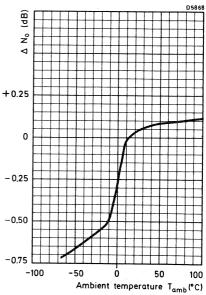
Typical i.f. impedance as a function of rectified current



Typical local oscillator power as a function of rectified current



Typical overall noise figure as a function of rectified current



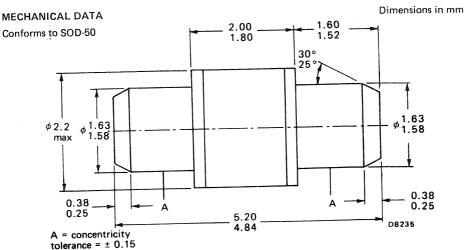
Typical change in overall noise figure as a function of temperature.

Silicon Schottky barrier mixer diode for use in low noise mixer applications in Q-band. It conforms to the environmental requirements of BS9300 where applicable and can be supplied to NATO stock No. 5961-99-038-0541. Available as a matched pair 2/BAV72M.

QUICK REFERENCE DATA

Frequency range		26 to 40	GHz	
Noise figure	typ.	8.5	dB	

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — ${\tt MICROWAVE}$ SEMICONDUCTORS



Terminal identification: red end indicates cathode



--- RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

Burn-out (r.f. spike) (note 1)			0.04	erg
Burn-out, peak pulse power		max.	0.5	W
Storage temperature range	T_{stg}		to + 100	°C
Ambient temperature range	T _{amb}		to +100	°C
CHARACTERISTICS (T _{amb} = 25 °C)				
Static				
Reverse current (V _R = 0.5 V)	I _R	max.	2.0	μΑ
Forward current ($V_F = 0.5 \text{ V}$)	1 _E	min.	2.0	mA
Dynamic				
Noise figure (note 2)	No	typ. max.	8.5 10	dB dB
Voltage standing wave ratio (note 3)	v.s.w.r.	typ. max.	1.8:1 2.0:1	
Intermediate frequency impedance (note 4)	Z _{if}	min. max.	700 1100	Ω
Frequency range	f	min. max.	26 40	GHz GHz
Conversion loss (note 5)	La	tvn	5.0	чD

Notes

1. Local oscillator frequency = 9.375 GHz, number of pulses = 6×10^{5} , pulse duration = 2 ns at half peak energy, p.r.f. = 2000 p.p.s., load resistance = 0Ω . $T_{amb} = 25 \, {}^{\circ}\text{C}$.

5.9

1.4:1

dB

typ.

typ.

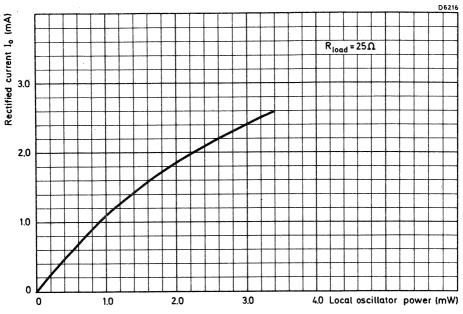
N_r

- 2. Measured with a local oscillator frequency of 34.86 GHz, I_0 = 0.5 mA, load resistance = 15 Ω , i.f. = 45 MHz. BS9300, method 1406.
- 3. Measured with a local oscillator frequency of 34.86 GHz, I_0 = 0.5 mA, load resistance = 15 Ω . BS9300, method 1409.
- 4. Measured with a local oscillator frequency of 34.86 GHz, I_0 = 0.5 mA, load resistance = 15 Ω , i.f. = 45 MHz. BS9300, method 1405.
- 5. Measured at 34.86 GHz, 450 μ W local oscillator power level and load resistance = 1 k Ω .
- 6. Measured at 34.86 GHz and i.f. = 45 MHz.

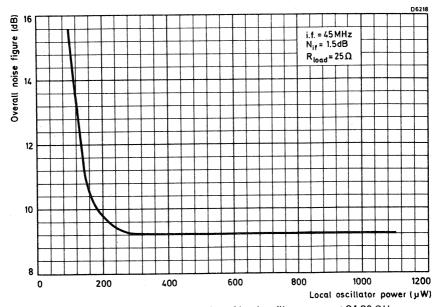
Noise temperature ratio (note 6)

- The diodes are measured in fixed tuned Q-band waveguide mounts. Details may be obtained from the manufacturer.
- 8. Matched pairs of diodes are available to customer specifications





Typical rectified current as a function of local oscillator power at 34.86 GHz



Typical overall noise figure as a function of local oscillator power at 34.86 GHz



Silicon Schottky barrier diode specially designed for use in Doppler radars where high detector sensitivity is required. It conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

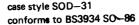
Frequency range		8 to 12	GHz
Tangential sensitivity with 100 μ A bias	typ.	50	dBm

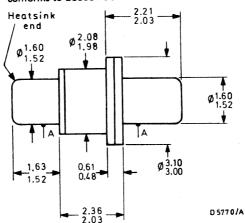
This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — ${\tt MICROWAVE}$ SEMICONDUCTORS

MECHANICAL DATA

Conforms to BS 3934 SO-86 and to SOD-31

Dimensions in mm





A = concentricity tolerance = ± 0.13

 $C_S = 0.25pF \text{ typ.}$ $L_S = 0.65nH \text{ typ.}$





Limiting values in accordance with the Absolute Maximum Rating System (IEC134)

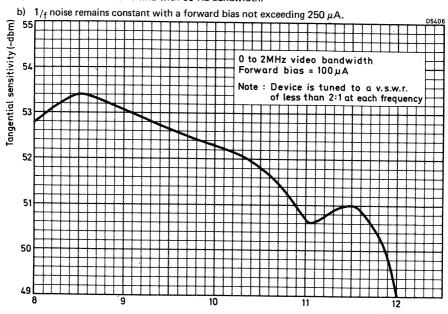
Storage temperature range		-55 to +150	οС
Ambient temperature range		-55 to +150	οС
Peak pulsed r.f. input power at 9.375 GHz, 0.5 μ s pulse length	max.	0.75	w

CHARACTERISTICS (T_{amb} = 25 °C)

		min.	typ.	max.	
Voltage standing wave ratio (notes 1, 2 and 3)	v.s.w.r.	-	1:4:1	2:1	
Video impedance (notes 4 and 5)	z_{v}	_	310		Ω
Tangential sensitivity (notes 1 and 2)	Sts	-49	-50		dBm
Flicker noise (notes 4 and 5)	1/ _f	_	10	15	dB

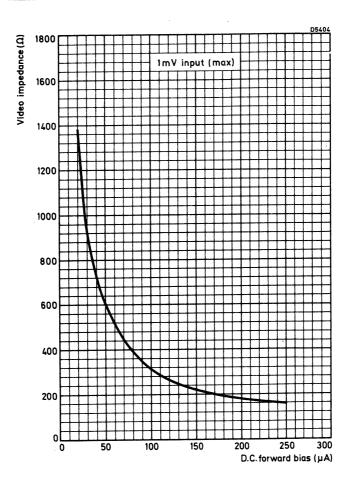
Notes

- 1. Measured at 10.687 GHz with 100 μ A forward bias.
- 2. Measured in a reduced height waveguide mount.
- 3. R.F. input power less than 5 μ W.
- 4. Measured with 100 μ A forward bias.
- 5. Maximum d.c. input voltage = 1 mV.
- 6. a) Measured at an i.f. of 1 kHz with 50 Hz bandwidth.

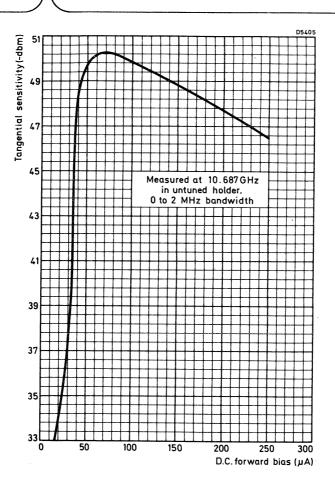


Tangential sensitivity as a function of frequency

Frequency (GHz)







MICROWAVE MIXER DIODES

A range of sub-miniature reversible low noise Schottky barrier mixer diodes. The planar technology employed imparts a high degree of reliability and reproducability. The metal-ceramic case is hermetically sealed and the devices conform to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

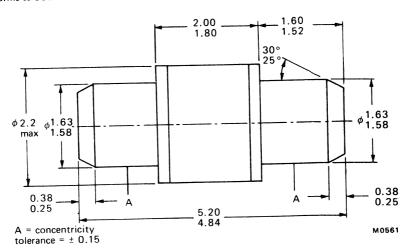
Operating frequency	max.	12	GHz
BAV96D	11162	0.0	
BAV96C	max.	6.0	dB
	max.	6.5	dB
BAV96B	max.	7.0	dB
BAV96A	max.	7.5	dB
Noise figure in X-band		75	d۵

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm

Conforms to SOD-50



Terminal identification: red end indicates cathode

Limiting values in accordance with the Absolute Maximum System (IEC134)

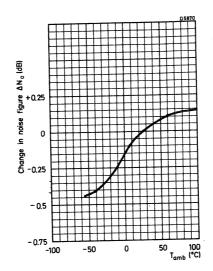
Storage temperature range	T _{stq}	-55 to +150	oC.
Ambient temperature range	T _{amb}	-55 to +150	°C
Burn-out (note 1)	max.	15	nJ

CHARACTERISTICS (T_{amb} = 25 °C)

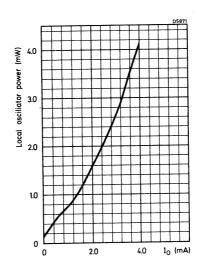
			min.	typ.	max.	
Noise figure (note 2)	BAV96A	No		7.0	7.5	dB
	BAV96B	•	_	6.5	7.0	dB
	BAV96C		-	6.0	6.5	dB
	BAV96D		-	5.5	6.0	dB
Voltage standing wave ratio (note 3)	BAV96A	v.s.w.r.		1.7:1	2.0:1	
	BAV96B		_	1.4:1	1.6:1	
	BAV96C		****	1.4:1	1.6:1	
	BAV96D			1.3:1	1.5:1	
I.F. impedance (note 4)		z_{if}	250		450	Ω
Tangential sensitivity (note 5)		Sts		E2		
Tangential sensitivity (note 6)			-	-52		dBm
rangement sensitivity (note 6)		S _{ts}		54		dBm

NOTES

- 1. Burn out is defined as the r.f. pulse energy necessary to cause 1 dB degradation in noise figure when the diode is subjected to 2×10^8 pulses of 2 ns width.
- 2. Measured at 9.375 \pm 0.1 GHz. The noise figure includes i.f. amplifier contribution of 1 .5 dB, i.f. 45 MHz, d.c. return for diode 15 Ω max., rectified current 1 mA. BS9300, method 1406.
- Measured in a reduced height waveguide mount under the same test conditions as in note 2. BS9300, method 1409.
- 4. I.F. = 45 MHz, R $_L$ = 15 $\!\Omega,$ f = 9.375 \pm 0.1 GHz, I $_0$ = 1 mA. BS9300, method 1405.
- 5. Video bandwidth 0 to 2 MHz, 30 μA bias. BS9300, method 1411.
- 6. Video bandwidth 1 kHz to 1 MHz, 30 μ A bias. BS9300, method 1411.
- 7. A suitable holder for this diode is a modified version of Sanders type 6521.

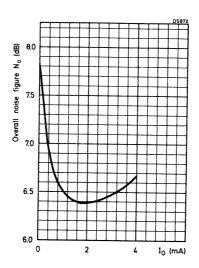


Typical change in overall noise figure as a function of temperature

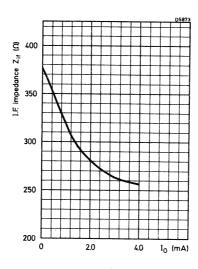


Typical local oscillator power as a function of rectified current





Typical overall noise figure as a function of rectified current



Typical i.f. impedance as a function of rectified current

A reversible silicon Schottky barrier diode with excellent sensitivity and very low 1/f noise. It conforms to the environmental requirements of BS9300 where applicable. The metal-ceramic case is hermetically sealed.

QUICK REFERENCE DATA

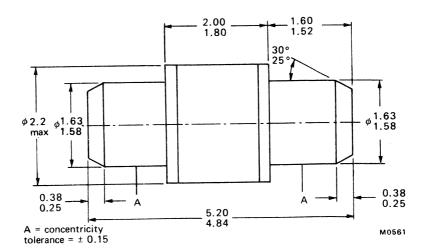
Operating frequency	f	max.	12	GHz
Tangential sensitivity	S _{ts}	typ.	54	dBm
1/f noise	N _f	typ.	10	dB

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-50

Dimensions in mm



Terminal identification:

The positive end (cathode) is marked red.



Limiting values in accordance with the Absolute Maximum System (IEC134)

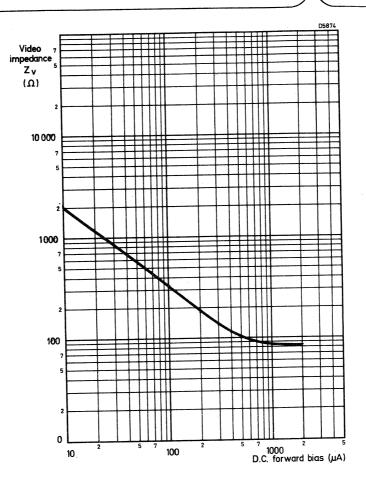
Temperature

Storage temperature range Ambient temperature range	T _{stg} T _{amb}		55 to		oC oC
Burn-out	amb		00 10	. 100	
Burn-out (note 1)		max.		18 0.18	nJ erg
CHARACTERISTICS (T _{amb} = 25 °C)	•				
		min.	typ.	max.	
Tangential sensitivity (note 2)	S _{ts}	-52	-54	-58	dBm
1/f noise (note 3)	N _f	_	10	15	dB
Video impedance (note 4)	Z_{v}		500	_	Ω

Notes

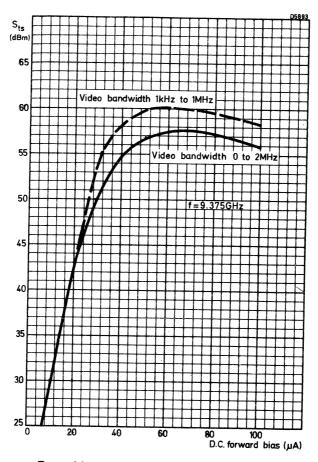
1. Burn-out is defined as the r.f. pulse energy necessary to cause 1 dB degradation in noise figure when the diode is subjected to 2×10^8 pulses of 2 ns width.

- 2. Video bandwidth 0 to 2 MHz, 50 μ A bias, f = 9.375 GHz. BS9300, method 1411. (A 2 dBm improvement in tangential sensitivity may be obtained by limiting the bandwidth to 1 kHz to 1 MHz).
- 3. Measured at 30 μ A bias, f = 1 kHz, 50 Hz bandwidth. 1/f noise is unchanged with values of bias up to 150 μA.
- 4. Measured at 50 μ A forward bias.



Video impedance as a function of d.c. forward bias





Tangential sensitivity as a function of d.c. forward bias.

MICROWAVE MIXER DIODES

A range of silicon Schottky barrier mixer diodes in reversible cartridge outline. The diodes are suitable as replacements for the 1N23 and 1N415 series and conform to environmental requirements of BS9300 where applicable.

Unless otherwise stated, data is applicable to all types.

QUICK REFERENCE DATA

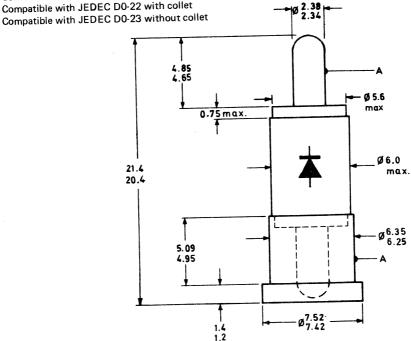
Noise figure at X-band	BAW95D BAW95E BAW 9 5F BAW95G	N _o	max. max. max. max.	8.2 7.5 7.0 6.5	dB dB dB dB

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm

Conforms to SOD-47 Compatible with JEDEC D0-22 with collet



 $A = concentricity tolerance = \pm 0.2$

Terminal identification:

Diode symbol indicates polarity

D4868

BAW95D BAW95F BAW95E BAW95G

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

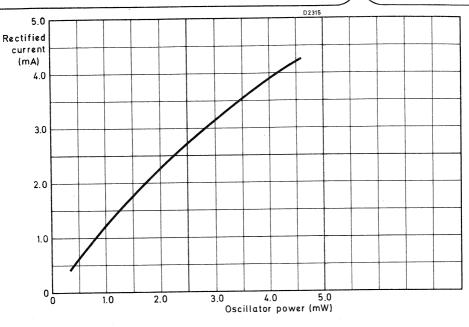
Temperature

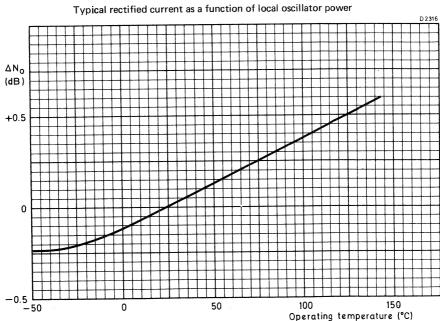
Storage temperature ra	ange	T _{stg}		5·	5 to +150	οс
Ambient temperature	range	T _{amb}			5 to +150	°C
Burn-out						
Burn-out (note 1)			max.		20	nJ
Peak pulse power	0.5				0.2	erg
f = 9.375 GHz, t _p =			max.		1.0	W
CHARACTERISTICS	(T _{amb} = 25 °C)					
Naiss firm ()	5		min.	typ.	max.	
Noise figure (note 2)	BAW95D	No	_	7.8	8.2	dB
	BAW95E BAW95F		-	7.2	7.5	dB
	BAW95G			6.8	7.0	dB
			_	6.3	6.5	dB
Voltage standing wave	ratio (note 3)	v.s.w.r.		manus.	1.3:1	
Intermediate frequency	/ impedance (note 4)	Z_{if}	250	415	500	0

Notes

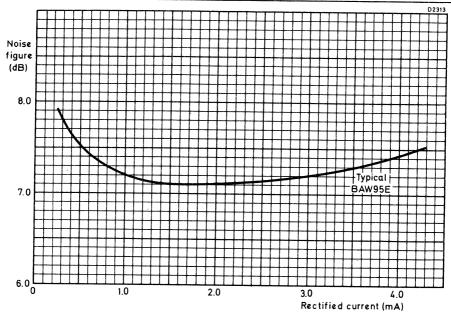
- Burn-out is defined as the r.f. pulse energy necessary to cause 1 dB degradation in noise figure when the diode is subjected to 2 x 10⁸ pulses of 2 ns width.
- 2. Measured at 9.375 GHz, 1 mA rectified current, R $_L$ = 15 $\Omega.\,$ No includes N $_{if}$ = 1.5 dB with 45 MHz intermediate frequency. BS9300, method 1406.
- 3. With respect to JAN-106 holder measured at 9.375 GHz, 1 mA rectified current, R $_{L}$ = 15 Ω_{\cdot} BS9300, method 1409.
- 4. Measured at 9.375 GHz, 1 mA rectified current, R $_{L}$ = 15 Ω with 45 MHz intermediate frequency. BS9300, method 1405.







Typical change in noise figure as a function of temperature



Typical noise figure as a function of rectified current

1.F. Impedance (Ω)
500
400
300
1.0
2.0
3.0
Rectified current (mA)

I.F. impedance as a function of rectified current

MICROWAVE MIXER DIODE

Silicon Schottky barrier mixer diode in reversible cartridge outline. It conforms to the environmental requirements of BS9300 where applicable.

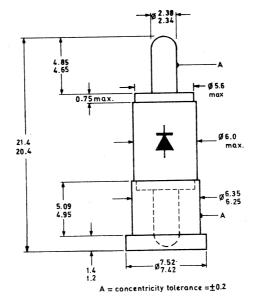
QUICK REFERENCE DATA

Noise figure at X-band	No	max.	7.5	ďB

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-47 Compatible with JEDEC DO-22 with collet Compatible with JEDEC DO-23 without collet Dimensions in mm



D4868

Terminal identification:

Diode symbol indicates polarity



Limiting values in accordance with the Absolute Maximum System (IEC134)

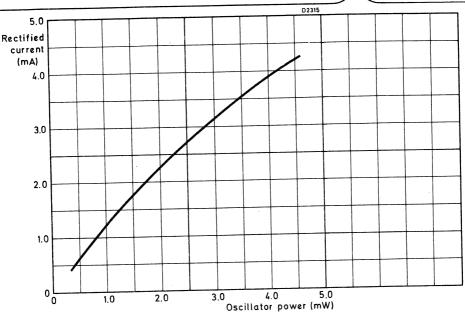
Temperature

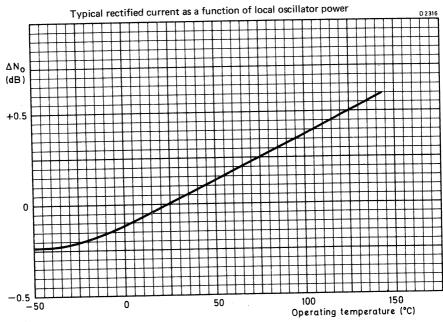
Storage temperature range Ambient temperature range	T _{stg} T _{amb}		-55 to +150 -55 to +150		oC OC
Burn-out					_
Burn-out (note 1)		max	ζ.	20 0.2	nJ
Peak pulse power				0.2	erg
f = 9.375 GHz, t _p = 0.5 μs		max	ζ.	1.0	W
CHARACTERISTICS (T _{amb} = 25 °C)					
		min.	typ.	max.	
Noise figure (note 2)	N_{o}	_	7.2	7.5	dB
Voltage standing wave ratio (note 3)	v.s.w.r.	****	_	1.3:1	
Intermediate frequency impedance (note 4)	z_{if}	335	400	465	Ω

Notes

- 1. Burn-out is defined as the r.f. pulse energy necessary to cause 1 dB degradation in noise figure when the diode is subjected to 2 \times $10^8\,$ pulses of 2 ns width.
- 2. Measured at 9.375 GHz, 1 mA rectified current, R $_{L}$ = 15 $\Omega.\ N_{O}$ includes N_{if} = 1.5 dB with 45 MHz intermediate frequency. BS9321/1406.

- 3. With respect to JAN-106 holder measured at 9.375 GHz, 1 mA rectified current, R $_{L}$ = 15 Ω_{\cdot} BS9321/1409.
- 4. Measured at 9.375 GHz, 1 mA rectified current, R $_{L}$ = 15 Ω with 45 MHz intermediate frequency. BS9321/1405.

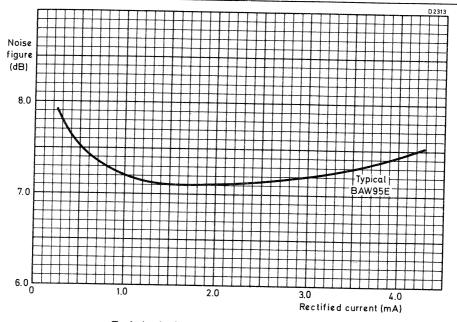




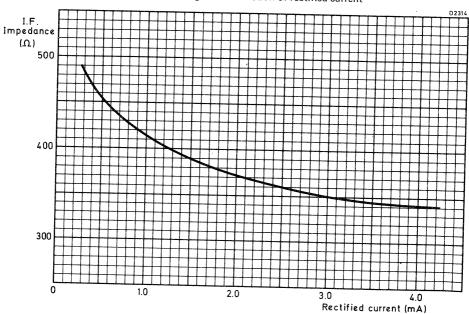
Typical change in noise figure as a function of temperature











I.F. impedance as a function of rectified current

BACKWARD DIODES



Sub-miniature germanium backward diode primarily intended for broadband low level detector applications in X-band. It conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

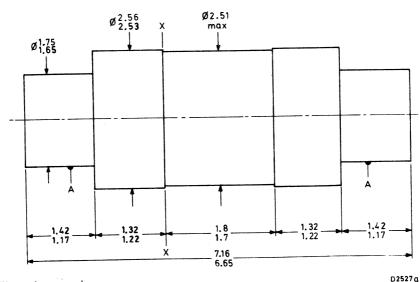
Frequency range		1 to 18	GHz	
Zero bias tangential sensitivity in X-band	typ.	-53	dBm	

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — ${\tt MICROWAVE}$ SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm

Conforms to SOD-42



XX = reference plane

 $AA = concentricity tolerance = \pm 0.15$

Terminal identification:

The AEY17 is colour coded as follows:

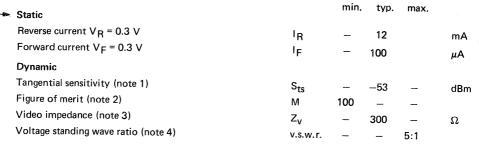
The positive end (cathode) is marked red and the negative end (anode) is marked blue. The positive end indicates the electrode which becomes positive in an a.c. rectifier circuit.



Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T _{sta}	55 to +85	οс
Ambient temperature range	T _{amb}	55 to +85	οС

CHARACTERISTICS (Tamb = 25 °C)



Notes

- 1. Measured at 9.375 GHz, zero bias, video bandwidth = 1.0 MHz. BS9300, method 1411.
- 2. Measured at 9.375 GHz, M is taken as the product of current sensitivity, expressed in μ A per μ W, and the square root of video impedance in ohms. BS9300, method 1414.
- 3. Zero bias, input 1:0 mV max (d.c. or a.c. r.m.s.). BS9300, method 1404.
- 4. With respect to 50 Ω , measured at f = 9.375 GHz, zero bias and c.w. input power less than 1.0 μ W. The nominal rectifier admittance at a reference plane X-X taken at the end faces of the ceramic insulator (see outline drawing on page 1) is:

$$(2.0 - j \ 2.0) \ \frac{1}{50} \ \text{mho}$$

typ.

18

No

max.

dB

APPLICATION INFORMATION

Detector performance at other than Test Radio Frequency

Measured overall noise figure, f = 9.375 GHz, N_{if} = 2.0 dB

	Tangential sensitivity, f = 1.0 to 18 GHz, B = 1.0 MHz Voltage standing wave ratio, f = 1.0 to 18 GHz, Z_0 = 50 Ω	Sts v.s.w.r.	53 	- 5:1	dBm
2.	Mixer performance (I.F. = 45 MHz)				
	Measured overall noise figure, f = 9.375 GHz, N_{if} = 1.5 dB, $P_{L.O.}$ = 200 μ W, I_{out} = 1.0 mA f = 16.5 GHz, N_{if} = 1.5 dB, $P_{L.O.}$ = 200 μ W,	No	9.0		dB
	$I_{out} = 1.0 \text{ mA}$		9.5	_	dB
	I.F. impedance, I _{out} = 1.0 mA	Zif	130		Ω
	Voltage standing wave ratio, f = 1 to 18 GHz, Z_0 = 50 Ω , I_{out} = 1.0 mA			2.5:1	-
3.	Doppler mixer performance (I.F. = 3 kHz)				

Germanium backward diodes primarily intended for low level detector applications in J-band (Ku-band). They are packaged in the standard coaxial outline for this frequency band, similar to 1N78 types. The encapsulation is hermetically sealed and is cadmium plated. The AEY29 and AEY29R conform to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

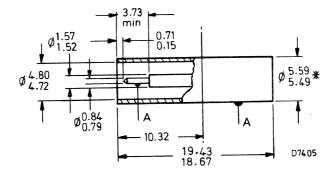
Frequency range		12 to 18	GHz	
Zero bias tangential sensitivity in J- band	typ.	-53	dBm	

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm

Conforms to SOD-49 Similar to JEDEC DO-37



A = concentricity tolerance = ± 0.35

Terminal identification:

AEY29

Pin

cathode

Body (red)

Pin

anode

AEY29R

/

anode

Body (green)

cathode

^{*}These limits apply only to the 10.32 dimension

AEY29 AEY29R

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stg}	-55 to +85			οС
Ambient temperature range	T _{amb}	55 to +85		35	οС
CHARACTERISTICS (T _{amb} = 25 °C)		min.	typ.	max.	
Static					
Reverse current V _R = 0.3 V	I _R	_	12		mΑ
Forward current $V_F = 0.3 V$	1 _F	-	100		μΑ
Dynamic					
Tangential sensitivity (note 1)	S _{ts}		-53	_	dBm
Figure of merit (note 2)	M	50		_	
Video impedance (note 3)	z_{v}		300	-	Ω

Notes

Voltage standing wave ratio (note 4)

- Measured at 16.5 GHz in JAN201 holder, zero bias, video bandwidth = 1.0 MHz. BS9300, method 1411.
- 2. Measured at 16.5 GHz in JAN201 holder, M is taken as the product of the current sensitivity, expressed in μ A per μ W, and the square root of the video impedance in ohms. BS9300, method 1414.

v.s.w.r.

5:1

- 3. Zero bias, input 1.0 mV max. (d.c. or a.c. r.m.s.). BS9300, method 1404.
- 4. With respect to 50 $\Omega,$ measured at f = 16.5 GHz, zero bias and c.w. input power less than 1.0 $\mu\text{W}.$



Sub-miniature germanium backward diodes primarily intended for broadband low level detector applications in X-band. They conform to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

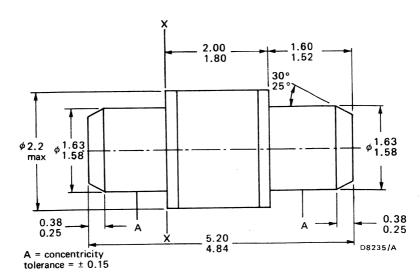
Frequency range			1 to 18	GHz
Zero bias tangential sensitivity in X-band	AEY31	typ.	-53	dBm
2010 Blue cange construction ,	AEY31A	typ.	50	dBm

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-50

Dimensions in mm



XX = reference plane

Terminal identification:

The AEY31 and AEY31A are colour coded as follows:

The positive end (cathode) is marked red and the negative end (anode) is marked blue.

The positive end indicates the electrode which becomes positive in an a.c. rectifier circuit.

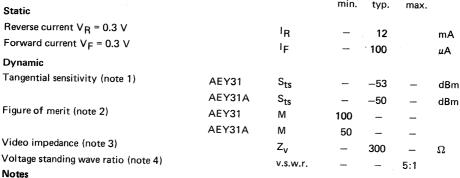


Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stq}	55 to +85	οс
Ambient temperature range	T _{amb}	-55 to +85	°C

min.

CHARACTERISTICS (Tamb = 25 °C)



- 1. Measured at 9.375 GHz, zero bias, video bandwidth = 1.0 MHz. BS9300, method 1411.
- 2. Measured at 9.375 GHz, M is taken as the product of current sensitivity, expressed in μA per μW , and the square root of video impedance in ohms. BS9300, method 1414.
- 3. Zero bias, input 1.0 mV max. (d.c. or a.c. r.m.s.). BS9300, method 1404.
- 4. With respect to 50 Ω , measured at f = 9.375 GHz, zero bias and c.w. input power less than 1.0 μ W. The nominal rectifier admittance at a reference plane X-X taken at the end faces of the ceramic insulator (see outline drawing on page 1) is:

$$(2.0 - j 2.0) \frac{1}{50}$$
 mho

APPLICATION INFORMATION

1. Detector performance at other than Test Radio Frequency

		typ.	max.	
Tangential sensitivity, $f = 1.0$ to 18 GHz , $B = 1.0 \text{ MHz}$,			
AEY31	S _{ts}	53		dBm
AEY31A	S _{ts}	-50		dBm
Voltage standing wave ratio, $f = 1.0$ to 18 GHz, $Z_0 = 5$	0Ω v.s.w.r.		5:1	
2. Mixer performance (I.F. = 45 MHz)			•	
Measured overall noise figure, f = 9.375 GHz, N _{if} = 1.5 c	dB			
^P L.O = 200 μW, I _{OUT} = 1.0 mA f = 16.5 GHz, N _{if} = 1.5 dB, P _{L.O.} = 200 μW,	N _o	9.0		dB
lout = 1.0 mA		9.5		dB
I.F. impedance, I _{out} = 1.0 mA Voltage standing wave ratio, f = 1 to 18 GHz, Z _o = 50 S	Z _{if}	130		Ω
l _{out} = 1.0 mA	-,		2.5:1	
3. Doppler mixer performance (i.f. = 3 kHz)			2.0.1	
Measured overall noise figure, $f = 9.375 \text{GHz}$, $N_{if} = 2.0 \text{c}$	IB No	18	_	dВ

Sub-miniature germanium backward diode primarily intended for broadband low level detector applications in Q-band (Ka-band). It conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

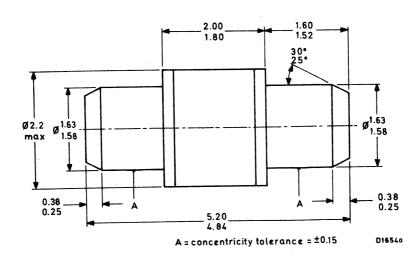
			18 to 40	GHz
Frequency range			18 to 40	GHZ .
	ç.	typ.	2.0	$\mu A/\mu W$
Zero bias current sensitivity in the band 18 to 40 GHz	٦,	cyp.	2.0	les () les s .

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-50

Dimensions in mm



Terminal identification:

The AEY32 is colour coded as follows:

The positive end (cathode) is marked red and the negative end (anode) is marked blue. The positive end indicates the electrode which becomes positive in an a.c. rectifier circuit.



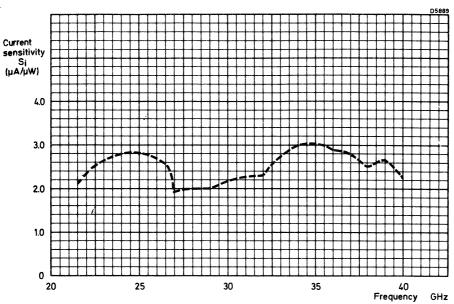
→ RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

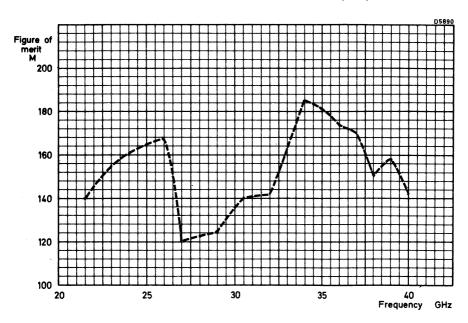
Storage temperature range	T_{stq}		55 to	+85	oC
Ambient temperature range	T _{amb}		-55 to		οС
Pulsed r.f. input power (f = 9.375 GHz, t_p = 0.5 μ s, p.r.f. = 2000 p.p.s.)	amb	max.	00 10	40	mW
CHARACTERISTICS (T _{amb} = 25 °C)					
		min.	typ.	max.	
1/f noise (note 1)		Manage		7.0	dB
Swept v.s.w.r. (26.5 to 40 GHz) (note 2)				5:1	45
Video impedance (note 3)	Z_{v}	3.0	_	5.0	kΩ
Current sensitivity (note 4)	S _i	_	2.0	J.U	μΑ/μW
Figure of merit (note 5)	M	EΩ			μΑΙμαν

Notes

- 1. Measured at an i.f. of 1 kHz with 50 Hz bandwidth and zero bias.
- 2. Measured in a Q-band broadband mount (specification 7313-731-0091). The v.s.w.r. measurement is swept over the band 26.5 to 40 GHz at a power level not exceeding 100 μ W and with zero bias.
- 3. Measured at an i.f. of 1.6 kHz with an input not exceeding 1 mV and with zero bias.
- 4. Measured in the same mount as described in note 2 at frequencies of 27 GHz, 34 GHz and 40 GHz, with an input power not exceeding 1 μ W and with zero bias. Rectified current measured by a microammeter of resistance less than 10 Ω .
- 5. Measured at frequencies of 27 GHz, 34 GHz and 40 GHz. M is the product of current sensitivity expressed in $\mu A/\mu W$ and square root of the video impedance expressed in ohms.



Typical current sensitivity as a function of frequency



Typical figure of merit as a function of frequency



Germanium backward diode primarily intended for low level detector applications in J-band (Ku-band). It is packaged in the standard coaxial outline for this frequency band, similar to 1N78 types. The encapsulation is hermetically sealed and is cadmium plated. The AEY33 conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

		12 to 18	GHz
Frequency range	AL III	-53	dBm
Zero bias tangential sensitivity in J-band	typ.	-55	ubiii

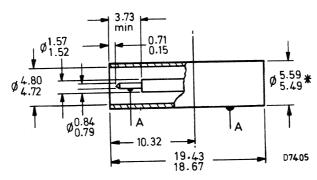
This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — ${\tt MICROWAVE}$ SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm

Conforms to SOD-49

Similar to JEDEC DO-37



A = concentricity tolerance = \pm 0.35

*These limits apply only to the 10.32 dimension

Terminal identification:

Pin

cathode

Body

anode



Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stg}	-55 to +100	οС
Ambient temperature range	T_{amb}	55 to +100	οС

CHARACTERISTICS (T _{amb} = 25 °C)					
		min.	typ.	max.	
Static					
Reverse current V _R = 0.3 V	I _R		9	_	mA
Forward current $V_F = 0.3 \text{ V}$	IF.	-	130		μΑ
Dynamic					
Tangential sensitivity (note 1)	Sts		-53		dBm
Figure of merit (note 2)	M	50		_	abiii
Video impedance (note 3)	Z_{v}	250	_	400	Ω
Voltage standing wave ratio (note 4)	v.s.w.r.	_	_	5:1	
Current sensitivity (note 5)	s _i	3.2	5.0	_	

Notes

- 1. Measured at 16.5 GHz in JAN201 holder, zero bias, video bandwidth = 1.0 MHz. BS9300, method 1411.
- 2. Measured at 16.5 GHz in JAN201 holder, M is taken as the product of the current sensitivity, expressed in μA per μW , and the square root of the video impedance in ohms. BS9300, method 1414.
- 3. Zero bias, input 1.0 mV. (d.c. or a.c. r.m.s.).
- 4. With respect to 50 Ω , measured at f = 16.5 GHz, zero bias and c.w. input power less than 1.0 μ W.
- 5. Measured at 16.5 GHz in a JAN201 holder with zero bias and an input power of 1.0 μ W. BS9300, method 1412.



MULTIPLIER VARACTOR DIODES



SILICON MULTIPLIER VARACTOR DIODE

Silicon planar epitaxial varactor diode for use as a high efficiency frequency multiplier in the v.h.f. and u.h.f. bands. As a tripler from 150 to 450 MHz it has a typical efficiency of 64% and can handle inputs up to 40 W. The BAY96 has a very low series resistance and is packaged in a low inductance, hermetically sealed, welded ceramic-metal envelope with stud cathode. It conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

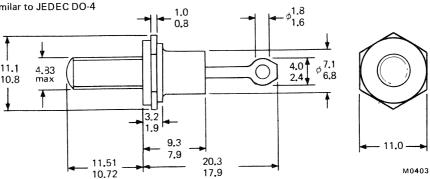
D.C. reverse voltage Total power dissipation Junction temperature	V _R P _{tot} T _i	max. max. max.	120 20 175	oC M A
Total capacitance (V _R = 6.0 V, f = 1.0 MHz)	c _T		28 to 39	pF
Series resistance (V _R = 6.0 V, f = 400 MHz) Cut-off frequency	r _s	max.	1.2	Ω
$\frac{1}{2\pi r_s C_T} \text{ at V}_R = 120 \text{ V}$	f_{CO}	typ.	25	GHz

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm

Conforms to SOD-4/8 Conforms to BS3934 SO-10 Similar to JEDEC DO-4



Diameter of clearance hole: max. 5.2

Torque on nut: min. 0.9 Nm max. 1.7 Nm

Accessories supplied on request:

56295 (PTFE bush, 2 mica washers, plain washer, tag) 56262A (mica washer, insulating ring, plain washer)

Supplied with device; 1 nut, 1 lock washer

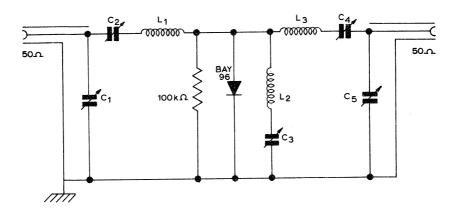
Nut dimensions across the flats: 9.5

Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range Junction temperature (operating) D.C. reverse voltage Total power dissipation (T _{mb} = 25 °C)	T _{stg} T _j V _R P _{tot}	ma ma	ıx. ıx.	5 to +175 175 120 20	oC V W
THERMAL RESISTANCE Thermal resistance from junction to mounting base CHARACTERISTICS	R _{th j-mb}			7.5	°C/W
		min.	typ.	max.	
Total capacitance $V_R = 6.0 \text{ V}, f = 1.0 \text{ MHz}$ Series resistance $V_R = 6.0 \text{ V}, f = 400 \text{ MHz}$	C _T	28	- 0.9	39 1.2	pF Ω
	r _s		0.9	1.2	22
Cut-off frequency $\frac{1}{2\pi r_s C_T} \text{ at } V_R = 120 \text{ V}$	f _{co}	_	25	_	GHz

APPLICATION INFORMATION

Typical operating characteristics as a frequency tripler



Frequency tripler circuit - 150 to 450 MHz

 $L_1 = 6.5 \text{ turns } 18 \text{ s.w.g. wire, } 0.297'' \text{ I.D., } 0.562'' \text{ long}$

 $L_2 = 2 \text{ turns } 14 \text{ s.w.g. wire, } 0.266" \text{ I.D., } 0.312" \text{ long}$

 L_3 = 1.0" \times 0.25" \times 0.020" copper strip, 0.562" from chassis

 $C_1 = 7.0$ to 100 pF variable

 C_2 , C_3 , $C_4 = 2.0$ to 13 pF variable

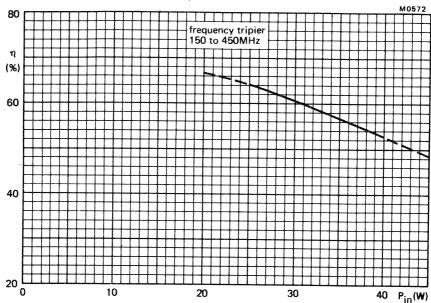
 $C_5 = 2.0$ to 25 pF variable

Efficiency $P_{in} = 25 \text{ W}, f_{in} = 150 \text{ MHz}$

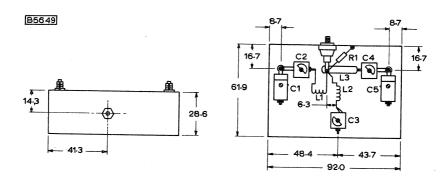
 η min. typ.

60 64

APPLICATION INFORMATION (continued)

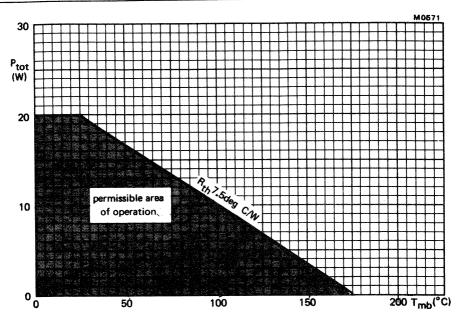


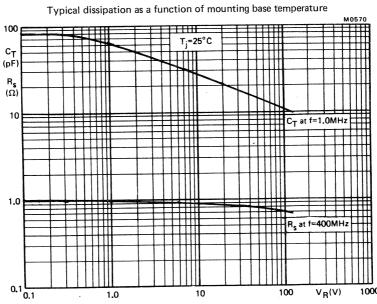
Typical tripler efficiency as a function of input power See circuit on page 3



Component layout of tripler circuit

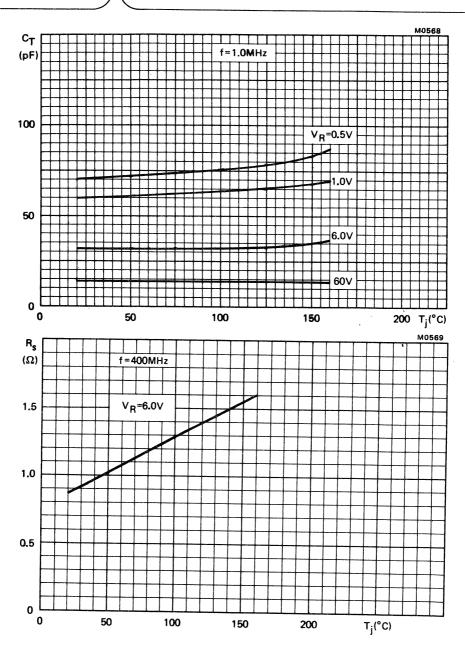






Typical diode capacitance and series resistance as a function of reverse voltage





Typical diode capacitance and series resistance as a function of junction temperature

STEP RECOVERY DIODE

Silicon planar epitaxial varactor diode exhibiting step recovery characteristics, especially suitable for use in frequency multiplier circuits up to S-band output frequency. It is a diffused silicon device and is mounted in a small double-ended ceramic-metal case with hermetic seal and conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

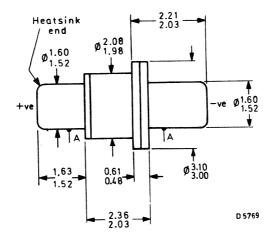
Operation as a frequency doubler 1 to 2 GHz in a	typical circu	it,		
Input r.f. power Output r.f. power	P _{in} P _{out}		10 5.0	W W
Resistive cut-off frequency VR = 6.0 V	f_{CO}	typ.	100	GHz
Total capacitance $V_R = 6.0 \text{ V}$ Junction temperature	$^{C_T}_{j}$	typ. max.	4.5 150	oC bE

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-31

Dimensions in mm



A = concentricity tolerance = ± 0.13

Chips from this range of devices may be supplied in alternative packages to customers' requirements.

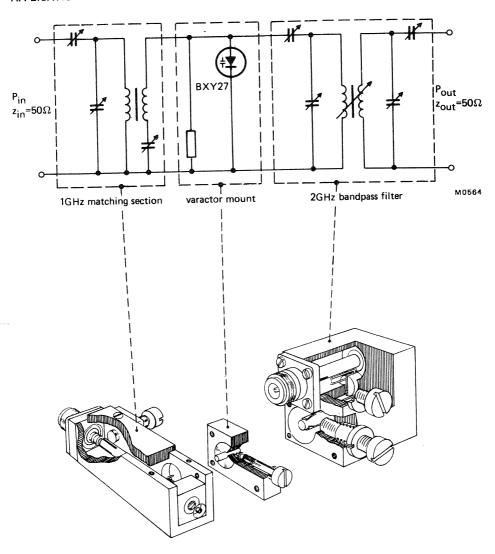


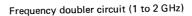
Limiting values in accordance with the Absolute Maximum System (IEC134)

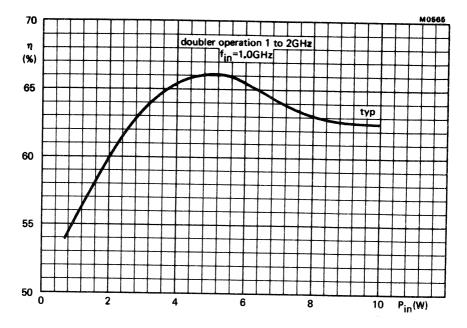
Storage temperature range	T_{stg}		-55	to +150	οС
Junction temperature	Тj	max.		150	οС
D.C. reverse voltage	ν̈́R	max.		55	V
Total power dissipation R.F. $T_{pin} \le 70$ °C $T_{pin} > 70$ °C, derating factor	P _{tot}	max.		4.0 50	W mW/°C
THERMAL RESISTANCE					
Thermal resistance from junction to pin	R _{th j-pin}	max.		20	oC/W
CHARACTERISTICS (T _{amb} = 25 °C)					
Reverse breakdown voltage	V _{(BR)R}	min. 55	typ.	max.	٧
Reverse current, V _R = 6.0 V	^I R		0.001	1.0	μΑ
Cut-off frequency, $V_R = 6.0 \text{ V}$					•
2πr _s C _i	f _{co}	50	100		GHz
Total capacitance (C _i + C _s)					
$V_R = 6.0 \text{ V, f} = 1.0 \text{ MHz}$	C _T	3.0	4.5	6.0	pF
Stray capacitance	C _s	_	0.25		рF
Series inductance	L _s	_	650		рН
Series resistance, V _R = 6.0 V	r _s	_	0.4		Ω
Overall efficiency Pin = 10 W, fin = 1.0 GHz					
frequency doubler	η	50	60	_	%
frequency trebler	η	_	40		%



APPLICATION INFORMATION









Overall efficiency as a function of input power for doubler operation

STEP RECOVERY DIODE

Silicon planar epitaxial varactor diode exhibiting step recovery characteristics, especially suitable for use in frequency multiplier circuits up to C-band output frequency. It is a diffused silicon device and is mounted in a small double-ended ceramic-metal case with hermetic seal and conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

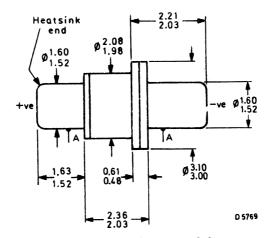
Operation as a frequency doubler 2 to 4 GHz in a typical circuit. 7.0 W Input r.f. power 3.5 Pout Output r.f. power 120 GHz f_{CO} typ. Resistive cut-off frequency, VR = 6.0 V 1.5 ρF Ст Total capacitance, VR = 6.0 V typ. 150 oC Junction temperature Ti max.

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-31

Dimensions in mm



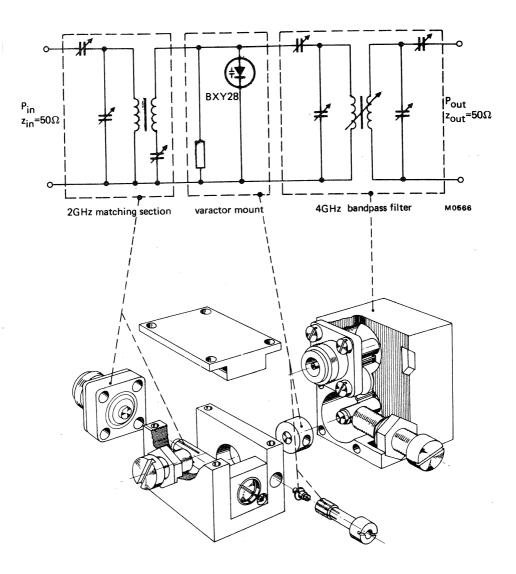
A = concentricity tolerance = ± 0.13

Chips from this range of devices may be supplied in alternative packages to customers' requirements.

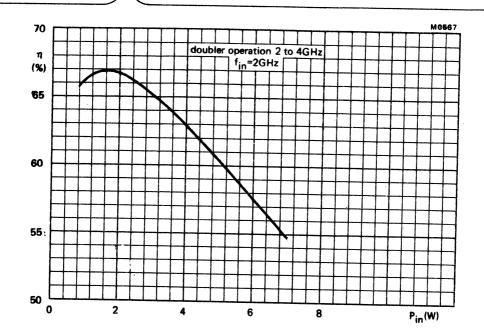
Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stg}		-55 t	o +150	°C
Junction temperature	T _j	max.		150	oC O
D.C. reverse voltage	v _R	max.		45	V
Total power dissipation R.F. $T_{pin} \le 70$ °C $T_{pin} > 70$ °C, derating factor	P _{tot}	max.		2.7 34	W mW/ ^o C
THERMAL RESISTANCE					
Thermal resistance from junction to pin	R _{th j-pin}	max.		30	oC/W
CHARACTERISTICS (T _{amb} = 25 °C)					
		min.	typ.	max.	
Reverse breakdown voltage	$V_{(BR)R}$	45	60		V
Reverse current, $V_R = 6.0 \text{ V}$	I _R		0.001	1.0	μΑ
Cut-off frequency, $V_R = 6.0 \text{ V}$					·
2 π r _s C _j					
Total capacitance ($C_j + C_s$) V _R = 6.0 V, f = 1.0 MHz	С _Т	1.0	1.5	2.5	pF
Stray capacitance	C _s		0.25		pF
Series inductance	L _s		650		•
Series resistance, V _R = 6.0 V	-s r _s		1.0		Hq Ω
Overall efficiency P _{in} = 7.0 W, f _{in} = 2.0 GHz	3		1.0		72
frequency doubler	η	50			%

APPLICATION INFORMATION



Frequency doubler circuit (2 to 4 GHz)



Overall efficiency as a function of input power for doubler operation

STEP RECOVERY DIODE

Silicon planar epitaxial varactor diode exhibiting step recovery characteristics, especially suitable for high order frequency multiplier circuits up to X-band output frequency. It is a diffused silicon device and is mounted in a small double-ended ceramic-metal case with hermetic seal and conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

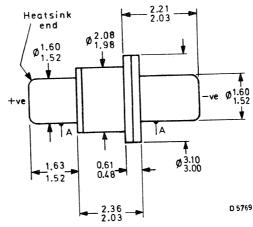
Operation as a frequency quadrupler 2.25 Input r.f. power Output r.f. power	to 9.0 GHz in a tyl P _{in} Pout	pical circuit.	1.0 0.3	W W
Resistive cut-off frequency V _R = 6.0 V	f _{co}	typ.	120	GHz
Total capacitance V _R = 6.0 V Junction temperature	С _Т Т _ј	typ. max.	1.0 150	oC pF

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-31

Dimensions in mm



-A= concentricity tolerance = ± 0.13

Chips from this range of devices may be supplied in alternative packages to customers' requirements.



Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range					
Junction temperature	т.		-55	to +150	°C
D.C. reverse voltage	т _ј	max.		150	οС
Total power dissipation R.F. $T_{pin} \le 70^{\circ}C$	V _R P _{tot}	max. max.		25 2.0	V W
THERMAL RESISTANCE					••
Thermal resistance from junction to pin	R _{th j-pin}	max.		40	oc/w
CHARACTERISTICS (T _{amb} = 25 °C)					-,
Reverse breakdown voltage		min.	typ.	max.	
I _R = 1.0 mA	V _{(BR)R}	25			V
Reverse current, $V_R = 6.0 \text{ V}$	^I R	_	0.001	1.0	μΑ
Cut-off frequency, V _R = 6.0 V (note 1)	f _{co}	90	120	_	GHz
Total capacitance (C _j + C _s)					GHZ
$V_R = 6.0 \text{ V, } f = 1.0 \text{ MHz}$	CT	0.8	1.0	1.5	pF
Stray capacitance	C _s		0.25	_	pF
Series inductance	L _s		650		•
Overall efficiency	•		030		На
$P_{in} = 1.0 \text{ W}, f_{in} = 2.25 \text{ GHz}$					
frequency quadrupler	n	30			

Notes

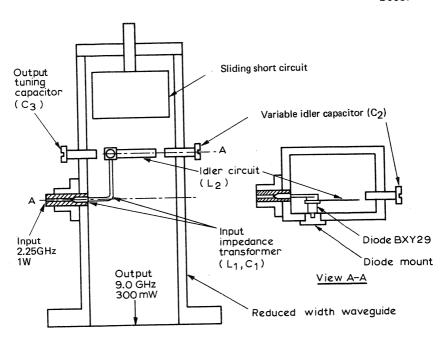
1. The cut-off frequency f_{CO} is defined as: $f_{CO} = \frac{1}{2\pi r_S C_j}$ where C_j is the junction capacitance and is measured at 1.0 MHz, r_S is measured on a slotted line at 2.0 GHz.

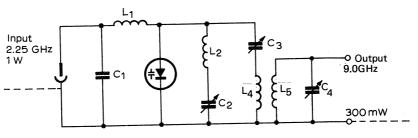


2

S-X band quadrupler

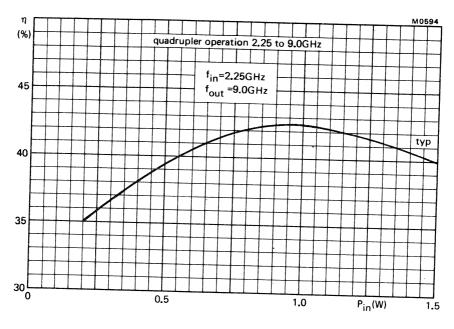
B9937





Approximate equivalent circuit





Overall efficiency as a function of input power for quadrupler operation



STEP RECOVERY DIODE

Silicon planar epitaxial varactor diode exhibiting step recovery characteristics, especially suitable for high order frequency multiplier circuits up to X-band output frequency. It is a diffused silicon device and is mounted in a small double-ended ceramic-metal case with hermetic seal and conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

Operation as a high order frequency multiplier 1.0 to 10 GHz in a typical circuit.

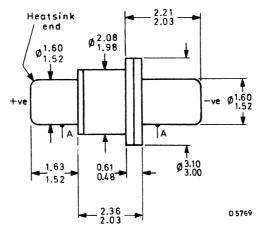
Input r.f. power	P _{in}		500	mW
Output r.f. power	P _{out}		20	mW
Resistive cut-off frequency VR = 6.0 V	f _{co}	typ.	150	GHz
Total capacitance $V_R = 6.0 \text{ V}$ Junction temperature	с _Т	typ.	0.75	pF
	т _ј	max.	150	oC

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-31

Dimensions in mm



A = concentricity tolerance = ± 0.13

Chips from this range of devices may be supplied in alternative packages to customers' requirements.



Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T _{stg}	T _{stg} -55 to +150			oC
Junction temperature	Tj	max.		150	οС
D.C. reverse voltage	V _R	max.		20	V
Total power dissipation R.F. $T_{pin} \le 70$ °C	P _{tot}	max.		1.6	w
THERMAL RESISTANCE					
Thermal resistance from junction to pin	R _{th j-pin}	max.		50	oC/W
CHARACTERISTICS (T _{amb} = 25 °C)					
		min.	typ.	max.	
Reverse breakdown voltage					
$I_R = 1.0 \text{ mA}$	V(BR)R	20	_	-	V
Reverse current, V _R = 6.0 V	^I R	_	0.001	1.0	μΑ
Cut-off frequency, V _R = 6.0 V (note 1)	f _{co}	100	150	-	GHz
Total capacitance (C _i + C _s)					
$V_{R} = 6.0 \text{ V, f} = 1.0 \text{ MHz}$	C _T	0.5	0.75	1.0	рF
Stray capacitance	C _s	_	0.25	_	рF
Series inductance	L_S		625		рН
Transition time	t _{tr}		-	150	ps
Storage time	t _s	_	50		ns

Notes

1. The cut-off frequency f_{CO} is defined as: $f_{CO} = \frac{1}{2\pi r_s C_s}$

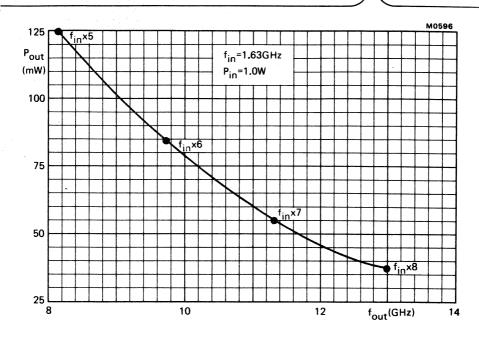
where C_j is the junction capacitance and is measured at 1.0 MHz, r_s is measured on a slotted line at 8.0 GHz

MULTIPLIER PERFORMANCE

		min.	typ.	max.	
Power output, fin = 1.0 GHz					
P_{in} = 500 mW, f_{out} = 10 GHz	Pout	15	20	_	mW

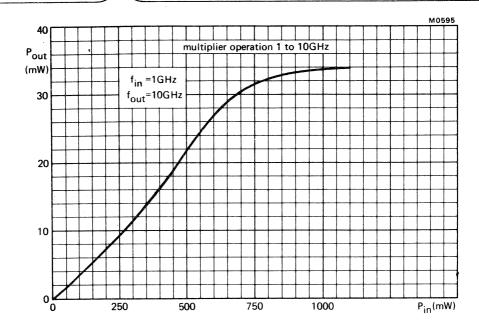


2









STEP RECOVERY DIODES

Silicon planar varactor diodes exhibiting step recovery characteristics, especially suitable for use in frequency multipliers. They conform to the environmental requirements of BS9300 where applicable.

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

			BXY35	BXY36	BXY37	BXY38	BXY39	BXY40	BXY41	
Reverse breakdown voltage	V	min.	100	70	70	50	40	25	25	.,
$I_R = 10 \mu\text{A}$	V(BR)R	111111.	100	70	70	50	40	25	25	٧
Cut-off frequency V _R = 6.0 V	f _{co}	min.	25	75	100	120	150	180	200	GHz
Diode capacitance										
V _R = 6.0 V	c _j	min. max.	6.0 12	4.0 6.0	2.0 4.0	1.2 2.0	0.8 1.2	0.4 0.9	0.25 0.5	pF pF
Transition time	t _{tr}	max.	_	500	350	300	200	150	100	ps
Storage time	ts	typ.	_	150	100	75	50	50	25	ns
Thermal resistance, juntion to mounting base, types A,D,E	R _{th j-mb}		10	20	20	30	40	50	50	°C/W
Thermal resistance	''tn j-mb		.0	20	20	30	40		50	C/W
junction to pin, types B,C	R _{th j-pin}		10	20	20	30	40	50	50	oC/W
Multiplier performance										
Typical output frequency										
range		min.	0.75	2	4	6	7	- 8	10	GHz
		max.	2	4	6	8	9	10	14	GHz
Outlines available			Α	_	_	_		_	_	
			_	В	В	В	В	В	В	
			-	С	С	С	С	С	С	
				D	D	D	D	D	D	
			-	E	E	E	E	E	E	

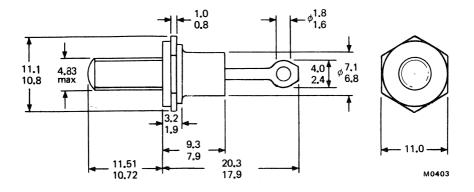
Devices may be selected from this range to suit customers' specific requirements, including further alternative packages.



MECHANICAL DATA

Dimensions in mm

Outline A Conforms to SOD-4/8 and BS3934 SO-10



Diameter of clearance hole: 5.2

Torque on nut: min. 0.9 Nm

max. 1.7 Nm

Accessories supplied on request:

56295 (PTFE bush, 2 mica washers, plain washer, tag)

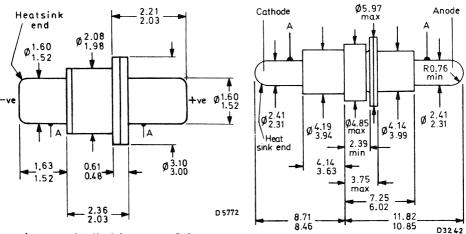
56262A (mica washer, insulating ring, plain washer)

Supplied with device: 1 nut, 1 lock washer

Nut dimensions across the flats: 9.5

Outline B Conforms to SOD-31

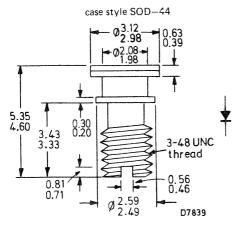
Outline C Conforms to SOD-43



A = concentricity tolerance = ± 0.13



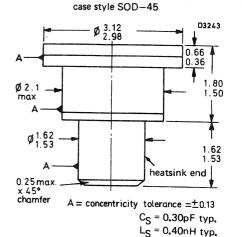
Outline D Conforms to SOD-44



neatsink end

 $C_3 = 0.25pF$ typ. $L_5 = 0.65nH$ typ.

Outline E Conforms to SOD-45







HIGH EFFIENCY STEP RECOVERY DIODES

High efficiency silicon varactor diodes suitable for operation in low and high order multiplier circuits with output frequencies in the range 3 to 8 GHz. These diodes are of the diffused epitaxial type, having mesa construction for optimum performance and conform to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

			BXY56	BXY57	
Reverse breakdown voltage I _R = 10 μA	V _{(BR)R}	min.	60	60	V
Junction capacitance V _R = 6 V	C _j	min. max.	1.5 2.5	2.5 3.5	pF pF
Cut-off frequency V _R = 6 V	f _{co}	min.	160	140	GHz

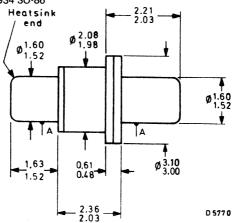
Unless otherwise shown, data is applicable to both types.

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm

Conforms to SOD-31 and BS3934 SO-86



A = concentricity tolerance = ± 0.13

Normal operation with reverse bias, i.e. heatsink end positive.

Devices may be selected to suit customers' specific requirements, including alternative packages.

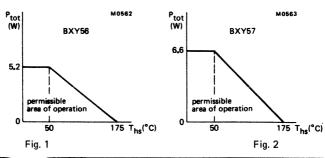


Limiting values in accordance with the Absolute Maximum System (IEC134)

			BXY56	BXY57	
Storage temperature range	T_{stg}		-55 to +175	-55 to +175	oC
Junction temperature	Тj	max.	175	175	oc
D.C. reverse voltage	VR	max.	60	60	V
Total power dissipation T _{hs} max. 50 °C (note 1)	P _{tot}	max.	5.2	6.6	w
THERMAL RESISTANCE					
Thermal resistance from junction to heatsink	R _{th j-hs}	max.	24	19	oc/w
CHARACTERISTICS (Tpin = 25 °C	:)				
Reverse breakdown voltage $I_R = 10 \mu A$	V _{(BR)R}	min.	60	60	V
Cut-off frequency V _R = 6 V (note 2)	f _{co}	min.	160	140	GHz
Junction capacitance V _R = 6 V, f = 1 MHz	C.	min.	1.5	2.5	ρF
VR = 0 V, 1 = 1 WHZ	c _j	max.	2.5	3.5	pF
Stray capacitance	Cs	typ.	0.25	0.25	рF
Series inductance	Ls	typ.	650	650	рН
Transition time	t _{tr}	typ.	150	200	ps
Lifetime	au	typ.	60	150	ns
MULTIPLIER PERFORMANCE (note 3)					
Low order multiplier efficiency in a 2.1 to 4.2 GHz doubler	η	typ.	60	60	%
High order multiplier efficiency in a 0.45 to 3.6 GHz 8x multiplier	m	tvn:	20	20	%
ox murupilei	η	typ.	20	20	/0

Notes

1. $P_{tot} = P_{in} - P_{out}$. Derating curves are sued for value of T_{hs} greater than 50 °C:-



Notes (continued)

- 2. Cut-off frequency is measured using a slotted line system at 2 GHz. $f_{CO} = \frac{1}{2\pi r_s C_i}$
- 3. For high power applications it is essential that the heatsink end of the device is gripped by a collet or equivalent clamping system to ensure the best possible thermal conductivity. This in turn should be coupled to an adequate heatsink. Care must be taken to avoid unnecessary deformation of this diode pin, as this may cause cracking of the metal-ceramic hermetic seal. The location of the top cap should be a hold of diameter 1.8 to 2.2 mm bearing on the flange with a force not exceeding 10 N.





GALLIUM ARSENIDE PARAMETRIC AMPLIFIER VARACTOR DIODE

Gallium arsenide varactor diode with a high cut-off frequency for use in parametric amplifiers, frequency multipliers and switches. The diodes are of the diffused mesa type, are mounted in a small ceramic-metal case with a welded hermetic seal and conform to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

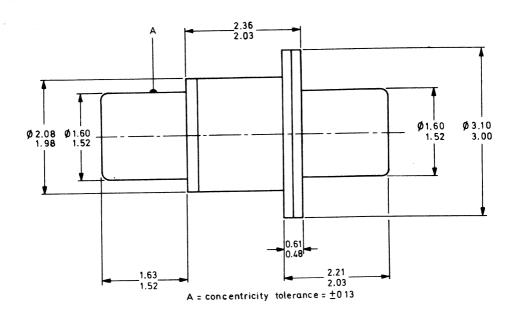
D.C. reverse voltage Average forward current	V _R	max. max.	6.0 70	V mA
Total power dissipation T _{stud} ≤ 107 °C	P _{tot}	max.	50	mW
$T_{stud} > 107$ °C, see derating curve Junction operating temperature range Cut-off frequency, $V_R = 6.0 \text{ V}$	T _j f _{co}	typ.	-196 to +150 240	oC GHz

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm

Conforms to SOD-31 and BS3934 SO-86

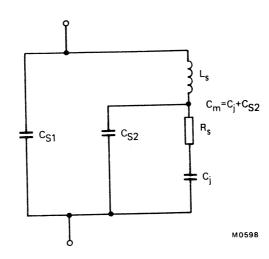


Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stg}		-196	6 to +150	οс
Junction temperature operating range	Тj		196	6 to +150	°C
D.C. reverse voltage	ν̈́R	max.		6.0	V
Average forward current	I _{F(AV)}	max.		70	mΑ
Total power dissipation T _{stud} ≤ 107 °C	P _{tot}	max.		50	mW
CHARACTERISTICS (T _{amb} = 25 °C)					
		min.	typ.	max.	
Reverse current, V _R = 6.0 V	^I R		0.1	1.0	μΑ
Forward voltage drop $I_F = 1.0 \mu A \text{ (note 3)}$	V _F		0.9	_	V
Series resonant frequency	- 1		0.0		V
$V_R = 0$ (notes 1 and 2)	$f_{\mathbf{o}}$	8.9	10	11.6	GHz
Cut-off frequency	· ·				GIIZ
$V_R = 0$ (note 2)	f_{CO}	125	150		GHz
Cut-off frequency					
$V_R = 6.0 V \text{ (note 2)}$	f_{CO}	_	240	-	GHz
Effective diode capacitance at X-band					
frequency, V _R = 0 (notes 1 and 2)	C _{mo}	0.3	0.4	0.5	pF
Capacitance variation coefficient (note 3)					
	γ	0.12	0.15	_	
Stray capacitance (note 1)	C _{S1}	_	0.1	_	pF
Stray capacitance (note 1)	c _{S2}	_	0.15	_	pF
Series inductance (note 1)	L _s	_	625	_	pН

Notes

A suitable lumped circuit equivalent for the device may be drawn as follows:



 Measured at and about the series resonant frequency, in a suitable waveguide holder, enable the values of f_O and the diode Q factor to be determined. The effective diode capacitance and the cut-off frequency can be calculated taking L_S to be the typical value.

$$f_{co} = Q_o f_o$$

where $\mbox{ f}_{0}$ is the series resonant frequency $\mbox{ Q}_{0}$ is the Q factor at zero bias

$$C_{\text{mo}} = \frac{1}{4\pi^2 f_0^2 L_s}$$

3. The capacitance variation coefficient γ is defined as

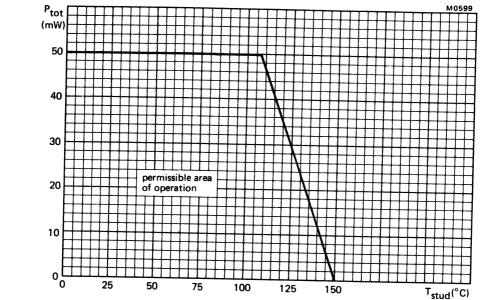
$$\gamma = \frac{C_{\text{m}} \text{ max.} - C_{\text{m}} \text{ min.}}{2(C_{\text{m}} \text{ max.} + C_{\text{m}} \text{ min.})}$$

where C_m min. = effective capacitance at V_R = 1.0 V C_m max. = effective capacitance at I_F = 1.0 μ A

This can be re-written in the form

$$\gamma = \frac{(1 - V)^{-1/3} - 2^{-1/3}}{2 (1 - V)^{-1/3} + 2^{-1/3}} + \frac{4C_{S2}}{C_{jo}}$$

where
$$V = V_F$$
 at 1.0 μ A
 $C_{jo} = C_{mo} - C_{S2}$





GALLIUM ARSENIDE PARAMETRIC AMPLIFIER VARACTOR DIODE

Gallium arsenide varactor diode with a high cut-off frequency suitable for use in parametric amplifiers and may be used in frequency multipliers and switches. The diodes are of the diffused mesa type, mounted in a small ceramic-metal case with a hermetic welded seal and conform to the environmental requirements of BS9300 where applicable.

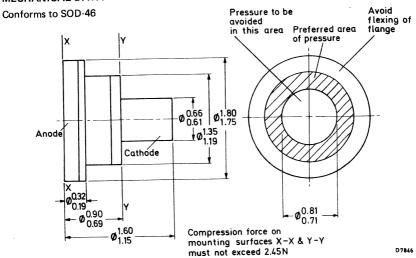
OHICK	REFE	RENC	E DATA
-------	------	------	--------

COLOR HET ENERGY STATE	\/_	max.	6.0	V
D.C. reverse voltage	V _R	max.	0.0	•
Total power dissipation		max.	50	mW
T _{pin} ≤ 25 °C	P _{tot}	max.	30	
Typical X-band parametric amplifier performance				
Signal frequency	f		8.5	GHz
Gain			15	d₿
	В		70	MHz
Bandwidth (3 dB)	_	typ.	200	οĸ
Noise temperature		typ.		

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm



Devices may be selected to suit customers' specific requirements, including alternative packages.



Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T _{stq}		196	6 to +175	οс
Junction temperature operating range	T _j			-196 to +135	
D.C. reverse voltage	v _R	max.		6.0	oC C
Total power dissipation $T_{pin} \le 25 {}^{o}\text{C}$	P _{tot}	max.		50	mW
THERMAL RESISTANCE	-				
Thermal resistance from junction to pin	R _{th j-pin}	max.		0.9	^o C/mW
CHARACTERISTICS (T _{amb} = 25 °C)					
		min.	typ.	max.	
Reverse current, V _R = 6.0 V	ⁱ R	_	0.1	1.0	μΑ
Series resonant frequency					
V _R = 0 (note 1)	^f res	27	30	34	GHz
Cut-off frequency VR = 0 (note 1)	f _{co}	200	350	_	GHz
Product of capacitance variation coefficient and cut-off frequency					
$V_R = 0$ (note 2)	γ f $_{ m co}$	35	50	_	GHz
Microwave value of effective device series resistance (notes 1 and 4)	R _m	_	2.25		Ω
Microwave value of effective device capacitance					
$V_R = 0$ (notes 3 and 4)	C _m		0.2		pF
Stray capacitance (L.F. measurement)	C _s		0.3	_	pF
Microwave value of effective device series inductance (note 3)					·
(10000)	L _S		140	_	pН

Notes

- Measured in a reduced height waveguide holder at Q-band.
- γf_{CO} is guaranteed by a functional X-band paramp test at room temperature. The capacitance 2. variation coefficient, γ , is defined as follows:

$$\gamma = \frac{C_{\text{m}} \text{ max.} - C_{\text{m}} \text{ min.}}{2(C_{\text{m}} \text{ max.} + C_{\text{m}} \text{ min.})}$$

where C_m min. = effective capacitance at V_R = 1.0 V $C_{\rm m}$ max. = effective capacitance at $I_{\rm F}$ = 1.0 $\mu{\rm A}$

C_m is calculated using the frequency cut-off and the series resistance:

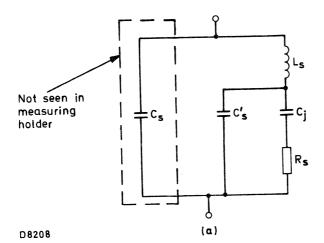
$$C_{m} = \frac{1}{2\pi R_{m} f_{co}}$$

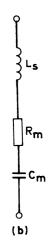
 L_s is also calculated using f_{res} and C_m :

$$L_{s} = \frac{1}{4\pi^{2} f_{res^{2}} C_{m}}$$

Notes (continued)

- 4. (a) Diode circuit model.
 - (b) Equivalent circuit in measuring holder.





Operating note

The CXY10 varactor diode will give good noise performance in a parametric amplifier of suitable design.

For example:

The effective input noise temperature of the amplifier, less the contribution due to the circulator, would be typically 200 $^{\rm O}$ K and a maximum of 250 $^{\rm O}$ K, with the amplifier at room temperature under the following conditions:

gain	15 dB
bandwidth	50 MHz (3 dB)
signal frequency	in X-band
overcoupled ratio	4 to 5 dB
numn frequency	in Q-band

In cooled parametric amplifiers, the device would give appropriately lower effective input noise temperatures due to its low temperature working capability.

• •			

GALLIUM ARSENIDE MULTIPLIER VARACTOR DIODE

Gallium arsenide varactor diode suitable for use in frequency multiplier circuits up to O-band output frequency. The diodes are of the diffused mesa type, are mounted in a small ceramic-metal case with hermetic welded seal and conform to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

Operation as a frequency quadrupler 9.0 to 36 GHz in a typical circuit.

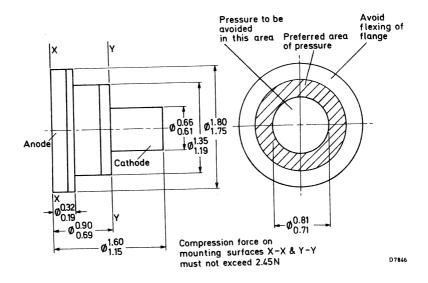
Operation as a modulo of the			E00	mW
Input r.f. power	P _{in}	max.	500	mvv
· ·	Pout	min.	50	mW
Output r.f. power	' out		F00	CH-
Resistive cut-off frequency, VR = 6.0 V	f _{co}	typ.	500	GHz
	T:	max.	175	oC
Junction temperature	۱,	111471		

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-46

Dimensions in mm



Devices may be selected to suit customers' specific requirements, including alternative packages.

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T _{stg}		-55 to +1	175	οС
Junction temperature	T _i	max.		175	oC
D.C. reverse voltage	V _R	max.	!		_
Total power dissipation	'n	max.		10	V
T _{pin} = 25 °C (note 1)	P _{tot}	max.	•	800	mW
Input power R.F.	P _{in}	max.		600	
	. 111	mux.	J	000	mW
THERMAL RESISTANCE					
Thermal resistance from junction to pin	R _{th j-pin}	max.	(0.5	°C/mW
CHARACTERISTICS (T _{amb} = 25 °C					
		min.	typ.	max.	
Reverse breakdown voltage					
I _R = 100 μA	V _{(BR)R}	10	15	_	V
Reverse current, $V_R = 6.0 V$	I _R	_	0.001	1.0	μΑ
Series resonance frequency			3.551	1.0	μΛ
V _R = 6.0 V (note 2)	f _{res}	27	29	35	GHz
Cut-off frequency	163	_,	20	35	GHZ
V _R = 6.0 V (note 2)	f _{co}	300	500		011
Microwave value of effective device	'CO	300	500		GHz
capacitance					
V _R = 6.0 V (note 3)	C _m	_	0.25		- F
Microwave value of effective device	-111		0.25		pF
series resistance					
$V_R = 6.0 V$ (notes 2 and 4)	R _m		1.3		Ω
Stray case capacitance	***************************************		1.5		7.2
(L.F. measurement)	c _s				_
•	O _S		0.3	_	pF
Microwave value of effective device					
series inductance (note 3)	L _s	_	120	_	pН

Notes

1. The maximum value of P_{tot} is based on a d.c. dissipation life test. The R.F. power may well exceed this figure in a practical circuit.

2. Measurements on semiconductor devices at microwave frequencies are very much dependent upon the kind of holder used. The dynamic parameters are quoted using a holder which takes the form of a double four section Q-band (Ka-band) 26 to 40 GHz waveguide wide band low v.s.w.r. transformer to a reduced height of 0.25 mm. The transformer is step down followed by step up in order to use standard Q-band components on either side. A d.c. isolated coaxial choke system allows the diode to be inserted across the 0.25 mm reduced height section and to be biased. Using a swept frequency transmission loss measurement system, the series resonant frequency and the Q of the diode holder system can be measured. Hence, the resistive cut-off frequency which

is defined as Q X fres. Separately, by measuring the transmission loss past the diode at resonance, the effective diode series resistance can be found.

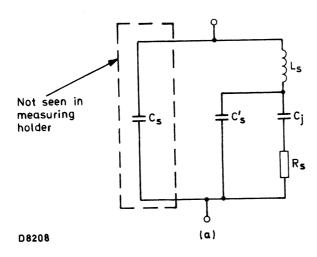
3. C_{m} is calculated using the frequency cut-off and the series resistance:

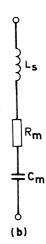
$$C_{m} = \frac{1}{2\pi R_{m} f_{co}}$$

Ls is also calculated using fres and Cm:

$$L_{s} = \frac{1}{4\pi^{2} f_{res}^{2} C_{m}}$$

- 4. (a) Diode circuit model.
 - (b) Equivalent circuit in measuring holder.

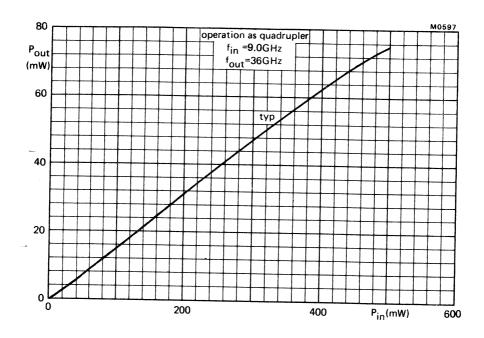




Application note

In a suitable frequency quadrupler, this device is capable of producing 50 mW at 36 GHz for an input of 400 mW at 9.0 GHz.





Output power as a function of input power Quadrupler operation

STEP RECOVERY DIODES

Silicon planar epitaxial varactor diodes exhibiting step recovery characteristics, especially suitable for use in frequency multiplier circuits up to S-band output frequency. They conform to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

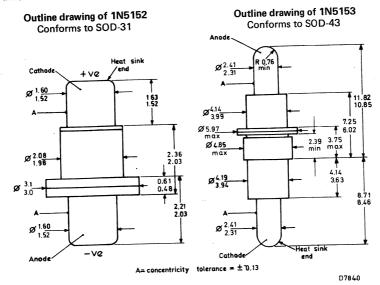
Operation as a frequency doubler 1 to 2 GHz in a ty	pical circuit.			
Input r.f. power	P _{in}		12	W
Output r.f. power	P_{out}		6.0	W
Resistive cut-off frequency $V_R = 6.0 \text{ V}$	f _{co}	typ.	100 6.0	GHz bF
Total capacitance, $V_R = 6.0 \text{ V}$	CT	typ.	0.0	μr

Unless otherwise stated, data is applicable to both types.

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm



Devices may be selected to suit customers' specific requirements, including alternative packages.



1N5152 1N5153

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stg}		-55 to	+175	οС
Junction temperature	Тj	max		175	оС
D.C. reverse voltage	٧ _R	max		75	٧
Total power dissipation R.F. $T_{pin} \le 70$ °C	P_{tot}	max.		5.0	W
THERMAL RESISTANCE					
Thermal resistance from junction to pin	R _{th j-pin}	max.		20	oC/W
CHARACTERISTICS (T _{amb} = 25 °C)					
		min.	typ.	max.	
Reverse breakdown voltage, $I_R = 10 \mu A$	V _{(BR)R}	75			V
Reverse current, V _R = 60 V	I _R		0.001	1.0	μΑ
Forward voltage, I _F = 10 mA	٧ _F	_		1.0	V
Cut-off frequency, V _R = 6.0 V, f _{measured} = 2.0 GHz	f _{co}	55	100	_	GHz
Total capacitance V _R = 6.0 V, f= 1.0 MHz	C _T	5.0	_	7.5	pF
Overall efficiency P _{in} = 12 W, f _{in} = 1.0 GHz	-1	5.0		7.5	þГ
frequency doubler	η	50	60	_	%



STEP RECOVERY DIODE

Silicon planar epitaxial varactor diode exhibiting step recovery characteristics, especially suitable for use in frequency multiplier circuits up to C-band output frequency. It conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

Total capacitance, VR = 6.0 V

Ст

typ.

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

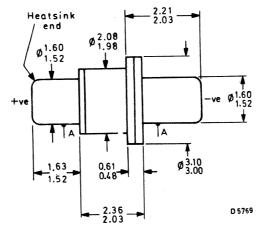
MECHANICAL DATA

Conforms to SOD-31

Dimensions in mm

pΕ

2.0



A = concentricity tolerance = ± 0.13

Devices may be selected to suit customers' specific requirements, including alternative packages.



RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

		/			
Storage temperature range	T _{stg}		-55 to	+175	οс
Junction temperature	T _j	max.		175	°C
D.C. reverse voltage	v _R	max.		35	V
Total power dissipation R.F.	- N	mux.		30	V
T _{pin} ≤ 70 °C	P_{tot}	max.		3.0	w
THERMAL RESISTANCE					
Thermal resistance from junction to pin	R _{th j-pin}	max.		35	oc/w
CHARACTERISTICS (T _{amb} = 25 °C)					
		min.	typ.	max.	
Reverse breakdown voltage, $I_R = 10 \mu A$	$V_{(BR)R}$	35			V
Reverse current, V _R = 26 V	I _R	_	0.001	1.0	μA
Forward voltage, I _F = 10 mA	V _E	-		1.0	μΛ V
Cut-off frequency, $V_R = 6.0 \text{ V}$,				1.0	V
f _{measured} = 2.0 GHz	f _{co}	100	120		GHz
Total capacitance	CO		120		UIIZ
$V_R = 6.0 V, f = 1.0 MHz$	C _T	1.0	_	3.0	pF
Overall efficiency	•			0.0	þ.
$P_{in} = 5.0 \text{ W}$, $f_{in} = 2.0 \text{ GHz}$, frequency tripler	η	40			0/



STEP RECOVERY DIODE

Silicon planar epitaxial varactor diode exhibiting step recovery characteristics, especially suitable for use in frequency multiplier circuits up to X-band output frequency. It conforms to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

Total capacitance, VR = 6.0 V

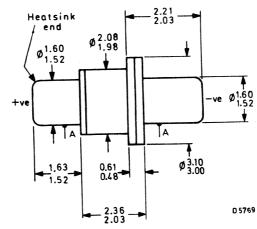
Operating as a frequency doubler 5 to 10 GHz in a typical	circuit.			
Input r.f. power	P _{in}		2.6	W
	Pout		1.0	W
Output r.f. power	1	+un	200	GHz
Resistive cut-off frequency, $V_R = 6.0 \text{ V}$	'co	typ.		
Total capacitance Vp = 6.0 V	СT	typ.	0.8	рF

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Conforms to SOD-31

Dimensions in mm



A = concentricity tolerance = ±0.13

Devices may be selected to suit customers' specific requirements, including alternative packages.



RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stg}		55 to	+175	οс
Junction temperature	Ti	max.		175	°C
D.C. reverse voltage	ν̈́R	max.		20	v
Total power dissipation R.F. $T_{pin} \le 70$ °C	P _{tot}	max.		2.5	w
THERMAL RESISTANCE					
Thermal resistance from junction to pin	R _{th j-pin}	max.		38.5	oC/W
CHARACTERISTICS (T _{amb} = 25 °C)	•				
		min.	typ.	max.	
Reverse breakdown voltage, $I_R = 10 \mu A$	$V_{(BR)R}$	20		_	V
Reverse current, V _R = 16 V	I _R			0.1	μA
Forward voltage, I _F = 10 mA	VF	_		1.0	V
Cut-off frequency, V _R = 6.0 V	•			1.0	٧
f _{measured} = 8.0 GHz	$f_{\mathbf{co}}$	180	200	-	GHz
Total capacitance					
$V_R = 6.0 \text{ V}, f = 1.0 \text{ MHz}$	СŢ	0.6	_	1.0	pF
Overall efficiency					
P _{in} = 2.6 W, f _{in} = 5.0 GHz frequency doubler					
	η	38	-		%



TUNING VARACTOR DIODES



SILICON PLANAR VARACTOR TUNING DIODES

This is a range of planar epitaxial varactor tuning diodes with highly reproducible abrupt junction performance. The devices are specifically designed for frequency tuning in military and professional applications where high stability is essential.

A \pm 10% capacitance tolerance is supplied as standard; closer tolerances are available on request. This series of diodes is available in a wide range of ceramic packages, including those shown here. They conform to the environmental requirements of BS CECC 50.006–010 where applicable.

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Storage temperature range Ambient temperature range for operation Reverse voltage	BXY48-20 BXY48-30 BXY48-40	T _{stg} T _{amb} VR VR VR	max max max	—65 to c. c.	20 30 40	∨ ∨ ∘C ∘C
CHARACTERISTICS (T _{amb} = 25 °C)						
20 volt series, BXY48—20			min.	typ.	max.	
Reverse breakdown voltage, $I_R = 10 \mu A$		V _{(BR)R}	22	25	-	V
Reverse leakage current, V _R = 20 V		^I R			0.1	μΑ
Junction capacitance, —4 V (note 1) Capacitance law (note 2)		c _j	0.3	-	1.6	рF
Q at -4 V (note 3)			-	2500	_	
30 volt series, BXY48-30				-00		.,
Reverse breakdown voltage, $I_R = 10 \mu A$		V _{(BR)R}	33	36		٧
Reverse leakage current, V _R = 30 V		1 _R	_		0.1	μΑ
Junction capacitance, —4 V (note 1) Capacitance law (note 2)		Cj	0.4		1.8	рF
Q at -4 V (note 3)			-	1500	_	
40 volt series, BXY48-40		.,	45	48		v
Reverse breakdown voltage, $I_R = 10 \mu A$		V _{(BR)R}	49	40	0.1	μA
Reverse leakage current, V _R = 40 V		^I R	-		4.5	pF
Junction capacitance, —4 V (note 1) Capacitance law (note 2)		Cj	0.6		4.5	þг
Q at -4 V (note 3)			_	1000	_	



BXY48 SERIES

Notes

1. The customer should specify the required <u>total</u> capacitance value and measurement voltage (0 or -4 V). A \pm 10% capacitance tolerance is supplied as standard; closer tolerances are available on request.

Capacitance is measured at 1 MHz.

2. All junctions are abrupt and obey the following law:

$$C_T = C_{jo} (1 + \frac{V_R}{\phi})^{-n} + C_s$$

where CT

C_T is total capacitance

 C_{jo} is zero bias junction capacitance

V_R is reverse voltage

 ϕ is 0.65 V, typically

n is 0.46, typically

C_s is package capacitance

- 3. Measurements at microwave frequencies are converted to Q at 50 MHz.
- 4. Case parasitics C_s and L_s are shown on the outline drawings.

Ordering information

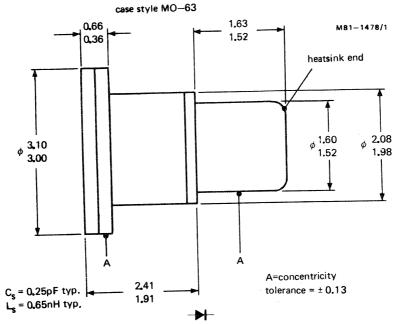
When ordering, please specify:

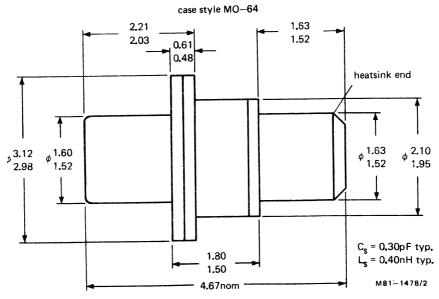
- 1. Reverse breakdown voltage.
- 2. Total capacitance and measurement voltage.
- 3. Capacitance tolerance.
- 4. Case style.





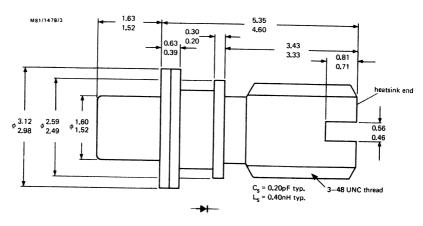
Dimensions in mm

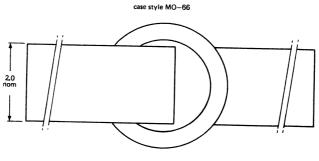


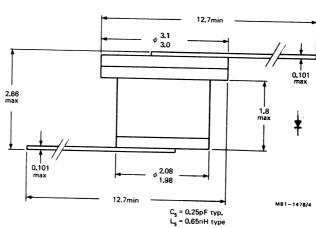


3

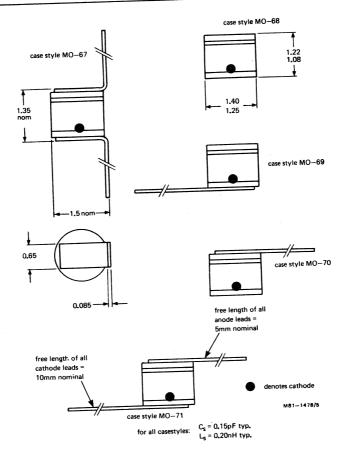
case style MO-65



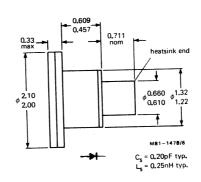




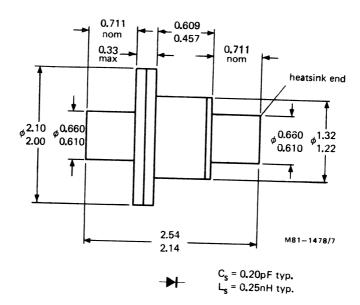




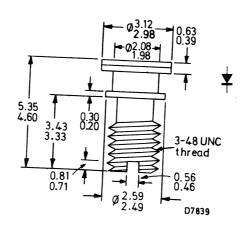
case style MO-72

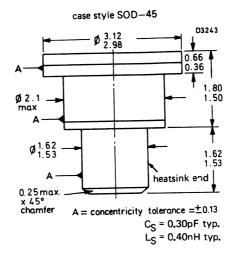


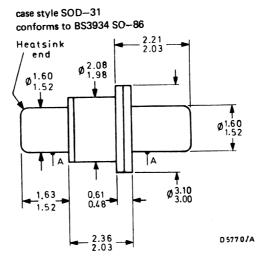
case style MO-73

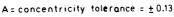












 $C_S = 0.25pF \text{ typ.}$ $L_S = 0.65nH \text{ typ.}$







SILICON VARACTOR TUNING DIODES

This is a range of epitaxial silicon tuning varactor diodes of the mesa type. The device structure is optimized for abrupt junction performance and highest Q. They are useful in a large number of microwave tuning applications and are available in a wide range of ceramic packages. A \pm 10% capacitance tolerance is supplied as standard; closer tolerances are available on request.

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Storage temperature range	T_{stq}	-55 to	+150	oC
Ambient temperature range for operation	T _{amb}	-55 to	+150	oC
Reverse voltage (note 1)	VR	max.	60	V

CHARACTERISTICS (T_{amb} = 25 °C)

		min.	typ.	max.	
Reverse breakdown voltage, $I_R = 10 \mu A$	V _{(BR)R}	60	65	-	V
Reverse leakage current, V _R = 55 V	l _R	_	_	1.0	μΑ
Junction capacitance, —4 V (note 2)	Сj	0.6	_	4.5	рF
Capacitance law (note 3)					
Q at -4 V (note 4)	typ typ	450		8 pF dev 7 pF dev	

Notes

- 1. Below 25 $^{\rm o}{\rm C}$ V $_{R}$ max. must be derated at 7 x 10 $^{\rm -2}$ $\,$ V/oC.
- The customer should specify the required total capacitance value and measurement voltage (0 or -4 V). A ± 10% capacitance tolerance is supplied as standard; closer tolerances are available on request.

Capacitance is measured at 1 MHz.

3. All junctions are abrupt and obey the following law:

$$C_{T} = C_{jo} \left(1 + \frac{V_{R}}{\phi}\right)^{-n} + C_{s}$$

where

C_T is total capacitance

Cio is zero bias junction capacitance

V_R is reverse voltage

 ϕ is 0.65 V, typically

n is 0.46, typically

C_s is package capacitance

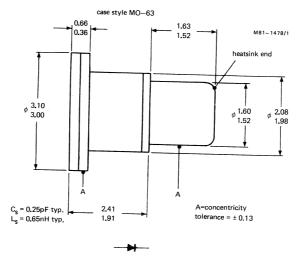
- 4. Measurements at microwave frequencies are converted to $\ensuremath{\text{O}}$ at 50 MHz.
- 5. Case parasitics $C_{\mbox{\scriptsize S}}$ and $L_{\mbox{\scriptsize S}}$ are shown on the outline drawings.

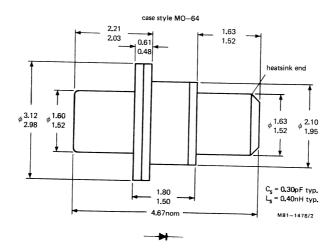


Ordering information

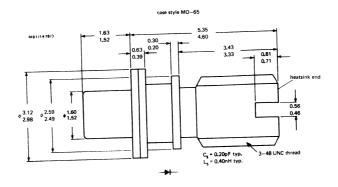
When ordering, please specify:

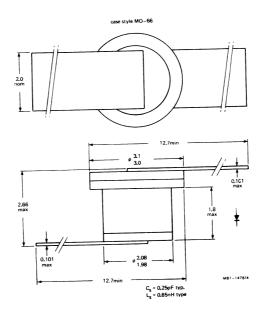
- 1. Total capacitance and measurement voltage.
- 2. Capacitance tolerance.
- 3. Case style.



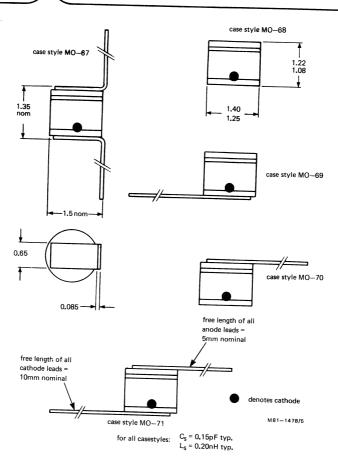




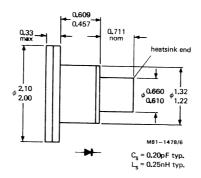






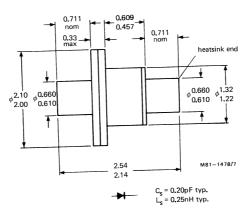


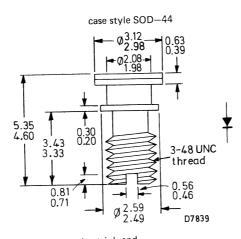
case style MO-72







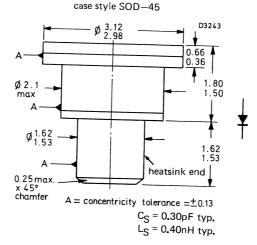


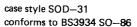


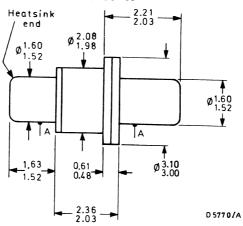
heatsink end

 $C_S = 0.25$ pF typ. $L_S = 0.65$ nH typ.









A = concentricity tolerance = ± 0.13

 $C_S = 0.25pF \text{ typ.}$ $L_S = 0.65nH \text{ typ.}$



GALLIUM ARSENIDE TUNING DIODES

This is a range of high Q gallium arsenide varactor tuning diodes with highly reproducible abrupt junction performance. The devices are specifically designed for broadband tuning applications up to Q-band (Ka-band). A \pm 10% capacitance tolerance is supplied as standard; closer tolerances are available on request.

This series of diodes is available in a wide range of ceramic packages.

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS -MICROWAVE SEMICONDUCTORS

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Storage temperature range Ambient temperature range for operation Reverse voltage		T _{stg} T _{amb} VR	-	-55 to + -55 to + nax.		oC oC
CHARACTERISTICS ($T_{amb} = 25$ °C) Reverse breakdown voltage, $I_R = 10 \mu A$ Junction capacitance, 0 V (note 1) Junction capacitance, -4 V (note 1) Capacitance law (note 2) 0 at -4 V (note 3)	V _{(BR)R} C _j		min. 35 0.6 0.3	typ. - - - -	max 4.8 2.0	V pF

Notes

- 1. The customer should specify the required total capacitance value and measurement voltage (0 or -4 V). A \pm 10% capacitance tolerance is supplied as standard; closer tolerances are available on request.
 - Capacitance is measured at 1 MHz.
- 2. All junctions are abrupt and obey the following law:

$$C_{T} = C_{jo} (1 + \frac{V_{R}}{\phi})^{-n} + C_{s}$$

where C_T is total capacitance

Cio is zero bias junction capacitance

V_R is reverse voltage

 ϕ is 0.65 V typically

n is 0.46, typically

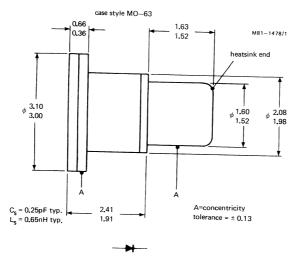
C_s is package capacitance

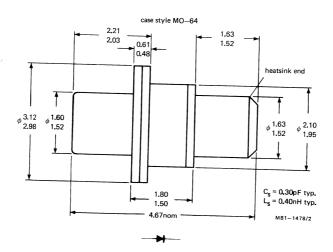
- 3. Measurements at microwave frequencies are converted to Q at 50 MHz.
- 4. Case parasitics $\mathbf{C_g}$ and $\mathbf{L_g}$ are shown on the outline drawings.

Ordering information

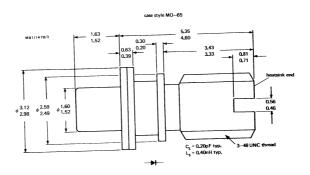
When ordering, please specify:

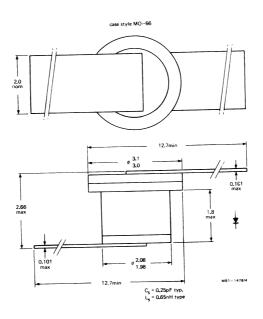
- 1. <u>Total</u> capacitance and measurement voltage.
- 2. Capacitance tolerance.
- Case style.

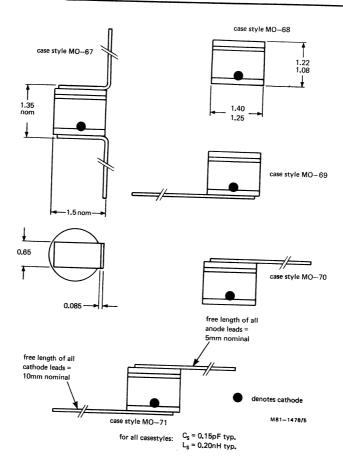




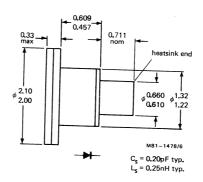




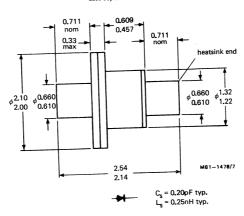


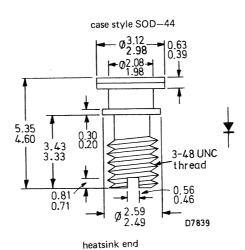


case style MO-72



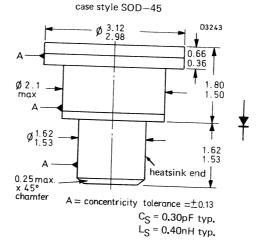




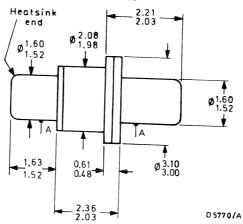


 $C_S = 0.25pF$ typ.

 $L_{S}^{3} = 0.65$ nH typ.



case style SOD-31 conforms to BS3934 SO-86



A = concentricity tolerance = ± 0.13

 $C_S = 0.25 pF \text{ typ.}$ $L_S = 0.65 nH \text{ typ.}$



LIMITER VARACTOR DIODES





GALLIUM ARSENIDE LIMITER DIODES

Gallium arsenide varactor diodes for limiter applications from C to X-band. Very low insertion loss and high isolation characteristics may be obtained. The diodes are of the diffused mesa type and are mounted in standard microwave packages. They conform to the environmental requirements of BS9300 where applicable.

QUICK REFERENCE DATA

QUICK REFERENCE DATA					
			CXY22A	CXY22B	
Operating frequency range	f		2.0 to 7.0	7.0 to 12	Ghz
•	Ст		0.85	0.55	рF
Total capacitance at 0 V	υ 1			0.3	dB
Insertion loss*		typ.	0.2	0.3	
High power attenuation*		typ.	20	16	dB
*Depends on circuit configuration, see pa	age 2				

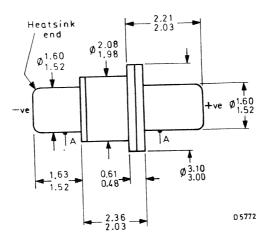
Unless otherwise shown, data is applicable to both types.

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm

Conforms to SOD-31 and BS3934 SO-86



A = concentricity tolerance = ± 0.13

Devices may be selected to suit customers' specific requirements, including alternative packages. It is recommended that the device is functionally tested, by the supplier, in the customer's circuit.



RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

Storage temperature range	T_{stq}	-55 to +150	°C
Ambient temperature range	- ~		-
D.C. reverse voltage	l amb	-55 to +100	oC
= 10110100 Voltage	V _R max.	6.0	V

CHARACTERISTICS

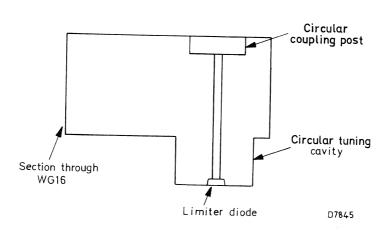
			CXY22A	CXY22B	
Reverse current, V _R = 6.0 V	I_{R}	max.	1.0	1.0	μΑ
D.C. forward voltage, $I_F = 50 \text{ mA}$	٧ _F	max.	1.45	1.45	V
Total capacitance, $V_R = 0$, $f = 1 \text{ MHz}$	c_T	typ.	0.85	0.55	рF
Series resistance, V _R = 0	r _s	typ.	1.0	1.2	Ω

TYPICAL X-BAND LIMITER USING CXY22B

This is a resonant circuit in rectangular waveguide, operating by reflection of a high input power:

Centre frequency	f	0.4	
Bandwidth at 1 mW max., v.s.w.r. = 1.2:1	'0	9.4	GHz
Insertion loss at 1 mW max.	$\triangle f_{\mathbf{o}}$	300	MHz
		0.3	dB
Insertion loss at 100 mW, c.w.		6.0	dB
Insertion loss at 5 W peak, p.r.f. 1 kHz, 1 μs		16	dB
Safe peak power handling*, p.r.f. 1 kHz, 1 μs			
, , , , , , , , , , , , , , , , , , , ,		50	W

^{*}Peak power handling depends on pulse length and duty cycle, as well as circuit design.





SILICON BIPOLAR TRANSISTORS

Н



SILICON BIPOLAR TRANSISTORS GENERAL OPERATIONAL RECOMMENDATIONS

INTRODUCTION

These devices operate at high frequencies and high powers. To avoid damage or destruction, it is advisable to follow the advice given below during testing, setting-up procedures and final operation.

MECHANICAL

- Good thermal and electrical conductivity is essential for efficient operation. Any metallic interface may introduce local overheating and an increase in contact resistance. It is therefore essential to use an adequate heatsink and heatsink compound between the rear face of the transistor or its flange and the heatsink.
- Connections between the test jig or amplifier circuitry must be as short as possible, in any case not more than 100 $\mu m. \,$ Special care must be taken to use the shortest possible high frequency earth (ground) connection.
- When mounting the transistor on its heatsink, the recommended torque must not be exceeded.

POLARIZATION

- When testing transistors in a new circuit, it is recommended that the supply voltage is reduced to approximately 70% of its nominal value and that series emitter or collector resistors are used (for common base and common emitter configurations respectively). After initial tests have been made, the series resistors may be decreased and the voltage increased.
- The use of high value capacitors must be avoided as far as possible. If their use cannot be avoided, series resistors of a few ohms must be inserted.

OPERATION

- Input power
 - While the circuit is not optimized, it is recommended that the power input should be at a lower level than that specified.
- Output waveform 2.
 - It is advisable to check the output waveform with a spectrum analyzer or similar equipment to ensure that no parasitic effects are introduced by the power supply or earth (ground) connections, thus causing unwanted modulation.
- Junction temperature
 - If the circuit design is likely to cause a large temperature rise, it is advisable to check the temperature rise with a pulsed input before applying full power.





N-P-N MICROWAVE TRANSISTOR

The BFQ33 is a small-signal silicon planar epitaxial transistor in a miniature hermetically sealed microstripline encapsulation, featuring an extremely high transition frequency and very low noise up to high frequencies.

It is primarily intended for use in microwave amplifier applications.

QUICK REFERENCE DATA

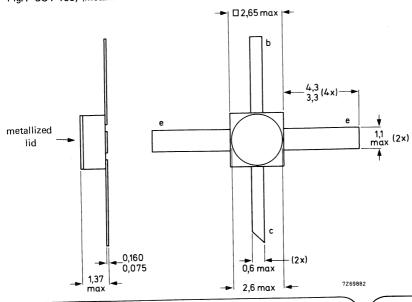
Collector-base voltage (open emitter)	v_{CBO}	max.	9 V
Collector-emitter voltage (open base)	v_{CEO}	max.	7 V
Collector current (d.c.)	۱c	max.	20 mA
Total power dissipation up to T _{amb} = 80 °C	P_{tot}	max.	140 mW
Transition frequency at $f = 1.5 \text{ GHz}$ $I_C = 14 \text{ mA}$; $V_{CE} = 5 \text{ V}$	f_{T}	typ.	12 GHz
Noise figure at optimum source impedance IC = 5 mA; VCE = 5 V; f = 2 GHz	No	typ.	2,5 dB
Maximum unilateral power gain (see page 3) $I_C = 14 \text{ mA}$; $V_{CE} = 5 \text{ V}$; $f = 2 \text{ GHz}$; $T_{amb} = 25 \text{ °C}$	G _{UM}	typ.	13,7 dB

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — ${\tt MICROWAVE}$ SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm

Fig.1 SOT-100, (metallized lid connected to emitter)



RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)							
Collector-base voltage (open emitter)	V_{CBO}	max.	9 V				
Collector-emitter voltage (open base)	VCEO	max.	7 V				
Emitter-base voltage (open collector)	V_{EBO}	max.	2 V				
Collector current (d.c.)	lc .	max.	20 mA				
Total power dissipation up to T _{amb} = 80 °C	P _{tot}	max.	140 mW				
Storage temperature	T _{sta}	-65 to	+ 150 °C				
Junction temperature	Ti	max.	150 °C				

THERMAL RESISTANCE

From junction to ambient in free air mounted on a fibre-glass print of 40 mm x 25 mm x 1 mm

 $R_{th j-a} = 500 \text{ }^{\circ}\text{C/W}$

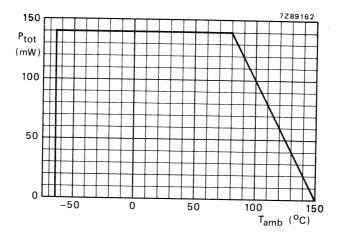


Fig. 2 Power derating curve versus ambient temperature.



CHARACTERISTICS			
T _{amb} = 25 °C unless otherwise specified			
Collector cut-off current I _E = 0; V _{CB} = 5 V	Ісво	<	50 nA
D.C. current gain* I _C = 14 mA; V _{CE} = 5 V	hFE	>	25
Collector capacitance at f = 1 MHz I _E = I _e = 0; V _{CB} = 5 V	C_{c}	typ.	0,45 pF
Feedback capacitance at $f = 1 \text{ MHz}$ $I_C = 0$; $V_{CE} = 5 \text{ V}$	c_{re}	typ.	0,2 pF
Transition frequency at f = 1,5 GHz* $I_C = 14 \text{ mA}$; $V_{CE} = 5 \text{ V}$	f_{T}	typ.	12 GHz
Noise figure at optimum source impedance $I_C = 5 \text{ mA}$; $V_{CE} = 5 \text{ V}$; $f = 2 \text{ GHz}$	No	typ.	2,5 dB
$I_C = 5 \text{ mA}; V_{CE} = 5 \text{ V}; f = 4 \text{ GHz}$	N_{o}	typ.	3,8 dB
Maximum unilateral power gain (s_{re} assumed to be zero) $\frac{ s_{fe} ^2}{(1- s_{ie} ^2)(1- s_{oe} ^2)}$			
$I_C = 14 \text{ mA}$; $V_{CE} = 5 \text{ V}$; $f = 2 \text{ GHz}$	G _{UM}	typ.	13,7 dB
$I_C = 14 \text{ mA}$; $V_{CE} = 5 \text{ V}$; $f = 4 \text{ GHz}$	G_{UM}	typ.	7,4 dB
s-parameters (common emitter) I_C = 14 mA; V_{CE} = 5 V; R_S = R_L = 50 Ω ; f = 2 GHz			0.40/ 4550
Input reflection coefficient Reverse transmission coefficient Forward transmission coefficient Output reflection coefficient	^s ie ^s re ^s fe ^s oe	typ. typ. typ. typ.	0,18/-155° 0,10/ +49° 4,3 / +75° 0,43/ -56°
I _C = 14 mA; V _{CE} = 5 V; R _S = R _L = 50 Ω; f = 4 GHz Input reflection coefficient Reverse transmission coefficient Forward transmission coefficient Output reflection coefficient	sie sre sfe soe	typ. typ. typ. typ.	



^{*} Measured under pulse conditions.

Conditions for Figs 3 and 4:

 V_{CE} = 5 V; I_{C} = 14 mA; T_{amb} = 25 °C.

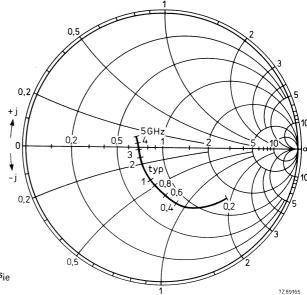


Fig. 3 Input impedance derived from input reflection coefficient s_{ie} co-ordinates in ohm \times 50.

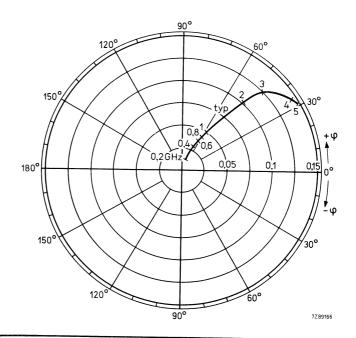


Fig. 4 Reverse transmission coefficient s_{re} .



Conditions for Figs 5 and 6:

 $V_{CE} = 5 \text{ V}; I_{C} = 14 \text{ mA};$ $T_{amb} = 25 \text{ oC}.$

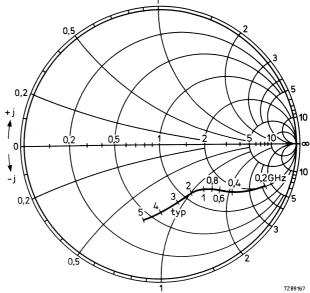


Fig. 5 Output impedance derived from output reflection coefficient $s_{\mbox{\scriptsize oe}}$ co-ordinates in ohm x 50.

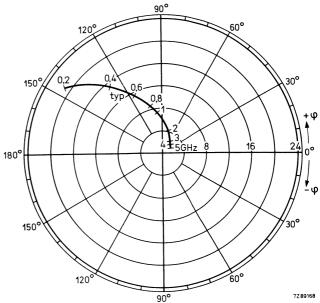
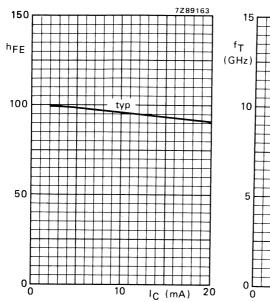


Fig. 6 Forward transmission coefficient s_{fe}.





5 10 I_C (mA) 20

Fig. 7 $V_{CE} = 5 \text{ V}$; $T_j = 25 \text{ °C}$.

Fig. 8 $V_{CE} = 5 \text{ V}$; f = 1,5 GHz; $T_j = 25 \text{ oC}$.

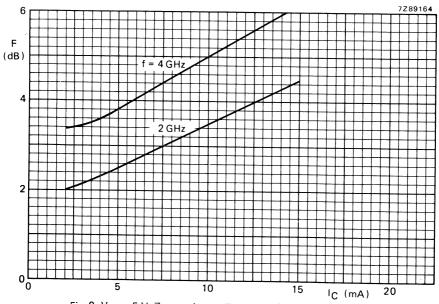


Fig. 9 $V_{CE} = 5 \text{ V}$; $Z_S = \text{optimum}$; $T_{amb} = 25 \text{ °C}$; typical values.

N-P-N SILICON MICROWAVE TRANSISTOR

The BFR49 is a microwave transistor featuring a high transition frequency and low noise. A miniature ceramic encapsulation is used for compatibility with stripline and microwave circuits. It is suitable for amplifiers up to S-band frequencies in instrumentation and microwave systems.

QUICK REFERENCE DATA

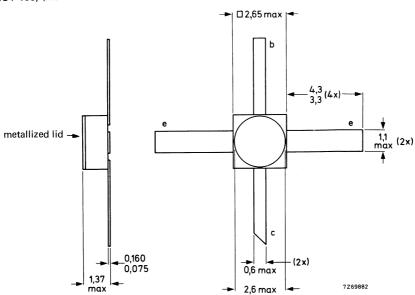
Transducer power gain IC = 14 mA; VCE = 10 V; f = 1 GHz	s _{fe} 2	typ	15,5 dB
Noise figure at optimum source impedance $I_C = 2 \text{ mA}$; $V_{CE} = 10 \text{ V}$; $f = 1 \text{ GHz}$	No	typ	2,5 dB
Transition frequency $I_C = 14 \text{ mA; } V_{CE} = 10 \text{ V}$	f _T	typ	5 GHz
Total power dissipation up to $T_{amb} = 110$ °C	P _{tot}	max	180 mW
Collector current (d.c.)	I _C	max	25 mA
Collector-emitter voltage (open base)	v_{CEO}	max	15 V
Collector-base voltage (open emitter)	v_{CBO}	max	20 V

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — ${\tt MICROWAVE}$ SEMICONDUCTORS

MECHANICAL DATA

SOT-100, (metallized lid connected to emitter)

Dimensions in mm





RATINGS

 $I_E = 0$; $V_{CB} = 10 \text{ V}$

 $I_C = 14 \text{ mA}; V_{CF} = 10 \text{ V}$

Collector capacitance at f = 1 MHz $I_E = I_e = 0$; $V_{CB} = 10 \text{ V}$

Emitter capacitance at f = 1 MHz $I_C = I_c = 0$; $V_{EB} = 0.5 \text{ V}$

 $I_C = 14 \text{ mA}$; $V_{CE} = 10 \text{ V}$; f = 500 MHz

D.C. current gain *

Transition frequency *

Limiting values in accordance with the Absolute Maximum System (IEC 134)			
Collector-base voltage (open emitter; $I_C = 10 \mu A$)	V_{CBO}	max	20	V
Collector-emitter voltage (open base; I _C = 10 mA)	VCEO	max	15	V
Emitter-base voltage (open collector; $I_E = 10 \mu A$)	V_{EBO}	max	2	V
Collector current (d.c.)	Ic	max	25	mA
Total power dissipation up to T _{amb} = 110 °C	P _{tot}	max	180	mW
Storage temperature	T _{stg}	-65 to +	200	οС
Junction temperature	Tj	max	200	oC
THERMAL RESISTANCE				
From junction to ambient in free air mounted on a fibre-glass print of 40 mm x 25 mm x 1 mm	R _{th j-a}	=	0,5	oC/mW
CHARACTERISTICS				
T _{amb} = 25 °C unless otherwise specified				
Collector cut-off current				

ICBO

hFE

fΤ

 $C_{\mathbf{c}}$

 C_{e}

<

>

typ

typ

typ

50 nA

5 GHz

25

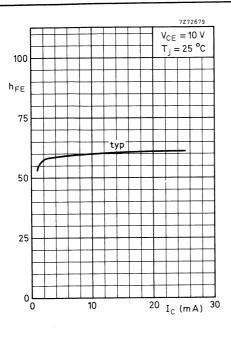
0,35 pF

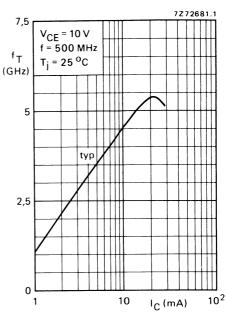
1,1 pF

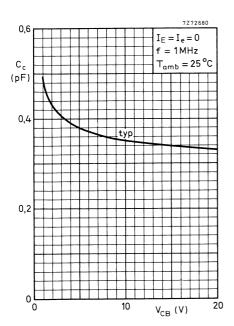


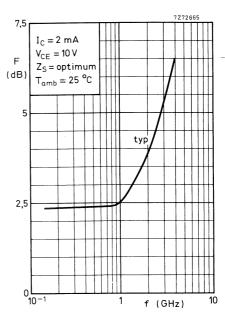
Feedback capacitance at f = 1 MHz	Ü	,,	, ,
IC = 2 mA; V _{CE} = 10 V	C_{re}	typ	0,3 pF
Noise figure at optimum source impedance			
$I_C = 2 \text{ mA}; V_{CE} = 10 \text{ V}; f = 1 \text{ GHz}$	No	typ	2,5 dB
$I_C = 2 \text{ mA}$; $V_{CE} = 10 \text{ V}$; $f = 4 \text{ GHz}$	No	typ	6,5 dB
Maximum unilateral power gain (sre assumed to be zero)			
G_{UM} (in dB) = 10 log $\frac{ s_{fe} ^2}{(1- s_{ie} ^2)(1- s_{Oe} ^2)}$			
$I_C = 14 \text{ mA}; V_{CE} = 10 \text{ V}; f = 1 \text{ GHz}$	G_{UM}	typ	17,0 dB
$I_C = 14 \text{ mA}$; $V_{CE} = 10 \text{ V}$; $f = 4 \text{ GHz}$	G_{UM}	typ	6,5 dB
Transducer power gain			
$I_C = 14 \text{ mA}$; $V_{CE} = 10 \text{ V}$; $f = 1 \text{ GHz}$	sfe 2	typ	15,5 dB
$I_C = 14 \text{ mA}$; $V_{CE} = 10 \text{ V}$; $f = 4 \text{ GHz}$	s _{fe} 2	typ	3,5 dB

^{*} Measured under pulse conditions.

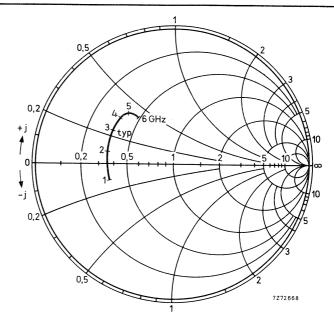








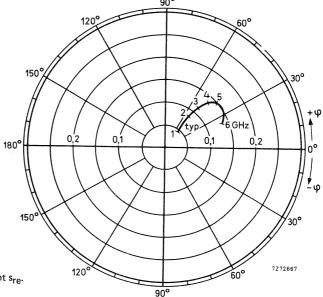
 $V_{CE} = 10 V$ $I_{C} = 14 \text{ mA}$ $T_{amb} = 25 \text{ °C}$



Input impedance derived from input reflection coefficient sie co-ordinates in ohm x 50.

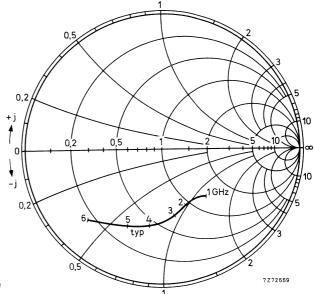


 $V_{CE} = 10 V$ $I_{C} = 14 \text{ mA}$ $T_{amb} = 25 \text{ }^{\circ}\text{C}$



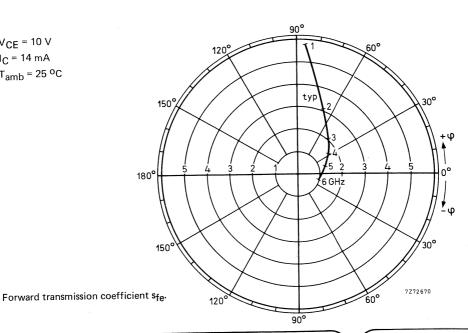
Reverse transmission coefficient s_{re} .

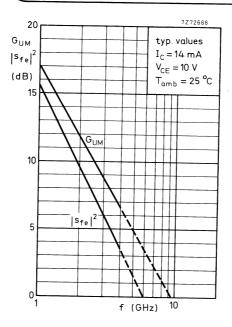
V_{CE} = 10 V $I_C = 14 \text{ mA}$ $T_{amb} = 25$ OC



Output impedance derived from output reflection coefficient soe co-ordinates in ohm x 50.









MICROWAVE LINEAR POWER TRANSISTOR

N-P-N transistor for common-emitter class-A linear power amplifiers up to 4 GHz. Self-aligned process entirely ion implanted and gold sandwich metallization ensure an optimum temperature profile, excellent performance and reliability.

A miniature ceramic encapsulation is used for compatibility with stripline and microwave circuits.

QUICK REFERENCE DATA

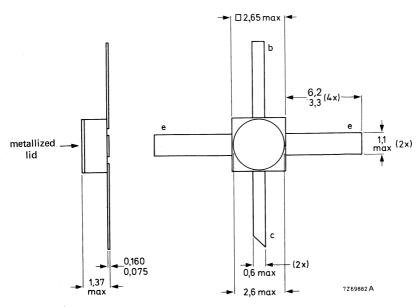
QOION TIE. ETTENT								
R.F. performance up to T _{case} = 25 °C in an unneutralized common-emitter class-A circuit								
mode of operation	f GHz	V _{CE} V	I _C	P _{L1} mW	G _{po} dB	$\frac{z_i}{\Omega}$	2 _L Ω	
c.w.; linear amplifier	4	15	25	typ. 110	typ. 9,5	typ. 7 + j22	typ. 10 + j38	

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — ${\tt MICROWAVE}$ SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm

Fig.1 SOT-100 (metallized lid connected to emitter)



Marking code

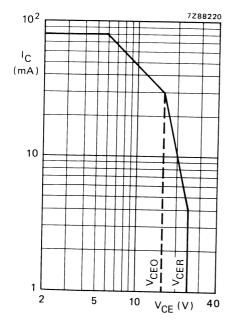
R8 = LAE4001R

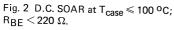


RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134).

	-, (. = 0.0.1).			
Collector-base voltage (open emitter)	V_{CBO}	max.	30	V
Collector-emitter voltage	000			-
$(R_{BE} = 220 \Omega)$	v_{CER}	max.	25	V
(open base)	VCEO	max.	16	V
Emitter-base voltage (open collector)	V_{EBO}	max.	2	V
Collector current (d.c.)	IC	max.	80	mΑ
Total power dissipation up to T _{case} = 100 °C	P _{tot}	max.	480	mW
Storage temperature	T _{stg}	-65 to		οС
Junction temperature	T _i	max.	200	°C
Lead soldering temperature	J		200	Ü
at 0,1 mm from the case; $t_{sld} \le 10 s$	T_{sld}	max.	235	οС





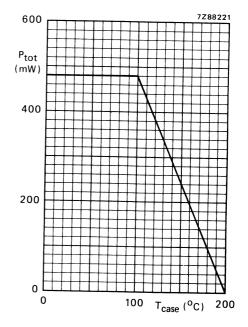


Fig. 3 Power derating curve vs. temperature.

THERMAL RESISTANCE

From junction to case

 $R_{th j-c} = 210 \, {}^{\circ}\text{C/W}$



Maximum available gain

 $I_C = 25 \text{ mA}; V_{CE} = 15 \text{ V}; f = 2 \text{ GHz}$

 $I_C = 25 \text{ mA}$; $V_{CE} = 15 \text{ V}$; f = 4 GHz

CHARACTERISTICS					
T _{case} = 25 °C					
Collector cut-off current I _F = 0; V _{CB} = 15 V	I _{CBO}	<	100	nA	
I _E = 0; V _{CB} = 30 V	^I CBO	<	100	μΑ	
V_{CB} = 25 V; R_{BE} = 220 Ω	ICER	<	500	μΑ	
Emitter cut-off current	I _{EBO}	<	35	nА	
$I_C = 0$; $V_{EB} = 1,5 \text{ V}$	IEBO	<	0,15	μA	
$I_C = 0; V_{EB} = 2,0 \text{ V}$	EBO	•	0,.0	<i>,</i>	
D.C. current gain	hFE	20 to	220		
$I_C = 25 \text{ mA}; V_{CE} = 5 \text{ V}$					
Collector-base capacitance at f = 1 MHz	C _{cb}	typ.	0,25	рF	
$I_E = I_C = 0$; $V_{CB} = 15 \text{ V}$; $V_{EB} = 1.5 \text{ V}$	CD	-,	-,	1	
Collector-emitter capacitance at f = 1 MHz	·	turo.	0,5	рF	
$I_E = I_C = 0$; $V_{CE} = 15$; $V_{EB} = 1,5 \text{ V}$	C _{ce}	typ.	0,5	ρı	
Emitter-base capacitance at f = 1 MHz	0	tu un	1,3	рF	
$I_E = I_C = 0$; $V_{EB} = 1.0 \text{ V}$; $V_{CB} = 15 \text{ V}$	C _{eb}	typ.	1,3	рг	
Forward power gain	2	du en	0.6	dB	
$I_C = 25 \text{ mA}; V_{CE} = 15 \text{ V}; f = 2 \text{ GHz}$	Sfe 2	typ.	9,6		
$I_C = 25 \text{ mA}; V_{CE} = 15 \text{ V}; f = 4 \text{ GHz}$	sfe 2	typ.	3,8	dB	

 G_{AM}

 G_{AM}

typ.

typ.



16 dB

10 dB

LAE4001R

s-parameters (common emitter)

Typical values; V_{CE} = 15 V; I_C = 25 mA; T_{case} = 25 °C; Z_o = 50 Ω

		•		
f MHz	s _{ie}	s _{re}	s _{fe}	s _{oe}
500	0,63/-165°	0,014(-37,1)/47°	10,7 (20,6)/ 101°	0,59/— 28°
600	0,64/-171°	0,015(-36,2)/47°	9,01(19,1)/ 96°	0,58/— 29°
700	0,65/-177°	0,018(-35,1)/47°	8,03(18,1)/ 89°	0,56/— 30°
800	0,65/ 180°	0,019(-34,5)/47°	7,08(17,0)/ 84°	0,55/— 31°
900	0,65/ 176°	0,021(-33,7)/48°	6,31(16,0)/ 80°	0,54/— 32°
1000	0,66/ 172°	0,023(-32,9)/49°	5,75(15,2)/ 76°	0,53/— 34°
1200	0,67/ 167°	0,026(-31,8)/50°	4,85(13,7)/ 69°	0,53/— 37°
1400	0,67/ 163 ⁰	0,030(-30,5)/50°	4,17(12,4)/ 62°	0,52/- 41°
1600	0,67/ 155 ⁰	0,034(-29,3)/50°	3,67(11,3)/ 56°	0,52/- 44°
1800	0,67/ 150 ⁰	0,038(-28,4)/51°	3,31(10,4)/ 50°	0,52/- 49°
2000	0,68/ 146°	0,043(-27,4)/50°	3,02(9,6)/ 45°	0,52/- 53°
2500	0,70/ 134°	0,053(-25,5)/47°	2,46(7,8)/ 31°	0,52/- 64°
3000	0,72/ 123°	0,064(-23,9)/43°	2,05(6,2)/ 18°	0,51/- 76°
3500	0,74/ 113°	0,075(-22,5)/38°	1,76(4,9)/ 3°	0,50/- 90°
4000	0,76/ 104°	0,085(-21,4)/33°	1,55(3,8)/ -11°	0,50/-105°
4500	0,77/ 95°	0,095(-20,4)/260	1,37(2,7)/ -23°	0,51/—123°
5000	0,79/ 88°	0,107(-19,4)/190	1,19(1,5)/ -35°	0,52/—141°
5500	0,80/ 81°	0,120(-18,4)/120	1,06(0,5)/ -48°	0,57/—158°
6000	0,80/ 75°	0,133(-17,5)/ 60	0,96(-0,4)/ -60°	0,62/—173°

The figures given between brackets are values in dB.



APPLICATION INFORMATION

R.F. performance up to T_{case} = 25 °C in an unneutralized common-emitter class-A circuit *

N.1. performance up to Tease								
mode of operation	f GHz	V _{CE} (1)	I _C (¹) mA	P _{L1} (²) mW(dBm)	G _{po} (³) dB	z _i Ω	Z _L Ω	
c.w.; linear amplifier	4	15	25	> 85(19,3) typ. 110(20,4)	> 8,5 typ. 9,5	typ.7+j22	typ.10+j38	

Notes

- 1 IC and VCE regulated.
- 2 Load power for 1 dB compressed power gain.
- 3 Low-level power gain associated with PL1.

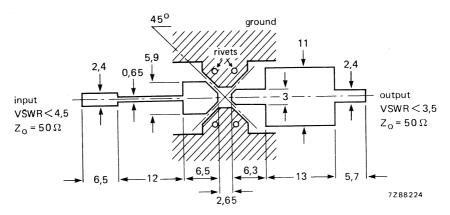


Fig. 4 Prematching test circuit board for 4 GHz. (Dimensions in mm.)

Striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric ($\epsilon_{\rm r}$ = 2,54); thickness 0,8 mm.



^{*} Circuit consists of prematching circuit board in combination with input and output slug tuners.

LAE4001R

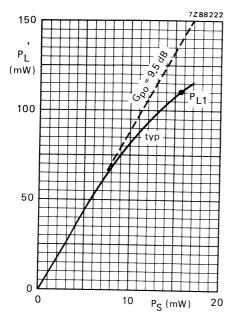


Fig. 5 V_{CE} = 15 V; I_{C} = 25 mA; f = 4 GHz; T_{case} = 25 °C.

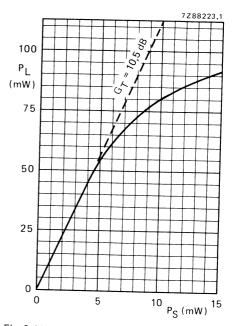


Fig. 6 V_{CE} = 15 V; I_{C} = 25 mA; f = 4 GHz; maximum low-level linear power gain.



MICROWAVE LINEAR POWER TRANSISTOR

N-P-N transistor for common-emitter class-A linear power amplifiers up to 4 GHz. Diffused emitter ballasting resistors, self-aligned process entirely ion implanted and gold sandwich metallization ensure an optimum temperature profile, excellent performance and reliability.

A miniature ceramic encapsulation is used for compatibility with stripline and microwave circuits.

QUICK REFERENCE DATA

R.F. performance up to $T_{case} = 25$ °C in an unneutralized common-emitter class-A circuit

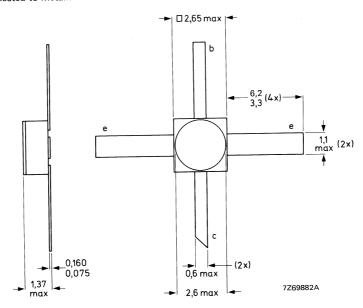
mode of operation	f GHz	V _{CE} V	I _C	P _{L1} mW	G _{po} dB	$\frac{\overline{z_i}}{\Omega}$	Z _L Ω
c.w.; linear amplifier	4	18	30	typ. 160	typ. 8	typ. 4 + j23	typ. 6,5 + j32

MECHANICAL DATA

Dimensions in mm

Fig. 1 SOT-100.

Emitter connected to metallized lid



Marking code

R9 = LAE4002S

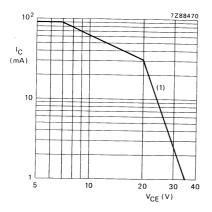


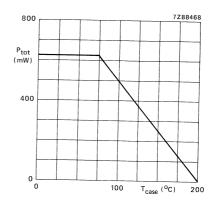
LAE4002S

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Collector-base voltage (open emitter)	V_{CBO}	max.	40	V
Collector-emitter voltage	050			
$(R_{BE} = 220 \Omega)$	v_{CER}	max.	35	V
(open base)	VCEO	max.	16	V
Emitter-base voltage (open collector)	V_{EBO}	max.	3	V
Collector current (d.c.)	l _C	max.	90	mΑ
Total power dissipation up to $T_{case} = 75 {}^{\circ}C$	P _{tot}	max.	625	mW
Storage temperature	T _{stg}	-65 to +	200	οС
Junction temperature	T _i	max.	200	οС
Lead soldering temperature	,			
at 0,1 mm from the case; $t_{sld} \le 10 s$	T_{sld}	max.	235	οС





(1) Second breakdown limit (independent of temperature).

Fig. 2 D.C. SOAR at $T_{case} \! \leqslant \! 75$ °C; $R_{BE} \! < \! 220~\Omega.$

THERMAL RESISTANCE

From junction to case

R_{th j-c} = 200 °C/W



CHARACTERISTICS

T _{case} = 25 °C			
Collector cut-off current	Ісво	<	100 nA
$I_E = 0$; $V_{CB} = 20 \text{ V}$	CBO	<	150 μΑ
$I_E = 0$, $V_{CB} = 40 \text{ V}$	CER	<	500 μΑ
V_{CB} = 35 V; R_{BE} = 220 Ω	CLIT		•
Emitter cut-off current	IEBO	<	50 nA
$I_C = 0; V_{EB} = 1,5 \text{ V}$	IEBO	<	25 μΑ
$I_C = 0$; $V_{EB} = 3.0 \text{ V}$	LBO		
D.C. current gain $I_C = 30 \text{ mA}$; $V_{CE} = 5 \text{ V}$	hFE	15 t	o 150
Collector-base capacitance at f = 1 MHz $I_E = I_C = 0$; $V_{CB} = 18 \text{ V}$; $V_{EB} = 1,5 \text{ V}$	C _{cb}	typ.	0,3 pF
Collector-emitter capacitance at $f = 1 \text{ MHz}$ $I_E = I_C = 0$; $V_{CE} = 18 \text{ V}$; $V_{EB} = 1,5 \text{ V}$	$C_{\mathbf{ce}}$	typ.	0,55 pF
Emitter-base capacitance at $f = 1 \text{ MHz}$ $I_E = I_C = 0$; $V_{EB} = 1,0 \text{ V}$; $V_{CB} = 18 \text{ V}$	C _{eb}	typ.	1,8 pF
Forward power gain	sfe 2	typ.	8,8 dB
$I_C = 30 \text{ mA}$; $V_{CE} = 18 \text{ V}$; $f = 2 \text{ GHz}$	s _{fe} 2	typ.	2,8 dB
$I_C = 30 \text{ mA}; V_{CE} = 18 \text{ V}; f = 4 \text{ GHz}$	ialei	.,,	
Maximum available gain $\frac{1}{100} = \frac{1}{100} \times \frac{1}{100} \times \frac{1}{100} \times \frac{1}{100} = \frac{1}{100} \times \frac{1}{100} = \frac{1}{100} \times \frac{1}{100} = \frac{1}{100} \times \frac{1}{100} \times \frac{1}{100} = \frac{1}{100} \times \frac{1}{100} \times \frac{1}{100} = \frac{1}{100} \times \frac{1}{$	G_{AM}	typ.	14 dB
$I_C = 30 \text{ mA}; V_{CE} = 18 \text{ V}; f = 2 \text{ GHz}$	GAM	typ.	11 dB
$I_C = 30 \text{ mA}$; $V_{CE} = 18 \text{ V}$; $f = 3 \text{ GHz}$	AWI		



s-parameters (common emitter)

Typical values; V_{CE} = 18 V; I_C = 30 mA; T_{case} = 25 °C; Z_o = 50 Ω

f MHz	s _{ie}	s _{re}	s _{fe}	s _{oe}
500 600 700 800 900 1000 1200 1400 1600 1800 2000 2500 3000 3500 4000 4500 5500 6000	0,63/—153° 0,63/—161° 0,63/—168° 0,64/—173° 0,64/—177° 0,64/—177° 0,65/—165° 0,65/—159° 0,65/—154° 0,66/—147° 0,67/—134° 0,70/—122° 0,71/—111° 0,73/—101° 0,75/—92° 0,76/—85° 0,77/—78°	0,023(-32,7)/38° 0,024(-32,2)/38° 0,026(-31,6)/38° 0,028(-30,9)/38° 0,030(-30,4)/38° 0,032(-29,9)/40° 0,035(-29,0)/40° 0,039(-28,1)/41° 0,044(-27,1)/41° 0,044(-27,1)/41° 0,048(-26,3)/41° 0,053(-25,5)/40° 0,064(-23,9)/37° 0,076(-22,4)/33° 0,088(-21,1)/28° 0,101(-19,9)/22° 0,112(-19,0)/16° 0,125(-18,1)/8° 0,138(-17,2)/2°	9,89(19,9)/ 980 8,22(18,3)/ 940 7,33(17,3)/ 870 6,46(16,2)/ 820 5,82(15,3)/ 780 5,25(14,4)/ 740 4,47(13,0)/ 660 3,80(11,6)/ 590 3,35(10,5)/ 520 3,02(9,6)/ 460 2,75(8,8)/ 400 2,24(7,0)/ 250 1,84(5,3)/ 110 1,58(4,0)/ -40 1,38(2,8)/-120 1,21(1,7)/-320 1,05(0,4)/-450 0,92(-0,7)/-580	0,55/ -34° 0,53/ -35° 0,51/ -36° 0,50/ -37° 0,50/ -38° 0,49/ -40° 0,48/ -44° 0,48/ -53° 0,48/ -59° 0,48/ -64° 0,48/ -77° 0,48/ -91° 0,48/ -108° 0,50/ -125° 0,52/ -143° 0,56/ -161° 0,61/ -178°
0000	0,77/ 710	0,150(-16,5)/-40	0,81(-1,8)/-690	0,67/ 168º

Typical values; V_{CE} = 15 V; I_C = 15 mA; T_{case} = 25 °C; Z_o = 50 Ω

f MHz	s _{ie}	s _{re}	s _{fe}	s _{oe}
500 600 700 800 900 1000 1200 1400 1600 1800 2000 2500 3500 4000 4500 5000 5500 6000	0,63/-145° 0,63/-154° 0,63/-161° 0,64/-167° 0,64/-172° 0,64/-177° 0,65/ 170° 0,65/ 170° 0,65/ 157° 0,66/ 149° 0,67/ 136° 0,69/ 124° 0,71/ 112° 0,73/ 102° 0,75/ 93° 0,76/ 86° 0,77/ 78° 0,77/ 78° 0,77/ 72°	0,030(-30,5)/36° 0,031(-30,1)/35° 0,033(-29,6)/33° 0,035(-29,2)/33° 0,036(-28,8)/32° 0,038(-28,4)/32° 0,041(-27,8)/33° 0,045(-27,0)/36° 0,048(-26,3)/34° 0,052(-25,7)/35° 0,056(-25,0)/33° 0,066(-23,6)/32° 0,076(-22,3)/28° 0,089(-21,0)/24° 0,100(-20,0)/20° 0,112(-19,0)/13° 0,125(-18,1)/6° 0,136(-17,3)/0° 0,148(-16,6)/-7°	9,22(19,3)/103° 7,76(17,8)/ 97° 6,92(16,8)/ 90° 6,16(15,8)/ 85° 5,56(14,9)/ 81° 5,01(14,0)/ 76° 4,26(12,6)/ 68° 3,67(11,3)/ 61° 3,23(10,2)/ 55° 2,92(9,3)/ 48° 2,66(8,5)/ 42° 2,14(6,6)/ 26° 1,78(5,0)/ 12° 1,53(3,7)/ –2° 1,29(2,2)/–17° 1,16(1,3)/–31° 1,01(0,1)/–43° 0,88(–1,1)/–56° 0,79(–2,1)/–67°	0,58/ -38° 0,56/ -39° 0,52/ -40° 0,51/ -41° 0,50/ -42° 0,49/ -44° 0,48/ -48° 0,47/ -57° 0,47/ -67° 0,47/ -68° 0,47/ -95° 0,47/ -112° 0,49/-130° 0,52/-148° 0,56/-166° 0,61/-177°

The figures given between brackets are values in dB.



s-parameters (common emitter)

Typical values; V_{CE} = 18 V; I_C = 10 mA; T_{case} = 25 °C; Z_o = 50 Ω

f	s _{ie}	s _{re}	s _{fe}	s _{oe}
MHz 500	0,65/–135 ⁰	0,032(-29,8)/340	8,41(18,5)/1050	0,64/ -340
600 700	0,65/—147 ⁰ 0,65/—154 ⁰	0,033(-29,5)/33° 0,036(-28,9)/30°	7,16(17,1)/100 ⁰ 6,46(16,2)/ 92 ⁰ 5,68(15,1)/ 87 ⁰	0,62/ -36° 0,59/ -37° 0,57/ -38°
800 900	0,65/161 ⁰ 0,65/166 ⁰	0,037(-28,6)/29 ⁰ 0,038(-28,3)/28 ⁰	5,13(14,2)/ 82°	0,56/ —40 ^o
1000 1200	0,65/—172 ⁰ 0,65/ 180 ⁰	0,040(-28,0)/28° 0,042(-27,5)/29°	4,68(13,4)/ 78 ⁰ 3,98(12,0)/ 69 ⁰ 3,43(10,7)/ 62 ⁰	0,55/ -42° 0,54/ -46° 0,53/ -50°
1400 1600 1800	0,65/ 174 ⁰ 0,65/ 165 ⁰ 0,66/ 159 ⁰	0,045(-27,0)/29° 0,048(-26,4)/29° 0,051(-25,9)/30°	3,43(10,7)/ 62 ⁰ 3,06(9,7)/ 55 ⁰ 2,75(8,8)/ 48 ⁰	0,53/ -55° 0,53/ -61°
2000 2500 3000 3500	0,67/ 152° 0,68/ 138° 0,69/ 125° 0,71/ 114°	0,054(-25,4)/30° 0,063(-24,1)/29° 0,072(-22,8)/27° 0,083(-21,6)/24°	2,49(7,9)/ 42 ⁰ 2,02(6,1)/ 25 ⁰ 1,67(4,5)/ 12 ⁰ 1,44(3,2)/ -4 ⁰	0,53/ -65° 0,53/ -78° 0,52/ -93° 0,53/-109°
4000	0,74/ 103º	0,095(-20,4)/20 ^o	1,26(2,0)/—190	0,55/-1270
4500 5000 5500 6000	0,75/ 94 ⁰ 0,76/ 86 ⁰ 0,77/ 79 ⁰ 0,77/ 72 ⁰	0,106(-19,5)/14° 0,118(-18,6)/ 7° 0,132(-17,6)/ 0° 0,145(-16,8)/-6°	1,10(0,8)/-32° 0,94(-0,5)/-44° 0,83(-1,7)/-57° 0,72(-2,8)/-68°	0,57/-145° 0,61/-163° 0,65/-179° 0,71/ 168°

The figures given between brackets are values in dB.



APPLICATION INFORMATION

R.F. performance up to $T_{case} = 25$ °C in an unneutralized common-emitter class-A circuit*

mode of operation	f GHz	V _{CE} (1)	I _C (¹) mA	P _{L1} (²) mW(dBm)	G _{po} (³) dB	$\frac{\overline{z_i}}{\Omega}$	$\frac{\overline{Z_L}}{\Omega}$
c.w.; linear amplifier	4	18	30	> 126(21) typ. 160(22)	> 7,5 typ. 8,0	typ. 4 + j23	typ. 6,5 + j32

Notes

- 1. I_C and V_{CE} regulated.
- 2. Load power for 1 dB compressed power gain.
- 3. Low-level power gain associated with PL1.

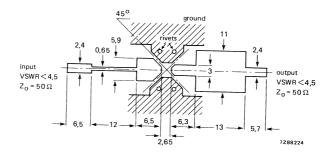
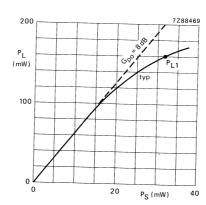
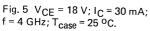


Fig. 4 Prematching test circuit board for 4 GHz. (Dimensions in mm.)

Striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric ($\epsilon_{\rm r}$ = 2,54); thickness 0,8 mm.





^{*} Circuit consists of prematching circuit board in combination with input and output slug tuners.



LOW-NOISE MICROWAVE TRANSISTOR

N-P-N transistor for common-emitter class-A low-noise amplifiers up to 4GHz. Diffused emitter ballasting resistors, self-aligned process entirely ion implanted and gold sandwich metallization ensure an optimum temperature profile, excellent performance and reliability.

A miniature ceramic encapsulation is used for compatibility with stripline and microwave circuits.

QUICK REFERENCE DATA

R.F. performance up to $T_{case} = 25$ °C in an unneutralized common-emitter class-A circuit

mode of operation	f GHz	V _{CE} V	T _C	F _{min} dB	G _a dB
c.w.; linear amplifier	2	10	4	typ. 1,8	typ. 12

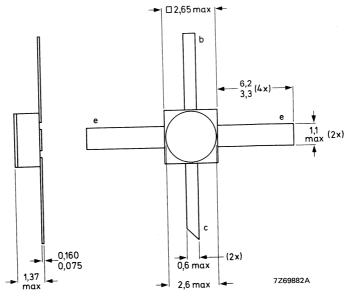
This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm

Fig. 1 SOT-100.

Emitter connected to metallized lid



R7 = LAE6000Q

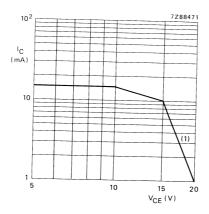
Marking code



RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134).

Collector-base voltage (open emitter)	V_{CBO}	max.	25	V
Collector-emitter voltage	CBO			•
$(R_{BE} = 150 \Omega)$ (open base)	v_{CER}	max.	20	V
. ,	V _{CEO}	max.	12	V
Emitter-base voltage (open collector)	V_{EBO}	max.	2	V
Collector current (d.c.)	l _C	max.	15	mΑ
Total power dissipation up to T _{case} = 150 °C	_			
Storage temperature	P _{tot}	max.	150	mW
	T_{stg}	-65 to +	200	οС
Junction temperature	T_{i}	max.	200	οС
Lead soldering temperature	•			
at 0,1 mm from the case; $t_{sld} \le 10 s$	T_{sld}	max.	235	оС



(1) Second breakdown limit (independent of temperature).

Fig. 2 D.C. SOAR at T $_{case}$ \leqslant 150 $^{o}\text{C};$ R $_{BE}$ \leqslant 150 $\Omega.$

THERMAL RESISTANCE

From junction to case

R_{th j-c}

300 oC/W



CHARACTERISTICS

 $T_{case} = 25 \, {}^{o}C$

Collector cut-off current

 $I_E = 0$; $V_{CB} = 10 \text{ V}$

Emitter cut-off current I_C = 0; V_{EB} = 1,5 V

D.C. current gain

 $I_C = 4 \text{ mA}$; $V_{CE} = 10 \text{ V}$

Collector-base capacitance at f = 1 MHz

 $I_E = I_C = 0$; $V_{CB} = 10 \text{ V}$

Collector-emitter capacitance at f = 1 MHz

IE = IC = 0; VCE = 10 V

Emitter-base capacitance at f = 1 MHz

I_E = I_C = 0; V_{EB} = 1,0 V; V_{CB} = 10 V



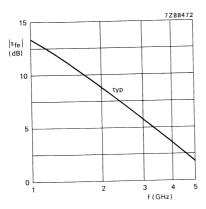
I_{EBO} < 15 nA

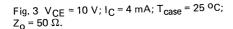
h_{FF} 20 to 250

C_{cb} typ. 0,15 pF

C_{ce} typ. 0,50 pF

 $C_{\mbox{\footnotesize eb}}$ typ. 0,70 pF





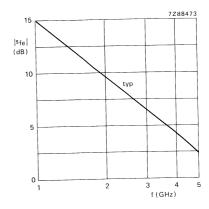


Fig. 4 V_{CE} = 10 V; I_C = 8 mA; T_{case} = 25 °C; Z_o = 50 Ω .

s-parameters (common emitter)

Typical values; V_{CE} = 10 V; I_C = 4 mA; T_{case} = 25 °C; Z_o = 50 Ω

f MHz	s _{ie}	^s re	s _{fe}	s _{oe}	
500 600 700 800 900 1000	0,65/ -780 0,62/ -940 0,59/-1000 0,57/-1110 0,56/-1200	0,025(-32,1)/500 0,028(-30,9)/470 0,032(-30,0)/430 0,034(-29,4)/390 0,036(-29,0)/360	6,53(16,4)/126° 6,16(15,8)/121° 5,82(15,3)/113° 5,40(14,6)/107° 5,00(14,0)/101°	0,83/ -16° 0,83/ -18° 0,83/ -25° 0,80/ -27° 0,79/ -29°	
1200 1400 1600 1800	0,55/—129° 0,53/—143° 0,52/—156° 0,51/—168° 0,51/—176°	0,039(-28,6)/340 0,040(-27,9)/320 0,042(-27,5)/290 0,045(-26,8)/280 0,047(-26,5)/280	4,71(13,5)/ 960 4,19(12,4)/ 860 3,70(11,4)/ 770 3,35(10,5)/ 700 3,04(9,7)/ 620	0,78/ -31° 0,76/ -34° 0,74/ -40° 0,74/ -41° 0,73/ -45°	
2000 2500 3000 3500 4000	0,51/ 175° 0,51/ 156° 0,52/ 139° 0,55/ 126° 0,57/ 114°	0,049(-26,1)/27° 0,055(-25,2)/26° 0,062(-24,2)/24° 0,069(-23,3)/22° 0,076(-22,0)/20°	2,78(8,9)/ 56° 2,30(7,3)/ 41° 1,95(5,8)/ 27° 1,70(4,6)/ 12° 1,54(3,7)/ –2°	0,73/ -49° 0,71/ -57° 0,70/ -68° 0,70/ -80° 0,70/ -93°	
4500 5000 5500 6000	0,60/ 104° 0,61/ 95° 0,63/ 87° 0,63/ 80°	0,084(-21,5)/14° 0,094(-20,5)/ 8° 0,105(-19,6)/ 3° 0,114(-18,9)/-3°	1,38(2,8)/-15° 1,22(1,8)/-29° 1,11(0,8)/-42° 1,00(0)/-55°	0,70/—108° 0,70/—124° 0,71/—141° 0,74/—157°	

Typical values; V_{CE} = 10 V; I_C = 8 mA; T_{case} = 25 o C; Z $_{o}$ = 50 Ω

f MHz	s _{ie}	s _{re}	s _{fe}	s _{oe}	
500 600 700 800 900 1000 1200 1400 1600 1800 2000 2500 3000 3500 4000 4500 5500 6000	0,52/-111° 0,51/-126° 0,50/-134° 0,50/-143° 0,50/-150° 0,50/-157° 0,50/-168° 0,50/-176° 0,50/-167° 0,50/-160° 0,52/-144° 0,54/-131° 0,56/-119° 0,59/-108° 0,61/-99° 0,63/-91° 0,64/-84° 0,64/-77°	0,019(-34,6)/470 0,020(-33,9)/450 0,022(-33,1)/430 0,024(-32,5)/420 0,025(-32,0)/420 0,027(-31,4)/410 0,030(-30,5)/410 0,036(-28,8)/390 0,039(-28,1)/400 0,042(-27,5)/410 0,050(-26,0)/380 0,060(-24,5)/350 0,068(-23,3)/320 0,078(-22,2)/280 0,086(-21,3)/220 0,098(-20,2)/140 0,110(-19,2)/80 0,119(-18,5)/20	9,43(19,5)/117° 8,19(18,3)/109° 7,53(17,5)/102° 6,70(16,5)/ 97° 6,17(15,8)/ 92° 5,68(15,1)/ 87° 4,88(13,8)/ 79° 4,22(12,5)/ 70° 3,76(11,5)/ 64° 3,40(10,6)/ 58° 3,08(9,8)/ 52° 2,54(8,1)/ 38° 2,13(6,6)/ 24° 1,86(5,4)/ 10° 1,66(4,4)/ -4° 1,48(3,4)/-17° 1,31(2,4)/-30° 1,19(1,5)/-43°	0,80/ -21° 0,78/ -23° 0,76/ -25° 0,74/ -26° 0,73/ -28° 0,73/ -29° 0,72/ -33° 0,70/ -39° 0,70/ -43° 0,70/ -47° 0,69/ -56° 0,68/ -66° 0,67/ -78° 0,67/ -91° 0,67/-106° 0,67/-122° 0,69/-139°	
·		0,110(-10,0)/ 20	1,07(0,6)/_560	0.73/-1550	

The figures given between brackets are values in dB.



MICROWAVE LINEAR POWER TRANSISTORS

N-P-N bipolar transistors for use in a common-emitter class-A linear power amplifier up to 1 GHz. Diffused emitter ballasting resistors, interdigitated structure, multicell geometry and gold sandwich metallization ensure an optimum temperature profile, excellent performance and reliability.

The LBE1004R and LBE1010R have a metal ceramic studless envelope. The LCE1004R and LCE1010R have a metal ceramic capstan envelope.

QUICK REFERENCE DATA

R.F. performance up to T_{mb} = 25 $^{\rm o}$ C in an unneutralized common-emitter class-A circuit

type number	mode of operation	f GHz	V _{CE}	I _C mA	P _{L1} mW	G _{po} dB	$\frac{\overline{z_i}}{\Omega}$	Z _L Ω
	c.w.; linear amplifier c.w.; linear amplifier	1	15 15		typ. 500 typ. 1000	1	1	25 + j25 20 + j15

MECHANICAL DATA

see page 2

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS—MICROWAVE SEMICONDUCTORS.

POTENTIAL HAZARD-BERYLLIUM OXIDE

This device contains beryllium oxide, the dust of which is toxic. The device is entirely safe, provided that the beryllium oxide disc is not damaged. Care should be taken to ensure that all those who may handle, use or dispose of this device are aware of its nature and of the necessary safety precautions. In particular, it should never be thrown out with general industrial or domestic waste.



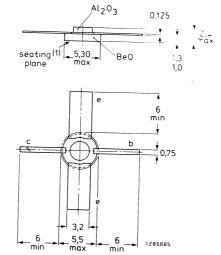
LBE/LCE1004R LBE/LCE1010R

MECHANICAL DATA

Fig. 1a LBE1004R and LBE1010R.

Marking code

RTC109 = LBE1004R RTC143 = LBE1010R Dimensions in mm



(1) Metallized.



MECHANICAL DATA (continued)

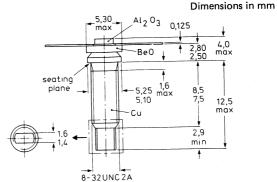
Fig. 1b LCE1004R and LCE1010R.

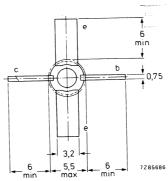
Marking code

RTC108 = LCE1004R RTC142 = LCE1010R

Torque on nut: min. 0,75 Nm 0,85 Nm

Diameter of clearance hole in heatsink: max. 4,2 mm.





RATINGS

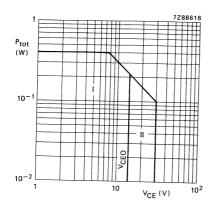
Limiting values in accordance with the Absolute Maximum System (IEC 134)

			1004R	1010R	
Collector-base voltage (open emitter)	V_{CBO}	max.	30	30	٧
Collector-emitter voltage $ \begin{array}{l} {\rm R_{BE}=250~\Omega} \\ {\rm R_{BE}=500~\Omega} \\ {\rm (open~base)} \end{array} $	V _{CER} V _{CER} V _{CEO}	max. max. max.	- 30 14	30 - 14	V V V
Emitter-base voltage (open collector)	V _{EBO}	max.	3	3	٧
Collector current d.c. (peak value); f > 1 MHz	I _C	max. max.	400 800	800 1600	mA mA
Total power dissipation up to T _{mb} = 75 °C	P _{tot}	max.	3	6	w
Storage temperature	T _{stg}		-65	to + 150	oC
Operating junction temperature	τ _j	max.		200	оC
Lead soldering temperature at 0,3 mm from the case; t _{sld} = 10 s	T _{sld}	max.		235	°C

LBE/LCE

LBE/LCE

LBE/LCE1004R



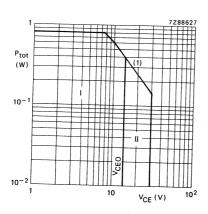
30 7288617 VCE (V)
25
20
10
10
10²
10³
R_{BE} (Ω) 10⁴

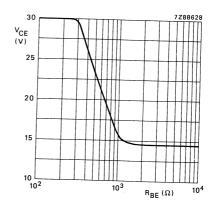
Fig. 2 D.C. SOAR at $T_{mb} \le 75$ °C.

- I Region of permissible d.c. operation.
- II Permissible extension provided $R_{\mbox{\footnotesize{BE}}} \leqslant 500~\Omega.$

Fig. 3 Maximum permissible collector-emitter voltage as a function of RBE.

LBE/LCE1010R





- (1) Second breakdown limit (independent of temperature).
- Fig. 4 D.C. SOAR at $T_{mb} \le 75$ °C.
- I Region of permissible d.c. operation.
- II Permissible extension provided R_{BE} \leq 250 Ω .

Fig. 5 Maximum permissible collector-emitter voltage as a function of RBE.



THERMAL RESISTANCE			LBE/LCE 1004R	LBE/LCE 1010R	
From junction to mounting base	R _{th j-mb}	=	30	17	°C/W
From mounting base to heatsink	R _{th mb-h}	=	1,5	1,5	°C/W
CHARACTERISTICS					
T _{mb} = 25 °C			LBE/LCE 1004R	LBE/LCE 1010R	
Collector-base breakdown voltage open emitter; $I_C = 1.0 \text{ mA}$	V _(BR) CBO	>	_	30	٧
open emitter; I _C = 0,5 mA	V _(BR) CBO	>	30	_	٧
Collector-emitter breakdown voltage $R_{BE} = 250 \Omega; I_{C} = 10 \text{ mA}$	V _(BR) CER	>	_	30	٧
$R_{BE} = 500 \Omega; I_C = 5 \text{ mA}$	[∨] (BR)CER	>	30	_	V
open base; -I _E = 10 mA	V _(BR) CEO	>	_	14	V
open base; $-I_E = 5 \text{ mA}$	V(BR)CEO	>	14	_	V
Emitter-base breakdown voltage open collector; I _E = 2 mA	V(BR)EBO	>	_	3	٧
open collector; IE = 1 mA	V(BR)EBO	>	3	_	V
Collector cut-off current $I_E = 0$; $V_{CB} = 20 \text{ V}$	I _{CBO}	<	0,2	0,4	mΑ
Emitter cut-off current $I_C = 0$; $V_{EB} = 2 V$	I _{EBO}	<	0,2	0,4	mΑ
D.C. current gain $I_C = 75 \text{ mA}$; $V_{CE} = 5 \text{ V}$	hFE	>	20	20	
Collector-base capacitance at $f = 1 \text{ MHz}$ $I_E = I_C = 0$; $V_{CB} = 14 \text{ V}$	C _{cb}	typ.	1,7	2,0	pF
Collector-emitter capacitance at $f = 1$ MHz $I_B = I_b = 0$; $V_{CE} = 14$ V	C _{ce}	typ.	1,2	2,0	pF
Emitter-base capacitance at $f = 1$ MHz $I_E = I_e = 0$; $V_{EB} = 1$ V	C _{eb}	typ.	4,2	8,2	pF
Forward power gain I _C = 100 mA; V _{CE} = 15 V; f = 1 GHz I _C = 200 mA; V _{CE} = 15 V; f = 1 GHz	s _{fe} ² s _{fe} ²	typ.		4,0	dB dB
Maximum available gain $I_C = 100 \text{ mA}; V_{CE} = 15 \text{ V}; f = 1 \text{ GHz}$ $I_C = 200 \text{ mA}; V_{CE} = 15 \text{ V}; f = 1 \text{ GHz}$	G _{AM} G _{AM}	typ typ		- 10,0	dB dB

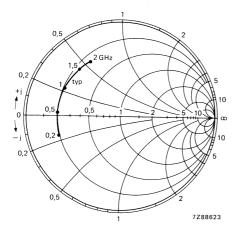


s-parameters (common emitter)

LBE/LCE1004R: Typical values; V_{CE} = 15 V; I_{C} = 100 mA; T_{mb} = 25 °C; Z_{o} = 50 Ω

f GHz	s _{ie}	s _{re}	s _{fe}	s _{oe}
0,2 0,5 1 1,5	0,69/-162° 0,68/ 177° 0,68/ 154° 0,68/ 132° 0,67/ 120°	0,063(-24)/30° 0,079(-22)/38° 0,10 (-20)/45° 0,14 (-17)/46° 0,16 (-16)/46°	7,95(18)/100° 3,99(12)/ 80° 2,24(6,5)/ 60° 1,41(3)/ 40° 1,13(1)/ 20°	0,38/-129° 0,36/-159° 0,37/-175° 0,38/ 176° 0,42/ 168°

The figures given between brackets are values in dB.



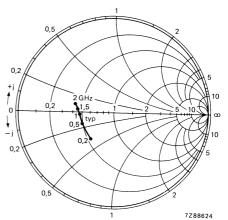


Fig. 6 Input reflection coefficient sie.

Fig. 7 Output reflection coefficient soe.

Conditions for Figs 6 and 7:

LBE/LCE1004R: Typical values; V_{CE} = 15 V; I_C = 100 mA; T_{mb} = 25 °C; Z_o = 50 Ω .



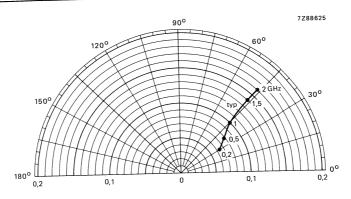


Fig. 8 Reverse transmission coefficient s_{re} .

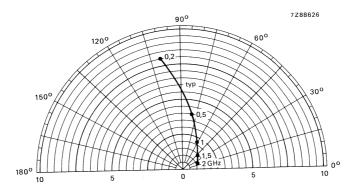


Fig. 9 Forward transmission coefficient sfe.

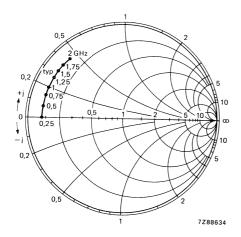
Conditions for Figs 8 and 9:

LBE/LCE1004R: Typical values; V_{CE} = 15 V; I_{C} = 100 mA; T_{mb} = 25 °C; Z_{o} = 50 Ω .

LBE/LCE1010R: Typical values; V_{CE} = 15 V; I_C = 200 mA; T_{mb} = 25 °C; Z_o = 50 Ω

f GHz	s _{ie}	s _{re}	sfe	s _{oe}
0,25 0,50 0,75 1 1,25 1,50 1,75	0,85/180° 0,85/172° 0,85/164° 0,85/158° 0,85/150° 0,85/144° 0,85/139° 0,85/133°	0,04(-28)/350 0,05(-26)/450 0,07(-23)/550 0,09(-21)/550 0,10(-20)/550 0,11(-19)/520 0,12(-18)/500 0,15(-16)/500	5,0 (14)/95° 2,8 (9)/75° 2,0 (6)/65° 1,6 (4)/60° 1,26(2)/58° 1,13(1)/53° 0,90(-1)/50° 0,80(-2)/45°	0,51/—157° 0,53/—175° 0,54/—178° 0,58/—173° 0,59/—167° 0,61/—163° 0,62/—159° 0,62/—154°

The figures given between brackets are values in dB.



0,5 1,75 2 GHz 1,75 1,25

Fig. 10 Input reflection coefficient sie-

Fig. 11 Output reflection coefficient soe-

Conditions for Figs 10 and 11:

LBE/LCE1010R: Typical values: V_{CE} = 15 V; I_{C} = 200 mA; T_{mb} = 25 °C; Z_{o} = 50 Ω .



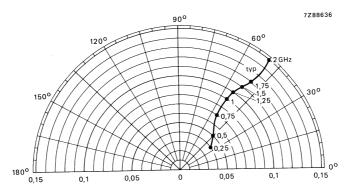


Fig. 12 Reverse transmission coefficient s_{re} .

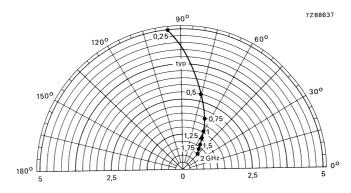


Fig. 13 Forward transmission coefficient sfe.

Conditions for Figs 12 and 13:

LBE/LCE1010R: Typical values: V_{CE} = 15 V; I_{C} = 200 mA; T_{mb} = 25 °C; Z_{o} = 50 Ω .



APPLICATION INFORMATION

R.F. performance LBE/LCE1004R up to T_{mb} = 25 °C in an unneutralized common-emitter class-A circuit

f	V _{CE} (1)	I _C (1)	P _{L1} (2)	G _{po} (3)	P _{Lsat} (4)
GHz		mA	mW(dBm)	dB	mW (dBm)
1	15	100	≥ 400(26) typ. 500(27)	≥ 8 typ. 10	typ. 631(28)

Notes

- 1. VCE and IC regulated.
- 2. Load power for 1 dB compressed power gain.
- 3. Low-level power gain associated with PL1.
- 4. Saturated output power of the transistor.

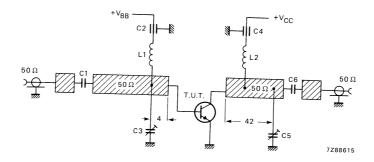


Fig. 14 Class-A test circuit at f = 1 GHz. (Dimensions in mm.)

List of components:

C1 = C6 = 1 nF multilayer ceramic chip capacitor

C2 = C4 = 500 pF ceramic feed-through capacitor

C3 = C5 = 0 to 10 pF film dielectric trimmer

L1 = L2 = 5 turns enamelled Cu wire (0,5 mm); internal diameter 2,5 mm

Striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric ($\epsilon_{\rm r}$ = 2,54); thickness 0,8 mm.



R.F. performance LBE/LCE1010R up to T_{mb} = 25 °C in an unneutralized common-emitter class-A circuit

f	V _{CE} (1)	I _C (1)	P _{L1} (2)	G _{po} (3)	P _{Lsat} (4)
GHz	V	mA	mW(dBm)	dB	mW(dBm)
1	15	200	≥ 800(29) typ. 1000(30)		- typ. 1600(32)

Notes

- 1. V_{CE} and I_C regulated.
- 2. Load power for 1 dB compressed power gain.
- 3. Low-level power gain associated with PL1.
- 4. Saturated output power of the transistor.

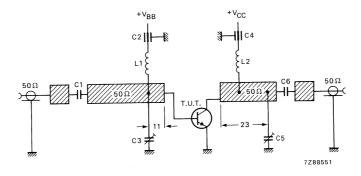


Fig. 15 Class-A test circuit at f = 1 GHz. (Dimensions in mm.)

List of components:

C1 = C6 = 1 nF multilayer ceramic chip capacitor

C2 = C4 = 500 pF ceramic feed-through capacitor

C3 = C5 = 0 to 10 pF film dielectric trimmer

L1 = L2 = 5 turns enamelled Cu wire (0,5 mm); internal diameter 2,5 mm

Striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric (ϵ_r = 2,54); thickness 0,8 mm.

LBE/LCE1004R

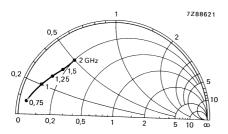


Fig. 16 Input impedance as a function of frequency for $P_{1,1}$.

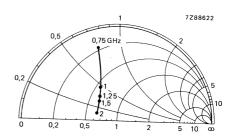


Fig. 17 Optimum load impedance as a function of frequency for PL1.

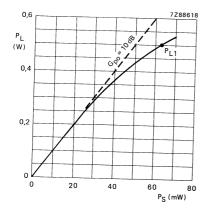


Fig. 18 Load power as a function of source power at f = 1 GHz.

Conditions for Figs 16 to 20:

VCE and IC regulated.

 $V_{CE} = 15 \text{ V}; I_{C} = 100 \text{ mA};$

 $T_{mb} = 25$ °C; typical values.

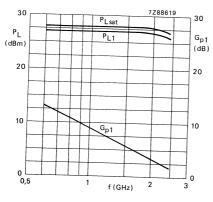


Fig. 19 $\,P_{Lsat},\,P_{L1}$ and $\,G_{p1}$ associated with $\,P_{L1}$ as a function of frequency.

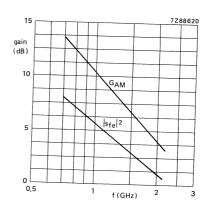


Fig. 20 G_{AM} and $|s_{fe}|^2$ as a function of frequency.



LBE/LCE1010R

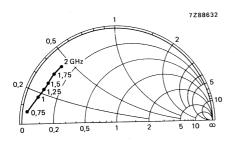


Fig. 21 Input impedance as a function of frequency for PL1.

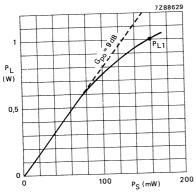


Fig. 23 Load power as a function of source power at f = 1 GHz.

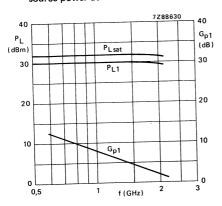


Fig. 24 P_{Lsat} , P_{L1} and G_{p1} associated with P_{L1} as a function of frequency.

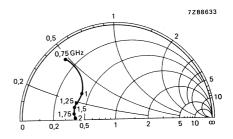


Fig. 22 Optimum load impedance as a function of frequency for $\ensuremath{^{P}L1}.$

Conditions for Figs 21 to 25: V_{CE} and I_{C} regulated. $V_{CE} = 15 \text{ V}$; $I_{C} = 200 \text{ mA}$; $T_{mb} = 25 ^{\circ}\text{C}$; typical values.

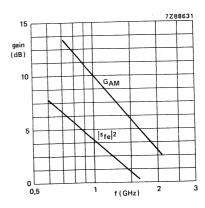


Fig. 25 G_{AM} and $|s_{fe}|^2$ as a function of frequency.

MICROWAVE LINEAR POWER TRANSISTORS

N-P-N transistors for use in a common-emitter class-A linear power amplifier up to 2 GHz.

Diffused emitter ballasting resistors, self-aligned process entirely ion implanted and gold metallization ensure an optimum temperature profile, excellent performance and reliability.

The LBE2003S and LBE2009S have a metal ceramic studless envelope. The LCE2003S and LCE2009S have a metal ceramic capstan envelope.

QUICK REFERENCE DATA

R.F. performance up to T_{mb} = 25 o C in an unneutralized common-emitter class-A circuit

type number	mode of operation	f GHz	V _{CE}	I _C	P _{L1} mW	G _{po} dB	z _i Ω	Z _L Ω
	c.w.; linear amplifier c.w.; linear amplifier	2 2	18 18	30 110	typ. 250 typ. 900		6,2 + j30 7,5 + j15	17,5 + j7 17,5 + j39

MECHANICAL DATA

see page 2

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS—MICROWAVE SEMICONDUCTORS.

POTENTIAL HAZARD-BERYLLIUM OXIDE

This device contains beryllium oxide, the dust of which is toxic. The device is entirely safe, provided that the beryllium oxide disc is not damaged. Care should be taken to ensure that all those who may handle, use or dispose of this device are aware of its nature and of the necessary safety precautions. In particular, it should never be thrown out with general industrial or domestic waste.



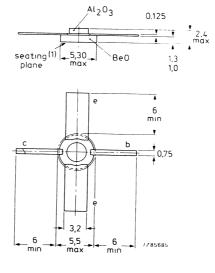
LBE/LCE2003S LBE/LCE2009S

MECHANICAL DATA

Fig. 1a LBE2003S and LBE2009S.

Marking code

RTC407 = LBE2003S RTC409 = LBE2009S Dimensions in mm





LBE/LCE2003S LBE/LCE2009S

MECHANICAL DATA (continued)

Fig. 1b LCE2003S and LCE2009S.

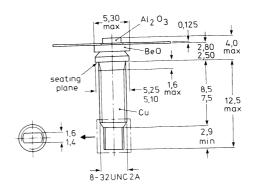
Marking code

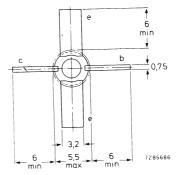
RTC406 = LCE2003S RTC408 = LCE2009S

Torque on nut: min. 0,75 Nm 0,85 Nm

Diameter of clearance hole in heatsink: max. 4,2 mm.

Dimensions in mm



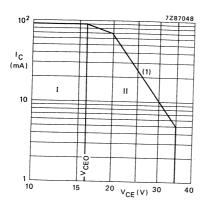


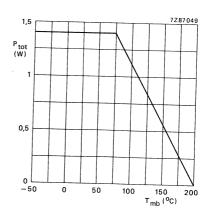
RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Limiting values in accordance with the Absolute	, Maximani Oyou		LBE/LCE 2003S	LBE/LCE 2009S	
Collector-base voltage (open emitter)	V _{CBO}	max.	40	40	٧
Collector-emitter voltage R_{BE} = 100 Ω	V _{CER}	max.	-	35	V
$R_{BE} = 220 \Omega$	v_{CER}	max.	35	_	V
(open base)	v_{CEO}	max.	16	16	V
Emitter-base voltage (open collector)	V_{EBO}	max.	3	3	٧
Collector current (d.c.)	1 _C	max.	90	250	mA
Total power dissipation up to T _{mb} = 75 °C	P _{tot}	max.	1,4	3,5	W
Storage temperature	T _{stg}		-65	to + 150	oC
Operating junction temperature	T _j	max.		200	οС
Lead soldering temperature at 0,3 mm from the case; t _{Sld} = 10 s	T _{sld}	max.		235	oC

LBE/LCE2003S





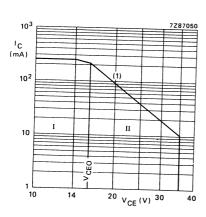
(1) Second breakdown limit (independent of temperature).

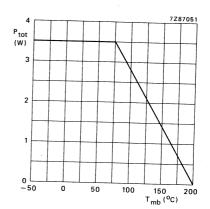
Fig. 2 D.C. SOAR at $T_{mb} \le 75$ °C.

- I Region of permissible d.c. operation.
- II Permissible extension provided $R_{BE} \le 220 \ \Omega$.

Fig. 3 Power derating curve vs. mounting base temperature.

LBE/LCE2009S





Second breakdown limit (independent of temperature).

Fig. 4 D.C. SOAR at $T_{mb} \le 75$ °C.

- I Region of permissible d.c. operation.
- II Permissible extension provided $R_{\mbox{\footnotesize{BE}}} \leqslant 100~\Omega.$

Fig. 5 Power derating curve vs. mounting base temperature.



THE PROJECT ANCE			LBE/LCE 2003S	LBE/LCE 2009S	
THERMAL RESISTANCE	R _{th i-mb}	=	65	36	°C/W
From junction to mounting base		=	1,5	1,5	°C/W
From mounting base to heatsink	R _{th} mb-h		.,-	,	
CHARACTERISTICS					
$T_{mb} = 25 {}^{\circ}C$			LBE/LCE 2003S	LBE/LCE 2009S	
Collector cut-off current	Ісво	<	0,1	0,1	μΑ
I _E = 0; V _{CB} = 20 V	ICBO	<	150	250	μΑ
$I_E = 0$; $V_{CB} = 40 \text{ V}$	CER	<	500	_	μΑ
V_{CB} = 35 V; R_{BE} = 220 Ω		<	_	1000	μΑ
V_{CB} = 35 V; R_{BE} = 100 Ω	CER				
Emitter cut-off current	I _{EBO}	<	0.05	0,2	μΑ
$I_C = 0; V_{EB} = 1,5 V$		<	25	50	μΑ
$I_C = 0$; $V_{EB} = 3.0 \text{ V}$	IEBO				
D.C. current gain	hFE	>	15	_	
$I_C = 30 \text{ mA}; V_{CE} = 5 \text{ V}$	"FE	•	150	15	
	hFE	> <	_	15 150	
$I_C = 110 \text{ mA}; V_{CE} = 5 \text{ V}$				100	
Collector-base capacitance at f = 1 MHz	С.	typ.	0,3	0,6	рF
$I_E = I_C = 0$; $V_{CB} = 18 \text{ V}$; $V_{EB} = 1,5 \text{ V}$	C _{cb}	typ.	0,0		•
Collector-emitter capacitance at f = 1 MHz	C _{ce}	typ.	0,45	0,6	рF
I _E = I _C = 0; V _{CE} = 18 V; V _{EB} = 1,5 V	oce .	-71	•		
Emitter-base capacitance at $f = 1 \text{ MHz}$ $I_F = I_C = 0$; $V_{EB} = 1 \text{ V}$; $V_{CB} = 10 \text{ V}$	C _{eb}	typ.	1,7	3,3	рF
IE = IC = 0; AEB - 1 A' ACB - 10 A	GD			•	



LBE/LCE2003S LBE/LCE2009S

s-parameters (common emitter)

LBE/LCE2003S: Typical values; V_{CE} = 18 V*; I_C = 30 mA*; T_{mb} = 25 °C; Z_{o} = 50 Ω

f GHz	s _{ie}	s _{re}	s _{fe}	s _{oe}
	\$ie 0,56/-143° 0,55/-154° 0,55/-164° 0,55/-171° 0,55/-178° 0,55/+170° 0,55/+165° 0,56/+159° 0,55/+146° 0,55/+142° 0,55/+142° 0,57/+132° 0,58/+128° 0,60/+121° 0,62/+114° 0,64/+108° 0,66/+102° 0,68/ +96° 0,71/ +92° 0,73/ +89° 0,75/ +86° 0,76/ +82° 0,77/ +79° 0,78/ +75° 0,80/ +73° 0,81/ +69°	\$re 0,037(-28,6)/ 41° 0,040(-28,0)/ 39° 0,040(-27,9)/ 40° 0,041(-27,7)/ 40° 0,043(-27,4)/ 41° 0,045(-26,9)/ 40° 0,048(-26,4)/ 40° 0,051(-25,9)/ 41° 0,056(-25,1)/ 41° 0,060(-24,5)/ 41° 0,062(-24,2)/ 40° 0,065(-23,8)/ 42° 0,068(-23,3)/ 42° 0,070(-23,1)/ 41° 0,072(-22,9)/ 40° 0,074(-22,7)/ 40° 0,081(-21,8)/ 39° 0,091(-20,8)/ 37° 0,099(-20,1)/ 36° 0,105(-19,6)/ 33° 0,108(-19,4)/ 31° 0,124(-18,7)/ 29° 0,125(-18,0)/ 27° 0,137(-17,3)/ 25° 0,142(-17,0)/ 23° 0,149(-16,6)/ 20° 0,155(-16,2)/ 17° 0,167(-15,5)/ 15° 0,177(-15,0)/ 12°	9,50(19,6)/1010 8,28(18,4)/930 7,13(17,1)/880 6,35(16,1)/820 5,69(15,1)/770 5,14(14,2)/720 4,72(13,5)/680 4,37(12,8)/640 4,05(12,2)/600 3,76(11,5)/570 3,52(10,9)/530 3,33(10,5)/500 3,15(10,0)/460 2,96(9,4)/420 2,80(8,9)/390 2,66(8,5)/360 2,43(7,7)/280 2,24(7,0)/230 2,08(6,4)/160 1,90(5,6)/100 1,79(5,1)/40 1,63(4,3)/-20 1,58(4,0)/-70 1,46(3,3)/-130 1,40(2,9)/-180 1,31(2,3)/-280 1,25(1,9)/-280 1,20(1,6)/-340	0,56/ -340 0,51/ -350 0,50/ -360 0,49/ -370 0,47/ -380 0,46/ -390 0,46/ -390 0,45/ -410 0,45/ -460 0,43/ -480 0,43/ -500 0,43/ -530 0,43/ -560 0,43/ -560 0,42/ -570 0,41/ -610 0,40/ -670 0,39/ -750 0,38/ -820 0,39/ -870 0,39/ -870 0,39/ -1120 0,38/-1280 0,38/-1280 0,38/-1280 0,39/-1420
4,8 5,0 5,2 5,4 5,6 5,8	0,81/ +68° 0,81/ +65° 0,80/ +60° 0,81/ +56° 0,81/ +51° 0,81/ +48°	0,187(-14,6)/ 10° 0,194(-14,3)/ 6° 0,203(-13,8)/ 4° 0,219(-13,2)/ -1° 0,229(-12,8)/ -3° 0,243(-12,3)/ -8°	1,14(1,1)/-38° 1,10(0,8)/-43° 1,04(0,4)/-47° 1,03(0,3)/-53° 0,98(-0,2)/-57° 0,97(-0,3)/-62° 0,92(-0,7)/-68°	0,39/-151° 0,42/-159° 0,44/-165° 0,47/-169° 0,48/-175° 0,49/+178° 0,51/+171°
6,0	0,80/ +440	0,245(-12,2)/-120	0,90(-0,9)/-720	0,55/+ 165°

The figures given between brackets are values in dB.



^{*} VCE and IC regulated.

s-parameters (common emitter)

LBE/LCE2009S: Typical values; V_{CE} = 18 V*; I_{C} = 110 mA*; T_{mb} = 25 °C; Z_{o} = 50 Ω

f GHz	sie	s _{re}	Sfe	s _{oe}
0,5 0,6 0,7 0,8 0,9 1,0 1,1 1,2 1,3 1,4 1,5 1,6 1,7 1,8 1,9	0,70/177° 0,70/171° 0,70/168° 0,70/163° 0,71/159° 0,71/151° 0,71/148° 0,71/144° 0,72/143° 0,72/136° 0,72/130° 0,72/130° 0,73/127° 0,73/123°	0,029(-30,7)/50° 0,033(-29,6)/51° 0,036(-29,0)/53° 0,039(-28,4)/54° 0,041(-27,8)/55° 0,049(-26,2)/54° 0,054(-25,4)/54° 0,060(-24,5)/53° 0,066(-23,6)/54° 0,070(-23,1)/52° 0,075(-22,5)/53° 0,080(-21,9)/51° 0,084(-21,5)/49° 0,087(-21,2)/48°	7,55(17,6)/ 83° 6,43(16,2)/ 77° 5,46(14,6)/ 73° 4,80(13,6)/ 68° 4,27(12,6)/ 64° 3,84(11,7)/ 60° 3,53(11,0)/ 56° 3,27/10,3)/ 52° 3,01(9,6)/ 48° 2,80(9,0)/ 45° 2,61(8,3)/ 41° 2,47(7,9)/ 38° 2,33(7,3)/ 34° 2,18(6,8)/ 30° 2,05(6,3)/ 26°	0,25/ -48° 0,22/ -50° 0,23/ -52° 0,22/ -54° 0,22/ -56° 0,21/ -59° 0,21/ -65° 0,20/ -74° 0,20/ -79° 0,21/ -83° 0,21/ -83° 0,22/ -87° 0,22/ -90° 0,22/ -94°
2,0 2,2 2,4 2,6 2,8 3,0 3,2	0,74/120° 0,75/114° 0,77/108° 0,79/103° 0,80/ 97° 0,81/ 92° 0,83/ 88°	0,090(-20,9)/46 ⁰ 0,100(-20,0)/43 ⁰ 0,112(-19,0)/40 ⁰ 0,123(-18,2)/37 ⁰ 0,129(-17,8)/33 ⁰ 0,134(-17,5)/30 ⁰ 0,143(-16,9)/26 ⁰	1,97(5,9)/ 23° 1,78(5,0)/ 15° 1,63(4,3)/ 10° 1,51(3,6)/ 2° 1,36(2,7)/ -4° 1,28(2,1)/-11° 1,15(1,2)/-17°	0,22/ -97° 0,22/-109° 0,21/-122° 0,24/-133° 0,25/-143° 0,27/-151° 0,28/-163° 0,30/-173°
3,4 3,6 3,8	0,85/ 85 ⁰ 0,86/ 82 ⁰ 0,87/ 79 ⁰	0,152(-16,4)/24 ⁰ 0,163(-15,8)/20 ⁰ 0,168(-15,5)/17 ⁰	1,10(0,9)/-21 ⁰ 1,00(0)/-28 ⁰ 0,96(-0,4)/-32 ⁰	0,34/+ 178 ⁰ 0,37/+ 173 ⁰
4,0 4,2 4,4 4,6 4,8 5,0	0,88/ 75° 0,88/ 71° 0,89/ 69° 0,90/ 66° 0,90/ 64° 0,90/ 61°	0,175(-15,2)/14° 0,180(-14,9)/11° 0,193(-14,3)/ 8° 0,200(-14,0)/ 5° 0,211(-13,5)/ 2° 0,214(-13,4)/-2°	0,88(-1,1)/-39° 0,83(-1,6)/-42° 0,79(-2,1)/-48° 0,74(-2,6)/-51° 0,71(-3,0)/-56° 0,66(-3,6)/-59°	0,41/+ 168 ⁰ 0,42/+ 162 ⁰ 0,45/+ 155 ⁰ 0,48/+ 149 ⁰ 0,52/+ 145 ⁰ 0,55/+ 144 ⁰

The figures given between brackets are values in dB.



^{*} VCE and IC regulated.

APPLICATION INFORMATION

Microwave performance in c.w. operation for the LBE/LCE2003S up to T_{mb} = 25 °C in an unneutralized common-emitter class-A circuit*.

f GHz	V _{CE} (1) V	I _C (1) mA	P _{L1} (2) mW(dBm)	G _{po} (3) dB	$\frac{\overline{z_i}}{\Omega}$	$\frac{\overline{z_L}}{\Omega}$
2	18	30	≥ 200(23) typ. 250(24)	≥ 10 typ. 11	6,2 + j30	17,5 + j7

Notes

- 1. VCE and IC regulated.
- 2. Load power for 1 dB compressed power gain.
- 3. Low-level power gain associated with PL1.

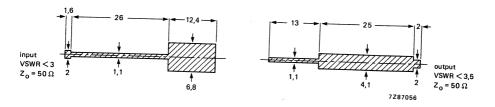


Fig. 6 Prematching test circuit board for 2 GHz. (Dimensions in mm.)

Striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric ($\epsilon_{\rm r}\approx$ 2,54); thickness 0,8 mm.

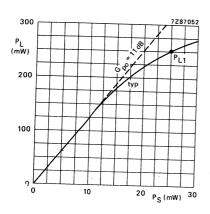


Fig. 7 V_{CE} = 18 V; I_{C} = 30 mA; f = 2 GHz; T_{mb} = 25 °C.

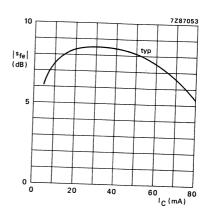


Fig. 8 V_{CE} = 18 V; class-A operation; f = 2 GHz; T_{mb} = 25 °C.

* Circuit consists of prematching circuit board in combination with input and output slug tuners.

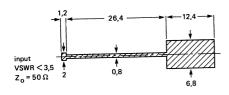
APPLICATION INFORMATION

Microwave performance in c.w. operation for the LBE/LCE2009S up to T_{mb} = 25 °C in an unneutralized common-emitter class-A circuit*.

f	V _{CE} (1)	I _C (1)	P _{L1} (2)	G _{po} (3)	z _i	Z _L
GHz		mA	mW(dBm)	dB	Ω	Ω
2	18	100	≥ 700(28,5) typ. 900(29,5)	≥ 9 typ. 9,8	7,5 + j14,5	17,5 + j38,5

Notes

- 1. VCE and IC regulated.
- 2. Load power for 1 dB compressed power gain.
- 3. Low-level power gain associated with PL1.



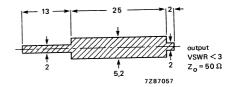
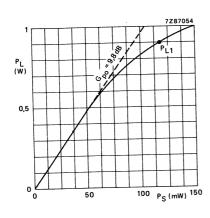


Fig. 9 Prematching test circuit board for 2 GHz. (Dimensions in mm.)

Striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric ($\epsilon_r \approx 2,54$); thickness 0,8 mm.



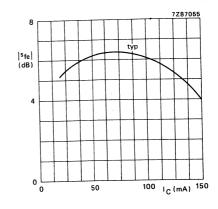


Fig. 10 V_{CE} = 18 V; I_{C} = 110 mA; f = 2 GHz; T_{mb} = 25 °C.

Fig. 11 V_{CE} = 18 V; class-A operation; f = 2 GHz; T_{mb} = 25 °C.

* Circuit consists of prematching circuit board in combination with input and output slug tuners.

			(
•				

MICROWAVE LINEAR POWER TRANSISTOR

N-P-N transistor for use in a common-emitter class-A linear power amplifier up to 1 GHz. Diffused emitter ballasting resistors, interdigited structure, multicell geometry and gold sandwich metallization ensure an optimum temperature profile and excellent performance and reliability.

QUICK REFERENCE DATA

R.F. performance up to T_{mb} = 25 o C in an unneutralized common-emitter class-A circuit.

R.F. performance up to 1 _{mb} = 25 °C in an announce							
mode of operation	f GHz	V _{CE}	I _C mA	P _{L1} mW	G _{po} dB	$\frac{\overline{z_i}}{\Omega}$	Z _L Ω
c.w.; linear amplifier	1	15	100	typ. 400	typ. 11	6,5 + j4	13 + j23

MECHANICAL DATA see page 2

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS.

POTENTIAL HAZARD-BERYLLIUM OXIDE

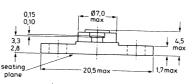
This device contains beryllium oxide, the dust of which is toxic. The device is entirely safe, provided that the beryllium oxide disc is not damaged. Care should be taken to ensure that all those who may handle, use or dispose of this device are aware of its nature and of the necessary safety precautions In particular, it should never be thrown out with general industrial or domestic waste.



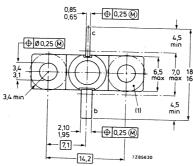
LKE1004R

MECHANICAL DATA

Fig. 1. FO-53 Emitter connected to flange. Dimensions in mm



Torque on nut: max. 0,5 Nm Recommended screw: M3



Marking code

RTC112 = LKE1004R

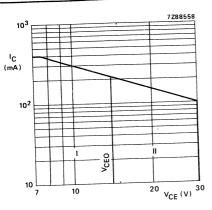
(1) Flatness of this area ensures full thermal contact with bolt head.

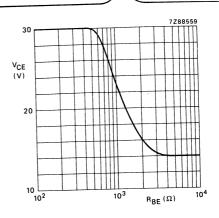


RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Collector-base voltage (open emitter)	V			
Collector-emitter voltage	V _{CBO}	max.	30	V
$(R_{BE} \le 500 \Omega)$ (open base)	VCER	max.	30	
Emitter-base voltage (open collector)	VCEO	max.	14	V
Collector current (d.c.)	v_{EBO}	max.	3	V
	l _C	max.	400	mΔ
Total power dissipation up to $T_{mb} = 75 {}^{\circ}\text{C}$	P _{tot}	mov		
Storage temperature		max.		W
Junction temperature	T_{stg}	65 to -	+ 200	οС
Lead soldering temperature	T_{j}	max.	200	οС
at 0,3 mm from the case; $t_{sld} \le 10 s$	T _{sld}	max.	235	οс





(1) Second breakdown limit (independent of temperature).

Fig. 2 D.C. SOAR at $T_{mb} \le 75$ °C.

- Region of permissible d.c. operation.
- Permissible extension provided $R_{BE} \leqslant 500~\Omega.$

Fig. 3 Maximum permissible collector-emitter voltage as a function of R_{BE} .

THERMAL RESISTANCE

From junction to mounting base From mounting base to heatsink

$$R_{th j-mb}$$
 = 30 °C/W
 $R_{th mb-h}$ = 0.7 °C/W

CHARACTERISTICS

Collector-base breakdown voltage open emitter; $I_C = 0.5 \text{ mA}$ Collector-emitter breakdown voltage $R_BE = 500 \Omega$; $I_C = 5 \text{ mA}$ open base; $-I_E = 5 \text{ mA}$ Emitter-base breakdown voltage open collector; $I_E = 1 \text{ mA}$ Collector cut-off current $I_E = 0$; $V_{CB} = 20 \text{ V}$ Emitter cut-off current $I_C = 0$; $V_{EB} = 2 \text{ V}$

D.C. current gain I_C = 75 mA; V_{CE} = 5 V

Collector-base capacitance at f = 1 MHz $I_E = I_C = 0$; $V_{CB} = 14 \text{ V}$

Collector-emitter capacitance at f = 1 MHz $I_E = I_C = 0$; $V_{CE} = 14 \text{ V}$

Emitter-base capacitance at f = 1 MHz

$$I_E = I_C = 0$$
; $V_{EB} = 1 \text{ V}$

 C_{eb}

typ. 4,4 pF

Forward power gain

$$V_{CE} = 15 \text{ V}; I_{C} = 100 \text{ mA}; f = 1 \text{ GHz}$$

|sfe|2

typ. 6 dB

Maximum available power gain

$$V_{CE} = 15 \text{ V}; I_{C} = 100 \text{ mA}; f = 1 \text{ GHz}$$

 G_{AM}

typ. 11 dB

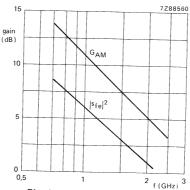


Fig. 4 VCE and IC regulated.

Typical values; $V_{CE} = 15 \text{ V}$; IC = 100 mA; T_{mb} = 25 oC.

s-parameters (common-emitter)

Typical values; V_{CE} = 15 V*; I_{C} = 100 mA*; Z_{o} = 50 Ω .

f GHz	s _{ie}	s _{re}	s _{fe}	s _{oe}
0,75	0,72/170°	0,07(-23)/35°	2,24(7,0)/80°	0,52/-145°
1	0,71/165°	0,08(-22)/40°	2,00(6,0)/70°	0,52/-152°
1,5	0,67/151°	0,10(-20)/43°	1,33(2,5)/52°	0,52/-156°
2	0,61/134°	0,14(-17)/40°	1,12(1,0)/30°	0,52/-160°
2,5	0,61/ 89°	0,15(-16)/35°	1,05(0,5)/15°	0,52/-162°

The figures given between brackets are values in dB.

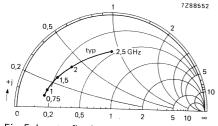


Fig. 5 Input reflection coefficient sie-

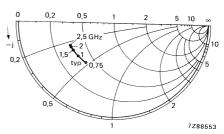


Fig. 6 Output reflection coefficient soe.

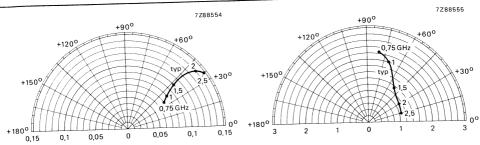


Fig. 7 Reverse transmission coefficient sre.

Fig. 8 Forward transmission coefficient sfe.

Conditions for Figs 5 up to 8:

Typical values; V_{CE} = 15 V*; I_{C} = 100 mA*; T_{mb} = 25 °C; Z_{o} = 50 Ω .

* VCE and IC regulated.

APPLICATION INFORMATION

R.F. performance in c.w. operation up to T_{mb} = 25 $^{\rm o}$ C in an unneutralized common-emitter class-A circuit.

circuit.			:		D (4)
f GHz	V _{CE} (1)	I _C (1) mA	P _{L1} (2) mW (dBm)	G _{po} (3) dB	P _{Lsat} (4) mW (dBm)
			≥ 320(25)	≥ 8	_
1	15	100	typ. 400(26)	typ. 11	typ. 630(28)

Notes

- 1. V_{CE} and I_C regulated.
- 2. Load power for 1 dB compressed power gain.
- 3. Low-level power gain associated with P_{L1} .
- 4. Saturated output power of the transistor.

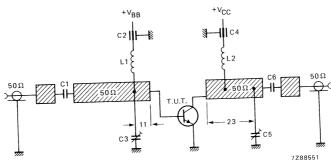


Fig. 9 Class-A test circuit at f = 1 GHz. (Dimensions in mm.)



List of components:

C1 = C6 = 1 nF multilayer ceramic chip capacitor

C2 = C4 = 500 pF ceramic feed-through capacitor

C3 = C5 = 0 to 10 pF film dielectric trimmer

L1 = L2 = 5 turns enamelled Cu wire (0,5 mm); internal diameter 2,5 mm

Striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric (ϵ_r = 2,54); thickness 0,8 mm.

Conditions for Figs 10 up to 13:

$$V_{CE} = 15 V$$
 $I_{C} = 100 \text{ mA}$ regulated; $T_{mb} = 25 \text{ oC}$

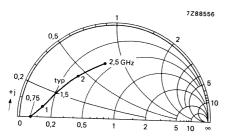
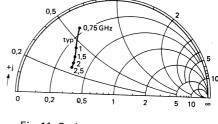


Fig. 10 Input impedance as a function of frequency for P_{L1}.



7Z88557

Fig. 11 Optimum load impedance as a function of frequency for PL1.

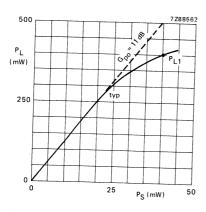


Fig. 12 Load power as a function of source power at f = 1 GHz.

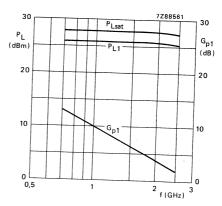


Fig. 13 P_{Lsat} , P_{L1} and G_{pl} associated with P_{L1} as a function of frequency.



MICROWAVE LINEAR POWER TRANSISTOR

N-P-N transistor for use in a common-emitter class-A linear power amplifier up to 2 GHz.

Diffused emitter ballasting resistors, interdigitated structure, multicell geometry and gold sandwich metallization ensure an optimum temperature profile and excellent performance and reliability.

QUICK REFERENCE DATA

R.F. performance up to T_{mb} = 25 $^{\rm o}$ C in an unneutralized common-emitter class-A circuit

n.r. performance up to	THID						
mode of operation	f GHz	V _{CE} V	I _C	PL1 W	G _{po} dB	z _i Ω	Z _L Ω
c.w.; linear amplifier	2	20	200	typ. 1,6	typ. 8	2,5 + j12	4 + j4

MECHANICAL DATA

see page 2

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS—MICROWAVE SEMICONDUCTORS.

POTENTIAL HAZARD-BERYLLIUM OXIDE

This device contains beryllium oxide, the dust of which is toxic. The device is entirely safe, provided that the beryllium oxide disc is not damaged. Care should be taken to ensure that all those who may handle, use or dispose of this device are aware of its nature and of the necessary safety precautions. In particular, it should never be thrown out with general industrial or domestic waste.



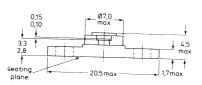
LKE2015T

MECHANICAL DATA

Fig. 1.

Emitter connected to flange

Dimensions in mm



Torque on nut: max. 0,5 Nm Recommended screw: M3

Marking code RTC144 = LKE2015T

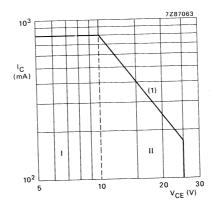
(1) Flatness of this area ensures full thermal contact with bolt head.



RATINGS

2010
meas
_
=
-
-

Limiting values in accordance with the Absolute Maximum System (IEC 134)			
	V _{CBO}	max.	45	٧
Collector-base voltage (open emitter)	OBO			
Collector-emitter voltage	VCER	max.	25	V
$(R_{BE} = 120 \Omega)$	VCEO	max.	20	V
(open base)		max.	3.5	V
Emitter-base voltage (open collector)	V _{EBO}		•	
Collector current (d.c.)	1C	max.	800	
Total power dissipation up to T _{mb} = 75 °C	P_{tot}	max.	8	W
	T_{stg}	-65 to +	200	oC
Storage temperature	Ti	max.	200	οС
Junction temperature	-)			
Lead soldering temperature at 0,3 mm from the case; t _{sld} ≤ 10 s	T _{sld}	max.	235	оC



(1) Second breakdown limit (independent of temperature).

Fig. 2 D.C. SOAR at $T_{mb} \le 75$ °C.

- I Region of permissible d.c. operation.
- II Permissible extension provided R_{BE} \leq 120 Ω .

THERMAL RESISTANCE

	D	=	11	°C/W
From junction to mounting base	R _{th j-mb}			C/ **
From Junetion to mounting pass	D	_	0.7	°C/W
From mounting base to heatsink	R _{th} mb-h	-	0,,	O/ VV
1 Tolli Mountaing 2000 to mount				

LKE2015T

CHARACTERISTICS

 $T_{mb} = 25 \, {}^{\circ}\text{C}$ Collector-base breakdown voltage open emitter; $I_C = 3 \text{ mA}$ Collector-emitter breakdown voltage R_{BE} = 120 Ω ; I_C = 15 mA open base; $-I_E = 15 \text{ mA}$ Emitter-base breakdown voltage open collector; IE = 1 mA Collector cut-off current $I_E = 0$; $V_{CB} = 20 \text{ V}$ Emitter cut-off current $I_C = 0$; $V_{EB} = 1.5 V$ D.C. current gain $I_C = 200 \text{ mA}$; $V_{CE} = 5 \text{ V}$ Collector-base capacitance at f = 1 MHz $I_E = I_C = 0$; $V_{CB} = 20 \text{ V}$; $V_{EB} = 1.5 \text{ V}$ Collector-emitter capacitance at f = 1 MHz $I_E = I_C = 0$; $V_{CE} = 20 \text{ V}$; $V_{EB} = 1.5 \text{ V}$ Emitter-base capacitance at f = 1 MHz $I_E = I_C = 0$; $V_{EB} = 1 \text{ V}$; $V_{CB} = 10 \text{ V}$ Forward power gain $V_{CE} = 20 \text{ V}; I_{C} = 200 \text{ mA}; f = 1 \text{ GHz}$ $V_{CE} = 20 \text{ V; I}_{C} = 200 \text{ mA; f} = 2 \text{ GHz}$ Maximum available power gain $V_{CE} = 20 \text{ V; I}_{C} = 200 \text{ mA; f} = 1 \text{ GHz}$

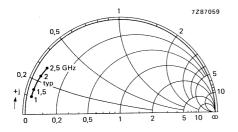
 $V_{CE} = 20 \text{ V}; I_{C} = 200 \text{ mA}; f = 2 \text{ GHz}$

V _{(BR)CBO}	\geqslant	45 V
V _(BR) CER V _(BR) CEO		25 V 20 V
V _{(BR)EBO}	≥	3,5 V
I _{CBO}	<	0,5 μΑ
^I EBO	<	300. μΑ
hFE	15	to 150
C _{cb}	typ.	3,5 pF
C _{ce}	typ.	2,9 pF
C _{eb}	typ.	17 pF
s _{fe} ² s _{fe} ²	typ.	2,4 dB -3,1 dB
G _{AM} G _{AM}	typ.	13,7 dB 8,4 dB

s-parameters (common-emitter)

 $V_{CE} = 20 \text{ V}$ $I_{C} = 200 \text{ mA}$ regulated; $T_{mb} = 25 \text{ °C}$; typical values.

f GHz	s _{ie}	s _{re}	^s fe	s _{oe}
0,5 0,6 0,7 0,8 0,9	0,94/174° 0,94/172° 0,94/170° 0,94/168° 0,94/167°	0,021(-33,6)/27° 0,022(-33,2)/30° 0,023(-32,7)/33° 0,025(-32,1)/35° 0,027(-31,5)/37° 0,028(-30,9)/38°	2,61(8,3)/72° 2,20(6,8)/68° 1,89(5,5)/63° 1,67(4,4)/59° 1,48(3,4)/54° 1,32(2,4)/49°	0,57/-173° 0,57/-176° 0,57/-177° 0,57/-178° 0,57/-179° 0,58/+180°
1,0 1,1 1,2 1,3 1,4	0,94/165° 0,93/163° 0,93/161° 0,92/160° 0,93/158°	0,030(-30,4)/39 ⁰ 0,033(-29,7)/41 ⁰ 0,035(-29,2)/42 ⁰ 0,036(-28,8)/43 ⁰	1,21(1,7)/46 ^o 1,12(1,0)/42 ^o 1,03(0,3)/38 ^o 0,96(-0,4)/34 ^o	0,59/+ 178° 0,60/+ 178° 0,60/+ 177° 0,61/+ 175°
1,5 1,6 1,7 1,8 1,9	0,93/156° 0,93/155° 0,94/152° 0,93/150° 0,93/148°	0,038(-28,4)/47° 0,044(-27,1)/48° 0,047(-26,5)/46° 0,050(-26,0)/44° 0,053(-25,5)/44°	0,90(-0,9)/32° 0,86(-1,3)/28° 0,83(-1,7)/23° 0,78(-2,2)/19° 0,74(-2,7)/16°	0,62/+175° 0,62/+174° 0,63/+173° 0,64/+171° 0,64/+171°
2,0 2,1 2,2 2,3 2,4	0,93/146° 0,92/144° 0,92/143° 0,92/141° 0,92/140°	0,056(-25,0)/43° 0,060(-24,5)/42° 0,064(-23,9)/41° 0,067(-23,5)/41° 0,071(-22,9)/39°	0,70(-3,1)/12° 0,67(-3,4)/ 9° 0,64(-3,8)/ 5° 0,61(-4,3)/ 2° 0,59(-4,5)/ 0°	0,64/+ 168° 0,65/+ 166° 0,66/+ 165° 0,67/+ 163° 0,68/+ 162°



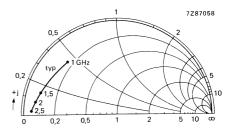


Fig. 3 Input impedance as a function of frequency for P_{L1} .

Conditions for Figs 3 and 4:

 $V_{CE} = 20 \text{ V}$ $I_{C} = 200 \text{ mA}$ regulated; T_{mb} = 25 °C; typical values.

Fig. 4 Optimum load impedance as a function of frequency for P_{L1}.

APPLICATION INFORMATION

R.F. performance in c.w. operation up to T_{mb} = 25 °C in an unneutralized common-emitter class-A circuit*

f GHz	V _{CE} (1)	I _C (1) mA	P _{L1} (2) mW(dBm)	G _{po} (3) dB	$\frac{\overline{z_i}}{\Omega}$	$\overline{Z_L}$
2	20	200	≥ 1300(31) typ. 1600(32)	≥ 7,5 typ. 8,0	2,5 + j12	4 + j4

Notes

- 1. V_{CE} and I_C regulated.
- 2. Load power for 1 dB compressed power gain.
- 3. Low-level power gain associated with P_{1.1}.

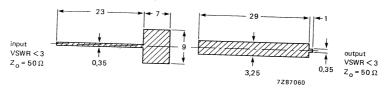


Fig. 5 Prematching test circuit board for 2 GHz. (Dimensions in mm.)

Striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric ($\epsilon_{\rm r}$ = 2,4); thickness 0,25 mm.

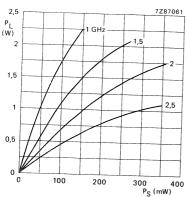


Fig. 6 Load power as a function of source power with frequency as parameter.

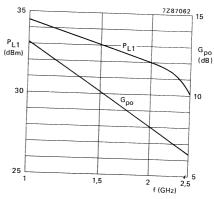


Fig. 7 Load power and power gain, associated with 1 dB compressed power gain, as a function of frequency.

Conditions for Figs 6 and 7:

$$V_{CE} = 20 \text{ V}$$
 $I_{C} = 200 \text{ mA}$ regulated; $T_{mb} = 25 \text{ °C}$; typical values.

^{*} Circuit consists of prematching circuit board in combination with complementary input and output slug tuners.

MICROWAVE LINEAR POWER TRANSISTOR

N-P-N transistor for use in a common-emitter class-A linear power amplifier up to 2,1 GHz.

Diffused emitter ballasting resistors, interdigitated structure, multicell geometry and gold sandwich metallization ensure an optimum temperature profile and excellent performance and reliability.

QUICK REFERENCE DATA

R.F. performance up to T_{mb} = 25 o C in an unneutralized common-emitter class-A circuit

mode of operation	f GHz	V _{CE} V	I _C mA	P _{L1} mW	G _{po} dB	$\frac{\overline{z_i}}{\Omega}$	Z _L Ω
c.w.; linear amplifier	2,1	15	140	typ. 600	typ. 10	6 + j8	4 + j8

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

see page 2

POTENTIAL HAZARD-BERYLLIUM OXIDE

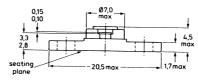
This device contains beryllium oxide, the dust of which is toxic. The device is entirely safe, provided that the beryllium oxide disc is not damaged. Care should be taken to ensure that all those who may handle, use or dispose of this device are aware of its nature and of the necessary safety precautions. In particular, it should never be thrown out with general industrial or domestic waste.



MECHANICAL DATA Dimensions in mm

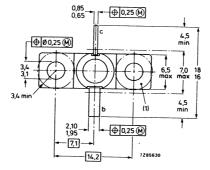
Fig. 1.

Emitter connected to flange



Torque on nut: max. 0,5 Nm

Recommended screw: M3



Marking code

RTC146 = LKE21004R

(1) Flatness of this area ensures full thermal contact with bolt head.



RATINGS

Limiting values in accordance with the Absolute Maximum Sys	tem (IEC 134)			
Collector-base voltage (open emitter)	V _{CBO}	max.	30	٧
Collector-emitter voltage $(R_{BE} = 500 \Omega)$	VCER	max.	20	v
(open base)	V _{CEO}	max.	14	٧
Emitter-base voltage (open collector)	v_{EBO}	max.	3	٧
Collector current (d.c.)	Ic	max.	600	mΑ
Total power dissipation up to T _{mb} = 75 °C	P _{tot}	max.	2,8	W
Storage temperature	T _{stg}	-65 to +	200	oC
Junction temperature	Tj	max.	200	oC
Lead soldering temperature at 0.3 mm from the case; t _{sld} ≤ 10 s	T _{sld}	max.	235	οС

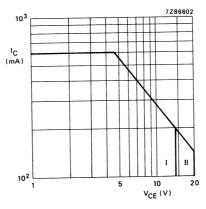


Fig. 2 D.C. SOAR at $T_{mb} \le 75$ °C.

- I Region of permissible d.c. operation. II Permissible extension provided RBE \leq 500 Ω .

THERMAL RESISTANCE

	_		22	00/4/
From junction to mounting base	R _{th j-mb}	=	22	oC/M
· · · · · · · · · · · · · · · · · · ·		_	0.7	oC/W
From mounting base to heatsink	R _{th} mb-h	=	0,7	OC/W



LKE21004R

CHARACTERISTICS

$T_{mb} = 25 {}^{\circ}\text{C}$			
Collector-base breakdown voltage open emitter; $I_C = 1 \text{ mA}$	V(BR)CBO	≥	30 V
Collector-emitter breakdown voltage R_{BE} = 500 Ω ; I_C = 10 mA	V(BR)CER	>	20 V
open base; –I _E = 10 mA	V(BR)CER	>	14 V
Emitter-base breakdown voltage open collector; I _E = 1 mA	V(BR)EBO	≽	3 V
Collector cut-off current I _E = 0; V _{CB} = 15 V	СВО	<	100 μΑ
D.C. current gain I _C = 140 mA; V _{CE} = 5 V		·	·
Collector-base capacitance at f = 1 MHz	hFE	15 t	o 150
$I_E = I_C = 0$; $V_{CB} = 15 \text{ V}$; $V_{EB} = 1,5 \text{ V}$ Collector-emitter capacitance at $f = 1 \text{ MHz}$	c_{cb}	typ.	2,7 pF
$I_E = I_C = 0$; $V_{CE} = 15 \text{ V}$; $V_{EB} = 1.5 \text{ V}$	C _{ce}	typ.	2,5 pF
Emitter-base capacitance at f = 1 MHz IE = IC = 0; VEB = 1 V; V _{CB} = 10 V	C _{eb}	typ.	27 pF

s-parameters (common-emitter)

 V_{CE} = 15 V | I_{C} = 125 mA | regulated; T_{mb} = 25 °C; typical values.

f GHz	s _{ie}	s _{re}	\$fe	s _{oe}
2,0 2,1 2,2 2,3 2,4 2,5 2,6 2,7 2,8 2,9 3,0 3,1 3,2 3,3 3,4 3,5	0,92/170° 0,94/168° 0,95/166° 0,97/167° 0,98/166° 0,99/163° 0,99/162° 0,98/157° 0,98/157° 0,96/158° 0,96/155° 0,97/153° 0,98/152°	0,015(-36,4)/-103° 0,007(-43,4)/-118° 0,001(-59,4)/-1140° 0,001(-64,3)/-172° 0,002(-55,1)/+159° 0,003(-50,9)/+127° 0,003(-50,1)/+101° 0,004(-48,3)/+101° 0,009(-41,1)/+90° 0,011(-39,1)/+75° 0,015(-36,6)/+69° 0,021(-33,4)/+68° 0,024(-32,5)/+69° 0,021(-33,4)/+63° 0,024(-32,4)/+61°	1,10(+0,85)/ -76° 0,94(-0,57)/ -85° 0,79(-2,09)/ -93° 0,67(-3,54)/-101° 0,57(-4,89)/-106° 0,50(-6,0)/-113° 0,44(-7,1)/-117° 0,38(-8,5)/-124° 0,33(-9,7)/-130° 0,28(-11,1)/-138° 0,24(-12,2)/-144° 0,22(-13,2)/-149° 0,16(-15,9)/-157° 0,15(-16,5)/-160° 0,14(-17,2)/-165° 0,12(-18,4)/-170°	0,94/-1710 0,94/-1770 0,93/+ 1790 0,92/+ 1750 0,91/+ 1730 0,89/+ 1710 0,87/+ 1690 0,84/+ 1670 0,81/+ 1630 0,79/+ 1580 0,77/+ 1550 0,77/+ 1550 0,73/+ 1540 0,72/+ 1530 0,72/+ 1530 0,70/+ 1510



APPLICATION INFORMATION

R.F. performance in c.w. operation up to T_{mb} = 25 °C in an unneutralized common-emitter class-A circuit*

f GHz	V _{CE} (1)	i _C (1) mA	P _{L1} (2) mW(dBm)	G _{po} (3) dB	$\overset{-}{\overset{z}{i}}$	$\overline{Z_L}$
2,1	15	140	≥ 400(26) typ. 600(27,8)	≥ 8,5 typ. 10	6 + j8	4 + j8

Notes

- 1. VCE and IC regulated.
- 2. Load power for 1 dB compressed power gain.
- 3. Low-level power gain associated with PL1.

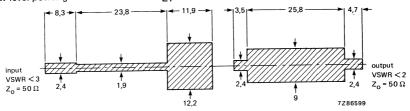


Fig. 3 Prematching test circuit board for 2,1 GHz. (Dimensions in mm.)

Striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric (ϵ_r = 2,54); thickness 0,8 mm.

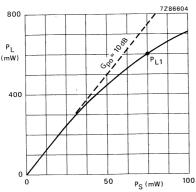


Fig. 4 Load power as a function of source power. Typical values;

$$V_{CE} = 15 \text{ V}$$

 $I_{C} = 140 \text{ mA}$ regulated;
 $f = 2,1 \text{ GHz}; T_{mb} = 25 \text{ °C}.$

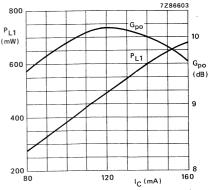


Fig. 5 Load power and power gain, associated with 1 dB compressed power gain, as a function of collector current.

Typical values; $V_{CE} = 15 \text{ V regulated}$; f = 2,1 GHz; $T_{mb} = 25 \text{ }^{\circ}\text{C}$.



^{*} Circuit consists of prematching circuit board in combination with complementary input and output slug tuners.

MICROWAVE LINEAR POWER TRANSISTOR

N-P-N transistor for use in a common-emitter class-A linear power amplifier up to 2,1 GHz.

Diffused emitter ballasting resistors, interdigitated structure, multicell geometry and gold sandwich metallization ensure an optimum temperature profile and excellent performance and reliability.

An internal input matching network facilitates wideband operation.

QUICK REFERENCE DATA

R.F. performance up to T_{mb} = 25 °C in an unneutralized common-emitter class-A circuit

mode of operation	f GHz	V _{CE} V	IC A	P _{L1} W	G _{po} dB	$\frac{\overline{z_i}}{\Omega}$	$\frac{\overline{Z_L}}{\Omega}$
c.w.; linear amplifier	2,1	20	1,2	typ. 5,5	typ. 9	2,5 + j8	2,5 — j7

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

see page 2

POTENTIAL HAZARD-BERYLLIUM OXIDE

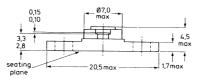
This device contains beryllium oxide, the dust of which is toxic. The device is entirely safe, provided that the beryllium oxide disc is not damaged. Care should be taken to ensure that all those who may handle, use or dispose of this device are aware of its nature and of the necessary safety precautions. In particular, it should never be thrown out with general industrial or domestic waste.



MECHANICAL DATA

Fig. 1.

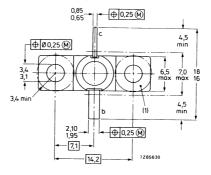
Emitter connected to flange.



Dimensions in mm

Torque on nut: max. 0,5 Nm

Recommended screw: M3



Marking code

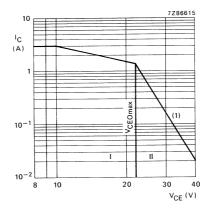
RTC190 = LKE21050T

(1) Flatness of this area ensures full thermal contact with bolt head.



F	ŀΑ	T	11	IGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)			
Collector-base voltage (open emitter)	V_{CBO}	max.	45 V	/
Collector-emitter voltage	V_{CER}	max.	40 V	,
$(R_{BE} = 47 \Omega)$	0	max.		
(open base)	v_{CEO}	max.	22 V	/
Emitter-base voltage (open collector)	v_{EBO}	max.	3,5 V	/
Collector current (d.c.)	1 _C	max.	3 A	4
Total power dissipation up to T _{mb} = 75 °C	P_{tot}	max.	30 M	٧
Storage temperature	T_{stg}	65 to +	- 200 o	C
Junction temperature	T_{j}	max.	200 o	C
Lead soldering temperature at 0,3 mm from the case; $t_{sld} \le 10 \text{ s}$	T _{sld}	max.	235 0	С



(1) Second breakdown limit (independent of temperature).

Fig. 2 D.C. SOAR at $T_{mb} \le 75$ °C.

I Region of permissible d.c. operation.

II Permissible extension provided R_{BE} \leq 47 Ω .

THERMAL RESISTANCE

From junction to mounting base
From mounting base to heatsink

 $R_{th j-mb} = 4 \text{ °C/W}$ $R_{th mb-h} = 0,7 \text{ °C/W}$

CHARACTERISTICS

 $T_{mb} = 25 \, {}^{\circ}C$

Collector-base breakdown voltage open emitter; I_C = 10 mA

Emitter-base breakdown voltage open collector: $L_{\pi} = 2 \text{ mA}$

open collector; I_E = 2 mA Collector cut-off current

I_E = 0; V_{CB} = 20 V

D.C. current gain

 $I_C = 500 \text{ mA}; V_{CE} = 5 \text{ V}$

Collector-base capacitance at f = 1 MHz

 $I_E = I_C = 0$; $V_{CB} = 20 \text{ V}$; $V_{EB} = 1 \text{ V}$

Collector-emitter capacitance at f = 1 MHz

 $I_E = I_C = 0$; $V_{CE} = 20 \text{ V}$; $V_{EB} = 1 \text{ V}$

Emitter-base capacitance at f = 1 MHz $I_E = I_C = 0$; $V_{EB} = 1 \text{ V}$; $V_{CB} = 15 \text{ V}$

APPLICATION INFORMATION

V _{(BR)CBO}	≥	45 V
V _{(BR)EBO}	≽	3,5 V
I _{CBO}	<	75 μA
hFE	20 to	o 120
C _{cb}	typ.	9 pF
C _{ce}	typ.	5 pF
Cob	tvp.	95 pF

Fig. 3 Input impedance as a function of frequency for $P_{1,1}$.

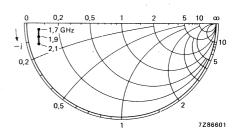


Fig. 4 Optimum load impedance as a function of frequency for P_{L1}.

Conditions for Figs 3 and 4:

regulated; typical values; T_{mb} = 25 °C.

APPLICATION INFORMATION (continued)

R.F. performance in c.w. operation up to $T_{mb} = 25$ °C in an unneutralized common-emitter class-A circuit*

f GHz	V _{CE} (1)	I _C (1)	P _{L1} (2) mW	P _{po} (3) dB	$\frac{\overline{z_i}}{\Omega}$	$\overline{Z_L}$ Ω
2,1	20	1,2	≥ 5 typ. 5,5	≥ 7 typ. 9	2,5 + j8	2,5 — j7

Notes

- 1. VCF and IC regulated.
- 2. Load power for 1 dB compressed power gain.
- 3. Low-level power gain associated with PL1.

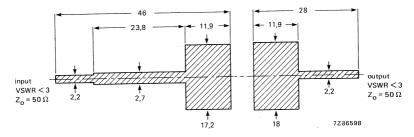


Fig. 5 Prematching test circuit board for 1,7 to 2,1 GHz. (Dimensions in mm.)

Striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric (ϵ_r = 2,5); thickness 0,8 mm.

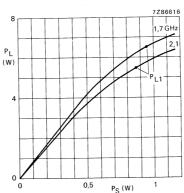


Fig. 6 Load power as a function of source power. Typ. values; T_{mb} = 25 °C. V_{CE} = 20 V_{CE} regulated. I_{C} = 1,2 A

* Circuit consists of prematching circuit board in combination with complementary input and output slug tuners.



MICROWAVE LINEAR POWER TRANSISTOR

N-P-N transistor for use in a common-emitter class-A linear power amplifier up to 3 GHz.

Diffused emitter ballasting resistors, interdigitated structure, multicell geometry and gold sandwich metallization ensure an optimum temperature profile and excellent performance and reliability.

An input matching cell improves the input impedance and facilitates the design of wideband circuits.

QUICK REFERENCE DATA

R.F. performance up to T_{mb} = 25 °C in an unneutralized common-emitter class-A circuit

mode of operation	f GHz	V _{CE} V	I _C	P _{L1} mW	G _{po} dB	$\frac{z_{i}}{\Omega}$	$\frac{\overline{Z_L}}{\Omega}$
c.w.; linear amplifier	3	12	50	typ. 210	typ. 9,5	50 + j48	3 + j11

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

see page 2

POTENTIAL HAZARD-BERYLLIUM OXIDE

This device contains beryllium oxide, the dust of which is toxic. The device is entirely safe, provided that the beryllium oxide disc is not damaged. Care should be taken to ensure that all those who may handle, use or dispose of this device are aware of its nature and of the necessary safety precautions. In particular, it should never be thrown out with general industrial or domestic waste.



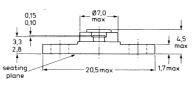
LKE32001QC

MECHANICAL DATA

Dimensions in mm

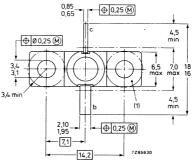
Fig. 1.

Emitter connected to flange.



Torque on nut: max. 0,5 Nm

Recommended screw: M3



Marking code

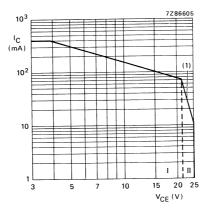
RTC168 = LKE32001QC

(1) Flatness of this area ensures full thermal contact with bolt head.



RATINGS

RATINGO				
Limiting values in accordance with the Absolute Maximum Sys	item (IEC 134)			
Collector-base voltage (open emitter)	VCBO	max.	45	٧
Collector-emitter voltage $(R_{BE} = 220 \Omega)$	V _{CER}	max.	25	
(open base)	V _{CEO}	max.	20	V
Emitter-base voltage (open collector)	VEBO	max.	3,5	V
Collector current (d.c.)	I _C	max.	400	mΑ
Total power dissipation up to T _{mb} = 75 °C	P_{tot}	max.	1,5	W
Storage temperature	T _{stq}	-65 to +	200	oC
Junction temperature	Tj	max.	200	oC
Lead soldering temperature at 0.3 mm from the case; t _{sld} ≤ 10 s	T _{sld}	max.	235	οС



(1) Second breakdown limit (independent of temperature).

Fig. 2 D.C. SOAR at $T_{mb} \le 75$ °C.

- I Region of permissible d.c. operation.
- II Permissible extension provided RBE \leq 220 $\Omega.$

THERMAL RESISTANCE

From junction to mounting base	R _{th i-mb}	=	45	oC/M
From mounting base to heatsink	R _{th mb-h}	=	0,7	oC/W



LKE32001QC

CHARACTERISTICS

 $T_{mb} = 25 \, {}^{\circ}C$ Collector-base breakdown voltage open emitter; IC = 1 mA Collector-emitter breakdown voltage $R_{BE} = 220 \Omega$; $I_C = 3 \text{ mA}$ open base; $I_C = 3 \text{ mA}$ Emitter-base breakdown voltage open collector; I_E = 0,25 mA Collector cut-off current IE = 0; VCB = 20 V Emitter cut-off current $I_C = 0$; $V_{EB} = 1.5 V$ D.C. current gain $I_C = 50 \text{ mA}$; $V_{CE} = 5 \text{ V}$ Collector-base capacitance at f = 1 MHz $I_E = I_C = 0$; $V_{CB} = 10 \text{ V}$; $V_{EB} = 1.5 \text{ V}$ Collector-emitter capacitance at f = 1 MHz $I_E = I_C = 0$; $V_{CE} = 10 \text{ V}$; $V_{EB} = 1.5 \text{ V}$ Emitter-base capacitance at f = 1 MHz $I_E = I_C = 0$; $V_{EB} = 1 \text{ V}$; $V_{CB} = 10 \text{ V}$ Forward power gain $V_{CE} = 12 \text{ V}; I_{C} = 50 \text{ mA}; f = 2 \text{ GHz}$ $V_{CE} = 12 \text{ V; I}_{C} = 50 \text{ mA; f} = 3 \text{ GHz}$ Maximum available power gain

 $V_{CE} = 12 \text{ V}; I_{C} = 50 \text{ mA}; f = 2 \text{ GHz}$

V(BR)CBO	≽	45 V
V _{(BR)CER} V _{(BR)CEO}		25 V 20 V
V _{(BR)EBO}	≽	3,5 V
ICBO	<	5 μΑ
IEBO	<	75 nA
hFE	15	to 150
C _{cb}	typ.	1 pF
C _{ce}	typ.	1,75 pF
C_{eb}	typ.	7 pF
s _{fe} ² s _{fe} ²	typ. typ.	5,6 dB 2,9 dB
G_{AM}	typ.	8 dB



s-parameters (common-emitter)

V_{CE} = 12 V I_C = 50 mA $^{\circ}$ regulated; T_{mb} = 25 °C; Z_O = 50 Ω ; typical values.

f GHz	^s ie	s _{re}	^s fe	s _{oe}
0,5 0,7 0,9 1,1 1,3 1,5 1,7 1,9 2,0 2,2 2,4 2,6 2,8 3,0 3,2	0,77/-170° 0,77/+178° 0,76/+172° 0,75/+166° 0,73/+160° 0,65/+147° 0,59/+139° 0,54/+134° 0,46/+127° 0,34/+124° 0,19/+130° 0,11/-179° 0,21/-157° 0,35/-167°	0,026(-31,8)/ 19° 0,024(-32,4)/ 19° 0,024(-32,4)/ 20° 0,029(-30,8)/ 22° 0,038(-28,5)/ 25° 0,043(-27,4)/ 25° 0,061(-24,3)/ 23° 0,066(-23,6)/ 21° 0,082(-21,7)/ 15° 0,097(-20,3)/ 6° 0,105(-19,6)/ -4° 0,102(-19,9)/-18° 0,094(-20,6)/-30° 0,083(-21,6)/-45°	5,30(14,5)/ 78° 3,92(11,9)/ 64° 3,12(9,9)/ 52° 2,65(8,5)/ 40° 2,37(7,5)/ 30° 2,15(6,7)/ 18° 2,05(6,2)/ 6° 1,95(5,8)/ -7° 1,90(5,6)/ -12° 1,84(5,3)/ -28° 1,78(5,0)/ -43° 1,70(4,6)/ -62° 1,56(3,9)/ -80° 1,40(2,9)/ -99° 1,20(1,6)/-118°	0,33/ -76° 0,32/ -82° 0,34/ -88° 0,37/ -92° 0,41/ -99° 0,44/-102° 0,49/-107° 0,54/-111° 0,57/-111° 0,63/-116° 0,72/-122° 0,80/-129° 0,87/-136° 0,91/-144° 0,94/-153°
3,4	0,48/+143 ^o	0,063(-24,0)/-540	0,99(-0,1)/-135°	0,94/162 ^o

The figures given between brackets are values in dB.

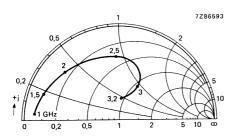


Fig. 3 Input impedance as a function of frequency for P_{L1}.

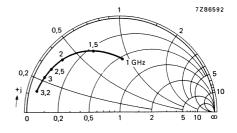


Fig. 4 Optimum load impedance as a function of frequency for P_{L1}.

Conditions for Figs 3 and 4:

 V_{CE} = 12 V_{IC} = 50 mA T_{mb} regulated; typical values; Z_{o} = 50 Ω ; T_{mb} = 25 °C.

APPLICATION INFORMATION

R.F. performance in c.w. operation up to T_{mb} = 25 $^{\rm oC}$ in an unneutralized common-emitter class-A circuit*

f GHz	V _{CE} (1) V	I _C (1) mA	P _{L1} (2) mW(dBm)	G _{po} (3) dB	$\frac{z_i}{\Omega}$	$\frac{\overline{Z_L}}{\Omega}$
3	12	50	≥ 90(19,5) typ. 210(23,2)	≥ 7 typ. 9,5	50 + j48	3 + j11

Notes

- 1. VCE and IC regulated.
- 2. Load power for 1 dB compressed power gain.
- 3. Low-level power gain associated with P_{1.1}.

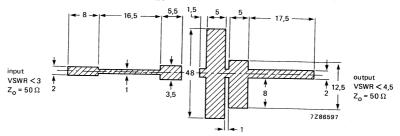


Fig. 5 Prematching test circuit board for 3 GHz. (Dimensions in mm.)

Striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric ($\epsilon_{\rm r}$ = 2,5); thickness 0,8 mm.

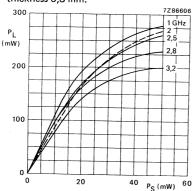


Fig. 6 Load power as a function of source power.

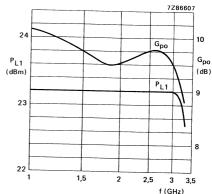


Fig. 7 Load power and power gain, associated with 1 dB compressed power gain, as a function of frequency.

Conditions for Figs 6 and 7:

$$V_{CE} = 12 \text{ V}$$

 $I_{C} = 50 \text{ mA}$ regulated; typical values; $T_{mb} = 25 \text{ °C}$.



Circuit consists of prematching circuit board in combination with complementary input and output slug tuners.

MICROWAVE LINEAR POWER TRANSISTORS

N-P-N transistors for use in a common-emitter class-A linear power amplifier up to 3 GHz.

Diffused emitter ballasting resistors, interdigitated structure, multicell geometry and gold sandwich metallization ensure an optimum temperature profile and excellent performance and reliability.

An input matching cell improves the input impedance and facilitates the design of wideband circuits.

QUICK REFERENCE DATA

R.F. performance up to T_{mb} = 25 $^{\rm o}$ C in an unneutralized common-emitter class-A circuit

111.	The period of th								
type no.	mode of operation	f GHz	V _{CE} V	I _C	P _{L1} mW	G _{po} dB	z _i Ω	$\frac{\overline{Z_L}}{\Omega}$	
LKE32002T	c.w.; linear amplifier c.w.; linear amplifier	l .	20 20	65 130	typ. 310 typ. 710	typ. 11,2 typ. 11,0	19 + j44 7,5 + j22	3,0 + j12 2,5 + j5	

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — ${\tt MICROWAVE}$ SEMICONDUCTORS

MECHANICAL DATA

see page 2

POTENTIAL HAZARD-BERYLLIUM OXIDE

This device contains beryllium oxide, the dust of which is toxic. The device is entirely safe, provided that the beryllium oxide disc is not damaged. Care should be taken to ensure that all those who may handle, use or dispose of this device are aware of its nature and of the necessary safety precautions. In particular, it should never be thrown out with general industrial or domestic waste.

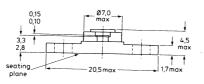


LKE32002T LKE32004T

MECHANICAL DATA

Fig. 1.

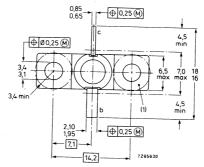
Emitter connected to flange.



Dimensions in mm

Torque on nut: max. 0,5 Nm

Recommended screw: M3



Marking code

RTC114 = LKE32002T RTC116 = LKE32004T

(1) Flatness of this area ensures full thermal contact with bolt head.



RATINGS

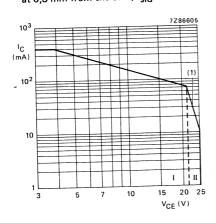
Limiting values in accordance with the Absolute Maximum System (IEC 134)

Collector-base voltage (open emitter)
Collector-emitter voltage $R_{BE} = 220 \Omega$ (open base)
(open base)
Emitter-base voltage (open collector)
Collector current (d.c.)
Total power dissipation up to T _{mb} = 75 °C

Storage temperature

Junction temperature

Lead soldering temperature at 0,3 mm from the case; t_{sld} = 10 s



(1) Second breakdown limit (independent of temperature).

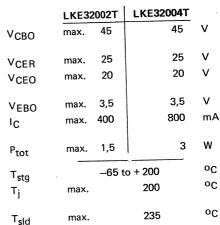
Fig. 2 D.C. SOAR **LKE32002T** at $T_{mb} \le 75$ °C.

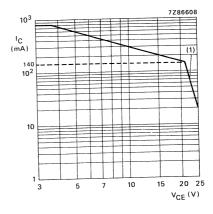
- I Region of permissible d.c. operation.
- II Permissible extension provided R_{BE} \leq 220 Ω .

THERMAL RESISTANCE

From junction to mounting base

From mounting base to heatsink





 Second breakdown limit (independent of temperature).

Fig. 3 D.C. SOAR **LKE32004T** at $T_{mb} \le 75$ °C.

- I Region of permissible d.c. operation.
- II Permissible extension provided R_{BE} \leq 220 Ω .

	LKE	32002T	LKE32004T		
R _{th i-mb}	=	45	22	oC/W	
R _{th mb-h}	=	0,7	0,7	oC/W	



LKE32002T LKE32004T

CHARACTERISTICS

 $T_{mb} = 25 \, {}^{\circ}C$

IIID 9					
Collector-base breakdown voltage		LK	E32002T	LKE320041	Г
open emitter; I _C = 1 mA	V _{(BR)CBO}	>	45	_	_ v
open emitter; I _C = 2 mA	V _{(BR)CBO}		_	45	V
Collector-emitter breakdown voltage					•
$R_{BE} = 220 \Omega; I_C = 3 \text{ mA}$	V(BR)CER	>	25	_	V
$R_{BE} = 220 \Omega$; $I_C = 5 \text{ mA}$	V(BR)CER	>	_	25	V
open base; $-I_E = 3 \text{ mA}$	V _{(BR)CEO}		20	_	V
open base; $-1_E = 5 \text{ mA}$	V _{(BR)CEO}	>	_	20	v
Emitter-base breakdown voltage	(=::,020			2.0	•
open collector; I _E = 250 μA	V _{(BR)EBO}	>	3,5	_	V
open collector; I _E = 500 μA	V _{(BR)EBO}	>		3,5	V
Collector cut-off current				-,-	•
$I_E = 0$; $V_{CB} = 20 \text{ V}$	ГСВО	<	5	10	μΑ
Emitter cut-off current I _C = 0; V _{EB} = 1,5 V					
D.C. current gain	^I EBO	<	75	150	nΑ
I _C = 65 mA; V _{CE} = 5 V		>	20	_	
C SS MAY CE SV	hFE	<	200	_	
$I_C = 130 \text{ mA}; V_{CE} = 5 \text{ V}$	h==	>	_	20	
	hFE	<	-	200	
Collector-base capacitance at $f = 1 \text{ MHz}$ $I_E = I_C = 0$; $V_{CB} = 20 \text{ V}$; $V_{EB} = 1,5 \text{ V}$					
Collector-emitter capacitance at f = 1 MHz	C _{cb}	typ.	0,85	1,8	pF
IC = IE = 0; VCE = 20 V; VEB = 1,5 V	0				
Emitter-base capacitance at f = 1 MHz	C_{ce}	typ.	1,7	1,7	рF
$I_C = I_E = 0$; $V_{EB} = 1 \text{ V}$; $V_{CB} = 10 \text{ V}$	C _{eb}	+1 m	0.5		
Forward power gain	eb	typ.	6,5	13	рF
$I_C = 65 \text{ mA}$; $V_{CE} = 20 \text{ V}$; $f = 3 \text{ GHz}$	s _{fe} 2	typ.	2,9		40
$I_C = 130 \text{ mA}$; $V_{CE} = 20 \text{ V}$; $f = 3 \text{ GHz}$	s _{fe} 2	typ.	2,0		dB
Maximum available gain	, ele	typ.	-	2,5	dB
$I_C = 65 \text{ mA}; V_{CE} = 20 \text{ V}; f = 3 \text{ GHz}$	G_{AM}	typ.	9		dB
$I_C = 130 \text{ mA}$; $V_{CE} = 20 \text{ V}$; $f = 3 \text{ GHz}$	GAM	typ.	_	12.5	
	\tag{\tau}\tau\tau\tau\tau\tau\tau\tau\tau\tau\tau	· , p.		12,5	dB



LKE32002T

s-parameters (common-emitter)

 V_{CE} = 20 V_{CE} = 25 o C; Z_{O} = 50 Ω ; typical values. I_{C} = 65 mA

.6		1		Soo
f GHz	sie	s _{re}	^s fe	
	sie 0,78/-174° 0,78/-179° 0,78/-179° 0,78/+177° 0,78/+177° 0,77/+170° 0,77/+166° 0,76/+163° 0,75/+160° 0,74/+157° 0,73/+154° 0,72/+150° 0,71/+148° 0,70/+144° 0,69/+140° 0,66/+136° 0,63/+133° 0,58/+125° 0,50/+117° 0,40/+108° 0,27/+97° 0,13/+88° 0,03/-165° 0,19/-141° 0,34/-148° 0,44/-158°	0,039(-28,1)/ 22° 0,039(-28,1)/ 22° 0,039(-28,1)/ 24° 0,040(-28,0)/ 25° 0,040(-27,8)/ 26° 0,046(-26,7)/ 29° 0,050(-26,1)/ 30° 0,055(-25,2)/ 31° 0,059(-24,6)/ 31° 0,066(-24,4)/ 32° 0,066(-23,6)/ 34° 0,072(-22,9)/ 33° 0,077(-22,3)/ 31° 0,081(-21,8)/ 29° 0,105(-19,6)/ 24° 0,122(-18,3)/ 16° 0,139(-17,1)/ 9° 0,156(-16,5)/ -3° 0,158(-16,0)/-13° 0,167(-15,5)/-27° 0,162(-15,8)/-39° 0,147(-16,6)/-53° 0,123(-18,2)/-62°	\$fe 5,16(14,3)/ 750 4,36(12,8)/ 680 3,81(11,6)/ 620 3,40(10,6)/ 550 3,04(9,7)/ 490 2,75(8,8)/ 430 2,56(8,2)/ 370 2,39(7,6)/ 320 2,25(7,0)/ 260 2,12(6,5)/ 210 2,01(6,1)/ 160 1,94(5,8)/ 100 1,88(5,5)/ 40 1,81(5,2)/ -20 1,75(4,8)/ -80 1,71(4,6)/ -130 1,65(4,3)/ -270 1,59(4,0)/ -390 1,54(3,7)/ -540 1,47(3,3)/ -690 1,40(2,9)/ -860 1,30(2,3)/-1020 1,16(1,3)/-1210 0,99(-0,0)/-1380 0,84(-1,6)/-1530	\$oe 0,36/ -65° 0,36/ -69° 0,37/ -73° 0,38/ -77° 0,39/ -81° 0,40/ -84° 0,42/ -88° 0,43/ -92° 0,45/ -96° 0,47/ -99° 0,48/-101° 0,51/-104° 0,53/-107° 0,55/-110° 0,56/-113° 0,60/-115° 0,64/-121° 0,69/-127° 0,75/-134° 0,82/-140° 0,88/-147° 0,93/-155° 0,96/-165° 0,97/-174° 0,99/+174°
4,0 4,2 4,4 4.6	0,51/-168 ⁰ 0,56/+179 ⁰ 0,60/+167 ⁰ 0,63/+156 ⁰	0,106(-19,5)/-72° 0,086(-21,3)/-80° 0,065(-23,7)/-87° 0,036(-28,9)/-89°	0,74(-2,6)/-167° 0,64(-3,9)/+178° 0,56(-5,1)/+162° 0,47(-6,5)/+146°	0,99/+ 168° 0,97/+ 161° 0,95/+ 154°

The figures given between brackets are values in dB.



LKE32004T

s-parameters (common-emitter)

 V_{CE} = 20 V I_{C} = 130 mA regulated; T_{mb} = 25 °C; Z_{o} = 50 Ω ; typical values.

f GHz	sie	s _{re}	s _{fe}	s _{oe}
0,5 0,7 0,9 1,1 1,3 1,5 1,7 1,9 2,0 2,2 2,4 2,6 2,8 3,0 3,2 3,4	0,88/-180° 0,87/+174° 0,87/+171° 0,86/+167° 0,85/+164° 0,83/+159° 0,82/+155° 0,78/+150° 0,75/+146° 0,71/+142° 0,65/+139° 0,55/+136° 0,42/+136° 0,31/+144° 0,31/+166° 0,42/+178°	0,007(-42,6)/ 20° 0,006(-44,4)/ 24° 0,006(-43,8)/ 28° 0,011(-39,3)/ 31° 0,019(-34,7)/ 34° 0,022(-33,2)/ 35° 0,030(-30,6)/ 37° 0,034(-29,3)/ 34° 0,038(-28,4)/ 32° 0,050(-26,0)/ 28° 0,062(-24,1)/ 21° 0,074(-22,7)/ 13° 0,076(-22,7)/ 0° 0,073(-22,8)/-13° 0,068(-23,3)/-30° 0,054(-25,3)/-43°	4,40(12,9)/ 74° 3,19(10,1)/ 61° 2,51(8,0)/ 51° 2,10(6,5)/ 41° 1,86(5,4)/ 31° 1,67(4,5)/ 22° 1,58(4,0)/ 11° 1,49(3,5)/ 0° 1,46(3,3)/ -6° 1,42(3,0)/ -18° 1,40(3,0)/ -30° 1,42(3,0)/ -46° 1,37(2,8)/ -63° 1,33(2,5)/ -82° 1,20(1,6)/-103° 1,02(0,2)/-123°	0,26/ -96° 0,28/-102° 0,32/-107° 0,36/-112° 0,41/-118° 0,45/-121° 0,49/-125° 0,56/-129° 0,61/-134° 0,66/-137° 0,74/-141° 0,81/-146° 0,87/-152° 0,92/-161° 0,94/-169°
		•	,	3,54,-109

The figures given between brackets are values in dB.



APPLICATION INFORMATION

R.F. performance in c.w. operation for the LKE32002T up to T_{mb} = 25 $^{\circ}$ C in an unneutralized common-emitter class-A circuit*

Common	Office of the same				_	
f GHz	V _{CE} (1) V	I _C (1) mA	P _{L1} (2) mW(dBm)	G _{po} (3) dB	z; Ω	2 _L
3	20	65	≥ 200(23) typ. 310(25)	≥ 8 typ. 11,2	19 + j44	3 + j12

Notes

- 1. V_{CE} and I_C regulated.
- 2. Load power for 1 dB compressed power gain.
- 3. Low-level power gain associated with PL1.

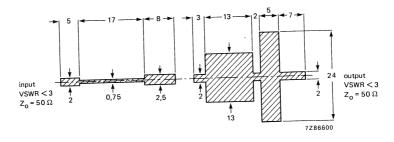
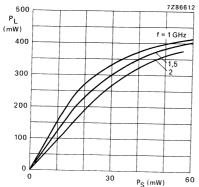


Fig. 4 Prematching test circuit board for 3 GHz. (Dimensions in mm.)

Striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric ($\epsilon_{\rm r}$ = 2,5); thickness 0,8 mm.

^{*} Circuit consists of prematching circuit board in combination with complementary input and output slug tuners.

LKE32002T



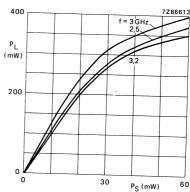


Fig. 5 Load power as a function of source power.

Fig. 6 Load power as a function of source power.

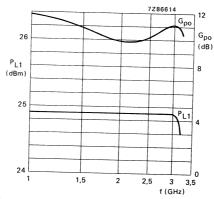


Fig. 7 Load power and power gain, associated with 1 dB compressed power gain, as a function of frequency.

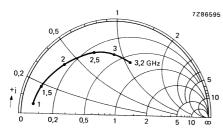


Fig. 8 Input impedance as a function of frequency for P_{L1} .

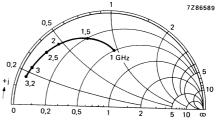


Fig. 9 Optimum load impedance as a function of frequency for $P_{l,1}$.

Conditions for Figs 5 up to 9:

 $V_{CE} = 20 \text{ V}$ $I_{C} = 65 \text{ mA}$

regulated; typical values; $Z_0 = 50 \Omega$; $T_{mb} = 25 \text{ oc.}$

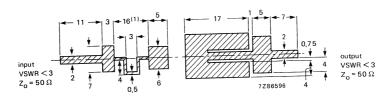
APPLICATION INFORMATION

R.F. performance in c.w. operation for the LKE32004T up to T_{mb} = 25 $^{\circ}$ C in an unneutralized common-emitter class-A circuit*

f	V _{CE} (1)	I _C (1)	P _{L1} (2)	G _{po} (3)	z _i	Z _L
GHz		mA	mW(dBm)	dB	Ω	Ω
3	20	130	≥ 630(28) typ. 710(28,5)	≥ 8 typ. 11	7,5 + j22	2,5 + j5

Notes

- 1. VCE and IC regulated.
- 2. Load power for 1 dB compressed power gain.
- 3. Low-level power gain associated with PL1.

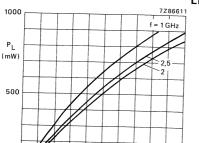


(1) Total path length.

Fig. 10 Prematching test circuit board for 3 GHz. (Dimensions in mm.)

Striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric ($\epsilon_{\rm r}$ = 2,5); thickness 0,8 mm.

* Circuit consists of prematching circuit board in combination with complementary input and output slug tuners.



50

P_S (mW)

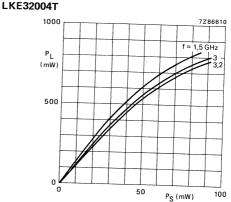


Fig. 11 Load power as a function of source power. Fig. 12 Load power as a function of source power.

100

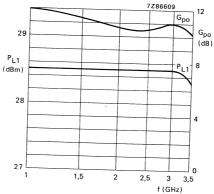


Fig. 13 Load power and power gain, associated with 1 dB compressed power gain, as a function of frequency.

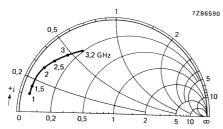


Fig. 14 Input impedance as a function of frequency for $\mbox{P}_{L1}.$

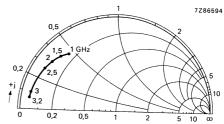


Fig. 15 Optimum load impedance as a function of frequency for $P_{L,1}$.

Conditions for Figs 11 up to 15:

$$V_{CE} = 20 \text{ V}$$

 $I_{C} = 130 \text{ mA}$

regulated; typical values; $Z_0 = 50 \Omega$; $T_{mb} = 25 \, ^{\circ}C$.

MICROWAVE LINEAR POWER TRANSISTORS

N-P-N transistors for use in a common-emitter class-A linear power amplifier up to 4,2 GHz. Diffused emitter ballasting resistors, self-aligned process entirely ion implanted and gold sandwich metallization ensure an optimum temperature profile and excellent performance and reliability. An input matching cell improves the input impedance and facilitates the design of wideband circuits.

QUICK REFERENCE DATA

R.F. performance up to T_{mb} = 25 °C in an unneutralized common-emitter class-A circuit.

type no.	mode of operation	f GHz	V _{CE} V	I _C mA	P _{L1} mW	G _{po} dB	z̄ _i Ω	Z _L Ω
LTE42005S	c.w. linear ampl.	4,2	18	110	typ.550	typ. 7,2	100 + j40	4 + j4
LTE42008R	c.w. linear ampl.	4,2	16	250	typ.940	typ. 7,5	17 + j12	3 — j9

MECHANICAL DATA

see page 2

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS—MICROWAVE SEMICONDUCTORS.

POTENTIAL HAZARD-BERYLLIUM OXIDE

This device contains beryllium oxide, the dust of which is toxic. The device is entirely safe, provided that the beryllium oxide disc is not damaged. Care should be taken to ensure that all those who may handle, use or dispose of this device are aware of its nature and of the necessary safety precautions. In particular, it should never be thrown out with general industrial or domestic waste.



LTE42005S LTE42008R

MECHANICAL DATA

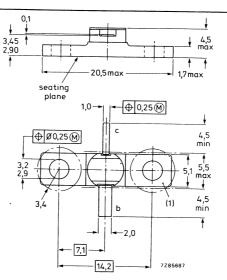
Fig. 1.

Emitter and metallic cap are connected to the seating plane.

Torque on nut: max. 0,4 Nm Recommended screw: M2,5

Marking code

RTC502 = LTE42005S RTC196 = LTE42008R



Dimensions in mm

(1) Flattness of this area ensures full thermal contact with bolt head.



From mounting base to heatsink

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Callestar base valters		LTE	42005S	LTE4	2008R	ł
Collector-base voltage (open emitter)	v_{CBO}	max.	40		40	V
Collector-emitter voltage R_{BE} = 100 Ω	V _{CER}	max.	35		_	V
$R_{BE} = 250 \Omega$	$v_{\sf CER}$	max.	_		20	٧
(open base)	V _{CEO}	max.	16		16	٧
Emitter-base voltage (open collector)	V _{EBO}	max.	3		3,5	٧
Collector current (d.c.)	IC	max.	250		450	m
Total power dissipation up to T _{mb} = 75 ^o C	P _{tot}	max.	4		6	W
Storage temperature	T_{stg}		65 to	+ 200		0
Junction temperature	T_{j}	max.	20	00		0
Lead soldering temperature at 0,3 mm from the case; t _{sld} = 10 s	T _{sld}	max.	23	35		0
THERMAL RESISTANCE		LTE	42005S	LTE4	2008F	3
From junction to mounting base	R _{th j-mb}	=	36		12	°C

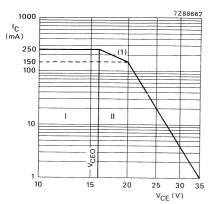
R_{th} mb-h

		_
		_

0,7 °C/W

0,7

LTE42005S



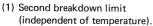


Fig. 2 D.C. SOAR at $T_{mb} \le 75$ °C.

- I Region of permissible d.c. operation.
- II Permissible extension provided $R_{BE} \le 100 \ \Omega$.

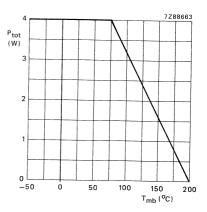
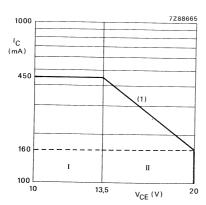


Fig. 3 Power derating curve vs. mounting base temperature.

LTE42008R



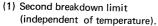


Fig. 4 D.C. SOAR at $T_{mb} \le 75$ °C.

- I Region of permissible d.c. operation.
- II Permissible extension provided RBE \leq 250 Ω .

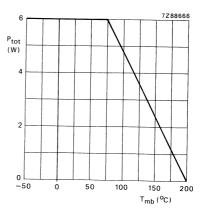


Fig. 5 Power derating curve vs. mounting base temperature.

CH	ARA	7CT	FR	IST	ICS

$T_{mb} = 25$ °C		LTE	42005S	LTE42008R
Collector cut-off current	Ісво	<	0,1	150 μA
I _E = 0; V _{CB} = 20 V I _E = 0; V _{CB} = 40 V	ICBO	<	0,25	1 mA
Emitter cut-off current	CBO		•	
I _C = 0; V _{FR} = 1,5 V	IEBO	<	200	400 nA
I _C = 0; V _{EB} = 3,5 V	IEBO	<	50	200 μΑ
D.C. current gain		>	15	_
$I_C = 110 \text{ mA}; V_{CE} = 5 \text{ V}$	hFE	> <	150	
I _C = 250 mA; V _{CF} = 5 V	hFE	> <		15
IC - 590 MA, ACE - 2 A	""	<		150
Collector-base capacitance at f = 1 MHz	C .	tun	0.5	_ pF
$I_E = I_C = 0$; $V_{CB} = 20 \text{ V}$; $V_{EB} = 1.5 \text{ V}$	C _{cb}	typ.	0,5	1
$I_E = I_C = 0$; $V_{CB} = 16 \text{ V}$; $V_{EB} = 1.5 \text{ V}$	C_{cb}	typ.	-	2 pF
Collector-emitter capacitance at f = 1 MHz	•		1.5	,,,
$I_C = I_E = 0$; $V_{CE} = 20 \text{ V}$; $V_{EB} = 1.5 \text{ V}$	C _{ce}	typ.	1,5	– pF
$I_C = I_E = 0$; $V_{CE} = 16 \text{ V}$; $V_{EB} = 1.5 \text{ V}$	C_{ce}	typ.	_	1,5 pF
Emitter-base capacitance at f = 1 MHz			C F	20.75
$I_C = I_E = 0$; $V_{EB} = 1 \text{ V}$; $V_{CB} = 10 \text{ V}$	c_{eb}	typ.	6,5	20 pF



LTE42005S

s-parameters (common-emitter)

 V_{CE} = 18 V_{CC} = 110 mA $^{\circ}$ regulated; T_{mb} = 25 $^{\circ}$ C; Z_{o} = 50 Ω ; typical values.

f GHz	sie	s _{re}	sfe	soe
				00
0,5	0,76/—176 ^o	0,022(-33,2)/370	8,13(18,2)/85 ⁰	0,35/62°
0,6	0,75/+ 180 ^o	0,023(-32,8)/370	6,95(16,8)/78 ^o	0,34/66°
0,7	0,76/+ 1770	0,023(-32,8)/40°	5,95(15,5)/730	0,34/710
0,8	0,76/+ 174 ^o	0,024(-32,5)/410	5,25(14,4)/670	0,35/-75°
0,9	0,76/+ 171 ^o	0,024(-32,3)/420	4,69(13,4)/62°	0,35/79 ⁰
1,0	0,75/+ 168 ^o	0,026(31,8)/430	4,23(12,5)/570	0,36/-830
1,1	0,75/+ 165 ⁰	0,028(31,0)/430	3,88(11,8)/53 ⁰	0,37/870
1,2	0,74/+ 163°	0,031(-30,1)/430	3,61(11,2)/49 ^o	0,39/90°
1,3	0,75/+ 160°	0,035(29,2)/430	3,36(10,5)/440	0,40/95°
1,4	0,74/+ 162 ^o	0,037(-28,5)/440	3,12(9,9)/410	0,43/-980
1,5	0,73/+ 157º	0,041(-27,8)/460	2,95(9,4)/370	0,43/-1010
1,6	0,73/+ 155 ⁰	0,045(-27,0)/460	2,83(9,0)/320	0.45/-1040
1,7	0,71/+ 154 ⁰	0,047(26,5)/440	2,70(8,6)/28 ^o	0.47/-1070
1,8	0,70/+ 151 ⁰	0,049(-26,1)/43 ^o	2,56(8,2)/23 ^o	0,48/-1100
1,9	0,69/+ 148 ⁰	0,050(25,9)/420	2,44(7,7)/190	0,50/-1140
2,0	0,68/+ 143°	0,051(25,9)/390	2,34(7,4)/ 140	0,51/-1160
2,2	0,67/+ 138 ^o	0,058(-24,7)/360	2,16(6,7)/ 49	0,55/-1240
2,4	0,65/+ 134 ^o	0,067(-23,5)/340	2,02(6,1)/ -20	0,59/1290
2,6	0,62/+ 129 ⁰	0,077(-22,3)/319	1,95(5,8)/—120	0,64/1340
2,8	0,57/+ 122 ^o	0,082(21,7)/250	1,84(5,3)/210	0,68/-138°
3,0	0,52/+ 113 ^o	0,086(-21,3)/210	1,78(5,0)/-320	0.72/-1430
3,2	0,49/+ 1040	0,093(-20,6)/160	1,67(4,5)/420	0,74/-1500
3,4	0,45/ +990	0,102(-19,8)/130	1,62(4,2)/520	0,80/-1570
3,6	0,38/ +92º	0,113(18,9)/ 80	1,52(3,6)/640	0,80/-1630
3,8	0,29/ +830	0,119(18,5)/ 60	1,43(3,1)/760	0,82/-170°
4,0	0,24/ +69º	0,137(-17,3)/ 20	1,27(2,1)/880	0,80/-1790
4,2	0,20/ +540	0,165(15,7)/50	1,08(0,7)/ —980	0,68/+1710
4,4	0,15/ +280	0,202(-13,9)/-200	0,92(-0,8)/-1000	0,51/+ 1720
4,6	0,12/ -360	0,206(-13,7)/-38°	0,93(-0,6)/-1020	0,52/-1740
4,8	0,17/860	0,195(-14,2)/-52°	0,97(-0,3)/-110°	0,63/-1710
5,0	0,24/1140	0,177(-15,0)/650	0,97(-0,3)/1220	0.73/-1740
5,2	0,31/—1370	0,164(-15,7)/-730	0,93(0,6)/-1330	0,79/180°
5,4	0,41/152 ⁰	0,154(16,2)/-830	0,88(-1,1)/-1450	0,83/+ 1740
5,6	0,48/1610	0,134(-17,4)/900	0,81(1,8)/156 ^o	0,85/+ 166 ^o
5,8	0,53/168 ^o	0,122(-18,2)/-970	0,77(-2,3)/-1670	0,87/+ 160°
6,0	0,56/—179 ^o	0,105(19,6)/—1040	0,70(-3,1)/-1780	0,89/+ 1540

The figures given between brackets are values in dB.



LTE42008R

s-parameters (common-emitter)

 V_{CE} = 16 V I_{C} = 250 mA T_{mb} regulated; T_{mb} = 25 °C; Z_{o} = 50 Ω ; typical values.

f GHz	s _{ie}	s _{re}	s _{fe}	s _{oe}
0,5	0,91/175°	0,021(33,6)/50°	4,25(12,6)/76 ⁰	0,42/177°
0,6	0,91/173°	0,024(32,5)/52°	3,59(11,1)/72 ⁰	0,42/180°
0,7	0,91/171°	0,027(31,4)/53°	3,11(9,9)/68 ⁰	0,42/+ 179°
0,8	0,90/169°	0,030(30,4)/53°	2,75(8,8)/64 ⁰	0,42/+ 178°
0,9	0,90/167°	0,033(-34,7)/54°	2,45(7,8)/59 ⁰	0,42/+ 177°
1,0	0,89/165°	0,036(-28,8)/53°	2,21(6,9)/55°	0,42/+ 176 ⁰
1,1	0,88/163°	0,039(-28,1)/54°	2,02(6,1)/53°	0,43/+ 174 ⁰
1,2	0,88/162°	0,042(-27,4)/54°	1,88(5,5)/49°	0,43/+ 174 ⁰
1,3	0,88/160°	0,046(-26,8)/53°	1,75(4,9)/46°	0,43/+ 174 ⁰
1,4	0,89/159°	0,048(-26,3)/54°	1,64(4,3)/42°	0,43/+ 173 ⁰
1,5	0,89/158°	0,054(-25,4)/57°	1,55(3,9)/40°	0,43/+ 173°
1,6	0,89/157°	0,059(-24,6)/54°	1,52(3,7)/36°	0,43/+ 172°
1,7	0,89/155°	0,063(-24,0)/52°	1,47(3,3)/32°	0,43/+ 172°
1,8	0,88/153°	0,066(-23,6)/50°	1,40(2,9)/28°	0,44/+ 171°
2,0	0,88/151°	0,076(-22,4)/49°	1,30(2,3)/22°	0,44/+ 169°
2,2	0,87/147°	0,085(-21,4)/47°	1,23(1,8)/ 15°	0,46/+ 168°
2,4	0,87/144°	0,092(-20,7)/44°	1,16(1,3)/ 8°	0,47/+ 168°
2,6	0,86/142°	0,102(-19,8)/42°	1,15(1,2)/ 2°	0,49/+ 170°
2,8	0,85/139°	0,110(-19,2)/37°	1,11(0,9)/ –7°	0,49/+ 170°
3,0	0,83/135°	0,119(-18,5)/34°	1,12(1,0)/–15°	0,50/+ 169°
3,2	0,82/129°	0,125(-18,1)/29 ⁰ 0,132(17,6)/26 ⁰ 0,138(-17,2)/21 ⁰ 0,143(-16,9)/19 ⁰ 0,148(-16,6)/13 ⁰	1,08(0,7)/—25°	0,54/+ 166°
3,4	0,81/126°		1,08(0,7)/—33°	0,57/+ 165°
3,6	0,79/122°		1,06(0,5)/—44°	0,62/+ 165°
3,8	0,76/120°		1,08(0,6)/—55°	0,65/+ 165°
4,0	0,73/117°		1,07(0,6)/—69°	0,70/+ 160°
4,2	0,69/115°	0,147(-16,7)/10°	1,04(0,4)/ -85°	0,76/+ 155°
4,4	0,67/112°	0,147(-16,6)/ 7°	1,00(0,0)/-104°	0,83/+ 149°
4,6	0,67/112°	0,140(-17,1)/ 6°	0,88(-1,1)/-122°	0,90/+ 142°
4,8	0,70/112°	0,147(-16,7)/ 9°	0,75(-2,5)/ -142°	0,93/+ 134°
5,0	0,72/114°	0,152(-16,3)/10°	0,59(-4,6)/-164°	0,92/+ 125°

The figures given between brackets are values in dB.



APPLICATION INFORMATION

R.F. performance in c.w. operation for the LTE42005S up to $T_{mb} = 25$ °C in an unneutralized common-emitter class-A circuit*

f	V _{CE} (1)	I _C (1)	P _{L1} (2)	G _{po} (3)	z _i	$\frac{\overline{Z_L}}{\Omega}$
GHz	V	mA	mW (dBm)	dB	Ω	
4,2	18	110	≥ 450(26,5) typ. 550(27,4)	≥ 6,6 typ. 7,2	100 + j40	4 + j4

Notes

- 1. VCE and IC regulated.
- 2. Load power for 1 dB compressed power gain.
- 3. Low-level power gain associated with PLI.

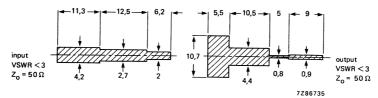


Fig. 6 Prematching test circuit board for 4,2 GHz. (Dimensions in mm.)

Input striplines on a double Cu-ciad printed-circuit board with PTFE fibre-glass dielectric ($\epsilon_{\rm r}$ = 2,54); thickness 1,6 mm.

Output striplines on a double Cu=clad Rexolite printed-circuit board with dielectric ($\epsilon_{\rm r}$ = 2,4); thickness 0,25 mm.

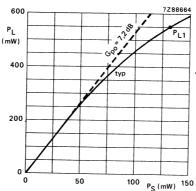


Fig. 7 Load power as a function of source power. f = 4,2 GHz; T_{mb} = 25 °C; V_{CE} = 18 V regulated regulated

* Circuit consists of prematching circuit boards in combination with complementary input and output slug tuners.



APPLICATION INFORMATION

R.F. performance in c.w. operation for the LTE42008R up to T_{mb} = 25 °C in an unneutralized common-emitter class-A circuit*.

f	V _{CE} (1)	I _C (1)	P _{L1} (2)	G _{po} (3)	z _i	<u>Z</u> L
GHz	V	mA	mW (dBm)	dB	Ω	Ω
4,2	16	250	≥ 800(29) typ. 940(29,7)	≥ 7 typ. 7,5	17 + j12	3 — j9

Notes

- 1. VCE and IC regulated.
- 2. Load power for 1 dB compressed power gain.
- 3. Low-level power gain associated with PL1.

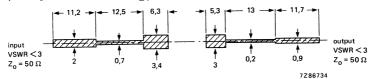


Fig. 8 Prematching test circuit board for 4,2 GHz. (Dimensions in mm.)

Input striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric (ϵ_r = 2,54); thickness 0,8 mm.

Output striplines on a double Cu-clad Rexolite printed-circuit board with dielectric (ϵ_r = 2,4); thickness 0,25 mm.

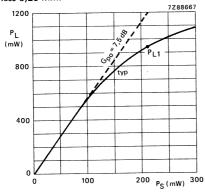


Fig. 9 Load power as a function of source power at 4,2 GHz.

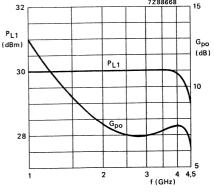


Fig. 10 Load power and power gain, associated with 1 dB compressed power gain, as a function of frequency.

Conditions for Figs 9 and 10:

$$V_{CE} = 16 \text{ V}$$
 regulated; typical values; $T_{mb} = 25 \text{ °C}$.

* Circuit consists of prematching circuit boards in combination with complementary input and output slug tuners.



LTE42008R

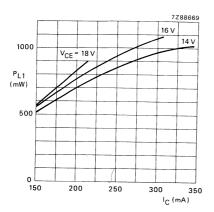


Fig. 11 Load power associated with 1 dB compressed power gain, as a function of collector current.

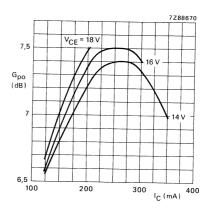


Fig. 12 Low-level power gain associated with PL1 as a function of collector current.

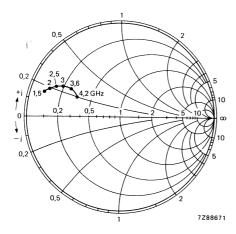


Fig. 14 Optimum load impedance as a function of frequency for P_{L1} .

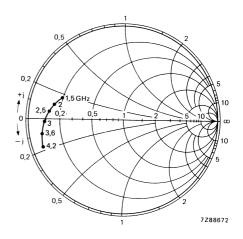


Fig. 13 Input impedance as a function of frequency for P_{L1} .

Conditions for Figs 11 and 12:

 V_{CE} and I_{C} regulated; typical values; T_{mb} = 25 ^{o}C .

Conditions for Figs 13 and 14:

$$\frac{V_{CE}}{I_{C}} = \frac{16 \text{ V}}{250 \text{ mA}}$$
 regulated; typical values; $Z_{o} = 50 \Omega$; $T_{mb} = 25 \text{ °C}$.



MICROWAVE POWER TRANSISTORS

N-P-N silicon transistors for use in space, military and professional applications.

They offer the following technological advantages:

- Interdigitated structure: high emitter efficiency.
- Diffused emitter ballasting resistors providing excellent current sharing and withstanding a high VSWR.
- Gold metallization realizes very good stability of the characteristics and excellent lifetime.
- Multicell geometry gives good balance of dissipated power and low thermal resistance.

The PEE family has an envelope with stud to be mounted with a nut and the PDE family an envelope without stud to be soldered directly onto the heatsink.

Transistors are mounted in a common-emitter configuration in class-B but they also can operate in class-A or C.

QUICK REFERENCE DATA

QUICK REFER	QUICK REFERENCE DATA								
R.F. performance up to T _{mb} = 25 °C in an unneutralized common-emitter class-B circuit									
type number	mode of operation	f GHz	V _{CE} V	P _L W	G _p dB	η %			
PEE1001U PDE1001U	c.w.	1	28	typ. 2	typ. 6,4	typ. 60			
PEE1003U PDE1003U	c.w	1	28	typ. 4,2	typ. 6,3	typ. 54			
PEE1005U PDE1005U	c.w.	1	28	typ. 7,6	typ. 5,8	typ. 58			
PEE1010U PDE1010U	c.w.	1	28	typ. 11	typ. 7,4	typ. 68			

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

see page 2

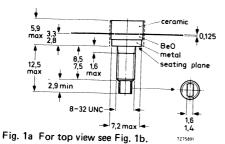
POTENTIAL HAZARD-BERYLLIUM OXIDE

This device contains beryllium oxide, the dust of which is toxic. The device is entirely safe, provided that the beryllium oxide disc is not damaged. Care should be taken to ensure that all those who may handle, use or dispose of this device are aware of its nature and of the necessary safety precautions. In particular, it should never be thrown out with general industrial or domestic waste.



MECHANICAL DATA

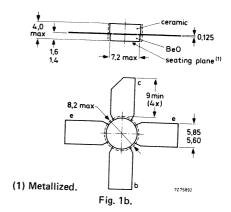
Dimensions in mm



Torque on nut: min. 0,75 Nm

max. 0,85 Nm

Diameter of clearance hole in heatsink: max. 4,2 mm.





RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Limiting values in accordance with the Ab	SOIGE Max	PEE/PDE	1001U	1003U	1005U	1010U	
O. Hanton hans voltage	1	LL/I DL	10010				NA Security .
Collector-base voltage open emitter	V _{CBO}	max.	39	39	39	45	V
Collector-emitter voltage $R_{BE} = 10 \Omega$	V _{CER}	max.	39	39	39	45	V
Emitter-base voltage open collector	V _{EBO}	max.	3,5	3,5	3,5	3,5	V
Collector current (peak value)	ICM	max.	250	450	900	1000	mΑ
	Civi						
Total power dissipation up to T _{mb} = 25 °C	P _{tot}	max.	5	7 5 to +15	12,5	20	oC M
Storage temperature	T_{stg}		0				°C
Operating junction temperature	Тj	max.		20	iU		٥,
Lead soldering temperature at 0,7 mm from ceramic; $t_{sld} \le 10 \text{ s}$	T _{sld}	max.		23	35		°C
		DEE/DDI	E1001U	1100311	1005U	1010U	
THERMAL RESISTANCE				18	10	6	oC/W
From junction to mounting base	R _{th j-mb}	max.	25	10	10		- 0/ 00
CHARACTERISTICS							
$T_{mb} = 25 {}^{\circ}C$							
Collector-base breakdown voltage open emitter; $I_C = 1 \text{ mA}$	V _(BR) CB	o > .	39				V
open emitter; I _C = 2 mA	V _(BR) CB	0 >		39			V
open emitter; I _C = 4 mA	V _(BR) CB	0 >			39		V
open emitter; I _C = 10 mA	V(BR)CB					45	V
Collector-emitter breakdown voltage	(=,==						
$R_{BE} = 10 \Omega$; $I_C = 1 \text{ mA}$	V(BR)CE		39	00			V V
$R_{BE} = 10 \Omega$; $I_C = 2 mA$	V(BR)CE			39	20		V
$R_{BE} = 10 \Omega$; $I_{C} = 4 \text{ mA}$	V _(BR) CE	$_{R}$ $>$			39	45	
$R_{BE} = 10 \Omega; I_{C} = 10 \text{ mA}$	V(BR)CE	:R >				45	V
Emitter-base breakdown voltage open collector; I _E = 0,1 mA	V _{(BR)EB}	_{3O} >	3,5				V
open collector; I _E = 0,2 mA	V(BR)EE	30 >		3,5			V
open collector; I _E = 0,4 mA	V(BR)EE				3,5		V
open collector; I _E = 0,5 mA	V(BR)EE			1		3,5	V
Collector cut-off current	(811/22	, ,					
$I_E = 0$; $V_{CB} = 30 \text{ V}$	ГСВО	<	50	100	200	1000	μΑ
Emitter cut-off current I _C = 0; V _{EB} = 2 V	¹ EBO	<	50	100	200	1000	μΑ
Collector capacitance at f = 1 MHz I _E = I _e = 0; V _{CB} = 30 V	$C_{\mathbf{c}}$	<	1,3	2	3,5	7	pF



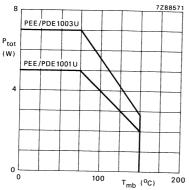


Fig. 2 Maximum permissible power dissipation as a function of mounting base temperature in class-B or C (c.w.).

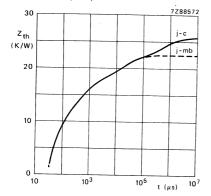


Fig. 4 Typ. transient thermal impedance as a function of time. **PEE/PDE1001U**

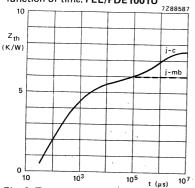


Fig. 6 Typ. transient thermal impedance as a function of time. PEE/PDE1005U

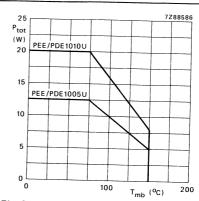


Fig. 3 Maximum permissible power dissipation as a function of mounting base temperature in class-B or C (c.w.).

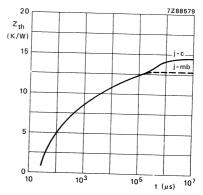


Fig. 5 Typ. transient thermal impedance as a function of time. **PEE/PDE1003U**

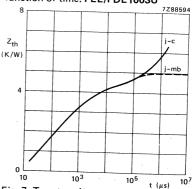


Fig. 7 Typ: transient thermal impedance as a function of time. **PEE/PDE1010U**



APPLICATION INFORMATION

R.F. performance in c.w. operation (common-emitter class-B circuit) up to T_{mb} = 25 $^{\rm o}$ C

type number	f GHz	V _{CE} V	P _L W	G _p dB	η %	$\overline{z_i}$ Ω	Z̄ _L
PEE1001U PDE1001U	1	28	> 1,5 2	> 6 typ. 6,4	> 55 typ. 60	7,5 + j13	13 + j37
PEE1003U PDE1003U	1	28	> 3,7 4,2	> 5,9 typ. 6,3	> 49 typ. 54	5 ·+ j15	10 + j20
PEE1005U PDE1005U	1	28	> 7 7,6	> 5,4 typ. 5,8	> 53 typ. 58	3 + j13	11 + j10

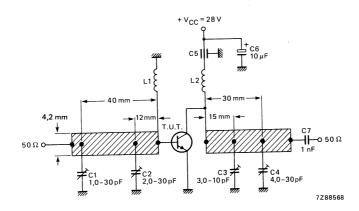


Fig. 8 1 GHz test circuit; c.w. class-B. T.U.T. = PEE/PDE1001U, PEE/PDE1003U and PEE/PDE1005U.

List of components:

C5 = 500 pF feed-through capacitor

C6 = $10 \mu F/40 V$ electrolytic capacitor

C7 = 1 nF ceramic capacitor

L1 = L2 = 5 turns enamelled Cu wire (0,3 mm); int. dia. 4,0 mm; length 10,0 mm

Striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric (ϵ_r = 2,74); thickness 1/16 in.



APPLICATION INFORMATION

R.F. performance in c.w. operation (common-emitter class-B circuit) up to T_{mb} = 25 ^{o}C

type number	f GHz	V _{CE}	P _L W	G _p dB	η %	$\overline{z_i}$ Ω	$\overline{Z_L}$
PEE1010U PDE1010U	1	28	> 9 11	> 6,5 typ. 7,4	> 60 typ. 68	2 + j1	7,5 + j18

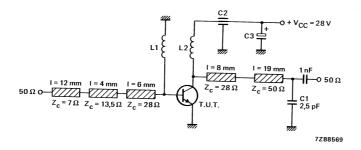


Fig. 9a 1 GHz test circuit; c.w. class-B. T.U.T. = PEE/PDE1010U.

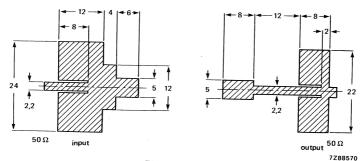


Fig. 9b Stripline dimensions.

List of components:

C1 = 2,5 pF ceramic capacitor

C2 = 500 pF feed-through capacitor

C3 = 10 μ F/40 V electrolytic capacitor

L1 = L2 = 5 turns enamelled Cu wire (0,3 mm); int. dia. 4,0 mm; length 10,0 mm

Striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric ($\epsilon_{\rm r}$ = 2,5); thickness 1/32 in.



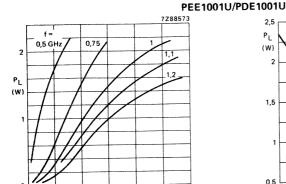
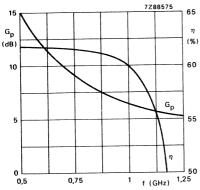


Fig. 10 Load power as a function of source power.



PS (W)

Fig. 12 Power gain and efficiency as a function of frequency.

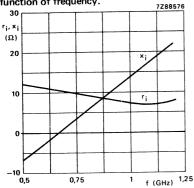


Fig. 13 Input impedance as a function of frequency. (See also Fig. 30).

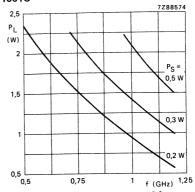


Fig. 11 Load power as a function of frequency.

Conditions for Figs 10 and 11:

V_{CE} = 28 V; T_{mb} = 25 °C; class-B operation; typical values.

Conditions for Figs 12, 13 and 14:

 $V_{CE} = 28 \text{ V; P}_{L} = 1 \text{ W; T}_{mb} = 25 \text{ }^{o}\text{C;}$

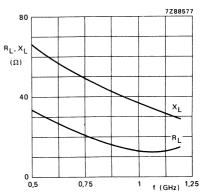


Fig. 14 Load impedance as a function of frequency. (See also Fig. 30).



PEE1003U/PDE1003U

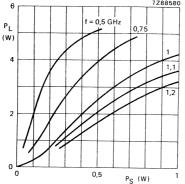


Fig. 15 Load power as a function of source power.

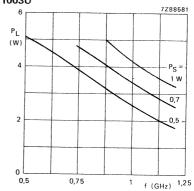


Fig. 16 Load power as a function of frequency.

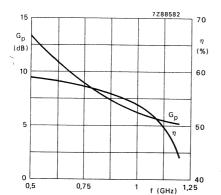


Fig. 17 Power gain and efficiency as a function of frequency.

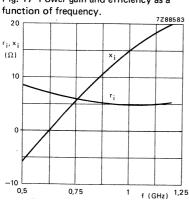


Fig. 18 Input impedance as a function of frequency. (See also Fig. 31).

Conditions for Figs 15 and 16:

$$V_{CE} = 28 \text{ V}; T_{mh} = 25 \text{ °C};$$

class-B operation; typical values.

Conditions for Figs 17, 18 and 19:

$$V_{CE} = 28 \text{ V}; P_L = 3 \text{ W}; T_{mb} = 25 \text{ }^{\circ}\text{C};$$

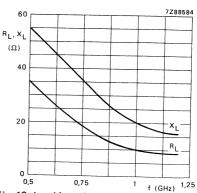


Fig. 19 Load impedance as a function of frequency. (See also Fig. 31).



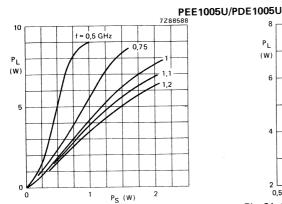


Fig. 20 Load power as a function of source power.

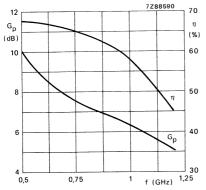


Fig. 22 Power gain and efficiency as a function of frequency.

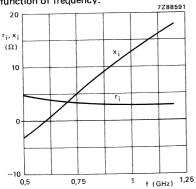


Fig. 23 Input impedance as a function of frequency. (See also Fig. 32).

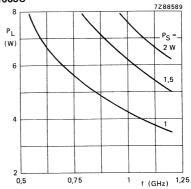


Fig. 21 Load power as a function of frequency.

Conditions for Figs 20 and 21:

 $V_{CE} = 28 \text{ V}; T_{mb} = 25 \text{ }^{\circ}\text{C};$

class-B operation; typical values.

Conditions for Figs 22, 23 and 24:

 V_{CE} = 28 V; P_L = 5 W; T_{mb} = 25 o C;

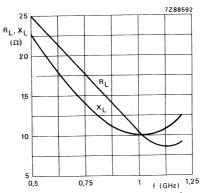


Fig. 24 Load impedance as a function of frequency. (See also Fig. 32).

PEE1010U/PDE1010U

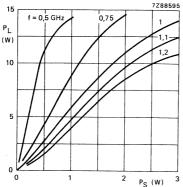


Fig. 25 Load power as a function of source power.

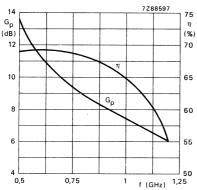


Fig. 27 Power gain and efficiency as a function of frequency.

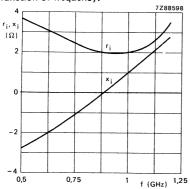


Fig. 28 Input impedance as a function of frequency. (See also Fig. 33).

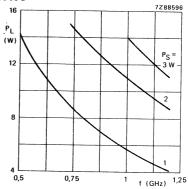


Fig. 26 Load power as a function of frequency.

Conditions for Figs 25 and 26:

 $V_{CE} = 28 \text{ V}; T_{mb} = 25 \text{ }^{\circ}\text{C};$

class-B operation; typical values.

Conditions for Figs 27, 28 and 29:

 V_{CE} = 28 V; P_L = 10 W; T_{mb} = 25 o C;

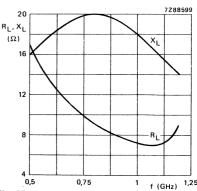


Fig. 29 Load impedance as a function of frequency. (See also Fig. 33).

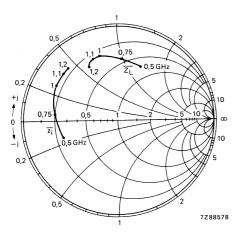


Fig. 30 Input and load impedance of PEE1001U/PDE1001U at $P_L = 1~W$.

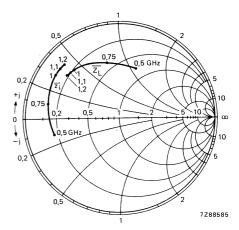


Fig. 31 Input and load impedance of PEE1003U/PDE1003U at $P_L = 3$ W.

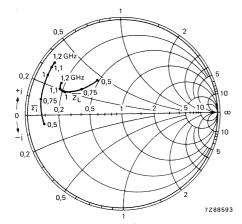


Fig. 32 Input and load impedance of PEE1005U/PDE1005U at $P_L = 5$ W.

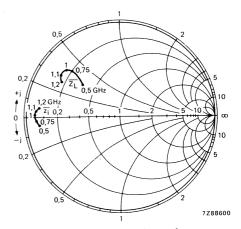


Fig. 33 Input and load impedance of PEE1010U/PDE1010U at P_L = 10 W.

Conditions for Figs 30 to 33:

 V_{CE} = 28 V; T_{mb} = 25 °C; class-B operation; typical values.

MICROWAVE POWER TRANSISTOR

N-P-N silicon transistor for use in space, military and professional applications.

It offers the following technological advantages:

- Interdigitated structure: high emitter efficiency.
- Diffused emitter ballasting resistors providing excellent current sharing and withstanding a high VSWR.
- Gold metallization realizes very good stability of the characteristics and excellent lifetime.
- Multicell geometry gives good balance of dissipated power and low thermal resistance.

QUICK REFERENCE DATA

R.F. performance up to T _{mb} = 25 °C in an unner	eutralized common-base class-C circuit
--	--

mode of operation	f	V _{CE}	PL	G _p	η	z̄ _i	Z _L
	GHz	V	W	dB	%	Ω	Ω
c.w.	1 2	28 28	typ. 25 typ. 10	typ. 11 typ. 6	typ. 58 typ. 42	2 + j6,5 7 + j6,75	5 + j1 1,5 j7

MECHANICAL DATA

see page 2

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS-MICROWAVE SEMICONDUCTORS.

POTENTIAL HAZARD-BERYLLIUM OXIDE

This device contains beryllium oxide, the dust of which is toxic. The device is entirely safe, provided that the beryllium oxide disc is not damaged. Care should be taken to ensure that all those who may handle, use or dispose of this device are aware of its nature and of the necessary safety precautions. In particular, it should never be thrown out with general industrial or domestic waste.

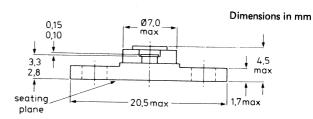


PKB20010U

MECHANICAL DATA

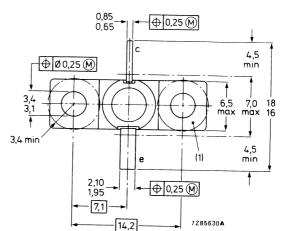
Fig. 1.

Base connected to flange



Torque on nut: max. 0,5 Nm

Recommended screw: M3



Marking code

RTC2010M = PKB20010U

(1) Flatness of this area ensures full thermal contact with bolt head.



Limiting values in accordance with the Absolute Maximum Syste	m (IEC 134)			
Collector-base voltage (open emitter)	v_{CBO}	max.	40	٧
Collector-emitter voltage (R _{RF} \leq 10 Ω)	V _{CER}	max.	40	٧
(open base)	VCEO	max.	22	V
Emitter-base voltage (open collector)	VEBO	max.	3	V
Collector current (d.c.)	Ic	max.	2	Α
Total power dissipation up to T _{mb} = 75 °C	P_{tot}	max.	25	W
Storage temperature	T_{stg}	-65 to	+ 200	οС
Junction temperature	Τj	max.	200	oC
Lead soldering temperature at 0,3 mm from the case; $t_{sld} \le 10 \text{ s}$	T _{sld}	max.	235	οС

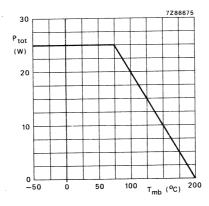


Fig. 2 Maximum permissible total power dissipation as a function of mounting base temperature.

THERMAL RESISTANCE

From junction to mounting base	R _{th j-mb}	=	4 °C/W
From mounting base to heatsink	R _{th mb-h}	=	0,7 °C/W



PKB20010U

CHAR	ACT	ER	ISTI	CS
------	-----	----	------	----

V(BB)CBO	≽	40 V
(511)050	,	10 1
V _{(BR)CER}	≥	40 V
V(BR)EBO	\geqslant	3 V
	_	
1CBO	<	100 μA
IFBO	<	1,2 μΑ
-50		.,
c_{cb}	typ.	10 pF
C _{ce}	typ.	4 pF
C _{eb}	typ.	100 pF
	V(BR)EBO ICBO IEBO Ccb Cce	V(BR)CER ≥ V(BR)EBO ≥ ICBO < IEBO < Ccb typ. Ccc typ.



APPLICATION INFORMATION

R.F. performance in c.w. operation up to T_{mb} = 25 °C in an unneutralized common-base class-C circuit*

f GHz	V _{CE}	P∟ W	G _p dB	η %	z̄ _i Ω	$\frac{\overline{Z_L}}{\Omega}$
1	28	> 20 typ. 25	> 10 typ. 11	typ. 58	2 + j6,5	5 + j1
2	28	> 8 typ. 10	> 5 typ. 6	typ. 42	7 + j6,75	1,5 — j7

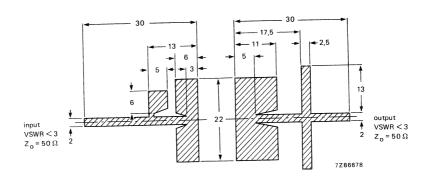


Fig. 3 Prematching test circuit board for 2 GHz. (Dimensions in mm.)

Striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric ($\epsilon_{\rm r}$ = 2,55); thickness 0,8 mm.



^{*} Circuit consists of prematching circuit board in combination with complementary input and output slug tuners.

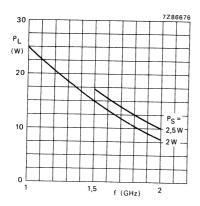


Fig. 4 Load power as a function of frequency.

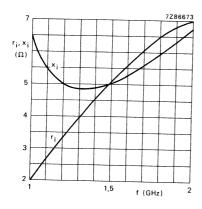
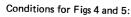


Fig. 6 Input impedance as a function of frequency.



 V_{CE} = 28 V; T_{mb} = 25 °C; typical values.

Conditions for Figs 6 and 7:

 V_{CE} = 28 V; T_{mb} = 25 °C; Z_{o} = 50 Ω ; typical values.

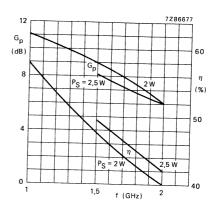


Fig. 5 Power gain and efficiency as a function of frequency.

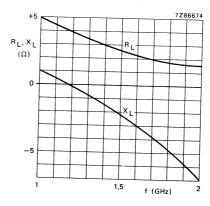


Fig. 7 Load impedance as a function of frequency.



MICROWAVE POWER TRANSISTORS

N-P-N silicon transistors for use in common-base class-B power amplifiers up to 3 GHz.

Diffused emitter ballasting resistors, interdigitated structure, multicell geometry and gold sandwich metallization ensure an optimum temperature profile and excellent performance and reliability.

QUICK REFERENCE DATA

utralized common-base class-B circuit
ι

type number	mode of operation	f GHz	V _{CE}	P _L W	G _p dB	η %	z _i Ω	Z _L Ω
PKB32001U PKB32003U PKB32005U	c.w. c.w.	3 3 3	28 28 28	typ. 1,3 typ. 3,2 typ. 5	typ. 8,1 typ. 6,3 typ. 5,2	typ. 34 typ. 33 typ. 31	11 + j1,8 14 – j4 13 + j2	3 + j3,5 2,5 - j1 2 - j4

MECHANICAL DATA

see page 2

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS—MICROWAVE SEMICONDUCTORS.

POTENTIAL HAZARD-BERYLLIUM OXIDE

This device contains beryllium oxide, the dust of which is toxic. The device is entirely safe, provided that the beryllium oxide disc is not damaged. Care should be taken to ensure that all those who may handle, use or dispose of this device are aware of its nature and of the necessary safety precautions. In particular, it should never be thrown out with general industrial or domestic waste.

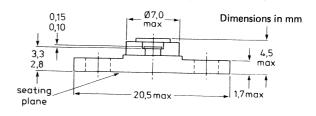


PKB32001U PKB32003U PKB32005U

MECHANICAL DATA

Fig. 1.

Base connected to flange

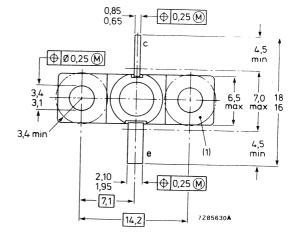


Torque on nut: max. 0,5 Nm Recommended screw: M3

Marking code

RTC3001M = PKB32001U RTC3003M = PKB32003U RTC3005M = PKB32005U

(1) Flatness of this area ensures full thermal contact with bolt head.





2

R	AT	LIL	VG	S

Limiting values in accordance with the	Absolute Maximum	System (IEC 134)
Limiting values in accordance with the	Absolute Maximum	System (IEC 134)

Littliffing values in accordance with the		PKB32	001U	32003U	32005U	
Collector-base voltage open emitter	V _{CBO}	max.	45	45	45	V
Collector-emitter voltage R_{BE} = 10 Ω	V _{CER}	max.	45	45	45	٧
Emitter-base voltage open collector	V _{EBO}	max.	3	3	3	٧
Collector current (d.c.)	IC	max.	0,4	0,8	2	Α
R.F. power dissipation (f $>$ 1 MHz) up to $T_{mb} = 75$ °C	P _{rf}	max.	4,5	9	15	w
Storage temperature	T _{stg}	max.	–65 t	o + 200		oC
Junction temperature	T_{j}	max.		200		oC .
Lead soldering temperature at 0,3 mm from ceramic; $t_{sld} \le 10 \text{ s}$	T _{sld}	max.		235		oC
THERMAL RESISTANCE	ъ.	max.	22	11	6,6	K/W
From junction to mounting base	R _{th j-mb}		0,7	0,7	0,7	K/W
From mounting base to heatsink	R _{th} mb-h	max.	0,7	0,7	1 0,,	,
CHARACTERISTICS		DKD3	200111	32003U	32005U	
Collector-base breakdown voltage			2001U 45	320030	+	• V
open emitter; I _C = 1 mA	V(BR)CBO	>	40	45	- 5	V
open emitter; I _C = 3 mA	V(BR)CBO	>		-	45	v
open emitter; I _C = 5 mA	V _(BR) CBO	≽			13	•
Collector-emitter breakdown voltage $R_{BF} = 10 \Omega$; $I_C = 5 \text{ mA}$	V _(BR) CER	≽	45	-	_	V
$R_{BE} = 10 \Omega$; $I_C = 15 \text{ mA}$	V _(BR) CER	≥		45	_	V
$R_{BE} = 10 \Omega$; $I_C = 25 \text{ mA}$	V _(BR) CER	≥	_	-	45	٧
Emitter-base breakdown voltage open collector; I _E = 1 mA	V _{(BR)EBO}	≥	3	3	3	٧
Collector cut-off current $I_E = 0$; $V_{CB} = 28 \text{ V}$	I _{CBO}	€	100	300	500	μΑ
Emitter cut-off current I _C = 0; V _{EB} = 1,5 V	^I EBO	≼	150	500	750	nA
Collector-base capacitance at $f = 1 \text{ MHz}$ $I_E = I_C = 0$; $V_{CB} = 28 \text{ V}$; $V_{EB} = 1,5 \text{ V}$	C _{cb}	typ.	2	4,5	6,2	pF
Collector-emitter capacitance at f = 1 MHz I _E = I _C = 0; V _{CB} = 28 V; V _{EB} = 1,5 V	C _{ce}	typ.	8,0	1,6	2,6	pF
Emitter-base capacitance at $f = 1 \text{ MHz}$ $I_E = I_C = 0$; $V_{EB} = 1 \text{ V}$; $V_{CB} = 10 \text{ V}$	C _{eb}	typ.	_	26	_	pF
I _E = I _C = 0; V _{EB} = 1 V; V _{CB} = 28 V	C _{eb}	typ.	12	_	43	рF
_ 0				•	•	

PKB32001U

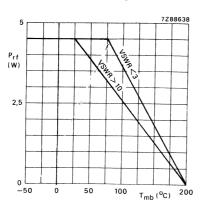


Fig. 2 Maximum permissible r.f. power dissipation as a function of mounting base temperature.

PKB32005U

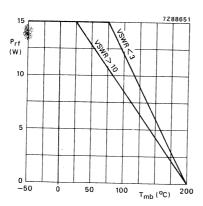


Fig. 4 Maximum permissible r.f. power dissipation as a function of mounting base temperature.

PKB32003U

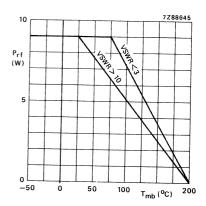


Fig. 3 Maximum permissible r.f. power dissipation as a function of mounting base temperature.

Conditions for Figs 2, 3 and 4: $V_{CB} \le 30 \text{ V}$; f > 1 MHz.



APPLICATION INFORMATION

R.F. performance up to T_{mb} = 25 $^{\rm o}{\rm C}$ in an unneutralized common-base class-B circuit*

type number	mode of operation	f GHz	V _{CE}	PL W	G _p dB	η %	$\frac{\overline{z_i}}{\Omega}$	<u>Z</u> L Ω
PKB32001U	c.w.	3	28	> 1 typ. 1,3	> 7 typ. 8,1	> 30 typ. 34	11 + j1,8	3 + j3,5
PKB32003U	c.w.	3	28	> 2,4 typ. 3,2	> 5,7 typ. 6,3	> 30 typ. 33	14 – j4	2,5 – j1
PKB32005U	c.w.	3	28	> 4,5 typ. 5	> 4,8 typ. 5,2	> 28 typ. 31	13 + j2	2 - j4

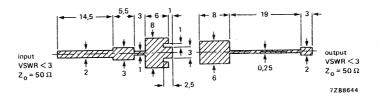


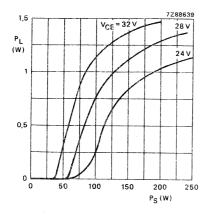
Fig. 5 Prematching test circuit boards for the PKB32003U at 3 GHz. (Dimensions in mm.)

Input striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric ($\epsilon_r = 2,54$); thickness 0,8 mm.

Output striplines on a double Cu-clad Rexolite printed-circuit board with dielectric ($\epsilon_r = 2,4$); thickness 0,25 mm.

^{*} Circuit consists of prematching circuit board in combination with complementary input and output slug tuners.

PKB32001U



1,5 P_L (W) 1 0,5 0 100 P_S (mW) 200

Fig. 6 Load power at f = 3 GHz as a function of source power with collector-emitter voltage as parameter.

Fig. 7 Load power at $V_{CE} = 28 \text{ V}$ as a function of source power with frequency as parameter.

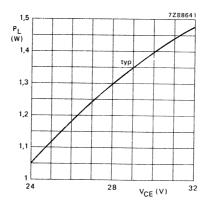
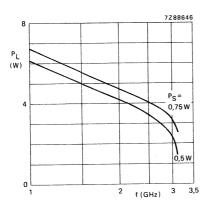


Fig. 8 Load power at f = 3 GHz and $P_S = 0.2$ W as a function of collector-emitter voltage.

Conditions for Figs 6, 7 and 8:

Class-B operation; $T_{mb} = 25$ °C; typical values.





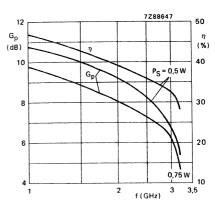


Fig. 9 Load power as a function of frequency with source power as parameter.

Fig. 10 Power gain and efficiency as a function of frequency with source power as parameter.

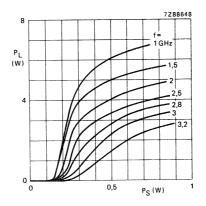


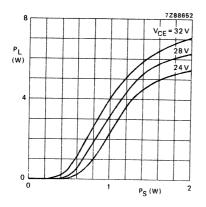
Fig. 11 Load power as a function of source power with frequency as parameter.

Conditions for Figs 9, 10 and 11:

Class-B operation; $V_{CE} = 28 \text{ V}$; $T_{mb} = 25 \text{ }^{o}\text{C}$; typical values.



PKB32005U



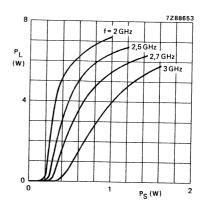


Fig. 12 Load power at f = 3 GHz as a function of source power with collector-emitter voltage as parameter.

Fig. 13 Load power at V_{CE} = 28 V as a function of source power with frequency as parameter.

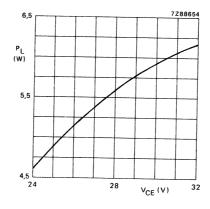


Fig. 14 Load power at f = 3 GHz and $P_S = 1,5$ W as a function of collector-emitter voltage.

Conditions for Figs 12, 13 and 14:

Class-B operation; T_{mb} = 25 °C; typical values.

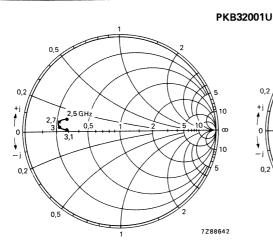


Fig. 15 Input impedance as a function of frequency.

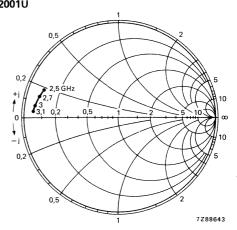


Fig. 16 Optimum load impedance as a function of frequency.

Conditions for Figs 15 and 16:

 V_{CE} = 28 V; class-B operation; T_{mb} = 25 o C; Z_{o} = 50 Ω ; typical values.

PKB32003U

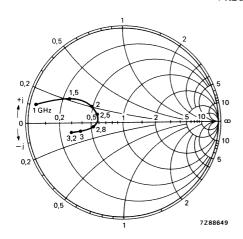


Fig. 17 Input impedance as a function of frequency.

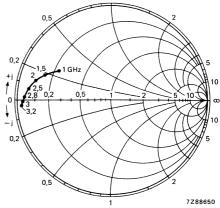


Fig. 18 Optimum load impedance as a function of frequency.

Conditions for Figs 17 and 18:

 V_{CE} = 28 V; class-B operation; T_{mb} = 25 °C; Z_{o} = 50 Ω ; typical values.

PKB32005U

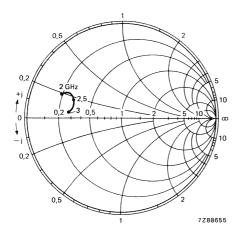


Fig. 19 Input impedance as a function of frequency.

Fig. 20 Optimum load impedance as a function of frequency.

Conditions for Figs 19 and 20:

 V_{CE} = 28 V; class-B operation; T_{mb} = 25 °C; Z_{o} = 50 Ω ; typical values.



MICROWAVE POWER TRANSISTORS

N-P-N silicon transistors for use in common-base class-B power amplifiers up to 4,2 GHz.

Diffused emitter ballasting resistors, interdigitated structure, multicell geometry, localized thick oxide auto-alignment process and gold sandwich metallization ensure an optimum temperature profile and excellent performance and reliability.

QUICK REFERENCE DATA

type	mode of operation	f	V _{CE}	P _L	G _p	η	z;	<u>Z</u>
number		GHz	V	W	dB	%	Ω	Ω
PTB42001X	c.w.	4,2	24	typ. 1,3	typ. 7,5	typ. 33	110 + j0	2 – j0,5
PTB42002X		4,2	24	typ. 2,3	typ. 7	typ. 35	36 + j58	2 – j7

MECHANICAL DATA

see page 2

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS—MICROWAVE SEMICONDUCTORS.

POTENTIAL HAZARD-BERYLLIUM OXIDE

This device contains beryllium oxide, the dust of which is toxic. The device is entirely safe, provided that the beryllium oxide disc is not damaged. Care should be taken to ensure that all those who may handle, use or dispose of this device are aware of its nature and of the necessary safety precautions. In particular, it should never be thrown out with general industrial or domestic waste.



PTB42001X PTB42002X

MECHANICAL DATA

Fig. 1.

Base and metallic cap connected to flange.

0,1 3,45 2,90 20,5 max 1,7 max seating plane ⊕ 0,25(M) 4.5 **⊕** Ø 0,25 **M** min 4,5 3,4 е mín -2,0 7Z85687A

Dimensions in mm

Torque on nut: max. 0,5 Nm

Recommended screw: M3

Marking code

RTC4001M = PTB42001X RTC4002M = PTB42002X

(1) Flatness of this area ensures full thermal contact with bolt head.



RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Collector-base voltage			PTB42001X	42002X	
open emitter	V_{CBO}	max.	40	40	٧
Collector-emitter voltage					
$R_{BE} = 10 \Omega$	VCER	max.	40	40	V
open base	VCEO	max.	15	15	V
Emitter-base voltage					
open collector	V_{EBO}	max.	3,5	3,5	V
Collector current (d.c.)	Ic	max.	0,25	0,5	Α
R.F. power dissipation (f > 1 MHz)					
up to T _{mb} = 75 °C	P_{rf}	max.	5,5	10	W
Storage temperature	T _{stg}		-65 to	0 + 200	οС
Junction temperature	Тj	max.		200	οС
Lead soldering temperature					
at 0,3 mm from ceramic; t _{sld} ≤ 10 s	T _{sld}	max.		235	οС

PTB42001X

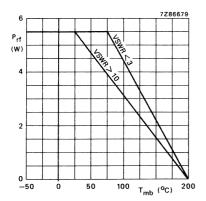


Fig. 2 Maximum permissible R.F. power dissipation as a function of mounting base temperature, f > 1 MHz.

THERMAL RESISTANCE

From junction to mounting base From mounting base to heatsink

PTB42002X

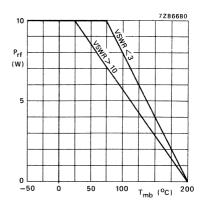


Fig. 3 Maximum permissible R.F. power dissipation as a function of mounting base temperature. f > 1 MHz.

		PTB42001X	42002X	
R _{th j-mb}	max.	22	12	°C/W
R _{th mb-h}		0,7	0,7	°C/W



PTB42001X PTB42002X

CHARACTERISTICS

Collector-base breakdown voltage			PTB42001X	42002X	
open emitter; I _C = 1 mA	V(BR)CBO	≽	40	_	V
open emitter; $I_C = 2 \text{ mA}$	V _{(BR)CBO}	≥	_	40	V
Collector-emitter breakdown voltage $R_{BE} = 10 \Omega$; $I_{C} = 10 \text{ mA}$	V _{(BR)CER}	≽	40	40	V
emitter-base breakdown voltage open collector; IE = 0,5 mA	V _{(BR)EBO}	≽	3,5		V
open collector; I _E = 1,0 mA	V(BR)EBO	≥	_	3,5	V
Collector cut-off current IE = 0; V _{CB} = 24 V	СВО	€	10	20	μΑ
Emitter cut-off current I _C = 0; V _{EB} = 1,5 V	^I EBO	€	0,2	0,4	μΑ
Collector-base capacitance at f = 1 MHz IE = IC = 0; VCB = 24 V; VEB = 1,5 V Collector-emitter capacitance at f = 1 MHz	C _{cb}	typ.	2,2	3	pF
I _E = I _C = 0; V _{CB} = 24 V; V _{EB} = 1,5 V	C _{ce}	typ.	0,3	0,6	pF

APPLICATION INFORMATION (see also page 4)

PTB42001X

1,25 PL (W) 1 0,75 0,50 0,25 0 0,2 P_S (W) 0,4

PTB42002X

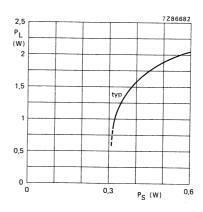


Fig. 4 Load power as a function of source power.

Fig. 5 Load power as a function of source power.

Conditions for Figs 4 and 5:

Class-B operation; V_{CE} = 24 V; f = 4,2 GHz; T_{mb} = 25 °C.



APPLICATION INFORMATION (see also page 3)

R.F. performance up to T_{mb} = 25 o C in an unneutralized common-base class-B circuit*

type number	mode of operation	f GHz	V _{CE} V	P _L W	G _p dB	η %	z̄ _i Ω	Z _L Ω
PTB42001X	c.w.	4,2	24	> 0,8 typ. 1,3	> 5 typ. 7,5	> 28 typ. 33	110 + j0	2 — j0,5
PTB42002X	c.w.	4,2	24	> 1,6 typ. 2,3	> 5 typ. 7	> 28 typ. 35	36 + j58	2 — j7

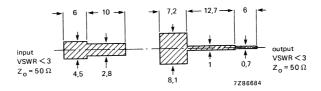


Fig. 6 Prematching test circuit boards for the PTB42001X at 4,2 GHz. (Dimensions in mm.)

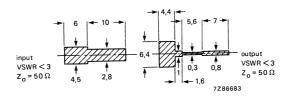


Fig. 7 Prematching test circuit boards for the PTB42002X at 4,2 GHz. (Dimensions in mm.)

Input striplines on a double Cu-clad printed-circuit board with PTFE fibre-glass dielectric (ϵ_r = 2,5); thickness 1,6 mm.

Output striplines on a double Cu-clad Rexolite printed-circuit board with dielectric (ϵ_r = 2,4); thickness 0,25 mm.

* Circuit consists of prematching circuit board in combination with complementary input and output slug tuners.



GALLIUM ARSENIDE FET TRANSISTORS



.

N-CHANNEL LOW-NOISE Ku-BAND GaAs FET

The transistor is housed in a miniature ceramic encapsulation and is specified in a low-noise amplifier circuit.

Features:

- Self-aligned process: high conformity and short gate length (0,5 μm);
- TiPtAu metallization ensures long life;
- Hermetically sealed encapsulation protects the chip to provide long term performance stability.

Also available in chip version (CFX13X).

QUICK REFERENCE DATA

Typical values in common-source configuration at T_{case} = 25 °C

. , p							
mode of operation	f GHz	V _{DS} V	I _D mA	F _{opt} dB	G _a dB	g _m * mA/V	
c.w.	10 12	3 3	10 10	2,2 2,5	8 7,5	28 28	

* Measuring conditions: --1 V < VGS < 0

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS—
MICROWAVE SEMICONDUCTORS.

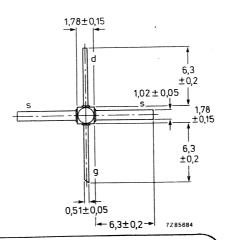
Dimensions in mm

MECHANICAL DATA

Fig. 1.

Source connected to metallized lid







RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

o maximum dystem	(140 134)		
Drain-source voltage	v_{DS}	max.	5 V
Gate-source voltage	V _{GS}	max.	6 V
Saturated drain current	DSS	max.	100 mA
Total power dissipation up to T _{case} = 115 °C	P _{tot}	max.	300 mW
Storage temperature	T _{stg}		+ 175 °C
Channel temperature	T _{ch}	max.	175 °C
Lead soldering temperature up to 0,1 mm	CH	max.	173 -0
from transistor edge; t _{sld} ≤ 8 s	T _{sld}	max.	250 °C

THERMAL RESISTANCE

From channel to case

 $R_{th ch-c} = 200 \text{ oC/W}.$

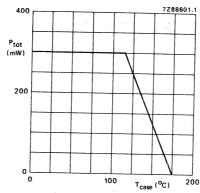


Fig. 2 Power derating curve as a function of case temperature.

CHARACTERISTICS

T_{amb} = 25 °C Gate-source cut-off current

 $V_{DS} = 3 \text{ V}; I_D = 200 \,\mu\text{A}$

Saturated drain current

 $V_{DS} = 3 V; V_{GS} = 0$

Pinch-off voltage

 $V_{DS} = 3 \text{ V; } I_D = 200 \,\mu\text{A}$

Mutual transconductance

 $V_{DS} = 3 V$; --1 $V < V_{GS} < 0$

Maximum available gain

 $V_{DS} = 3 V$; $I_D = 35 \text{ mA}$; f = 10 GHz

 $V_{DS} = 3 V; I_D = 35 mA; f = 12 GHz$

¹G typ. 1 μA 5 μA

DSS 35 to 100 mA

DSS 35 to 100 m/

-V_{(P)GS} typ. 3 V 1,5 to 4 V

g_m > 25 mA/V typ. 28 mA/V

G_{AM} typ. 10,5 dB

G_{AM} typ. 9,0 dB

s-parameters (common source)

Typical values; V_{DS} = 3 V; I_{D} = 10 mA; T_{amb} = 25 °C; Z_{o} = 50 Ω

f GHz	sis	s _{rs}	sfs	s _{OS}
6	0,91/-102°	0,027(-31,5)/27°	1,16(1,26)/81° 1,08(0,67)/68° 1,05(0,45)/57° 1,04(0,36)/44° 1 (0)/31° 0,94(-0,58)/20° 0,87(-1,19)/12°	0,75/ -71°
7	0,89/-113°	0,025(-31,9)/28°		0,75/ -81°
8	0,88/-123°	0,025(-32,1)/32°		0,76/ -90°
9	0,86/-136°	0,026(-31,8)/38°		0,76/-100°
10	0,85/-151°	0,028(-31,2)/46°		0,77/-108°
11	0,83/+160°	0,031(-30,1)/57°		0,77/-114°
12	0,82/+165°	0,036(-28,9)/69°		0,77/-117°

The figures given between brackets are values in dB.

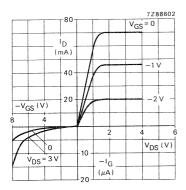


Fig. 3 Drain current as a function of drain-source voltage and gate cut-off current as a function of gate-source voltage. Typical values; $T_{\mbox{case}} = 25$ °C.

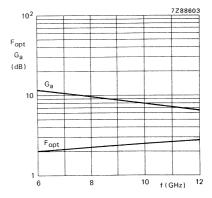


Fig. 4 Noise and associated gain as a function of frequency. Typical values; $V_{DS} = 3 \text{ V}$; $I_D = 10 \text{ mA}$.

APPLICATION INFORMATION

Low-noise amplifier (common-source) at T_{case} = 25 °C

mode of operation	f GHz	V _{DS} V	I _D mA	F _{opt} dB	G _a dB	
c.w.	12	3	10	< 3,0	>6,5	

Linear amplifier (common-source) at T_{case} = 25 °C

mode of operation	f	V _{DS}	I _D	P _{L1}	G _{po}
	GHz	V	mA	mW	dB
c.w.	10	3	35	>10	typ. 10



Conditions for Figs 5 and 6:

 V_{DS} = 3 V; I_{D} = 10 mA; T_{case} = 25 °C.

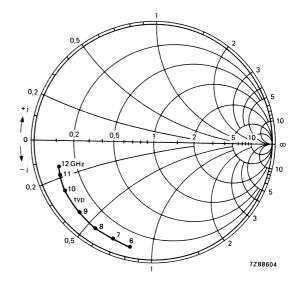


Fig. 5 Input impedance derived from input reflection coefficient s_{is} co-ordinates in ohm \times 50.



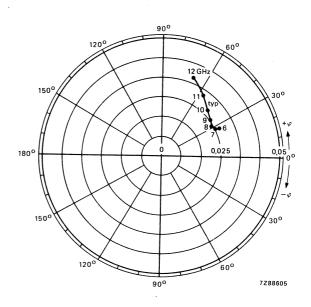


Fig. 6 Reverse transmission coefficient \mathbf{s}_{rs} .

Conditions for Figs 7 and 8:

 $V_{DS} = 3 V; I_{D} = 10 mA;$ $T_{case} = 25 °C.$

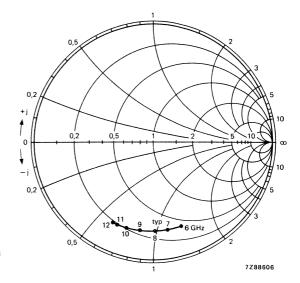


Fig. 7 Output impedance derived from output reflection coefficient $s_{\mbox{\scriptsize os}}$ co-ordinates in ohm x 50.

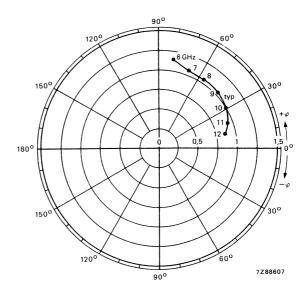


Fig. 8 Forward transmission coefficient s_{fs}.



N-CHANNEL LOW-POWER X-BAND GaAs FET

The transistor is housed in a miniature ceramic encapsulation and is specified in a linear amplifier circuit.

Features:

- \bullet Self-aligned process: high conformity and short gate length (0,8 μ m);
- TiPtAu metallization ensures long life;
- Hermetically sealed encapsulation protects the chip to provide high temperature stability.

Also available in chip version (CFX21X).

QUICK REFERENCE DATA

Typical values in con	nmon-source	configuration a	t T _{case} = 25	oC			
mode of operation	f GHz	V _{DS}	I _D mA	P _{L1} mW	G _{po} dB	g _m * mA/V	
c.w.	8	6	40 40	80 65	10 7,5	23 23	

* Measuring conditions: $V_{DS} = 3 V$; --1 $V < V_{GS} < 0$

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS—MICROWAVE SEMICONDUCTORS.

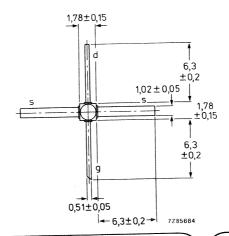
MECHANICAL DATA

Dimensions in mm

Fig. 1.

Source connected to metallized lid.







RATINGS

Limiting values in accordance with the Absolute Maximum System	(IEC 134)		
Drain-source voltage	V_{DS}	max.	8 V
Gate-source voltage	V _{GS}	max.	6 V
Saturated drain current	IDSS	max.	110 mA
Total power dissipation up to $T_{case} = 75 {}^{\circ}\text{C}$	P _{tot}	max.	500 mW
Storage temperature	T _{stq}	65 to	+ 175 °C
Channel temperature	T _{ch}	max.	175 °C
Lead soldering temperature up to 0,1 mm	•		
from transistor edge; $t_{sld} \le 8 s$	T_{sld}	max.	250 °C
THERMAL RESISTANCE			
From channel to case	R _{th ch-c}	=	200 °C/W

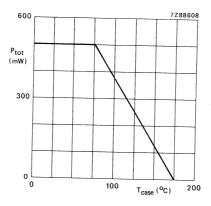


Fig. 2 Power derating curve as a function of case temperature.

CHARACTERISTICS

T_{case} = 25 °C Saturated drain current $V_{DS} = 3 V; V_{GS} = 0$ Pinch-off voltage $V_{DS} = 3 \text{ V}; I_{D} = 200 \,\mu\text{A}$ Mutual transconductance $V_{DS} = 3 V; -1 V < V_{GS} < 0$

IDSS 50 to 110 mA -V_{(P)GS} 1,5 to 5 V > 20 mA/V $g_{\mathbf{m}}$

200 °C/W.

s-parameters (common source)

Typical values; V_{DS} = 6 V; I_{D} = 40 mA; T_{amb} = 25 °C; Z_{o} = 50 Ω

f GHz	s _{is}	s _{rs}	sfs	s _{os}
6 7 8 9 10 11	0,87/119 ⁰ 0,85/132 ⁰ 0,82/146 ⁰ 0,81/162 ⁰ 0,80/177 ⁰ 0,78/+ 175 ⁰ 0,76/+ 171 ⁰	0,010(40,4)/63° 0,012(38,3)/79° 0,018(34,8)/89° 0,028(31,1)/91° 0,038(28,4)/89° 0,051(25,9)/87° 0,065(23,8)/88°	1,18(1,44)/68° 1,08(0,66)/54° 1,02(0,15)/40° 0,96(-0,35)/26° 0,88(-1,12)/12° 0,80(-1,97)/ 2° 0,73(-2,73)/-5°	0,86/69° 0,87/79° 0,87/89° 0,88/ -98° 0,90/107° 0,91/111° 0,92/113°

The figures given between brackets are values in dB.

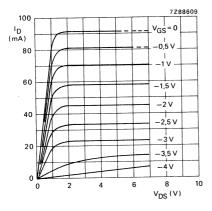


Fig. 3 Typical values; $T_{case} = 25$ °C.

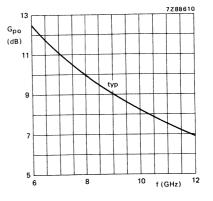


Fig. 4 Linear gain as a function of frequency. $V_{DS} = 6 \text{ V}$; $I_D = 40 \text{ mA}$.

APPLICATION INFORMATION

Linear amplifier (common-source) at T_{case} = 25 °C

mode of operation	f GHz	V _{DS} V	I _D mA	P _{L1} mW	G _{po} dB	g _m mA/V	
c.w.	11	6	40	> 50	> 7	> 20	

Low-noise amplifier (common-source) at T_{case} = 25 °C

mode of operation	f GHz	V _{DS}	I _D mA	F dB	G _a dB
c.w.	10	3	10	typ. 3,5	typ. 7



Conditions for Figs 5 and 6:

 V_{DS} = 6 V; I_D = 40 mA; T_{case} = 25 °C.

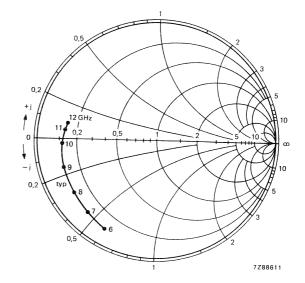


Fig. 5 Input impedance derived from input reflection coefficient s_{iS} co-ordinates in ohm \times 50.

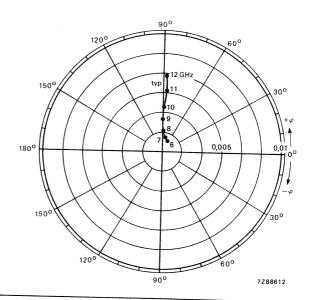


Fig. 6 Reverse transmission coefficient \mathbf{s}_{rs} .



Conditions for Figs 7 and 8:

 $V_{DS} = 6 \text{ V}; I_{D} = 40 \text{ mA};$ $T_{case} = 25 \text{ °C}.$

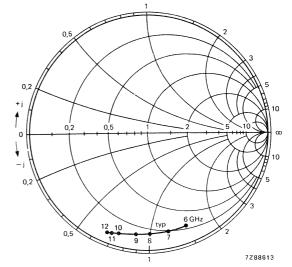


Fig. 7 Output impedance derived from output reflection coefficient s_{os} co-ordinates in ohm \times 50.

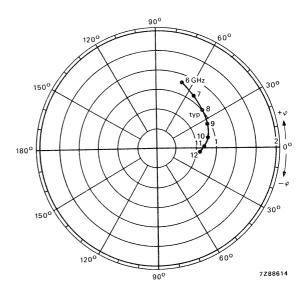


Fig. 8 Forward transmission coefficient s_{fs}.



OSCILLATORS





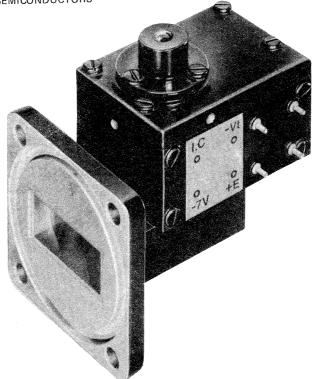
X-BAND GUNN OSCILLATOR

Solid state oscillator featuring wide electronic tuning range. Designed for applications in local oscillators employing a.f.c. systems.

QUICK REFERENCE DATA

QUICK HEI ENERGE BATTA			
		9.4	GHz
Centre frequency	min.	200	MHz
Electronic tuning range		± 50	MHz
Mechanical tuning range	min.		
Supply voltage		-7.0	V
Power output	typ.	5.0	mW
·	V	VG.16/WR.90	0
Output connector			

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

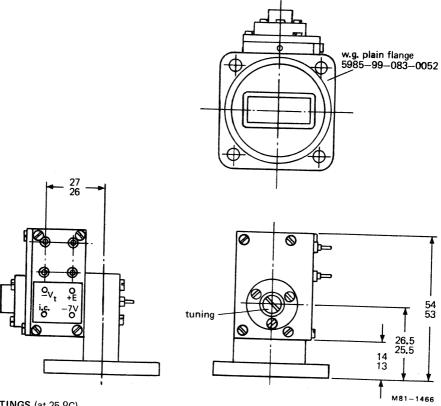




1

™ MECHANICAL DATA

Dimensions in mm





RATINGS (at 25 °C)

Limiting values in accordance with the Absolute Maximum System (IEC134)

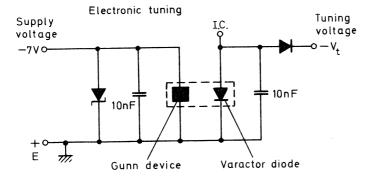
	, , , , , , , , , , , , , , , , , , , ,		
Operating temperature range Supply voltage	-30	0 to +70	оС
Gunn current, operating	max.	-8.0	V
starting	max.	200	mΑ
Tuning voltage	max.	250	mΑ
Tuning current	max.	-12	V
Load v.s.w.r.	max.	2.0	mA
	max.	1.5:1	

OPERATING CONDITIONS (typical)				
Supply voltage (note 1)			-7.0	V
Supply current			140	mA
Tuning voltage range		0	to -10	V
Tuning current			1.0	mA
CHARACTERISTICS at 25 °C				
Centre frequency			9.4	GHz
	min.	typ.	max.	
Electronic tuning range	200	250		MHz
Mechanical tuning range	± 50	_	_	MHz
Power output (note 2)	3.0	5.0	_	mW
Variation in power output over electronic tuning range	_	1.5		dB
Electronic tuning sensitivity	_	25	_	MHz/V
Frequency temperature coefficient		-1.0	_	MHz/ ^O C
Frequency pushing	_	30	_	MHz/V

Notes

- The oscillator circuit provides some protection against forward transients greater than -8V but care should be taken to avoid such transients as far as possible.
- 2. Power output min. is measured under all conditions of tuning.

ELECTRONIC TUNING



D6579





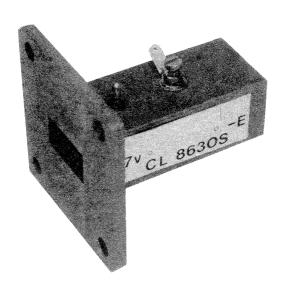
X-BAND GUNN OSCILLATORS

This is a series of Gunn oscillators with fixed frequencies in X-band. Applications include all forms of miniature radar systems. A suffix S indicates that the device operates as a self-oscillating mixer (auto detector).

QUICK REFERENCE DATA

9.35 9.47		V
typ. typ. 35-99-083-0052	8.0 0.25	mW MHz/°C
	GHz 10.68 9.35 9.47 10.52	10.525 +7.0 typ. 8.0 typ0.25

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — ${\tt MICROWAVE}$ SEMICONDUCTORS



RATINGS (at 25 °C)

Limiting values in accordance with the Absolute Maximum System (IEC134)

Cupply waltage (d.)				
Supply voltage (d.c.)		max.	+7.5	V
Supply voltage (for less than 1 ms)		max.	+9.0	V
Supply current, threshold		max.	200	mA
Supply current, operating		max.	160	mA
Temperature range			0 to +40	°C
CHARACTERISTICS				
D	min.	typ.	max.	
Power output (at 7.0 V)	5.0	10.0	_	mW
Frequency temperature coefficient	_	0.25	-0.4	MHz/°C
Second harmonic	_	-35		dBm
Threshold current	_	_	225	mA
Gunn operating current		120	160	mA
Frequency pushing		4.0		MHz/V
Frequency (fixed)				WIT 12/ V
CL8630, CL8630S CL8631, CL8631S CL8632, CL8632S CL8633, CL8633S	10.675 9.338 9.458 10.513	10.687 9.350 9.470 10.525	10.699 9.362 9.482 10.537	GHz GHz GHz GHz
A.M. noise to carrier ratio (1 Hz to 1 kHz bandwidth) CL8630 to CL8633	_	94	_	dB
Output voltage for input 66 dB down on output power (at 12 dB min. signal + noise)				GD.
CL8630S to CL8633S	80	120	-	μV

OPERATING NOTES (4 and 5 apply only to CL8630 to CL8633 and notes 6, 7 and 8 only to CL8630S to CL8633S).

- The active element will be damaged if the supply voltage is reversed. Care should be taken to avoid transients in excess of 9 volts. An 8.2 V 5% voltage regulator diode to shunt the power supply is recommended for this purpose.
- 2. The minimum supply voltage is 6.5 V for the frequency of oscillation to remain within the characteristic limits.
- It is recommended that a small capacitor (e.g. 10 nF) is connected across the oscillator terminals to suppress low frequency oscillation which may occur in the power supply.
- 4. When used in a Doppler radar system, modulation of the oscillator supply voltage within the 1 Hz to 1 kHz band will degrade the a.m. signal to noise ratio at the output of the associated mixer, as a result of direct conversion by the Gunn device to both a.m. and f.m. noise components. The a.m. component will contribute directly and the f.m. component may contribute from demodulation by the slope of the bandpass characteristic of the the mixer. The f.m. component may be demodulated by the non-linear response characteristic of the associated detecting element.

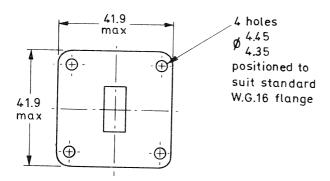
- 5. Second harmonic level is measured into a W.G.16 load with a v.s.w.r. <1.1:1 at fundamental frequency. The level is equivalent to that radiated from a low v.s.w.r. X-band antenna, for example, our ACX—01A.
- 6. A return signal 66 dB down on radiated power will be achieved from a man target of radar cross-section $1.0\ m^2$ at a range of $12\ m$, when operating with an antenna gain of $20\ dB$.
- 7. System bandwidth 1 Hz to 1 kHz.
- 8. Power supply ripple in the amplifier passband will degrade the signal to noise performance.

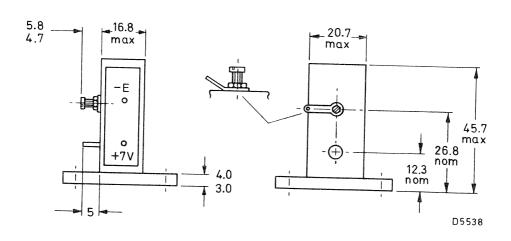
MECHANICAL DATA

Dimensions in mm

CL8630S

CL8633 CL8633S



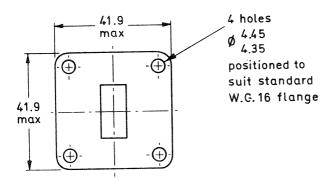


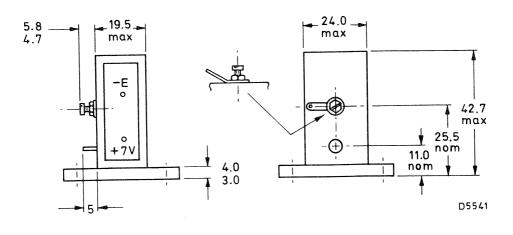
CL8630 SERIES

MECHANICAL DATA

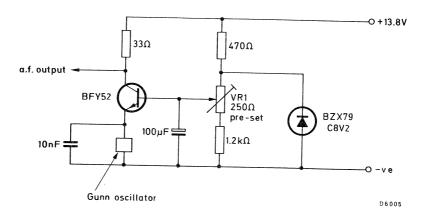
CL8631

CL8631S CL8632 CL8632S Dimensions in mm









 $\ensuremath{\text{VR}}_1$ is used to set voltage at 7.0 V across Gunn oscillator.

Circuit used for sensitivity measurement (self-oscillating versions only).



The issue of the information contained in this publication does not imply any authority or licence for the utilisation of any patented feature.

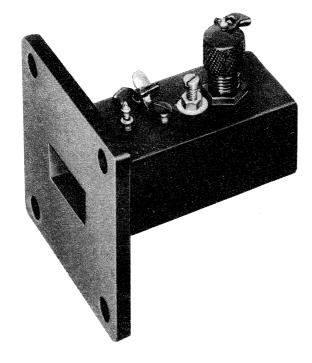
X-BAND GUNN OSCILLATORS

Mechanically and electronically tuned Gunn-effect oscillators in the 10.5 GHz band. The high Q cavity offers frequency stability compatible with application as the transmitter (CL8640T) and receiver local oscillator (CL8640R) in short range data link systems.

QUICK REFERENCE DATA

		CL8640R	CL8640T		
Centre frequency		10.49	10.56	GHz	
Mechanical tuning range	min.	120	120	MHz	
Electronic tuning range	min.	30	8.0	MHz	
Power output	typ.	6.0	6.0	mW	
Operating voltage		-7.0	7.0	V	
Output via square plain flange WG.16. WR.90. 5985-9	9-083-0052				

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS





---- RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

					CL864	0R	CL8640T	-
	Storage temperature rar			T_{stg}	-30 to +1	100	-30 to +10	o oc
	Operating temperature	range		T _{amb}	-15 to $+7$	7 0	-15 to +70	οС
	Supply voltage				max.		-7.2	V
	Supply voltage (transien	it)			max.		-8.0	V
	Tuning voltage				max.		-12	V
	Tuning current				max.		100	μΑ
	Load v.s.w.r.				max.		1.5:1	
	TYPICAL OPERATING	CONDITIO	ONS					
	Supply voltage (note 1)						-7.0	V
	Starting current						250	•
	Gunn operating current						170	mA
	Tuning voltage range (me	odulation)	(note 2)	CL8640)B	-0.5 to		mA
		·	. –,	CL8640		-0.5 to		V V
-	CHARACTERISTICS (T	amb = 25 ⁰	(C)					•
	Centre frequency		(tuning volt	age -2 5	5V)	1	0.49	GHz
		CL8640T	(tuning volt	tage —1.0	OV)		0.56	GHZ
					min.	typ.	max.	
	Mechanical tuning range				±60	_		MHz
	Electronic tuning range	CL8640R			±15		_	MHz
	(note 2)	CL8640T			±4.0		-	MHz
	Power output at -7.0 V				4.0	6.0		mW
	Gunn operating current				_	170	180	mA
	Frequency pushing				-	3.0		MHz/V
	Frequency pulling (note 3					1.5	_	MHz
	Frequency temperature c	oefficient			-	-0.25	-0.3	MHz/°C
	Tuning current					_	10	μΑ
	Mada							•

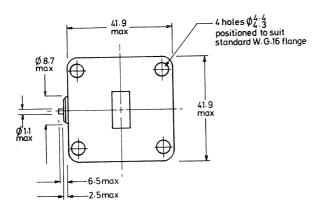
Notes

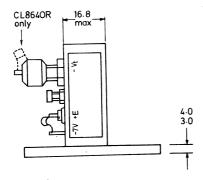
- The Gunn device will be damaged if the supply voltage is reversed. Care should be taken to avoid transients in the supply voltage.
- The electronic tuning provided by the varactor diode circuit is non-linear, following an approximately exponential rate of change of capacitance at low tuning voltages.
- 3. V.S.W.R. = 1.5:1

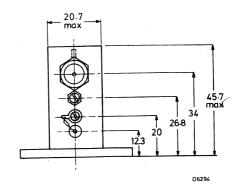


MECHANICAL DATA

Dimensions in mm











X-BAND GUNN OSCILLATOR

This is an electronically and mechanically tuned oscillator suitable for use as a solid state replacement for reflex klystrons. It may be used as a local oscillator in marine radar systems. The device has been tested to ensure its compliance with the requirements of Board of Trade specification BOT SBN 115 10057/1.

OUICK REFERENCE DATA

O LOUIS REFERENCE DATA		WG16		
Output connector		9.375	GHz	
Centre frequency				
Mechanical tuning range	min.	±75	MHz	
Electronic tuning range	min.	±25	MHz	
Power output	min.	5	mW	
Operating voltage		-7.5	V	

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS





TYPICAL OPERATING CONDITIONS

Supply voltage d.c. (note 1)	-7.5	V
Gunn operating current	160	mΑ
Tuning voltage range (notes 1 and 2)	−1 to −12	V
Tuning current	10	μΑ

→ LIMITING VALUES at 20 °C

In accordance with the Absolute Maximum System (IEC134)

Supply voltage	max.	-8	V
Supply voltage (for less than 1 ms)	max.	-9	V
Tuning voltage	max.	-15	V
Tuning current	max.	100	μА
Storage temperature range	-4	5 to +85	οС
Ambient operating temperature range	-1	5 to +50	οС

CHARACTERISTICS at 20 °C

Centre frequency (note 4) 9.375 GHz

	min.	typ.	max.	
Mechanical tuning range	±75	±100		MHz
Electronic tuning range	±25	±30		MHz
Power output (note 5)	5	8	_	mW
Gunn operating current (note 3)	_	160	200	mA
Frequency deviation over temperature range		±15	±25	MHz
Frequency pushing		10	15	MHz/V
Frequency pulling (note 6)	_		20	MHz
Mechanical tuning rate	_	-	250	MHz/turn

Notes

- The Gunn diode will be damaged if the supply voltage is reversed. In addition, care should be taken to avoid transients in the supply voltage as far as possible.
- 2. The tuning supply voltage should have a source impedance of less than 1 k Ω .
- 3. During the switch-on period, the Gunn diode current will rise to a peak of up to 300 mA at approximately -4 V and then fall to the specified operating current at -7.5 V.
- The centre frequency is measured with supply voltages of −7.5 V to the Gunn device and −5 V to the varactor diode.
- 5. Power output is measured under all conditions of tuning and temperature.
- 6. The load v.s.w.r. is 1.3 max. Frequency pulling is measured over all phases of mismatch.

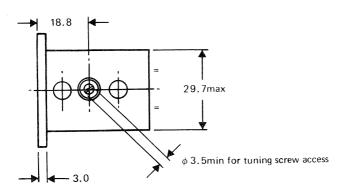


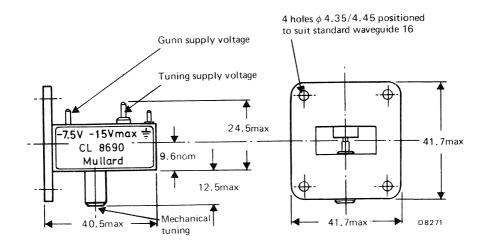
APPLICATION NOTES

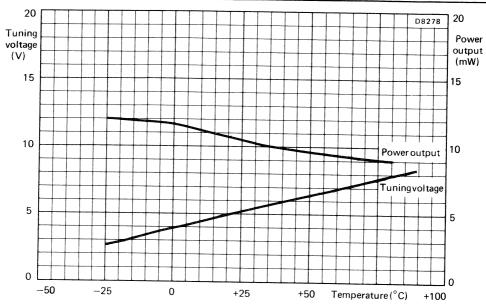
- 1. Three solder pins are provided for connection of the supply voltages and the earth contact.
- 2. To prevent parasitic low frequency oscillation, a 1 μF capacitor is connected across the Gunn device.
- 3. The centre frequency may be set within the limits given in the characteristics, by turning the screw.
- 4. A 8.2 V \pm 5% zener diode should be connected across the Gunn device supply for transient protection.

MECHANICAL DATA

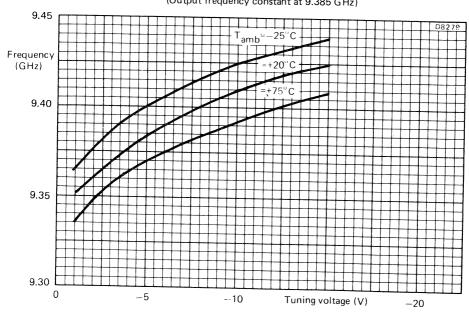
Dimensions in mm



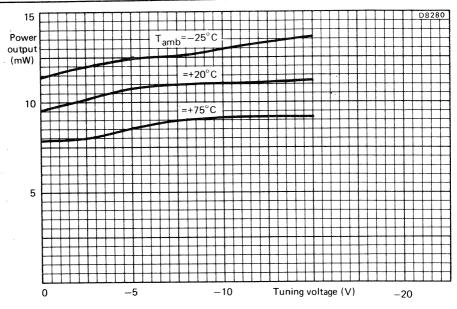




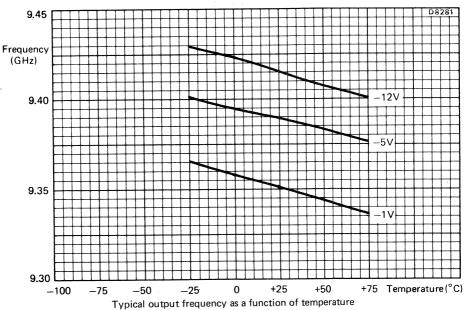
Typical power output and tuning voltage as a function of temperature. (Output frequency constant at 9.385 GHz)



Typical output frequency as a function of tuning voltage at three ambient temperatures

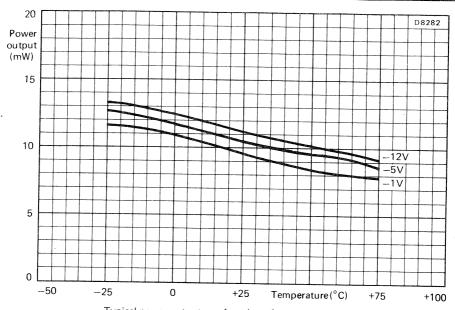


Typical power output as a function of tuning voltage at three ambient temperatures



Typical output frequency as a function of temperature at three tuning voltages.





Typical power output as a function of temperature at three tuning voltages



LOW NOISE STABLE IMPATT OSCILLATOR

Direct generating low noise stable oscillator specially designed for 11 GHz microwave link transmitters and receivers and similar equipment. It consists of a temperature compensated high Q transmission cavity to which an IMPATT diode is coupled via a coaxial circuit. The cavity is hermetically sealed and filled with dry nitrogen. Mechanical tuning facilities for frequency adjustment and power optimization are built in.

QUICK REFERENCE DATA

Frequency band	10,7 to 11,2 GHz, type JS100 11,2 to 11,7 GHz, type JS100
Mechanical tuning range	500 MHz
Stability $\frac{\Delta f}{f}$	better than ± 5 · 10 ⁻⁷ /°C
F.M. noise	< 1,2 Hz in a 100 Hz band
Output power	max. 125 mW

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS -MICROWAVE SEMICONDUCTORS

OPERATING CONDITIONS

+80 V (d.c.) max. Supply voltage 35 mA min. Supply current 65 mA max. Current stabilized power supply required.

-30 to +60 °C Ambient operating temperature 0 to 95 % Ambient humidity

CHARACTERISTICS at 25 $^{\circ}$ C and I_d = 55 mA

10,7 to 11,2 GHz, type JS1001 Frequency band 11,2 to 11,7 GHz, type JS1002 500 MHz Mechanical tuning range Frequency stability $\frac{\Delta f}{f}$ better than ± 5·10⁻⁷/°C

Frequency pushing $\frac{\Delta f}{\Delta Id}$ 10 kHz/mA max.

10 kHz max. Frequency pulling Δf

(measured with output isolator into output mismatch with V.S.W.R. of 1,5)



Harmonic level	<-50	dBc *
Spurious signal	<-70	dBc

F.M. noise $\Delta f_{r.m.s.}$ at 100 kHz off carrier <1,2 Hz in a 100 Hz band

A.M. noise $\frac{P_{AM}}{P_{carrier}}$ <-115 dB

P out to be adjusted by varying diode current (see curve) up to max. 125 mW

Ordering information

Type	Catalogue number
JS1001	9360 019 10112
JS1002	9360 019 20112

MECHANICAL DATA

Dimensions in mm

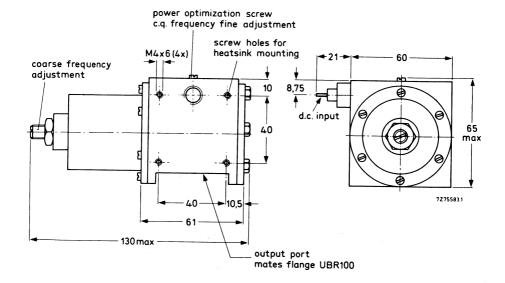


Fig. 1 Stable IMPATT oscillator.



^{*} Measured without coaxial line between oscillator output and analyser. When a coaxial line is used between the oscillator and the analyser these values will be greatly reduced.

COAXIAL OUTPUT ADAPTOR, type 2722 162 02841

Consists of a waveguide to coax SMA female transition with built in isolator.

10.7 to 11.7	GHz
> 25	dB
< 0,4	dB
< 1.05	
•	
< 1,2	
2	W
10 to ±70	oC.
=10 to 170	
	< 1,05 < 1,2

Mechanical data of adaptor

Material
Mating flange type
Connector type
Dimensions

brass and aluminium IEC-UBR 100 SMA female 50 see Fig. 2.

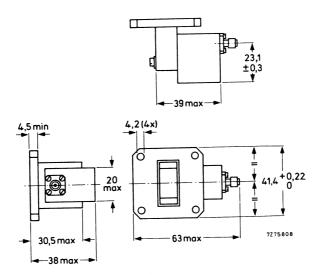


Fig.2 Coaxial output adaptor.

OPERATING NOTES

- 1. Positive voltage must be applied to the soldering pin; otherwise the active element will be damaged.
- 2. To adjust output power level at a particular frequency, bias current is increased from the start oscillation value (approximately 30 mA) until the required output power is obtained roughly. With the small screw, see Fig. 1, the output power is then maximized, after which bias current can be accurately set for the desired power.
- 3. Accurate setting of the desired frequency is obtained by adjusting and locking the main tuning screw as well as possible. The power optimization screw is now slightly detuned from its position obtained in 2 to afford the residual fine tuning of frequency. Generally the associated output power degradation is then very small, see Fig. 3. If necessary, the procedures 2 and 3 can be repeated.

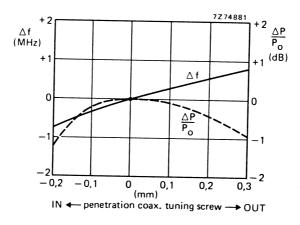


Fig. 3 Fine tuning Δf and associated power variation as a function of the coaxial tuning screw position at constant cavity tuning I_d = 55 mA; P_0 = 110 mW; f = (11 000 + Δf) MHz.

4. It is recommended that a filter be connected across the oscillator supply voltage terminal, see Fig. 4, to suppress low frequency oscillations which may occur in the power supply.

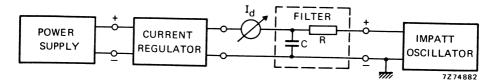


Fig. 4 Bias configuration for stable IMPATT oscillator. R = 82 Ω (carbon resistor, 1 W), C = 220 nF (film capacitor 160 V). Power supply: 110 V, 100 mA.



TYPICAL PERFORMANCE CURVES

The performance of JS1002 is similar to that of JS1001.

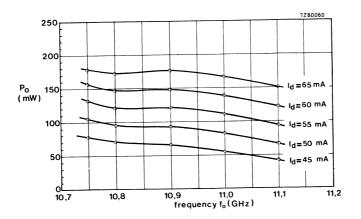


Fig. 5 Output power as a function of frequency for the IMPATT oscillator with diode current $I_{\mbox{\scriptsize d}}$ as a parameter.

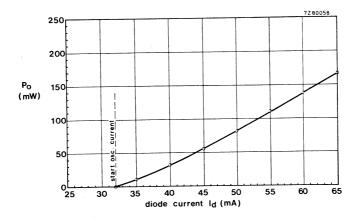


Fig. 6 Output power of the IMPATT oscillator, measured as a function of th diode current I_{d} at f_{0} = 11 GHz.



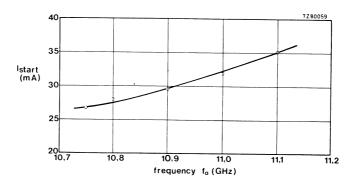


Fig. 7 Start oscillation current as a function of frequency, ambient temperature 25 °C.

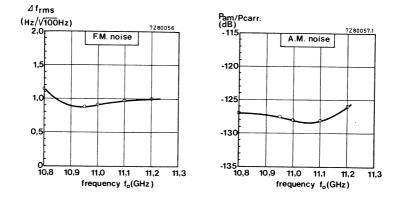
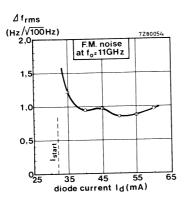


Fig. 8 A.M. and F.M. noise of the IMPATT oscillator, measured as a function of the carrier frequency in a bandwidth of 100 Hz at f_m = 100 kHz. I_d = constant = 55 mA.





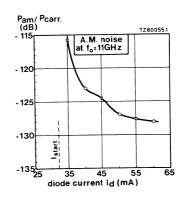
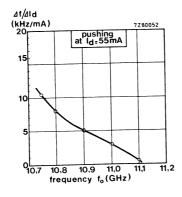


Fig. 9 A.M. and F.M. noise of the IMPATT oscillator, measured as a function of the diode current (output power) in a bandwidth of 100 Hz at $f_m = 100 \text{ kHz}$.



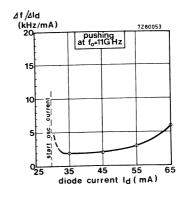


Fig. 10 Pushing of the IMPATT oscillator, measured as a function of frequency and diode current.

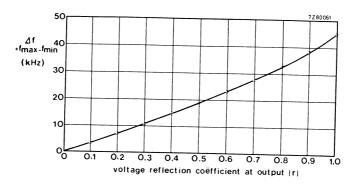


Fig. 11 Frequency pulling of the IMPATT oscillator as a function of the modulus of the voltage reflection coefficient. (Output via isolator and OSM connector.) I_d = 55 mA, I_d = 11 GHz, I_d = 110 mW.

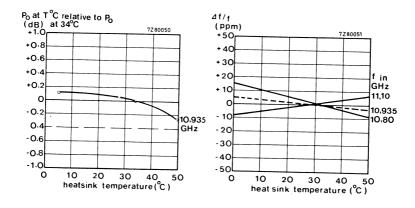


Fig. 12 Relative change of output power and frequency with heatsink temperature. I_d = 55 mA.



LOW NOISE STABLE GUNN OSCILLATOR

Direct generating low noise stable oscillator specially designed for 11 GHz microwave link transmitters and receivers and similar equipment. It consists of a temperature compensated high Q transmission cavity to which a Gunn diode is coupled via a coaxial circuit. The cavity is hermetically sealed and filled with dry nitrogen. Mechanical tuning facilities for frequency adjustment and power optimization are built in.

QUICK REFERENCE DATA

Frequency band	10,7 to 11,2 GHz, type JS1101 11,2 to 11,7 GHz, type JS1102
Mechanical tuning range	500 MHz
Stability $\frac{\Delta f}{f}$	Better than $\pm 5 \times 10^{-7}$ /OC
F.M. noise Δf_{rms}	< 0,5 Hz in a 100 Hz band
Output power*	min. 70 mW

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

OPERATING CONDITIONS

Supply voltage fixed; between 11 and 12 V (d.c.)

P_{tot max} at mounting base temperature = 70 °C 6 W

Voltage stabilized power supply required.

Ambient operating temperature

Ambient humidity

-30 to +60 °C

0 to 95 %

CHARACTERISTICS at 25 $^{\rm o}$ C and V_d = 12 V

Frequency band 10,7 to 11,2 GHz, type JS1101 11,2 to 11,7 GHz, type JS1102

Mechanical tuning range 500 MHz

Frequency stability $\frac{\Delta f}{f}$ better than $\pm 5 \times 10^{-7}$ /°C

Frequency pushing $\frac{\Delta f}{\Delta V_d}$ max. 100 kHz/V

Frequency pulling Δf max. 10 kHz

(measured with output isolator into output mismatch with V.S.W.R. of 1,5)



^{*} Other output powers available on request.

Harmonic level

Spurious signal

F.M. moise Δf_{rms} at 100 kHz off carrier

A.M. noise $\frac{P_{AM}}{P_{carrier}}$ at 100 kHz off carrier

< - 50 dBc*

< - 70 dBc

< 0,5 Hz in a 100 Hz band

< - 130 dB in a 100 Hz band

Ordering information

Туре	Catalogue number
JS1101	9360 021 00001
JS1102	9360 021 10001

MECHANICAL DATA

Dimensions in mm

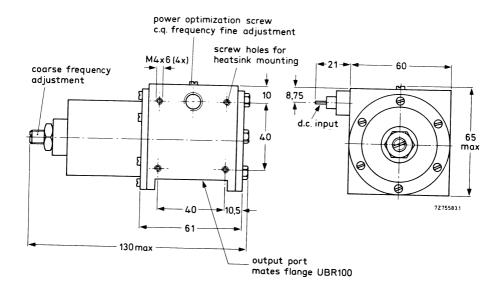


Fig. 1 Stable Gunn oscillator.



^{*} Measured without coaxial line between oscillator output and analyser. When a coaxial line is used between the oscillator and the analyser these values will be greatly reduced.

COAXIAL OUTPUT ADAPTOR, type 2722 162 02841

Consists of a waveguide to coaxial SMA female transition with built in isolator.

Consists of a waveguide to coaxial SWA formare	10,7 to 11,7 GHz
Frequency range	> 25 dB
Isolation	< 0,4 dB
Insertion loss	< 1,05
V.S.W.R. waveguide	< 1,2
SMA connector	2 W
Maximum power load	–10 to +70 °C
Temperature range	

Mechanical data of adaptor

Material

Mating flange type Connector type

Dimensions

brass and aluminium IEC-UBR 100 SMA female 50

see Fig. 2.

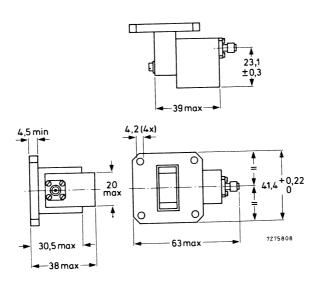


Fig. 2 Coaxial output adaptor.



OPERATING NOTES

- 1. Positive voltage must be applied to the soldering pin; otherwise the active element will be damaged.
- The power supply should be low-impedance voltage-regulated and capable of supplying approximately
 times the normal operating current to initiate oscillations.
- 3. It is recommended that an RC filter be connected in parallel with a voltage regulator diode across the oscillator supply voltage terminals. The filter prevents low-frequency bias supply oscillations, while the regulator diode protects the Gunn diode from over voltage. See Fig. 3.

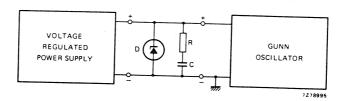


Fig. 3 Bias configuration for stable Gunn oscillator.

D = voltage regulator diode, e.g. BZX70-C15;

R = 1 to 10Ω , carbon resistor;

 $C = 0.47 \mu F$, film capacitor;

Power supply up to 15 V, min. 1 A.

- 4. The voltage across the oscillator terminals is set to a fixed value between 11 and 12 V d.c. The power delivered by the oscillator must be optimized at the desired frequency by means of the small screw.
 See Fig. 1.
- 5. Accurate setting of the desired frequency is obtained by adjusting and locking the main tuning screw as well as possible. The power optimization screw is now slightly detuned from its position obtained in 4 to afford the residual fine tuning of frequency. Generally the associated output power degradation is then very small. see Fig. 4. If necessary, the procedures 4 and 5 can be repeated.

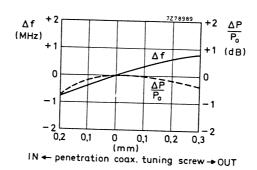


Fig. 4 Fine tuning Δf and associated power variation as a function of the coaxial tuning screw position at constant cavity tuning. $V_d = 12 \text{ V}$; $P_0 = 88 \text{ mW}$; $f = (11\,000 + \Delta f) \text{ MHz}$.

TYPICAL PERFORMANCE CURVES

The performance of JS1102 is similar to that of JS1101.

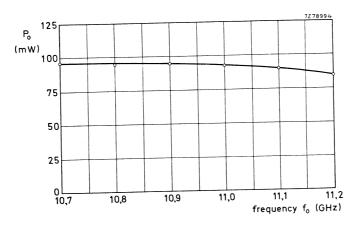
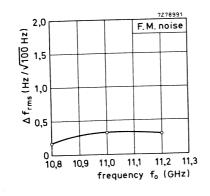


Fig. 5 Output power as a function of frequency for the Gunn oscillator with diode voltage V_d = 12 V.



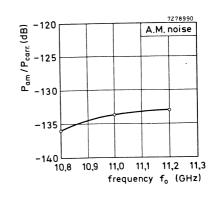
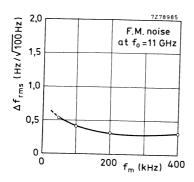


Fig. 6 A.M. and F.M. noise of the Gunn oscillator, measured as a function of the carrier frequency in a bandwidth of 100 Hz at f_m = 100 kHz. V_d = 12 V.





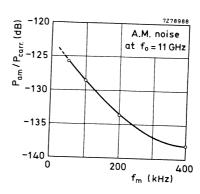
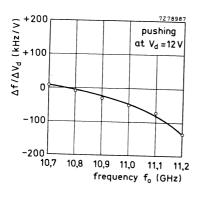


Fig. 7 A.M. and F.M. noise of the Gunn oscillator, measured in a bandwidth of 100 Hz at modulation frequencies (f_m) near to the carrier.



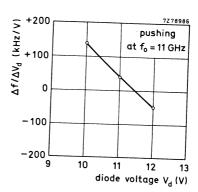


Fig. 8 Pushing of the Gunn oscillator, measured as a function of frequency and diode voltage.



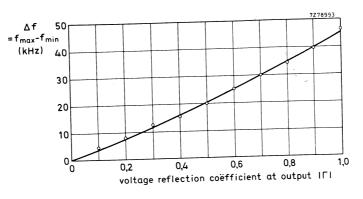


Fig. 9 Frequency pulling of the Gunn oscillator as a function of the modulus of the voltage reflection coefficient. (Output via isolator and OSM connector.) V_d = 12 V; f_O = 11 GHz; P_O = 88 mW; I_d = 495 mA.

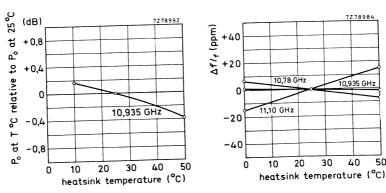


Fig. 10 Relative change of output power and frequency with heatsink temperature. V_d = 12 V.



DIELECTRIC RESONATOR STABILIZED OSCILLATOR

In this type of oscillator, with a Gunn-diode as the active element, high stability and low f.m. noise are obtained by using a small, high-Q, dielectric (ceramic) resonator as the frequency determining element.

Special features are:

- inexpensive
- small and lightweight
- high stability and low noise.

The oscillator is intended for applications as a local oscillator in radar and telecommunication equipment. Higher power output versions are suitable for transmitter applications.

QUICK REFERENCE DATA

Frequency	can be specified between 9 to 12 GHz
Output power at $V_d = -8 \text{ V}$	20 mW
Stability $\frac{\Delta f}{f}$ (-20 to +60 °C), without tuning	better than -4.10 ⁻⁶ /OC
F.M. noise Δf _{rms} at 100 kHz off carrier	typ. 0,15 Hz in a 1 Hz band

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS -- MICROWAVE SEMICONDUCTORS

OPERATING CONDITIONS

•		
Gunn oscillator supply voltage (d.c.) operating current	typ.	−8 V 220 mA
P _{tot max} at mounting base temperature = 70 °C		2,5 W
Voltage stabilized power supply required		105.00
Storage temperature range		to + 125 °C
Ambient operating temperature range	20	to +60 °C
CHARACTERISTICS at T_{amb} = 25 °C and V_d = -8 V		
Frequency (to be specified)	typ.	≈ 11 GHz*
Mechanical tuning range, see operating notes, note 4	up to	5 %
Operating current	typ.	220 mA
Output power		20 mW*
Frequency stability $\frac{\Delta f}{f}$ (-20 to +60 °C),		
without tuning, see operating notes, note 4	better than	1 -4.10 ⁻⁶ /°C
Frequency pushing $\frac{\Delta f}{\Delta V_{\mathbf{d}}}$	<	1 MHz/V
Frequency pulling Δf_p , measured without isolation into output mismatch with VSWR of 1,5		2,5 MHz

^{*} Other output frequencies and power available on request.



CHARACTERISTICS (continued)

F.M. noise $\Delta f_{\mbox{rms}}$ at 100 kHz off carrier

A.M. noise $\frac{P_{am}}{P_{carrier}}$ at 100 kHz off carrier

typ. 0,15 Hz in a 1 Hz band

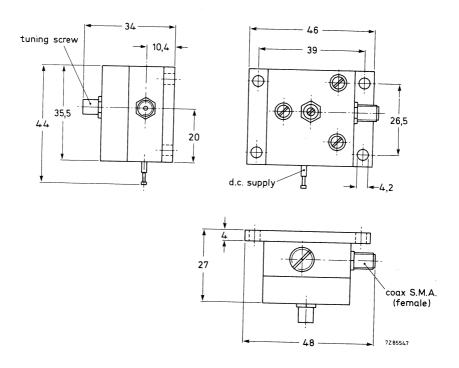
< -145 dBc in a 1 Hz band

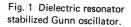
MECHANICAL DATA

The oscillator base plate has four screw holes so that it can be secured to a heatsink. Output power is taken via a coaxial SMA female connector into a 50 Ω load.

Outline drawing

Dimensions in mm







OPERATING NOTES

- Negative voltage must be applied to the soldering pin; the active element will be damaged if the supply voltage is reversed. The base plate is the common return for the Gunn diode voltage.
- 2. The power supply should be low-impedance voltage regulated and capable of supplying approximately 1,5 times the normal operating current to initiate oscillations. See Fig. 2.

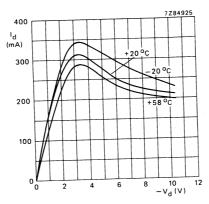


Fig. 2 D.C. bias characteristics of the Gunn oscillator for T_{hs} = -20, + 20 and + 58 °C.

3. It is recommended that a series R-C filter be connected in parallel with a voltage regulator diode across the oscillator supply voltage terminals. The filter prevents low-frequency bias supply oscillations, while the regulator diode protects the Gunn diode against transients. See Fig. 3.

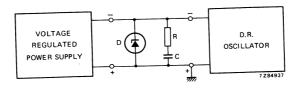


Fig. 3 Bias configuration for dielectric resonator stabilized Gunn oscillator.

D = voltage regulator diode, e.g. BZX70-C11

R = carbon resistor, 12 Ω .

C = film capacitor, 0,47 μ F.

OPERATING NOTES (continued)

4. A small screw on the top of the oscillator allows a limited range of tuning. Turning the screw clockwise, starting from the flush position of the internal pin ($\Delta f = 0$), increases the frequency. When tuning up to 0,5% (i.e. approx. $\Delta f = +50$ MHz), the stability of the oscillator remains unaffected; above that value the df/dT of the oscillator gradually increases due to Q-degradation of the dielectric resonator. A typical tuning curve is given in Fig. 4.



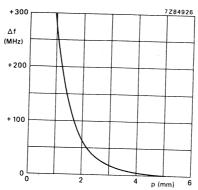
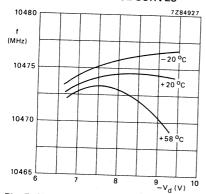


Fig. 4 Tuning of the oscillator as a function of the air gap between tuning screw and resonator: $f = f_0 + \Delta f$.

TYPICAL PERFORMANCE CURVES



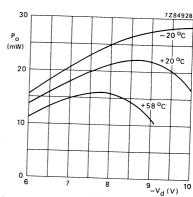
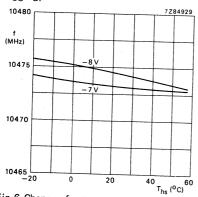


Fig. 5 Change of output power and frequency (pushing) with diode voltage for $T_{hs} = -20$, +20 and



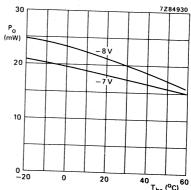
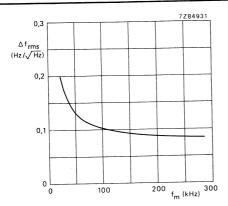


Fig. 6 Change of output power and frequency with heatsink temperature for $V_d = -7 \text{ V}$ and $V_d = -8 \text{ V}$.





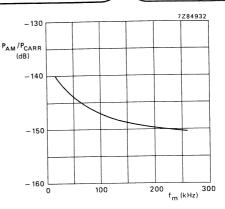


Fig. 7 Single-sideband a.m. and f.m. noise at $f_0\approx 10,\!5$ GHz, measured in a bandwidth of 1 Hz at modulation frequencies f_m near to the carrier (V $_d=-8$ V).

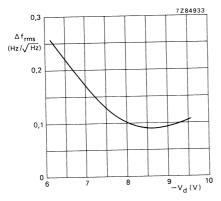


Fig. 8 Single-sideband f.m. noise at $f_0\approx$ 10,5 GHz, as a function of the diode voltage V_d , measured in a bandwidth of 1 Hz at 100 kHz distance from the carrier.

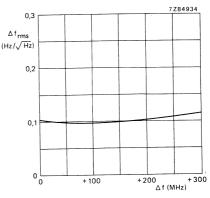


Fig. 9 Variation of the single-sideband f.m. noise at f = $f_0 + \Delta f$, with the tuning of the carrier frequency. Bandwidth = 1 Hz, $f_m = 100$ kHz, $V_d = -8$ V.



JS1200 SERIES

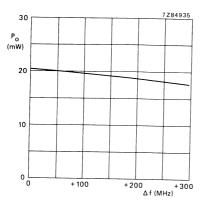


Fig. 10 Variation of the output power at f = $f_0 + \Delta f$ with frequency tuning Δf . $V_d = -8 \ V$, $T_{hs} = +25 \ ^{\circ}C$.

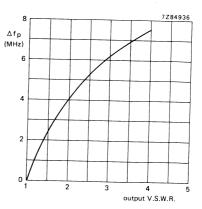


Fig. 11 Frequency pulling of the oscillator as a function of the output VSWR (all phases) for f0 \approx 10,5 GHz, P0 = 20 mW, V_d = -8 V.



MIXER AND DETECTOR MODULES



X-BAND MIXER/DETECTOR MODULES

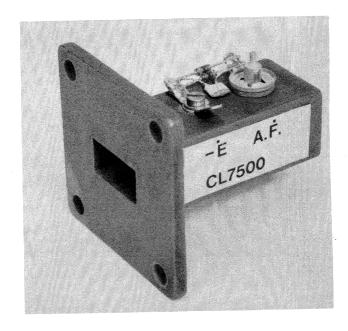
These are waveguide single ended mixers designed for use in the 9 to 11 GHz band. They are primarily intended for Doppler control systems, for example intruder alarms deriving local oscillator drive from the transmitter output of a Gunn oscillator from our CL8630 series.

These devices can be used as microwave detectors. Examples of this application are sensing deliberate beam obstruction in a microwave protected area and as a receiver in a microwave barrier or fence.

QUICK REFERENCE DATA

QUIDIC ITE! ETTE ETTE				
Centre frequency CL7500 CL7520		10.687 9.350	GHz GHz	
Sensitivity for –90 dBm input	typ.	40 1.0	μV μV	4
Noise level (32 μ A d.c. bias, 1 Hz to 1 kHz bandwidth)	typ.	1.0	μν	

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS





RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

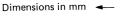
	Storage temperature range	T_{stg}		-10 to +	100	°C
	Ambient temperature range	T _{amb}		-10 to		°C
	TYPICAL OPERATING CONDITIONS					
	Local oscillator level			_	-18	dBm
	D.Cbias				32	
	Total load (d.c. and i.f.)				10	μA kΩ
	CHARACTERISTICS (T _{amb} = 25 °C)					
	Mixer		min.	typ.	max.	
-	Sensitivity for –90 dBm input (with a 10 $k\Omega$ load)		15	40		μV
	Noise level (32 μ A d.c. bias, 1 Hz to 1 kHz bandwidth) (note 1)		_	1.0	2.0	μV
	Detector					
	Tangential sensitivity at centre frequency (note 2)	s_{ts}	_	-50	_	dBm

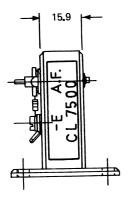
Notes

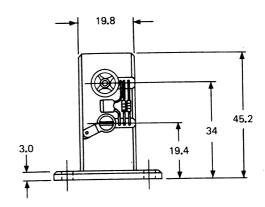
- When the local oscillator power is derived from a Gunn oscillator with an a.m. noise to carrier ratio
 of -94 dB (typically from our CL8630 series), the minimum sensitivity specified represents a signal
 to noise ratio at the mixer output of 18 dB (typically 24 dB).
- 2. When operated as a detector with 32 μA bias, measured in a 0 to 2 MHz bandwidth.
- 3. The module is supplied with a protection circuit connected between the mixer a.f. and earth terminals. The mixer has a low junction capacitance and may be damaged by transients of very short duration. It is therefore recommended that soldering irons are isolated from mains supplies and that the protection circuit is not removed when all wiring has been completed. Mixer and earth connections should be made direct to the appropriate terminals and not to the protection circuit tags.
- 4. Precautions similar to those required for CMOS devices are necessary, namely:
 - a) Earthed wrist straps should be worn.
 - b) Table tops or other working surfaces should be conductive and earthed.
 - c) Anti-static clothing should be worn.
 - d) No electrical testing should be carried out without specific, approved and written test procedures.
 - e) To prevent the development of damaging transient voltages, devices should not be inserted or removed from test fixtures with power applied.
- 5. Connections to be made to W.G.16 components.

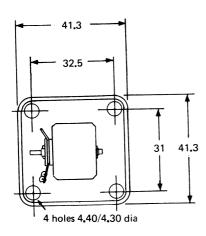


MECHANICAL DATA CL7500





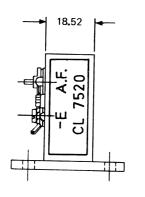


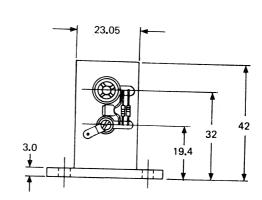


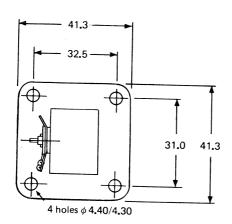
M81-1438/1

► MECHANICAL DATA CL7520

Dimensions in mm







M81-1438/2

DOWN CONVERTER

Down converter for use in microwave radio link receivers in the various communication bands between 3,8 and 11,7 GHz. It consists of a balanced mixer with two Schottky barrier diodes, integrated isolator behind the r.f. input port, and a 70 or 140 MHz i.f. preamplifier. R.F. input is coaxial or waveguide (below 5,0 GHz coaxial only).

QUICK REFERENCE DATA

Frequency bands	3,8 to 11,7 GHz, see table
Noise figure	≤ 7 dB including isolator and preamplifier
Conversion gain	20 dB min.
Intermediate frequency	70 or 140 MHz
I.F. bandwidth	35 MHz

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

ELECTRICAL DATA

Frequency bands	3,8	to 4,0	GHz
rrequericy bands	4,0	to 4,2	GHz
	4,4	to 4,7	GHz
	4,7	to 5,0	GHz
	5,4	to 5,9	GHz
	5,9	to 6,4	GHz
	6,4	to 7,2	GHz
	7,1	to 7,7	GHz
		to 8,5	
	10,7	to 11,7	7 GHz

Transfer characteristics

Conversion gain	$20 \pm 2 dB$, other values on reque	
Noise figure at 290 K	\leq 7,0 dB max.	
Isolation between l.o. and r.f. input	≥ 30 dB	
Flatness of i.f. output	± 0,3 dB	

Power supply

Maximum nower	200 mW
Voitage	+ 10 and + 30 V on request
Voltage	+ 12 V d.c. ± 10%, other values between

R.F. input

Maximum power

Connector	50 Ω SMA or waveguide (below 5,0 GHz
	amouth only

	coaxiai oniy)
Flange	IEC 154 UER70 or IEC 154 UBR100
Signal level	-20 dBm max.

≤ 1.2 V.S.W.R.

L.O. input

Connector

Level

V.S.W.R.

 $50~\Omega~\text{SMA}$

+ 20 dB m max.

≤2

I.F. output

Intermediate frequency

Bandwidth (-1 dB)

Connector

V.S.W.R.

Impedance

70 MHz or 140 MHz

≥ 35 MHz

BNC

≤ 1,25

75 Ω

ENVIRONMENTAL DATA

Temperature range

Humidity steady state

Vibration

Mechanical shock

Corrosion .

0 to 50 °C

MIL-STD- 103B and C

MIL-STD- 204C, cond. D

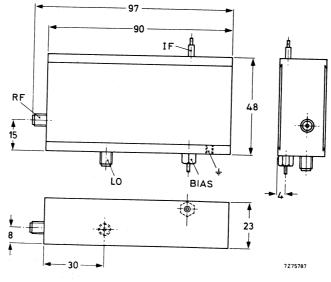
MIL-STD- 213B, cond. 1

MIL-STD- 101B, cond. B

MECHANICAL DATA

Outline

Dimensions in mm







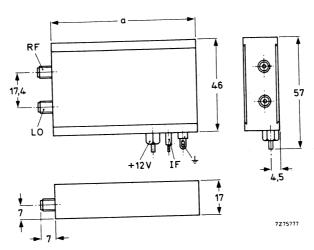


Fig. 2a: a = 75; 2b: a = 63.

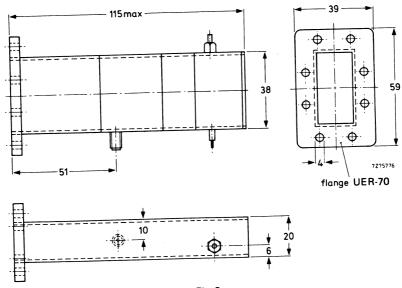
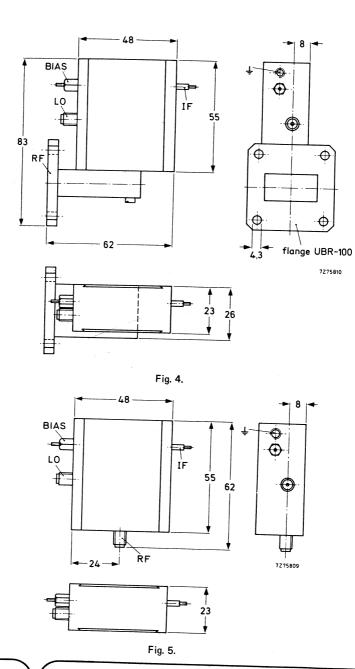


Fig. 3.





STANDARD TYPES

Frequency GHz	R.F. input	I.F. MHz	Figure	Type no.	Catalogue number
3,8 to 4,0	coaxial	70 140	1 1	JM1001 JM1002	9360 015 40000 50000
4,0 to 4,2	coaxial	70 140	1 1	JM1003 JM1004	60000 70000
4,4 to 4,7	coaxial	70 140	2a 2a	JM1005 JM1006	80000 90000
4,7 to 5,0	coaxial	70 140	2a 2a	JM1007 JM1008	9360 016 00000 10000
5,4 to 5,9	coaxial	70 140	2a 2a	JM1009 JM1010	20000 30000
	waveguide	70 140	3 3	JM1011 JM1012	40000 50000
5,9 to 6,4	coaxial	70 140	2b 2b	JM1013 JM1014	60000 70000
	waveguide	70 140	3 3	JM1015 JM1016	80000 90000
6,4 to 7,2	coaxial	70 140	2b 2b	JM1017 JM1018	9360 017 00000 10000
	waveguide	70 140	3 3	JM1019 JM1020	20000 30000
7,1 to 7,7	coaxial	70 140	2b 2b	JM1021 JM1022	40000 50000
	waveguide	70 140	3 3	JM1023 JM1024	60000 70000
8,0 to 8,5	coaxial	70 140	2b 2b	JM1025 JM1026	80000 90000
	waveguide	70 140	3 3	JM1027 JM1028	9360 018 00000 10000
10,7 to 11,7	coaxial	70 140	5 5	JM1029 JM1030	20000 30000
		70 140	4 4	JM1031 JM1032	40000 50000





DOPPLER MODULES AND VEHICLE DETECTORS





MICROWAVE VEHICLE DETECTORS

Fixed frequency microwave vehicle detectors with direction sense, for operation in the 10.6 GHz band using Doppler radar for vehicle actuated traffic signals. They comply with government regulations in the U.K. (D.o.E. specifications MCE0111, MCE0114 and MCG0500 and Home Office regulations BR14, 1975 specification). The CL8880BN has a rear cable entry and in the CL8880BNC the cable entry is via the mounting foot. The CL8882 is a 240 V a.c. version with separate signal and supply cables.

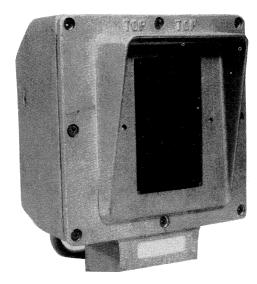
QUICK REFERENCE DATA

Centre frequency		10.587	GHz	
Transmitted power	typ.	5	mW	
Detection range for small vehicle moving at 50 km/h (30 m.p.h.) with detector mounted 2.5 m above typical road surface	typ.	100	m	
Supply voltage (a.c.) centre tapped		110	V	
Supply voltage (a.c.) CL8882 only		240	V	

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

SAFETY PRECAUTION

The centre-tap of the 55–0–55 V supply is connected to the case and must be earthed.





CL8880BN CL8880BNC CL8882

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

Supply voltage (a.c.)		550-	-55 ± 20%	V
Supply voltage (a.c.) CL8882 only		2	240 ± 10%	V
Storage temperature range			20 to +70	°C
Ambient operating temperature range			15 to +50	οС
OPERATING CONDITIONS				
Supply voltage (110 V _{ac} centre-tapped)			55-0-55	V
Supply voltage (a.c.) CL8882 only			240	V
 Power consumption	typ.		12	w
CHARACTERISTICS	min.	typ.	max.	
Centre frequency, fixed in the range	10.577	10.587	10.597	GHz
Transmitted power		5	10	mW
Detection range for vehicle moving at 50 km/h (30 m.p.h.) with the detector mounted				
2.5 m above typical road surface	85	100	_	m
Mass	_	3	_	kg



OPERATING NOTES

- 1. The detector is of single-chassis construction.
- It is recommended that the detector is mounted so that the centre of the microwave window (radome) is not less than 150 mm above the cowl of the red signal. There will then be minimal interruption of the beam by the cowl and the near-field performance of the detector will not be impaired.
- 3. In operation, the traffic signal controller demand input is connected to the 'relay output' terminals. In the standard unit, for use with portable signal heads, the relay is energized closed, except when a demand is present, (CL8880BN and CL8880BNC only).
- 4. CL8880BN and CL8880BNC units with 'normally open' relay connections are available on request.
- 5. A 47 Ω resistor in series with the relay output terminals is included for overcurrent and overvoltage protection.
- 6. Upon detection of oncoming traffic, the relay in the detector is de-energized and a pair of isolated contacts is opened to signify detection. The contacts remain open during the detection of a stream of oncoming traffic. The minimum open time is nominally 1 second, (CL8880BN and CL8880BNC only). A rear mounted red LED is illuminated during the detection period.
- 7. Signals caused by departing vehicles are ignored.
- 8. Should a fault occur in the detector or its supply voltage be interrupted, then the detector's relay will be permanently de-energized and a continuous demand will be applied to the controller. The traffic signals will then operate automatically in a fixed-time manner.
- 9. The power supply for the CL8880BN and CL8880BNC is derived from the main traffic control unit: a 55–0–55 V centre-tapped a.c. supply is necessary. This centre-tap is connected to the case and must be earthed.
- 10. The cable colour codes shown in table 1 and 2 must be observed.

	TABLE 1 (CL8880BN, BNC) Cable colour codes
Red Orange Black Green/Yellow Green	55 V _{ac} 55 V _{ac} 0 V (centre tap of 110 V a.c. supply) earth Normally closed output contacts (isolated)

TABLE 2 (CL8882) Cable colour codes									
Supply cable	240 V a.c.	line neutral earth	brown blue green/yellow						
Signal cable	green }	normally (opened	y closed output contacts when vehicle detected)						
common	blue }		y open output contacts when vehicle detected)						



OPERATING NOTES (continued)

- The equipment detects lone vehicles approaching the traffic signals in the presence of large departing vehicles or a heavy stream of departing traffic.
- 12. The equipment does not give false outputs in the absence of moving targets
- 13. Signals reflected from fluttering or waving trees at reasonable distances from the detector do not cause unwanted outputs, even if the detector is aimed directly at the trees.
- 14. For temporary traffic light systems, a 'NUDGE' facility is included.
- 15. The NUDGE facility is such that in the absence of a demand from approaching traffic for a period of 2½ minutes, a 'phantom' demand is applied. The relay in the detector is de-energized and the detector then returns to the vehicle-actuated mode. The period is set by a digital timer which is independent of the ambient temperature.
- 16. The 'phantom' demand overcomes the rare lock-up situations in traffic flow at temporary traffic lights where the possibility of a permanent 'red-red' can occur, caused by the non-detection of approaching vehicles.

SITE TESTS

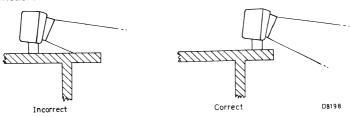
- 1. To check the operation of a detector, set it up in the operating position with the power supplies connected and connect a multimeter, switched to a resistance-measuring range, across the normally-closed contacts. (Note: high-voltage circuit testers must not be used as they will damage the detector). The measured resistance should be approximately 47 Ω ; this is the value of the protection resistor incorporated in the circuit.
- 2. Check the a.c. supply voltages at the microwave head. For the CL8880BN and BNC the line-to-line voltage should be 110 V_{rms} and the voltage between each line and the 0 V terminal should be 55 V_{rms} ; The tolerance on these voltages is $\pm 20\%$. For the CL8882 the supply voltage should be 240 $V_{rms} \pm 10\%$.
- 3. Arrange for a vehicle, preferably a small car, to be driven towards and past the detector at approximately 50km/h (30 m.p.h.). When the car is between 150 and 100 metres approximately from the detector (see fig.2), the measured resistance between the normally-closed contacts should quickly increase to indicate an open-circuit. This condition should continue for approximately 1 second after the car has passed out of the detector's range.

WORKSHOP TESTS FOR INOPERATIVE SENSORS

- These tests are intended to reveal inoperative detectors only. It must be noted that they do not
 replace any range tests carried out with a vehicle under site conditions.
 There is no attempt to correlate range measurements with these tests as they will only inform the
 operator that a detector is functioning correctly, not functioning or is functioning in reverse.
 They will, however, ensure that there is some consistency of testing between different operators.
- Ideally, the detector should be sited in an environment free, as far as possible, from extraneous movements of large bodies such as people, fork lift trucks, etc.

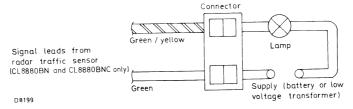


3. The detector should be placed on a level surface, e.g. a bench, as near to the edge as possible to avoid reflections from the bench surface.



It should not be pointed directly at fluorescent lights as they may cause false demands to be registered, due to interference.

- 4. Ensure that the environment is free as far as possible from microwave interference, for example, microwave vehicle detectors on soak test in the vicinity of the beam could cause interference giving rise to false demands.
- 5. The supply cable/s should be connected in accordance with the codings given in table 1 and 2 on page 3.
- 6. Demands may be observed by connecting the signal output leads (green and green/yellow) to a controller with a lamp which indicates presence of a demand. Alternatively, a bulb and power supply may be connected in series with the signal leads via a simple connector block of the push-button type. See diagram below.



This simple method will eliminate the possibility of controller faults.

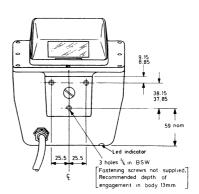
- 7. With the supply connected and switched on, the indicator lamp should be illuminated.
- 8. A demand will be indicated when the lamp is extinquished.
- 9. Leave the detector pointing into free space and check for false demands. The lamp should remain alight for approximately 2 to 2½ minutes until the 'nudge' circuitry puts in a 'phantom' demand. These 'nudge' demands will reappear at regular intervals of 2 to 2½ minutes; no other demands should occur between them.
- 10. With the detector placed on a level surface, (see note 3), about 1½ metres from ground level, the operator should stand about 5 metres away from the detector in a direct line with the microwave window (radome) and should have the demand indicator lamp in view. He should then walk at normal walking pace towards the detector, stopping at about 1 metre from it. If the detector is functioning correctly, a demand will be registered between starting to walk and stopping. He should then wait for the demand to clear and then walk backwards to his starting point. No demand should be registered. If a demand is observed, the detector is working in reverse and is therefore faulty.

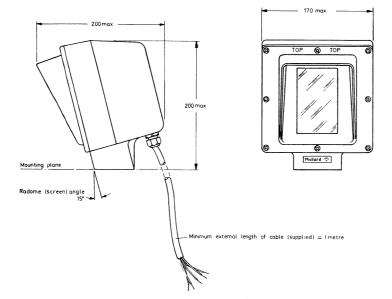


MECHANICAL DATA CL8880BN

Dimensions in mm

D8204b



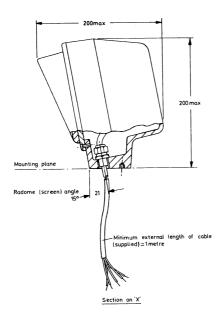


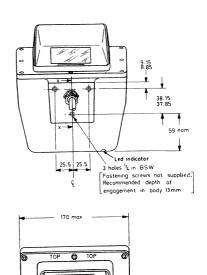


CL8880BN CL8880BNC CL8882

MECHANICAL DATA CL8880BNC

Dimensions in mm





Mullard 🌣

D8205b



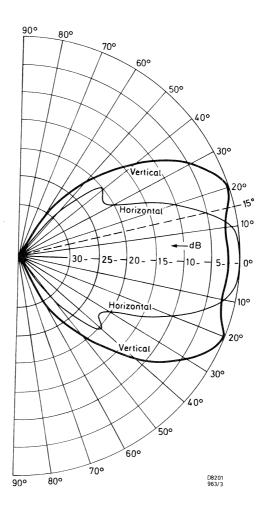




Fig.1 Typical polar diagram of microwave vehicle detector The broken line indicates the preferred mounting angle of 15°. This affects only the orientation of the vertical pattern.

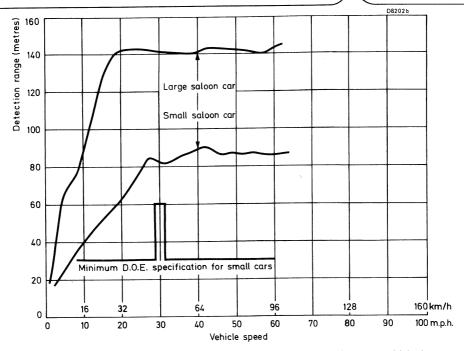
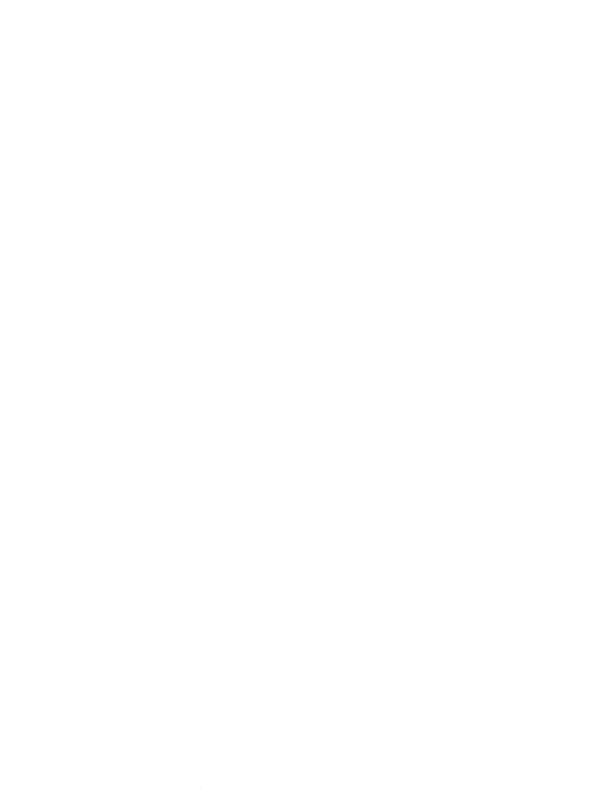


Fig.2 Typical detection curves obtained from road tests using six different microwave vehicle detectors.





X-BAND DOPPLER RADAR MODULES

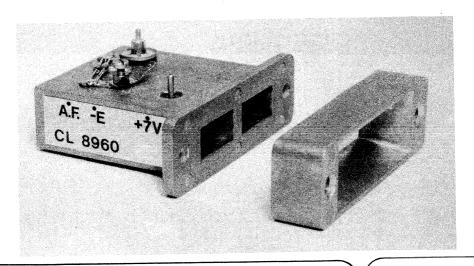
This is a series of fixed frequency Gunn oscillators and mixer cavities for operation in X-band. Applications include all forms of Doppler radar systems.

QUICK REFERENCE DATA

noise (note 1 and page 9)	typ.	40	μV
Voltage output for power input 100 dB down on power output at 18 dB min. signal + noise			
Power output (at 7.0 V)	typ.	10	,,,,,,
Supply voltage	typ	+7.0 10	v mW
CL8960 CL8961 CL8962 CL8963 CL8964 CL8965 CL8967	10.687 9.350 9.470 10.525 9.900 10.565 10.365 9.520	+7.0	V
Type No	Centre frequency GHz		

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS.

Module with antenna as supplied





CL8960 SERIES

RATINGS					
Limiting values in accordance with the	Absolute Ma	ximum Syst	em (IEC134)		
Supply voltage (d.c.)			max.	+7.5	V
Supply voltage (for less than 1 ms)			max.	+9.0	-
─► Load v.s.w.r.			max.	1.5:1	-
Storage temperature range				-10 to +70	
Ambient temperature range				0 to +40	_
OPERATING CONDITIONS					
Supply voltage range (note 2)				6.8 to 7.2	V
Gunn operating current (note 3)			typ.	130	mA
D.C. mixer bias current (into a.f. termi	nal w.r.t. eartl	n)	-71	30 to 35	μΑ
A.F. load (page 8)				10	kΩ
CHARACTERISTICS					
		min.	typ.	max.	
Voltage output for power input 100 dB down on power output at 18 dB min. signal + noise					
noise (notes 1 and 4 and page 9)		00			
Power output at 7.0 V		20	40	_	μV
Frequency temperature coefficient		· –	10		mW
Frequency pushing		_	-0.25	-0.40	MHz/°C
			4.0	_	MHz/V
Gunn operating current (note 3)			130	165	mA
Polar diagram			page 10		
Centre frequency, fixed in the range:	CL8960 CL8961	10.675 9.338	10.687 9.350	10.699 9.362	GHz GHz
	CL8962	9.458	9.470	9.482	GHz
	CL8963	10.513	10.525	10.537	GHz
	CL8964 CL8965	9.888	9.900	9.912	GHz
	CL8967	10.553 10.353	10.565 10.365	10.577	GHz
	CL8968	9.508	9.520	10.377 9.532	GHz GHz
MASS				210	g

Alternative antennae and operating frequencies may be made to suit customers' specific requirements.



NOTES

1. A return signal 100 dB down on radiated power will be achieved from a man target of radar cross-section 1.0 m² at a range of 15 m, when operating with the antenna supplied (antenna gain is 5 dB typ.).

Extended range may be obtained for a reduced $\frac{\text{signal + noise}}{\text{noise}}$ and this may be acceptable if the

environment in which the system operates is stable, i.e. free from extraneous moving or vibrating objects. For example, 110 dB path loss is obtained from a man target of radar cross-section 1.0 m²

at a range of 25 m and the $\frac{\text{signal + noise}}{\text{noise}}$ is reduced to 15 dB with an output voltage of 16 μ V min.

Alternatively, the range may be increased by an increase in target radar cross-section or by the use of a high gain antenna. The performance may then be calculated from the radar range equation. Further related information may be obtained on application to the manufacturer,

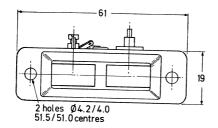
- 2. It is essential that the earth terminal is used as the common return for the Gunn voltage $(+7\ V)$ and the d.c. bias supplied to the a.f. terminal. In addition, the soldered connection to the mixer should be made direct to the mixer terminal and not to the associated protection circuit.
- 3. The Gunn effect device has a voltage current characteristic as shown on page 8. The power supply should have a low source impedance and be capable of supplying up to 250 mA at approximately 3 V during the switch-on phase.
- 4. Noise measured at a frequency 1 Hz to 1 kHz from carrier.
- 5. The Gunn device will be damaged if the supply is reversed.
- 6. The module is supplied with a protection circuit connected between the mixer a.f. and earth terminals. The mixer has a low junction capacitance and may be damaged by transients of very short duration. It is therefore recommended that soldering irons are isolated from mains supplies and the protection circuit is not removed when all wiring has been completed. Mixer and earth connections should be made direct to the appropriate terminals and not the the protection circuit tags.
- 7. Precautions similar to those required for CMOS devices are necessary, namely:
 - (a) Earthed wrist straps should be worn.
 - (b) Table tops or other working surfaces should be conductive and earthed.
 - (c) Anti-static clothing should be worn.
 - (d) No electrical testing should be carried out without specific, approved and written test procedures.
 - (e) To prevent the development of damaging transient voltages, devices should not be inserted or removed from test fixtures with power applied.
- 8. The above conditions apply when operated into the antenna supplied with the module.
- 9. A 10 nF capacitor should be connected across and close to the +7 V and earth terminals to suppress parasitic oscillations in the power supply.
- Signal + noise performance may be degraded if the antenna is covered by a radome of unsuitable 10. construction. Page 12 describes the preferred arrangement.

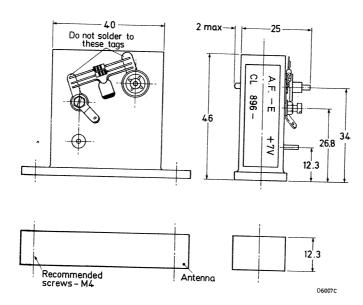


MECHANICAL DATA

Dimensions in mm

CL8960 CL8963 CL8965





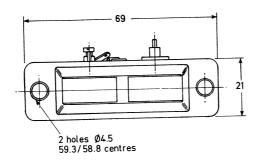
CL8960 SERIES

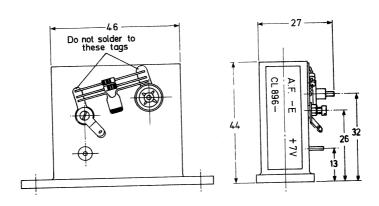
Dimensions in mm

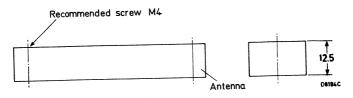
MECHANICAL DATA

CL8961

CL8962 CL8968



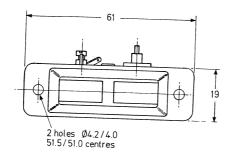


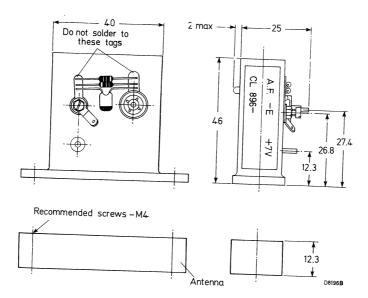


MECHANICAL DATA

CL8964

Dimensions in mm







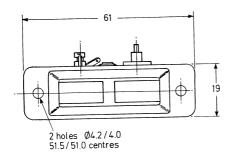
6

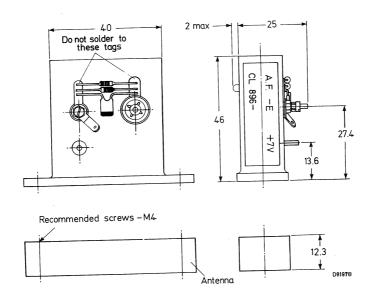
CL8960 SERIES

MECHANICAL DATA

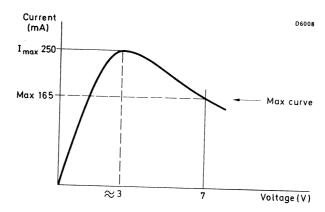
CL8967

Dimensions in mm

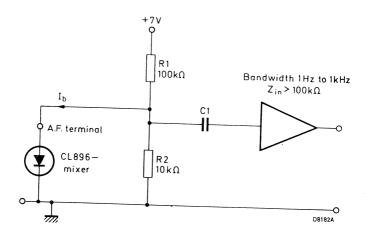








Typical Gunn device characteristic

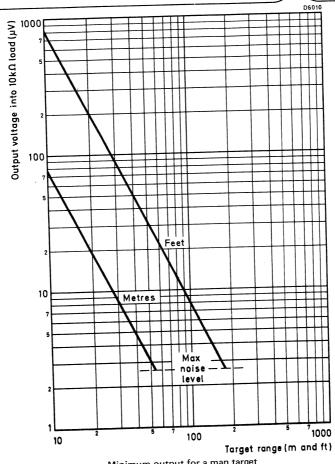


Circuit used to measure a.f. performance



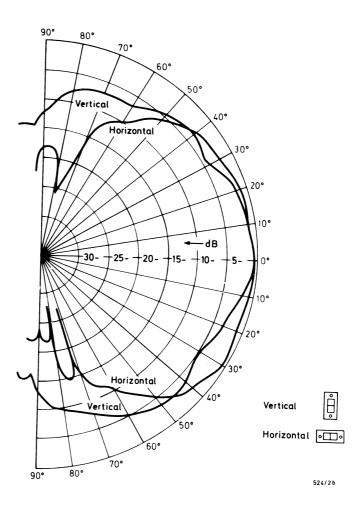
Notes

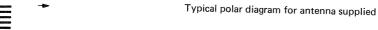
- 1. The current Ib should be approximately 35 μ A with the Gunn device disconnected and approximately 42 μ A with the Gunn device operational and the antenna operating into free space.
- 2. The coupling capacitor should have a small impedance compared with $Z_{\mbox{in}}$



Minimum output for a man target









MODULE MOUNTING

For optimum signal to noise ratio, it is recommended that the module and antenna are mounted, using M4 screws, to a 1.6 mm thick metal plate with aperture dimensions as shown on page 12. In this configuration, the metal plate forms the front panel of the equipment, and the antenna radiates into free space. If the equipment housing is all metal, any back radiation will be totally contained. Alternatively a metal based adhesive tape may be used to seal the joint between antenna and mounting plate.

The total mixer bias under the optimum operating conditions is approximately 42 μ A. (35 μ A d.c. bias + 7 μ A from -19 dBm of coupled l.o. power).

If, however, for environmental reasons, it is considered desirable to cover the antenna aperture, then it is recommended that a thin plastic material (approximately 0.25 mm thick) is fixed to the metal plate with adhesive. A suitable plastic material is described below.

In this case, the l.o. power coupled to the mixer will be -11 dBm, and the total mixer bias current will now be approximately 60 μ A.

The increase in I.o. power will, in general give rise to an increase in a.f. output voltage for a given target, but this will be accompanied by a degradation in signal to noise ratio. For —11 dBm of I.o. power, the degradation in signal to noise ratio should be acceptable for most applications. However, further increase in the level of coupled I.o. power arising from the use of thick or 'microwave' reflective covering materials, will:

- (a) continue to increase the a.f. output voltage from the mixer (N.B. the increase will not be the same for all modules) but at the same time, degrade the signal to noise ratio.
- (b) present a mismatch to the Gunn oscillator which may impair the switching and running performance and may 'pull' the frequency outside the allocated operating frequency band.

The following table compares the l.o. coupling level obtained for different covering materials at the antenna.

L.O. coupling (dBm)	Mixer total bias (μA)	Antenna covering material
_	35 (d.c.only)	–
_19	42	No covering
–19 –15	50	1 to 2 cm expanded polythene or polystyrene
-11	61	0.25 mm Cobex plastic
-6	70	0.5 mm Cobex plastic

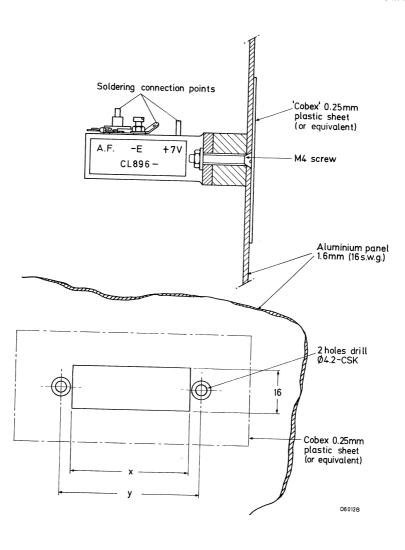
Cobex is a product of:

British Industrial Plastics, Sheet and Film Division, Brantham Works, Brantham, Manningtree, Essex, CO11 1NJ, England.



PANEL MOUNTING DETAILS

Dimensions in mm





CL8960 CL8963 CL8964 CL8965

CL8967

x = 43 y = 51.5/51.0 CL8961 CL8962 CL8968

x = 50 y = 59.3/58.8

CIRCULATORS AND ISOLATORS



MICROSTRIP CIRCULATORS AND ISOLATORS

These components are designed on the basis of microstrip transmission lines of nominally 50 Ω characteristic impedance. They are intended to be mounted between microstrip circuits where required.

The circulators consist of a ferrite substrate which supports a thin-film circulator pattern and ground plane. Two ticonal magnets mounted above and below the substrate provide the biasing magnetic field. For isolators the third port is terminated with a matched load.

To facilitate assembly between two adjacent circuits the units have a square or rectangular substrate, the edges of which are precision ground to fine tolerances. Assembly into the circuits should be carried out by bonding techniques or by pressure contacts. The use of soldering techniques for this purpose will result in the destruction of the component and/or degradation of its electrical performance. Some examples of suitable mounting techniques are given on pages 6 and 7.

The electrical characteristics are guaranteed when measured in our standard test jigs, which are available as standard accessories.

TERMS AND DEFINITIONS

Frequency range

This is the range within which the isolator or circulator meets the guaranteed specification.

Isolation

In an isolator, isolation is the ratio, expressed in dB, of the input power to the output power for signal injection in the reverse direction (matched source and load).

In a circulator, isolation is the ratio, expressed in dB, of the power entering a port to the power scattered into the adjacent port on the side opposed to the normal circulation (matched source and the other ports correctly terminated).

Insertion loss

This is the attenuation that results from including the device in the transmission system. It is given as a power ratio, expressed in dB, which compares the situation before and after the insertion of an isolator or circulator.

Maximum power

In an isolator, the maximum power is the highest power that may be passed through it (without damage) in the forward direction into a v.s.w.r. of 2. This power value must not be exceeded.

In a circulator, the maximum power is the highest power it can handle at sea level and at maximum ambient temperature when one port is terminated with a mismatch giving v.s.w.r. of 2, whilst the next port is matched with a v.s.w.r. of 1.2 or less. This power value must not be exceeded.

Temperature range

This is the ambient temperature range within which isolators and circulators function to specification. Circulators still function outside the temperature range but their electrical behaviour may be far outside the guaranteed specifications. Isolators can be stored at any temperature between —55 and +125 °C.



MICROSTRIP CIRCULATORS

Electrical data (as measured in the related test jig)

Maximum power (c.w.)

10 W

Storage temperature

-55 to + 125 °C

frequency	isola	isolation insertion loss v.s.w.r.		operational	catalogue	related			
range	min.	typ.	max.	typ.	max.	typ.	temperature	number	test jig
GHz	dB	dB	dB	dB			oC.	2722 169	followed by
1,7 to 1,9 1,9 to 2,1 2,1 to 2,3	20	22	0,5	0,30	1,25	1,15	-10 to +60	03161 03171 03181	00141
2,2 to 2,5 3 to 3,5 3,6 to 4,2	20 20 20	22 22 25	0,4 0,4 0,4	0,25 0,30 0,25	1,25 1,20 1,20	1,2 1,15 1,1	0 to +50 0 to +50 -10 to 70	03001 03011 03041	00021 00031 00041
4,4 to 5,0 4,7 to 5,2 5,9 to 6,5 6,4 to 7,1 7,1 to 7,7	20	25	0,4	0,20	1,20	1,1	-10 to 70	03051 03061 03071 03081 03091	00061
7,7 to 8,5	20	25	0,4	0,25	1,20	1,1	-10 to 70	03101	00081
8,5 to 9,6 8,0 to 10,4 8,0 to 12,0 9,0 to 11,5	20 20 17 20	25 22 19 22	0,4 0,4 0,5 0,4	0,25 0,25 0,40 0,25	1,20 1,25 1,35 1,25	1,1 1,15 1,25 1,15	-10 to 70	03111 03121 03131 03141	00101
14,4 to 15,25	20	22	0,5	0,30	1,25	1,15	-10 to 70	03151	00121

CAUTIONARY NOTE

Isolators and circulators have magnetic fields that are carefully adjusted for optimum operation; they should not, therefore, be subjected to strong external magnetic fields.

NOTE ON ELECTRICAL PARAMETERS

Stated electrical parameters are valid only when measured on a test jig supplied by us.

ENVIRONMENTAL DATA

The circulators have been tested by our independent Quality Control department in accordance with the following specifications:

Die shear strength: max. force 120 g/mm² to MIL-STD-883B method 2019.1.

Moisture resistance: 40 $^{\rm o}$ C, R.H. 90-95%, 10 days to IEC 68-2-3 (1969) Test Ca, damp heat steady state.

PACKING

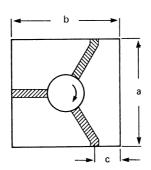
The minimum packing quantity is 5 units in one box. This is also the minimum ordering quantity.



Mechanical data (dimensions in mm)

Tolerances ± 0,05 mm unless otherwise stated.

	-,							
а	b	С	d ± 0,2	е	f max.	g ± 0,0025	h max.	mass g
38,1	38,1	8	21	16,5	7	1,02		17
25,4 25,4 18,98	25,4 25,4 18,98	8 5,5 5	13 14 10	12 12 9,5	7	1,02		8 8 5
12,62	12,62	4	6,3	5,2	8 8 10 10 10	1,02		2 2 2,5 2,5 2,5
10,40	12,62	4,5	5,8	5,2	7	0,51		2
8,17	9,85	2,95 2,95 3,4 3,4	5 5 4,65 4,65	5,2 5,2 4,3 4,3	7	0,51		1,5
6,32	7,6	2,5	3,6	3	8	0,51		0,75



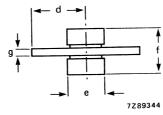


Fig. 1.



MICROSTRIP ISOLATORS

Electrical data (as measured in the related test jig)

Maximum power (c.w.)

10 W 100 mW

Maximum reverse power

Storage temperature

-55 to + 125 °C

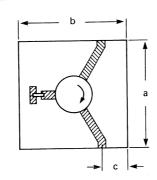
frequency	isol	ation	inserti	ion loss	v.s.	w.r.	operational	catalogue	related
range	min.	typ.	max.	typ.	max.	typ.	temperature	number	test jig
GHz	dB	dB	dB	dB			оС	2722 169	followed by
1,7 to 1,9 1,9 to 2,1 2,1 to 2,3	20	22	0,5	0,30	1,25	1,15	-10 to 60	01161 01171 01181	00151
2,2 to 2,5 3 to 3,5 3,6 to 4,2	20 20 20	22 22 25	0,4 0,4 0,4	0,25 0,30 0,25	1,25 1,20 1,20	1,2 1,15 1,1	0 to 50 0 to 50 -10 to 70	01191 01201 01041	00161 00171 00051
4,4 to 5,0 4,7 to 5,2 5,9 to 6,5 6,4 to 7,1 7,1 to 7,7	20	25	0,4	0,20	1,20	1,1	-10 to 70	01051 01061 01071 01081 01091	00071
7,7 to 8,5	20	25	0,4	0,25	1,20	1,1	-10 to 70	01101	00091
8,5 to 9,6 8,0 to 10,4 8,0 to 12,0 9,0 to 11,5	20 20 17 20	25 22 19 22	0,4 0,4 0,5 0,4	0,25 0,25 0,40 0,25	1,20 1,25 1,35 1,25	1,1 1,15 1,25 1,15	10 to 70	01111 01121 01131 01141	00111
14,4 to 15,25	20	22	0,5	0,30	1,25	1,15	-10 to 70	01151	00131

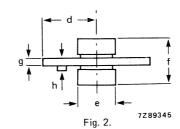


Mechanical data (dimensions in mm)

Tolerances \pm 0,05 mm unless otherwise stated.

Tolerances -	J,05 IIIII a	111000 0 11						
a	b	С	d ± 0,2	е	f max.	g ± 0,0025	h max.	ma ss g
38,1	38,1	8	21	16,5	7	1,02	1,7	17
25,4 25,4 18,98	25,4 25,4 18,98	8 5,5 5	13 14 10	12 12 9,5	7	1,02	1,7	8 8 5
12,62	12,62	4	6,3	5,2	8 8 10 10 10	1,02	1,7	2 2 2,5 2,5 2,5
10,40	16,0	3,5	10,2	5,2	7	0,51	1,3	2
8,17	12,62	2,4	8,4	5,2 5,2 4,3 4,3	7	0,51	1,3	1,5
6,32	11,0	2,5	7,0	3	8	0,51	1,3	0,75

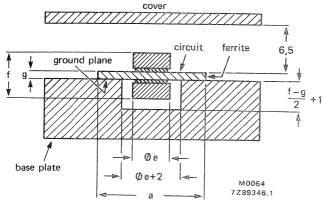




MOUNTING AND INTERCONNECTION IN MIC HOUSINGS

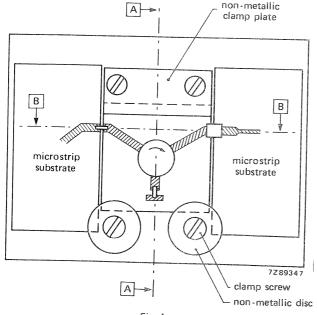
Dimensions in mm

All devices are rectangular to facilitate insertion into associated circuitry.



This figure gives the size of the recess in the base-plate and the height of the cover, assuming these parts are made of non-magnetic material. Increase these dimensions if magnetic material is used.

Fig. 3.



Two methods of mounting an isolator between MIC substrates:

o top:

mounting the isolator independent of the

MIC substrates using a non-metallic clamp-

plate.

bottom: clamping the isolator to the MIC substrates

using non-metallic (e.g. nylon) discs.

The figure also shows two ways of making the electrical connections:

left:

gold beam bonding

right:

pressure contact.

Fig. 4.

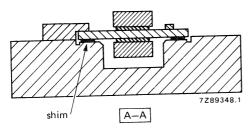


Fig. 5.

The cross-section through A-A (Fig. 4) shows again the clamp-plate mounting. The figure also shows how to obtain a good ground connection to the base plate by using a shim of ductile condicting material (such as indium). A shim provides other advantages too, notably:

- by choosing the proper thickness, it can be used to align the isolator (or circulator) surface with the adjacent MIC substrate surface
- -its ductility reduces stresses within the substrates caused by differential expansion.
- it compensates for small surface irregularities in the base-plate.

A good ground contact can also be made using solder or conducting adhesives. These may introduce stresses, however, so they are not recommended. If the use of solder or adhesive cannot be avoided, use a low temperature process; i.e. for solder, 10 seconds at a maximum of 200 °C and for an adhesive, curing temperatures of less than 150 °C.

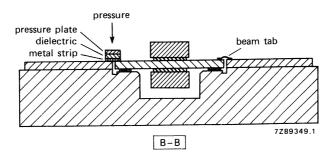


Fig. 6.

Cross section through B-B (Fig. 4) illustrating the connection techniques:

left: pressure contact

right: gold beam bond, which can be made ultrasonically or thermosonically, or by thermo-

compression.

Careful milling is essential (rectangular and no burrs). Air gaps should be minimized but should not be less than 25 μ m at room temperature.

Note: the linear expansion coefficient of ferrite is about 1 x 10⁻⁵ /OC.



ISOLATORS AND CIRCULATORS

Isolators and circulators are key elements in modern u.h.f. and microwave engineering. Their fundamental property of non-reciprocity is capable of simplifying the construction and improving the stability, efficiency and accuracy of radar, communication and testing systems.

The devices contain a core of ferrite material biased by a static magnetic field. This field orients the electron spins within the ferrite to produce a gyromagnetic effect. The non-reciprocal behaviour occurs when an r.f. signal, applied perpendicular to the biasing field, interacts with the precessing electrons to set up a standing-wave pattern within the core.

ISOLATORS

An isolator is a passive non-reciprocal 2-port device which permits r.f. energy to pass through it in one direction whilst absorbing energy in the reverse direction.

CIRCULATORS

A circulator is a passive non-reciprocal device with three or more ports. Energy introduced into one port is transferred to an adjacent port, the other ports being isolated. Although circulators can be made with any number of ports, the most commonly used are 3-port and 4-port ones, the symbols for which are given in Figs 1 and 2.

3

Fig. 1 Symbol for 3-port circulator.

Fig. 2 Symbol for 4-port circulator.

Energy entering into port 1 emerges from port 2; energy entering into port 2 emerges from port 3, and so on in cyclic order.



GENERAL

TERMS AND DEFINITIONS

Frequency range

This is the range within which the isolator or circulator meets the guaranteed specification.

Isolation

In an isolator, isolation is the ratio, expressed in dB, of the input power to the output power for signal injection in the reverse direction (matched source and load).

In a circulator, isolation is the ratio, expressed in dB, of the power entering a port to the power scattered into the adjacent port on the side opposed to the normal circulation (matched source and the other ports correctly terminated).

Insertion loss

The attenuation that results from including the device in the transmission system. It is given as a power ratio, expressed in dB, which compares the situation before and after the insertion of an isolator or circulator.

Maximum power

In an isolator, the maximum power is the largest power that may be passed through it in the forward direction into a load with a v.s.w.r. of 2. This power value must not be exceeded.

In a circulator, the maximum power is the largest power it can handle at sea level and at maximum ambient temperature when one port is terminated with a mismatch giving a v.s.w.r.of 2, whilst the next port is matched with a v.s.w.r. of 1,2 or less. This power value must not be exceeded. If the mismatch of the load is expected to exceed a v.s.w.r. of 2, a circulator of higher power handling capacity should be used.

For coaxial circulators, the maximum power is the maximum continuous-wave power unless a maximum peak power is separately stated. This is the power as defined by the CCIR signal standard and is given for circulators at the v.h.f. and u.h.f. television frequencies. If this value is exceeded the circulator can be damaged by arcing in its internal transmission structure. Power values are valid for one signal passage only. If more than one signal passes through the circulator, the peak power of the combined signal should not exceed the indicated maximum peak sync power.

Temperature range

The ambient temperature range within which isolators and circulators function to specification. (When necessary, special temperature compensation is built in for circulators.) Circulators still function outside the temperature range but their electrical behaviour may then be far outside the guaranteed specifications. However, no permanent damage can be expected unless a large temperature rise is caused by excessive power handling.

The storage temperature of isolators may be from -40 to + 125 °C unless otherwise specified in the data.



CAUTIONARY NOTE

Isolators and circulators have internal magnetic fields that are carefully adjusted for optimum operation, they should not, therefore, be subjected to strong external magnetic fields.

QUALITY GUARANTEE

Subject to the Conditions of Guarantee the Manufacturer guarantees that isolators/circulators supplied to the purchaser meet the specifications published in the Manufacturer's Data Handbook and are free from defects in material and workmanship.

Under this guarantee the Manufacturer will within one year from the date of shipment to the original purchaser, repair or replace at the Manufacturer's option, free of charge, any isolator/circulator proved by the Manufacturer's inspection to be thus defective.

STANDARD TEST SPECIFICATIONS

Initial measurements

These measurements have been carried out at room temperature and at the extreme temperatures, with a power level not exceeding 10 mW.

Tropical test

This test has been carried out completely in accordance with IEC 68 test D, accelerated damp heat. This test begins with the temperature at 55 ± 2 °C and R.H. at 95 to 100% for a period of 16 hours, followed by a period of 8 hours with the temperature at ± 25 °C and R.H. 80 to 100% to complete the 24-hour cycle: the test consists of 6 uninterrupted cycles.

Vibration test

This test has been carried out completely in accordance with MIL-STD-202D, method 201A: frequency range 10 to 55 to 10 Hz for 2 hours in each of the X, Y and Z directions, with a total excursion of 1,5 mm.

Thermal shock test

This test has been carried out completely in accordance with MIL-STD-202D, method 107C under condition A: 5 cycles with extreme temperatures of -55 °C and +85 °C; each cycle of 1 hour's duration.

Mechanical shock test

This test has been carried out in accordance with MIL-STD-202D, method 213A under condition G: peak value 100 g, durations 6 ms, and also with extreme peak values up to 800 g, duration approximately 1 ms for each device, referring to the results of the drop test.

Drop test

This test has been carried out in accordance with ISO 2248, part IV: packaging complete, filled transport packages, vertical impact.

R.F. power test

The devices have been tested in accordance with the definition of maximum power in the Data Handbook (v.s.w.r. = 2). The ambient temperature of 25 °C was increased to the maximum operating temperature and the duration of the test was 1 hour for each device.



GENERAL

Final measurements

On completion of the above tests final measurements were carried out at a temperature of ± 25 °C and with a power level not exceeding 10 mW. The results of these tests should be within the guaranteed values.

Dimensions and visual appearance

These have been checked in accordance with the published data.

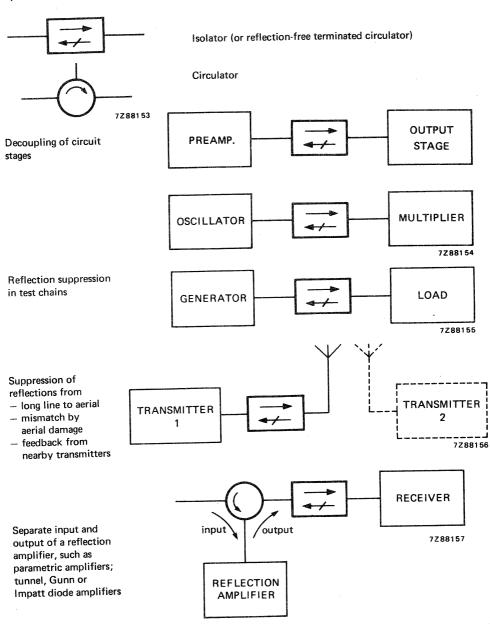
Note

On request, different tests and/or additional tests to those above can be carried out.

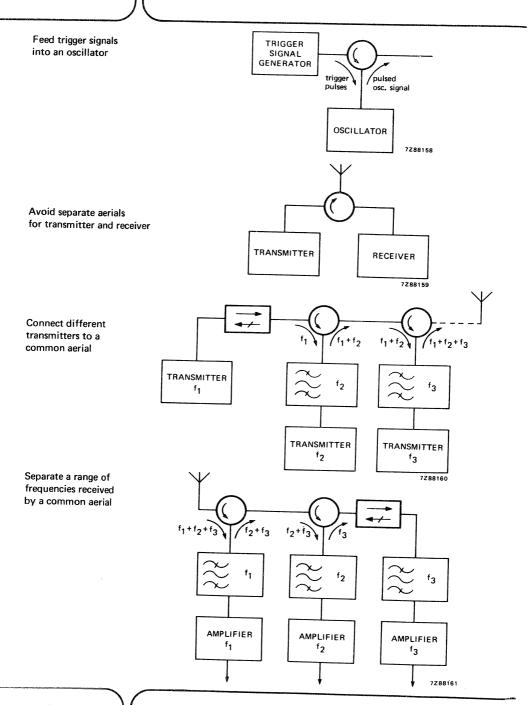


APPLICATIONS

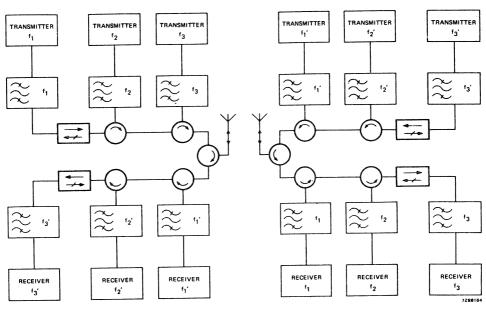
Symbols



GENERAL

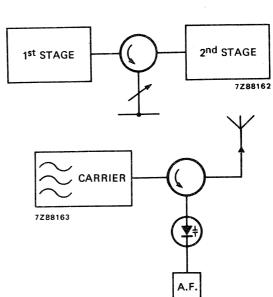


Signal combination and separation used together in a frequency-multiplexed, multichannel transceiver system



Variable phase shifters with a variable short-circuit

Phase modulation with a variable capacitance diode as a variable reactance



CATALOGUE NUMBER REFERENCE LIST

Waveguide types	5			Coaxial types (c	ontinued))	
catalogue number	frequence range (M	•	application	catalogue number	frequence range (M	су	application
2722 161 01101	4600 to	5000	0 micr. com.	2722 162 0155	1 470 to	. 600	TV IV/V
01191	5925		micr. com.	01559	., .,		
01211	8500	9600	X-band radar	0156			mob./fixed com. TV IV/V
01222	8500		X-band radar	01572			mob./fixed com.
01231	6825		micr. com.	01582	1	600	TV IV/V
01251			micr. com.	01592	590		TV IV/V
01261	1		X-band radar	01601	į.		TV IV/V
01291			micr. com.	01612	710		TV IV/V
01361	1,	9600	X-band radar	01632	1		TV IV/V
01531	10025	10325	X-band radar	01642	1		TV IV/V
02071	8200		micr. com.	01651	600	800	TV IV/V
02211			micr. com.	01662	710		TV IV/V
02232	3800		micr. com.	01811	4000		gen. purp.
02242			micr. com.	01822	7000	12400	gen. purp.
02252	3800	4200	micr. com.	01851	200		TV III
02262	3400	3800		01861	173	204	TV III
02311	6425		micr. com.	01871	160	178	mob./com.
02321	7125		micr. com.	01881	200		TV III
04001	5925	6425		01891	173	204	TV III
04051	6425		micr. com.	01901	160	178	mob./com.
04061	7125		micr. com.	01931	225	i	mob./fixed com.
2722 163 02004	2425	2475	ind. heating	01941	270	330	mob./fixed com.
02005	2425	2475	ind. heating	01951	330		mob./fixed com.
02024	2350		ind. heating	01981	710	860	TV IV/V
02025	2350	2400	ind. heating	02071	3000	6000	gen. purp.
Coaxial types				02091	2000	1	gen. purp.
				02101	2000		gen. purp.
catalogue	frequency		application	02111	4000		gen. purp.
number	range (MH	lz)		02122	7000	12400	gen. purp.
2722 162 01121	470 to	600	T) (1) () (02221	12000	18000	gen. purp.
01131	590		TV IV/V	02231	7900	10200	gen. purp.
01141	710		TV IV/V TV IV/V	02471	4200	4400	navigation
01261	470			02492	1427		micr. com.
01271	710		TV IV/V	02501	8900		micr. com.
[- 1	TV IV/V	02521	1470		micr. com.
01281	590		TV IV/V	02531	1590	1800	nicr. com.
01331	600		TV IV/V	02541	1760		nicr. com.
01491	2000		gen. purp.	02551	1890		nicr. com.
01501	2000		gen. purp.	02571	1700		nicr. com.
01511	3000	6000	gen. prup.	02581	1700		nicr. com.



Isolators and circulators

nuedi	•
	nued)

Coaxial types (co	Coaxial types (continued)										
catalogue number	frequency range (MH	z)	application	catalogue number		frequence range (N		application			
2722 162 02591 02601 02631 02641 02651	1900 to 1900 1470 1590 1760	2300 1620 1800	micr. com. micr. com. micr. com. micr. com. micr. com.	1	03831 03841 03851 03971 04031	156,9 to 157,9 165,4 600 3800	163,1 170,6 800	mob./fixed com. mob./fixed com. mob./fixed com. TV IV/V micr. com.			
02661 02691 02701 02711 02721	1890 470 600 400 83	600 800 470 84			04041 04051 04061 05001 05171	4400 1700 1900 138 600	2100 2300 141 960	micr. com. micr. com. micr. com. mob./fixed com. mob./fixed com.			
02731 02741 02751 02851 02861	73 790 600 460 86,5	800 468 87,5	mob./fixed com. TV IV/V mob./fixed com. mob./fixed com.	Isoductors catalogue number	06011	frequen	су	mob./fixed mob.			
02901 02911 02921 02931 02951	138 72 510 406 144,5	514 414	mob./fixed com. mob./fixed com. mob./fixed com. mob./fixed com. mob./fixed com.	2722 162	09001 09011 09021	68 to 140 230	150 260 470	i .			
02961 02981 03001 03011 03141	153,5 450 470 590 470	458 600 720	mob./fixed com. mob./fixed com. TV IV/V TV IV/V								
03151 03171 03181 03191 03201	600 225 225 600 590	270 270 800	TV IV/V mob./fixed com. mob./fixed com. TV IV/V TV IV/V								
03211 03261 03263 03301 03371	790 12000	1000 1000 18000	TV IV/V TV IV/V mob./fixed com. gen. purp. mob./fixed com.		,						
03411 03421 03431 03441 03591	270 3800 4400	330 4200 5000	mob./fixed com. mob./fixed com. micr. com. micr. com. navigation								
03722 03732 03802 03811 0382	2 225 2 1427 790	400 1535 1000	mob./fixed com. mob./fixed com micr. com. mob. com. TV IV/V								



MOBILE & FIXED RADIO COMMUNICATION: COAXIAL

frequency	circulator (c)	max. c.v	v. power		isola	ition
range (1,3) MHz	isolator (i)	forw. W	refl. W	catalogue number	min. dB	typ dB
72-73	i	25	20	2722 162 02911	20	23
73-74	i	25	20	02731	20	23
83-84	i	25	20	02721	20	23
86,5-87,5	i	25	20	02861	20	23
138-141	i	25	20	02901	22	24
	С	110		05001	22	24
144,5-147,5	i	25	20	02951	22	24
153,5-156,5	i	25	20	02961	22	24
156,9-162,1	С	110		03831	22	24
157,9-163,1	С	110		03841	22	24
165,4-170,6	С	110		03851	22	24
160-178	С	500		01871	20	24
	С	1000		01901	20	24
225-400	, c	60		03732	16	19
	c	60		03722	16	19
225-270	С	150		01931	18	21
	С	500		03171	20	24
	С	1000		03181	20	24
270-330	С	60		03421	18	21
000 400	С	150		01941	. 18	21
330-400	С	150		01951	18	21
400-470	i	25	20	02711	20	25
	С	100		03411	20	25
	С	300		01572	20	25
406-414	ic (4)	70	70	02931	45	55
450-458	ic (4)	70	70	02981	45	55
460-468	ic (4)	70	70	02851	45	55
462-468	C	60	60	01555	25	30
510-514	ic (4)	70	70	02921	45	55
600-960	C .	10		05171	16	20
	i	10	1	06011	16	20
790-1000	C	100		03811	20	25
	i	50	10	02741	20	25
	C -	100		03261	20	25
	С	100		03263 (5)	20	25

Notes

- 1. Other frequency ranges and other connectors are available on request.
- 2. If the devices are air cooled, dry-air should be used at a pressure of 250 Pa and with a maximum intake temperature of 40 °C. The connector temperature should then not exceed 55 °C.
- 3. For tunable devices see "ISODUCTORS".
- 4. "ic" denotes a 4-port device with one port terminated with a matched load.
- 5. Type 2722 162 03263 is an ultra-low-noise version of type 2722 162 03261.
- 6. Types 2722 162 05171 and 2722 162 06011 are 34 \pm 1 mm thick.



insertio	n loss	V.S.V	v.r.	temperature	connector	dimensions	mass
max. dB	typ. dB	max.	typ.	oC range	type (1)	see Fig. no.	approx.
0,7	0,6	1,25	1,2	0 to 55	Nfem	C17	350
0,7	0,6	1,25	1,2	0 to 55	Nfem	C17 C17	350 350
0,7	0,6	1,25	1,2	0 to 55	Nfem		350 350
0,7	0,6	1,25	1,2	0 to 55	Nfem	C17	
0,4	0,3	1,2	1,15	0 to 55	Nfem	C17	350
0,4	0,3	1,2	1,15	0 to 55	Nfem	C14	350
0,4	0,3	1,2	1,15	0 to 55	Nfem	C17	350
0,4	0,3	1,2	1,15	0 to 55	Nfem	C17	350
0,4	0,3	1,2	1,15	0 to 55	Nfem	C14	350
0,4	0,3	1,2	1,15	0 to 55	Nfem	C14	350
0,4	0,3	1,2	1,15	0 to 55	Nfem	C14	350
0,35	0,3	1,25	1,15	-10 to 60	Nfem	C1	2100
0,35	0,3	1,25	1,15	-10 to 40 (2)	HF7/16fem	C3	2150
	0,9	1,5	1,3	-40 to 80	Nfem	C8	400
1,4	0,9	1,5	1,3	-40 to 80	SMAfem	C9	380
1,4	0,9	1,35	1,25	0 to 70	Nfem	C6	725
0,35 0,35	0,2	1,25	1,15	-10 to 60	Nfem	C1	2100
0,35	0,3	1,25	1,15	-10 to 40 (2)	HF7/16fem	C3	2150
0,35	0,3	1,35	1,25	0 to 70	SMAfem	C7	725
0,35	0,2	1,35	1,25	0 to 70	Nfem	C6	725
0,35	0,3	1,35	1,25	0 to 70	Nfem	C6	725
	0,35	1,25	1,15	-10 to 60	Nfem	C17	350
0,5 0,5	0,35	1,25	1,15	-10 to 60	Nfem	C14	400
0,35	0,20	1,25	1,15	-10 to 60	Nfem	C4	1200
0,33	0,20	1,25	1,2	10 to 60	Nfem	C19	800
0,8	0,5	1,25	1,2	-10 to 60	Nfem	C19	800
0,8	0,5	1,25	1,2	-10 to 60	Nfem	C19	800
0,5	0,3	1,2	1,1	10 to 60	Nfem	C14	400
0,8	0,5	1,25	1,2	-10 to 60	Nfem	C19	800
	0,8	1,4	1,25	-25 to 65	SMAfem	C16 (6)	400
1,3	0,8 0,8	1,4	1,25	-25 to 65	SMAfem	C18 (6)	400
1,3 0,5	0,8	1,25	1,14	-10 to 60	SMAfem	C16	400
0,5 0,5	0,35	1,25	1,15	-25 to 65	SMAfem	C18	400
0,5	0,33	1,25	1,14	-10 to 60	Nfem	C14	400
0,5	0,3	1,25	1,14	-10 to 60	Nfem	C14	400



TELEVISION

£			forward			
frequency	circulator (c)	-	ower	catalogue number	isola	tion
range MHz	isolator (i)	c.w.	peak		min.	typ
IVITIZ		W	W		dB	dE
Band III						
173-204	С	500	1800	2722 162 01861	20	
	С	1000	1800	01891	20	24
200-230	С	500	1800	01851	20	24
	С	1000	1800	01881	20	24 24
Bands IV and V						
470-600	i	10	20	20004		
	С	100	200	02691	20	25
	c	300	500 500	01551	20	25
	c	300	500 500	01582	20	25
	c	500		01632	20	25
	c	500	900	01121	22	24
	C	2000	900	03141	20	24
	C		2000	01261	20	24
200 000		2000	8000	03001	20	25
600-800	į į	10	20	02701	20	25
	i	10	20	02751	20	25
	С	50	100	03821	20	25
	С	100	200	01561	20	25
	С	100	200	03971	20	25
	С	300	500	01601	20	25
	С	300	500	01651	20	25
	С	500	900	03191	22	24
	С	500	900	03151	20	24
	С	2000	2000	01331	20	24
90-720	С	300	500	01592	20	25
	С	300	500	01642	20	25
	С	500	900	01131	22	24
	С	500	900	03201	20	24
	С	2000	2000	01281	22	27
	С	2000	8000	03011	20	25
10-860	С	300	500	01612	20	25
	С	300	500	01662	20	25 25
	С	500	900	01002	22	25 24
1	С	500	900	03211	20	24 24
İ	С	2000	2000	01271	20	
	С	2000	8000	01981	20	26 25
90-1000	С	100	200	03261	20	20

Notes for TV band III

- 1. EIA 7/8-inch connectors can be provided on request.
- 2. If the devices are air cooled, dry-air should be used at a pressure of 250 Pa and with a maximum intake temperature of 40 $^{\rm o}$ C. The connector temperature should then not exceed 55 $^{\rm o}$ C.



Isolators and circulators

insertio	n loss	v.s.w	.r.	temperature	connector	dimensions	mass
max. dB	typ. dB	max.	typ.	oC Lange	type (1)	see Fig. no.	approx.
0,35	0,3	1,25	1,15	-10 to 60	Nfem	C1	2100
0,35	0,3	1,25	1,15	-10 to 40 (2)	HF7/16	C3 C1	2150 2100
0,35	0,3	1,25	1,15	-10 to 60 -10 to 40 (2)	Nfem HF7/16	C3	2150
0,35	0,3	1,25	1,15	-10 to 40 (2)	111 77 10	00	2100
0,5	0,35	1,25	1,15	-10 to 60	Nfem	C17 C14	400
0,5	0,35	1,25	1,15	-10 to 60	Nfem	C14 C4	400 1200
0,35	0,20	1,25	1,15	-10 to 60	Nfem HF7/16	C5	1200
0,35	0,20	1,25	1,15	−10 to 60 −10 to 70	Nfem	C1	2080
0,35	0,25	1,20 1,25	1,15 1,15	-10 to 70	HF7/16	C2	2200
0,35	0,25 0,17	1,25	1,13	-10 to 70 -10 to 40 (2)	HF7/16	C3	2200
0,35 0,4	0,17	1,25	1,15	5 to 65 (2)	EIA1 5/8"	C37	3900
		1,25	1,15	-10 to 60	Nfem	C17	400
0,5	0,35 0,35	1,25	1,15	-10 to 60	SMAfem	C18	400
0,5 0,5	0,35	1,25	1,15	-10 to 60	SMAfem	C16	400
0,5	0,35	1,25	1,15	-10 to 60	Nfem	C14	400
0,5	0,35	1,25	1,15	-10 to 60	Nmale	C15	400
0,35	0,25	1,25	1,15	-10 to 60	Nfem	C4	1200
0,35	0,25	1,25	1,15	-10 to 60	HF7/16	C5	1200
0,35	0,25	1,20	1,15	-10 to 70	Nfem	C1 C2	2080 2200
0,35	0,25	1,25	1,15	-10 to 70	HF7/16 HF7/16	C3	2200
0,35	0,17	1,25	1,13	-10 to 40 (2)			
0,35	0,20	1,25	1,15	-10 to 60	Nfem	C4 C5	1200 1200
0,35	0,20	1,25	1,15	-10 to 60	HF7/16	C5 C1	2080
0,35	0,25	1,20	1,15	–10 to 70 –10 to 70	Nfem HF7/16	C2	2200
0,35	0,25	1,25	1,15	-10 to 70 -10 to 40 (2)	HF7/16	C3	2200
0,35	0,15	1,20 1,25	1,10 1,15	5 to 65 (2)	EIA1 5/8"	C37	3900
0,4	0,30			-10 to 60	Nfem	C4	1200
0,35	0,20	1,25	1,15	-10 to 60	HF7/16	C5	1200
0,35	0,25	1,25	1,15 1,15	-10 to 70	Nfem	C1	2080
0,35	0,25	1,20 1,25	1,15	-10 to 70	HF7/16	C2	2200
0,35	0,25 0,16	1,25	1,15	-10 to 40 (2)	HF7/16	C3	2200
0,35 0,4	0,10	1,25	1,15	5 to 65 (2)	EIA1 5/8"	C37	3900
0,5	0,30	1,25	1,14	-10 to 60	Nfem	C14	400

Notes for TV band IV/V

- 1. Other connectors can be provided on request.
- 2. If the devices are air cooled, dry-air should be used at a pressure of 250 Pa and with a maximum intake temperature of 40 °C. The connector temperature should then not exceed 55 °C.



MICROWAVE COMMUNICATION: COAXIAL

frequency	circulator (c)	max. c.v	w. power		isolat	ion
range (1) GHz	isolator (i)	forw. W	refl. W	catalogue number	min. dB	typ. dB
1,427-1,535	С	10	The state of the s	1722 162 03802	20	
	i	10	1	02492	20	23 23
1,470-1,620	i	1	1	02521	20	
	i	15	2	02631	20	23 23
1,590-1,800	i	1	1	02531	20	
	i	15	2	02641	20	23
1,760-1,940	i	1	1	02541	20	23
	i	15	2	02651	20	23
1,890-2,110	i	1	1	02551	20	23
	i	15	2	02661		23
1,700-2,100	i	15	2	02571	20	23
	i	15	2	02571	26	28
	cc (2)	30	-	04051	26	28
1,900-2,300	i	15	2		26	28
,,	i	15	2	02591	26	28
	cc. (2)	30	2	02601	26	28
3,8-4,2	C (2)	10		04061	26	28
0,0 1,2	cc (2)	10		03431	25	27
4,4-5				04031	25	27
4,4-3	C (2)	10		03441	25	27
7,99-10,2	cc (2)	10		04041	25	27
8,9-9,6	:	5	1	02231	20	22
0,8-8,0	1	5	1	02501	20	22

Notes



^{1.} Other frequency ranges and other connectors are available on request.

^{2. &}quot;CC" denotes a 4-port circulator.

insertio	n loss	v.s.v	v.r.	temperature	connector	dimensions	mass
max. dB	typ. dB	max.	typ.	range °C	type (1)	see Fig. no.	approx.
0,4	0,3	1,25	1,15	0 to 55	Nfem	C14	400
0,4	0,3	1,25	1,15	0 to 55	Nfem	C17	400
0,4	0,3	1,25	1,15	0 to 55	solder pin	C24	
	0,3	1,25	1,15	0 to 55	SMAfem	C25	
0,4 0,4	0,3	1,25	1,15	0 to 55	solder pin	C24	
	0,3	1,25	1,15	0 to 55	SMAfem	C25	
0,4	0,3	1,25	1,15	0 to 55	solder pin	C24	
0,4	0,3	1,25	1,15	0 to 55	SMAfem	C25	
0,4	0,3	1,25	1,15	0 to 55	solder pin	C24	
0,4	0,3	1,25	1,15	0 to 55	SMAfem	C25	
0,4	0,3 0,2	1,11	1,09	0 to 55	SMAfem + m	C26	
0,25	0,2	1,11	1,09	0 to 55	SMAm + fem	C26	
0,25	•	1,11	1,09	0 to 55	SMAfem + m	C27	800
0,25	0,2	1,11	1,09	0 to 55	SMAfem + m	C26	
0,25	0,2	1,11	1,09	0 to 55	SMAm + fem	C26	
0,25	0,2	1,11	1,09	0 to 55	SMAfem + m	C27	800
0,25	0,2	1,12	1,10	-10 to 70	SMAfem	C31	110
0,25	0,2	1,12	1,10	-10 to 70	SMAfem	C32	220
0,25	0,2	1,12	1,10	-10 to 70	SMAfem	C31	110
0,25	0,2	1,12	1,10	-10 to 70	SMAfem	C32	220
0,25	0,2	1,12	1,23	-10 to 70	SMAfem	C33	30
0,4 0,4	0,35 0,35	1,25	1,23	-10 to 70	SMAfem	C34	30



NAVIGATION: COAXIAL

frequency range GHz	circulator (c)		vard power		isolation	
	13018(01 (1)	c.w. W	peak W	catalogue number	min. dB	typ. dB
0,96-1,225 4,2-4,4	c i	100 10	1000	2722 162 03591 02471	20 23	22

GENERAL PURPOSE, OCTAVE BANDWIDTH: COAXIAL

frequency	circulator (c)	max. c.w			isola	tion
range GHz	isolator (i)	forw. W	refl. W	catalogue number	min. dB	typ. dB
2-4	С	50		2722 400 04404		
	C	50		2722 162 01491	20	24
			_	01501	20	24
	!	50	5	02091	20	24
	1	50	5	02101	20	24
3-6	С	20		01511	20	
	í	20	5	02071	20	27
4-8	c '	10				27
	i	10	1	01811	20	23
7.40.4	•		,	02111	20	27
7-12,4	С	10		01822	20	23
	i	10	1	02122	20	
7,99-10,2	1	5			20	25
8,9-9,6			1	02231	20	22
	!	5	1	02501	20	22
12-18	С	5		03301		
	l i	5	1		18	22
				02221	18	22

INDUSTRIAL HEATING: WAVEGUIDE

frequency range	circulator (c)	max. c.w	•		isolation	
GHz	13018(0) (1)	forw. kW	refl. kW	catalogue number (1)	min. dB	typ. dB
2,35-2,4	i	6,5	6,5	2722 163 02024	20	26
2,425-2,475	i(L) i	6,5 6.5	6,5 6.5	02025	20	26
	i(L)	6,5	6,5	02004 02005	20 20	26 26

Notes for industrial heating

- 1. These types are water cooled; air cooled versions for max. 3 kW can be made available on request.
- 2. Water inlet temperature: 10 to 40 $^{\rm o}$ C. Water outlet temperature max. 50 $^{\rm o}$ C. Storage temperature: -10 to 70 °C.
- 3. In case of short-circuited output, v.s.w.r. max. 1,5.



insertior	n loss	v.s.v	v.r.	temperature	connector	dimensions	mass
max. dB	typ. dB	max.	typ.	oC range	type	see Fig. no.	approx.
0,5 0,3	0,35	1,25 1,2	1,20	-10 to 60 -55 to 90	Nfem SMAfem	C14 C30	460 110
insertion	typ.	v.s.v max.	v.r. typ.	temperature range °C	connector type	dimensions see Fig. no.	mass approx. g
0,5 0,5 0,5	0,35 0,35 0,35 0,35	1,25 1,25 1,25	1,15 1,15 1,1	10 to 70 10 to 70 10 to 70 10 to 70	Nfem SMAfem Nfem SMAfem	C10 C11 C12 C13	300 300 300 300
0,5 0,5 0,5	0,35 0,3 0,3	1,25 1,25 1,25	1,1 1,1 1,1	−10 to 70 −10 to 70	SMAfem SMAfem	C20 C21 C22	120 120 100
0,5 0,5 0,6	0,3 0,3 0,4	1,25 1,25 1,25	1,15 1,15 1,15	−10 to 70 −10 to 70 −10 to 70	SMAfem SMAfem SMAfem	C23 C28	100 60
0,6 0,4	0,35 0,35	1,25 1,25 1,25	1,12 1,23 1,23	−10 to 70 −10 to 70 −10 to 70	SMAfem SMAfem SMAfem	C29 C33 C34	60 30 30
0,4 0,6 0,6	0,35 0,35 0,35	1,25 1,25	1,2 1,2 1,2	−10 to 70 −10 to 70	SMA fem SMA fem	C35 C36	20 20
and the second s			.w.r.	temperature	flange	dimensions	mass
insertion max. dB	on ioss typ. dB	max. (3)	typ.	range (2)	IEČ	see Fig. no.	approx g
0,4 0,4	0,3 0,3	1,2 1,2	1,1 1,1		PDR26 monitor output	W13 W14 W13	4700 4700 4700

1,1

1,1

1,2

1,2

0,2

0,2

0,3

0,3



4700

W14

output

Nfem

MICROWAVE COMMUNICATION: WAVEGUIDE

frequency	circulator (c)		v. power		isola	ition
range GHz	isolator (i)	forw. W	refl. W	catalogue number	min. dB	typ. dB
3,4-3,8	С	50	The state of the s	2722 161 02242	00	
	cc	50			28	35
3,8-4,2	C	50		02262	28	35
-,,_	CC			02232	28	35
4,6-5,0	:	50		02252	28	35
	1	10	1	01101	30	35
5,925-6,425	С	200		02211	28	35
	i	200	3	04001	28	35
	i	20	2	01191		
6,425-7,125	С	200		02311	30	35
	i	200	3		28	35
	1	200		04051	28	35
6,825-7,425			2	01251	30	35
7,125-7,750	1	20	2	01231	30	35
7,125-7,750	C	200		02321	28	35
	1	200	3	04061	28	35
	} i	20	2	01291		
8,2-11,2	C	50	_	02071	30	33
				02071	22	30

X-BAND RADAR: WAVEGUIDE

frequency range	circulator (c)	max. c.w. power			isolation	
GHz	isolator (I)	forw. W	refl. W	catalogue number	min. dB	typ. dB
8,5-9,6	i	1		2722 161 01222 (1)	15	
	1	5		01361	30	
	1:	10		01211	30	
10,025-10,325	10		01261	55		
	1	ı		01531	20	

Notes for X-band radar

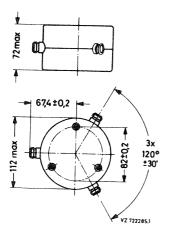
1. Type 2722 161 01222 has a special rugged construction; spread of phase shift $\pm\ 5^{o}.$



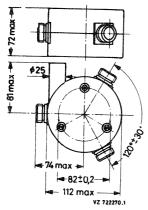
insertion loss		v.s.w.r.		temperature	flange	dimensions	mass
max. dB	typ. dB	max.	typ.	oC range	IEC	see Fig. no.	approx.
	0.15	1,08	1,04	0 to 55	UER40	W1	750
0,2	0,15	1,08	1,04	0 to 55	UER40	W2	1500
0,4	0,15	1,08	1,04	0 to 55	UER40	W1	750
0,2	0,15	1,08	1,04	0 to 55	UER40	. W2	1500
0,4	0,13	1,05	1,03	10 to 40	UER48	W7	
0,5 0,2	0,30	1,08	1,04	0 to 55	UER70	W5	
0,2	0,15	1,08	1,04	0 to 55	UER70	W6	
0,2	0,15	1,05	1,03	-10 to 70	UER70	W8	1450
0,3	0,15	1,08	1,04	0 to 55	UER70	W5	
0,2	0,15	1,08	1,04	0 to 55	UER70	W6	
0,2	0,15	1,05	1,03	-10 to 70	UER70	W8	1450
0,3	0,15	1,05	1,03	-10 to 70	UER70	- W8	1450
	0,15	1,08	1,04	0 to 55	UER70	W5	
0,2 0,2	0,15	1,08	1,04	0 to 55	UER70	W6	
0,2	0,13	1,05	1,03	-10 to 70	UER70	W8	1450
0,5 0,5	0,20	1,18	1,15	10 to 40	UBR100	W3	

insertior max. dB	n loss typ. dB	v.s. max.	w.r. typ.	range C	flange IEC	dimensions see Fig. no.	mass approx.
0,6 0,5 0,5 1,2 0,4		1,15 1,05 1,05 1,20 1,25		10 to 70 -10 to 70 -10 to 70 -10 to 70 -40 to 85	UBR100 UBR100 UBR100 UBR100 UBR100	W9 W10 W12 W11 W4	420 600

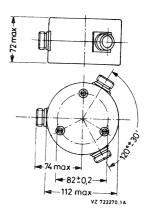




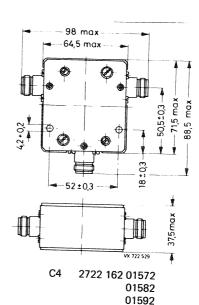
C1 2722 162 01121



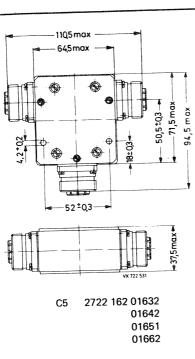
C3 2722 162 01261

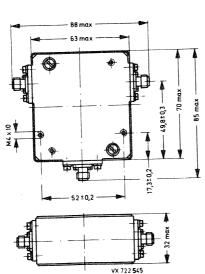


C2 2722 162 03141

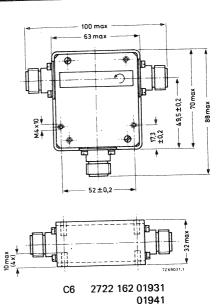


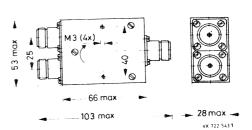






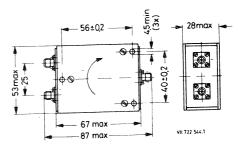
C7 2722 162 03421





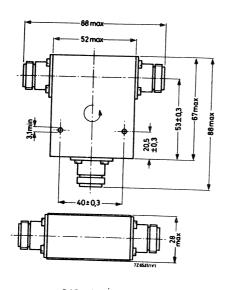
01951

C8 2722 162 03732

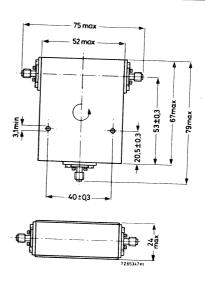


C9 2722 162 03722

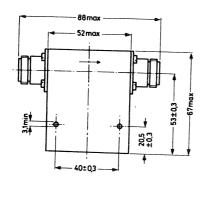




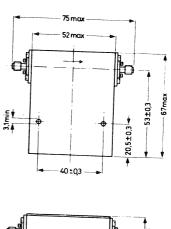
C10 2722 162 01491



C11 2722 162 01501



C12 2722 162 02091

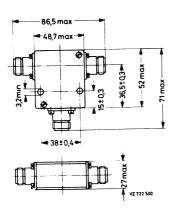


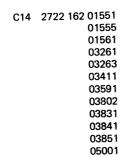


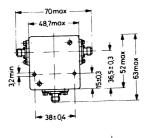
C13 2722 162 02101

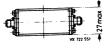


Isolators and circulators

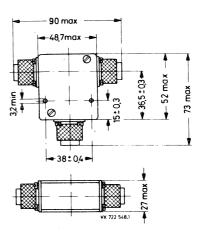








C16 2722 162 05171 03811 03821



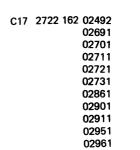
C15 2722 162 03971

86,5 max

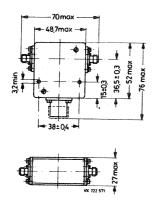
48,7 max

25,5 gg

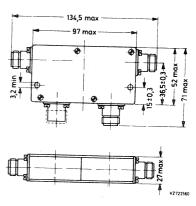
27,22 2672 - 38 ± 0,4



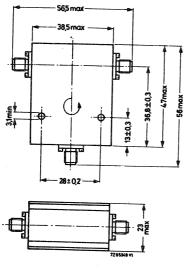




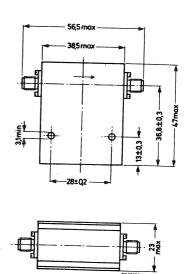
C18 2722 162 02741 02751 06011



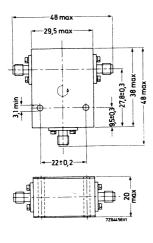
C19 2722 162 02851 02921 02931 02981



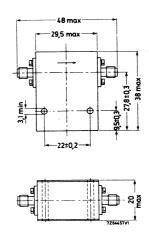




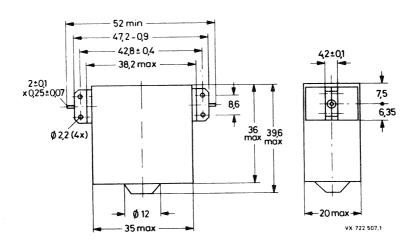
C21 2722 162 02071



C22 2722 162 01811

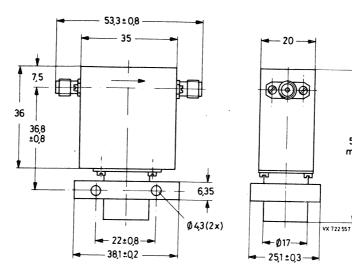


C23 2722 162 02111

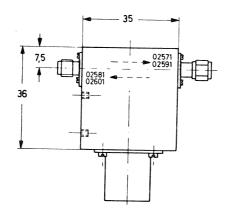


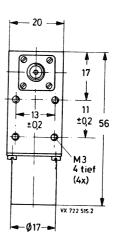
C24 2722 162 02521 02531 02541 02551





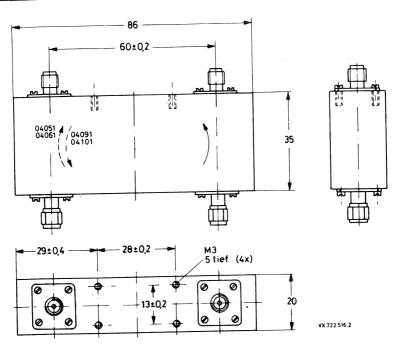
C25 2722 162 02631



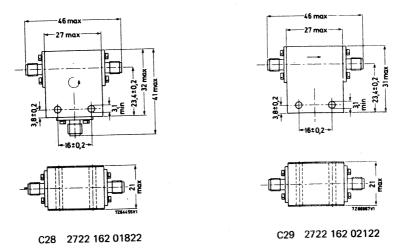


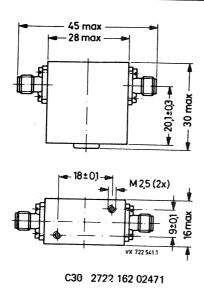
max

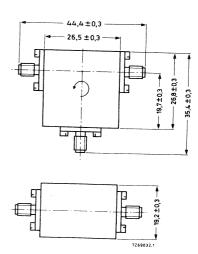
C26 2722 162 02571



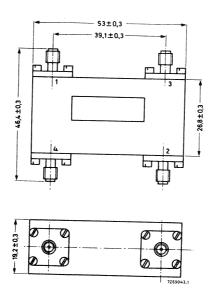
C27 2722 162 04051 04061







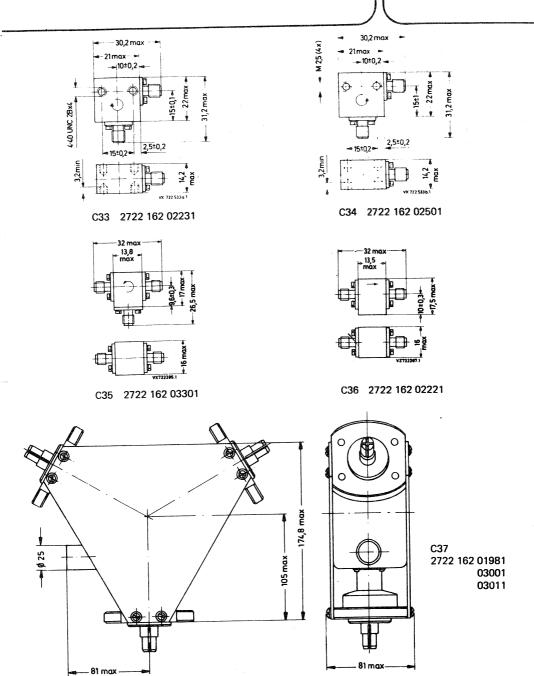
C31 2722 162 03431 03441



C32 2722 162 04031 04041

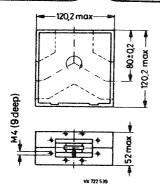


Isolators and circulators

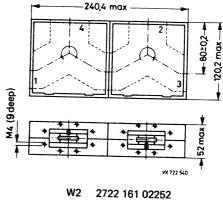


VX 722 550

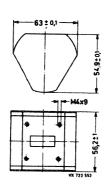
29



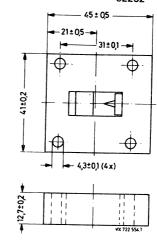
2722 161 02232 02242



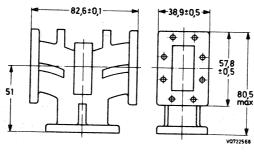
02262



W3 2722 161 02071

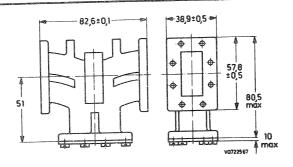


W4 2722 162 01531

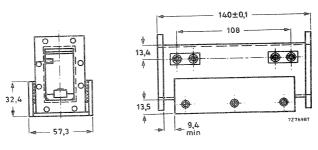


W5 2722 161 02211 02311 02321

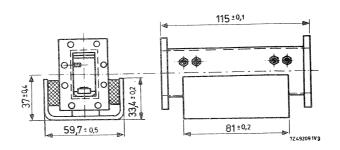




W6 2722 161 04001 04051 04061

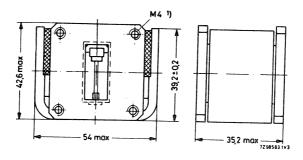


W7 2722 161 01101

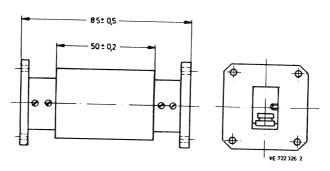


W8 2722 161 01191 01231 01251 01291

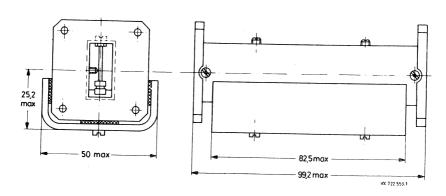




W9 2722 161 01222

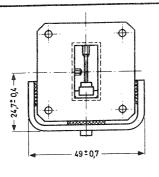


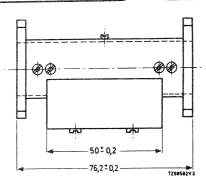
W10 2722 161 01361



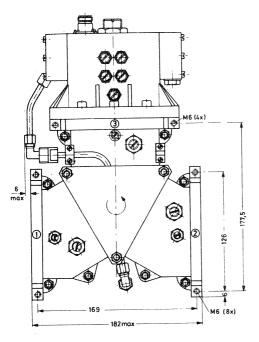
W11 2722 161 01261

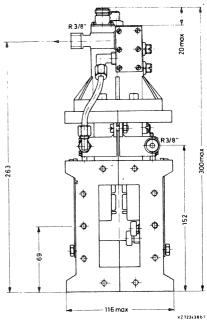


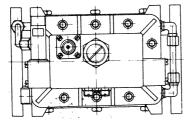




W12 2722 161 01211

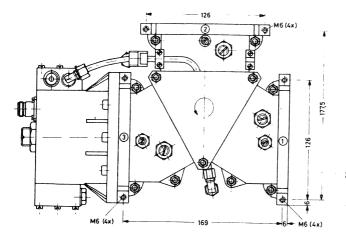


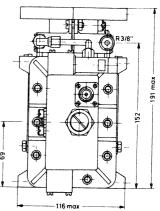


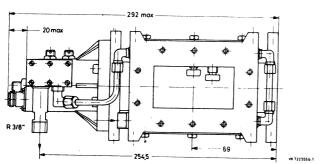


W13 2722 163 02004 02024









W14 2722 163 02005 02025



CONVERSION LISTS

alogue Number	Type Number
2,22 101	
01071	CL6201
01071	CL6240
01081	CL6202
01091	CL6203
01151	CL6210
01161	CL6214
* * * * *	CL6214
01171	CL6213
01181	CL6217
01191	CL6208
01211	CL6222
01221	CL6221
01231	CL6231
01241	CL6251
01251	CL6251
01261	
01271	CL6271
01291	CL6291
02081	CL5281
02091	CL5291
02101	CL5101
02191	CL5219
02231	CL5232
02261	CL5263
02271	CL5227
02281	CL5283
03001	CL5050
03011	CL5051
03031	CL5053
03041	CL5054
03051	CL5055
03061	CL5056
03081	CL5081
03091	CL5091

CONVERSION LISTS

AND THE PARTY OF T	
Catalogue Number 2722 162	Type Number
02091	CL6091
02101	CL6101
02111	CL6111
02121	CL6122
02221	CL6223
02231	CL6232
03171	CL5172
03181	CL5182
03261	CL5262
03301	CL5301
03411	CL5411
03431	CL5431
03441	CL5441
03591	CL5592
04031	CL5032
04041	CL5042

Catalogue Number 2722 163	Type Number
02004	CL6204
02024	CL6224



CONVERSION LISTS

e ber	Catalogue Number
27	2722 162 01121
028	2722 162 01121
5029	2722 162 01141
-5029 -5032	2722 162 04031
_5032 L5042	2722 162 04041
L5042 L5050	2722 161 03001
_5050 _5051	2722 161 03011
L5051 L5053	2722 161 03031
	2722 161 03041
CL5054 CL5055	2722 161 03041 2722 16 1 03051
CL5056	2722 161 03061
CL5056 CL5081	2722 161 03081
CL5091	2722 161 03091
CL5091	2722 161 02101
	2722 161 02101
CL5172	2722 162 03171
CL5182	2722 162 03181
CL5219	2722 161 02191
CL5227	2722 161 02271
CL5232	2722 161 02231
CL5261	2722 162 01261
CL5262	1
CL5263	2722 161 02261 2722 162 01271
CL5271	1
CL5281	2722 161 02081
CL5282	2722 162 01281
CL5283	2722 161 02281
CL5291	2722 161 02091 2722 162 03301
CL5301	2722 162 03301
CL5312	2722 162 01612
CL5322	2722 162 01622
CL5331	2722 162 01632
CL5332	2/22 102 01032

2722 162 01642

CL5342

2722 161 01101

CL6203

CONVERSION LISTS

Type	Catalogue
Number	Number
CL6204	2722 163 02004
CL6206	2722 161 01191
CL6210	2722 161 01151
CL6214	2722 161 01161
CL6215	2722 161 01171
CL6217	2722 161 01181
CL6221	2722 161 01221
CL6222	2722 161 01211
CL6223	2722 162 02221
CL6224	2722 163 02024
CL6231	2722 161 01231
CL6232	2722 162 02231
CL6240 CL6241	2722 161 01081
CL6251	2722 161 01241 2722 161 01251
CL6261	2722 161 01261
CL6271	2722 161 01271
CL6291	2722 161 01291



MISCELLANEOUS

MICROWAVE HORN ANTENNA

A general purpose X-band antenna for miniature radar systems. The unit gives a low v.s.w.r. and is of a strong cast construction.

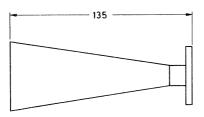
QUICK REFERENCE DATA

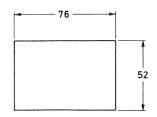
CHARACTERISTICS		
Frequency range	9.0 to 11	GHz
Gain	16	dB
Beam angle (both planes)	30	deg
v.s.w.r. max.	1.2	
MECHANICAL DATA		
Weight	160	g
Flange	UBR100 (UG135/U)	

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — ${\tt MICROWAVE}$ SEMICONDUCTORS

MECHANICAL DATA

Dimensions in mm





All dimensions in mm

D6006



January 1982

PARAMETRIC AMPLIFIER

A single-diode non-degenerate parametric amplifier designed for use as a low-noise pre-amplifier in microwave applications. It is supplied in a temperature stabilized enclosure with a solid state Gunneffect oscillator pump and integral power supply.

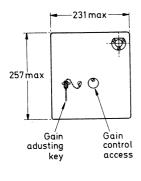
QUICK REFERENCE DATA

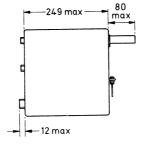
Power gain	20	dB
Tuning range min.	2.7 to 3.1	GHz
Noise figure max.	2.8	dB
Bandwidth	15	MHz
Input and output impedance	50	Ω
Mains supply	240 V, 2 A, 50 Hz	

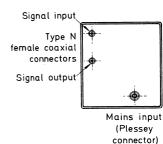
This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

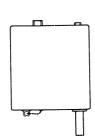
MECHANICAL DATA

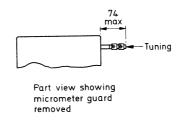
Dimensions in mm











D6574



RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC134)

Continuous r.f. input power		max.	100	mW
Input spike energy		max.	500	nJ
Mains supply voltage		max.	276	V _{ac}
Ambient operating temperature range		-	20 to +55	oC .
Storage temperature range			30 to +70	οС
CHARACTERISTICS (note 1)				
$T_{amb} = 25$ °C				
	min.	typ.	max.	
Power gain (recommended setting) (note 2)	_	20	_	dB
Operating frequency	2.7		3.1	GHz
Noise figure	MARKET .	2.6	2.8	dB
Bandwidth (note 3)	12		18	MHz
Input saturation level (note 4)	-35	32		dBm
Gain stability per hour		±0.1		dB
per day		±0.5		dB
Mains voltage supply limits	204	240	276	V _{ac}
MASS		5.4		kg

Notes

- 1. These are given for matched conditions.
- 2. The gain-set attenuator is adjusted with the hexagonal key provided.
- 3. Measured to the 3 dB points at a gain setting of 20 dB.
- 4. This is the input level at which the gain is compressed by 1 dB, at a gain setting of 20 dB.
- 5. The amplifier is designed for ease of maintenance; both the temperature control system and the Gunn oscillator power supply use field-replaceable plug-in boards.



JA1010

This information is derived from development samples made available for evaluation. It does not necessarily imply that the device will go into regular production.

X-BAND SOLID STATE LINEAR POWER FET AMPLIFIER

A solid state linear class-A amplifier for use as a driver amplifier for TWT power stages in radar equipment

QUICK REFERENCE DATA

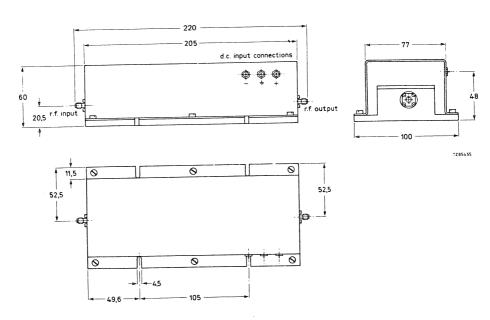
Frequency	8,5 to 9,6 GHz
Gain	32 ± 2 dB
Output power (1 dB compression)	>30 dBm

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS

MECHANICAL DATA

Outline drawing

Dimensions in mm



Input connector
Output connector

D.C. input

SMA female SMA female solder pins

OPERATING CONDITIONS

D.C. power supply 1,5 A \pm 12 V \pm 5% \pm 200 mA \pm 12 V \pm 5% Maximum r.f. input (damage level) \pm 20 dBm

ELECTRICAL CHARACTERISTICS

Frequency range 8,5 to 9,6 GHz Small signal gain 32 \pm 2 dB Gain variation over frequency range <1 dB

Gain variation over operating temp. range and

 \pm 5% variation of supply voltage $$<\pm 1\,\mathrm{dB}$$ Maximum input r.f. power (damage level) $$+20\,\mathrm{dBm}$$ Output power at 1 dB compression point $$>+30\,\mathrm{dBm}$$ Input and output impedance $$50\,\Omega$$ Input VSWR \$<1,5\$ Output VSWR \$<1,5\$ Spurious (other than IM) products, in a 1 MHz slot $$<-60\,\mathrm{dBm}$$

ENVIRONMENTAL CHARACTERISTICS

Operating temperature $-10 \text{ to } + 70 \text{ }^{\circ}\text{C}$ Maximum base plate temperature $+70 \text{ }^{\circ}\text{C}$ Storage temperature $-55 \text{ to } + 85 \text{ }^{\circ}\text{C}$ Relative humidity at $+40 \text{ }^{\circ}\text{C}$ 95%

Moisture resistance according to MIL-STD-202E, method 106D, omit step 7
Shock according to MIL-STD-202E, method 213E, cond. J

Vibration according to MIL-STD-202E, method 201A



YIG-TUNED OSCILLATORS

These oscillators consistor of a Gunn diode, a microstrip impedance transformer, a YIG sphere and electromagnetic coils. They are intended for use in wideband equipment for civil and military applications in frequency bands from 8 to 18 GHz.

QUICK REFERENCE DATA

type	frequency range GHz	guaranteed minimum output power over tuning range mW
YG1103	8 - 12,4	40
YG1104	10 - 15	20
YG1105	12 - 18	20

This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — MICROWAVE SEMICONDUCTORS.

POTENTIAL HAZARD-BERYLLIUM OXIDE

This device contains beryllium oxide, the dust of which is toxic. The device is entirely safe, provided that the beryllium oxide disc is not damaged. Care should be taken to ensure that all those who may handle, use or dispose of this device are aware of its nature and of the necessary safety precautions. In particular, it should never be thrown out with general industrial or domestic waste.

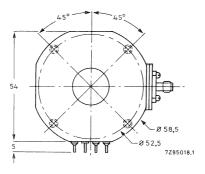


MECHANICAL DATA

48



12



--- 54

Fig. 1.

Connections:

1-2 Main coil

3-4 Fast coil

5 -V Gunn earth

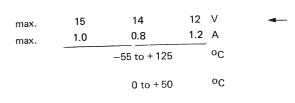
6 + V Gunn

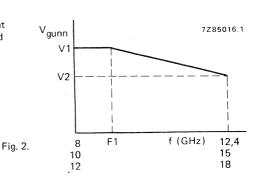
ELECTRICAL DATA		YG1103	YG1104	YG1105	
Frequency range		8 to 12,4	10 to 15	12 to 18	GHz
Linearity	typ.	± 2	± 3	± 3	‰
 Output power over tuning range, see Figs 5, 6 and 7, at 25 °C	min.	40	20	20	mW
Power variation in band, at 25 °C	max.	5	5	5	dB
Pulling (VSWR 1,5:1)	max.	15	15	15	MHz
Pushing	max.	20	20	20	MHz/V
Phase noise at 3 dBc	max.	50	50	50	kHz
Other parasitics	typ.	-40	-40	-40	dBc
Second harmonic	typ.	-20	-20	-20	dBc
Frequency drift from $0 \text{ to } +50 ^{\circ}\text{C}$	typ.	50	50	50	. 10 ⁻⁶ /°C
Sensitivity to external magnetic field	typ.	15	15	15	GHz/T
Hysteresis	typ.	10	12	15	MHz

OPERATING CONDITIONS

Supply voltage of Gunn diode
Supply current of Gunn diode
Storage temperature
Operating temperature, measured on
base plate of oscillator

To obtain optimum characteristics over the whole band, the supply voltage to the Gunn diode must be adjusted with the frequency at the value indicated on the test sheet supplied with the product.





A curve giving measured data is supplied with each oscillator. The Gunn diode will be damaged if its polarity is reversed. Maximum supply voltages of the Gunn diode must not be exceeded. The oscillator must be bolted to a heatsink. To ensure good thermal contact, the oscillator has an unpainted machined flat baseplate.

YG1100 SERIES

Typical coil data see Fig. 3.

Main coil:

Tuning sensitivity up to 100 Hz 17,5 MHz/mA

Current < 1,2 A

Resistance 7 Ω

Inductance at 1 kHz $165 \pm 15 \text{ mH}$

Fast coil:

Tuning sensitivity at 100 Hz, Fig. 4 typ. 320 kHz/mA Tuning sensitivity at 1 MHz, Fig. 4 typ. 90 kHz/mA

Resistance $<1~\Omega$

Inductance $$<10~\mu H$$ Current \$<1~A

main coil

fast coil

Gunn diode

loop

loop

impedance

Fig. 3.

transformer

7Z85015



PERFORMANCE CURVES

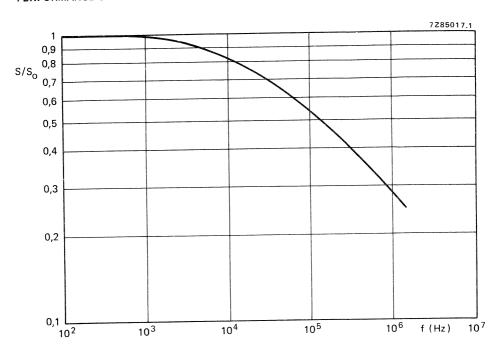


Fig. 4 Typical sensitivity variation of the fast coil versus the sweeping frequency $\rm S_{O}$ = 320 kHz/mA.

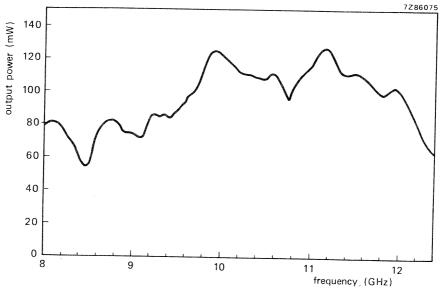


Fig. 5 Typical test curve of YG1103.

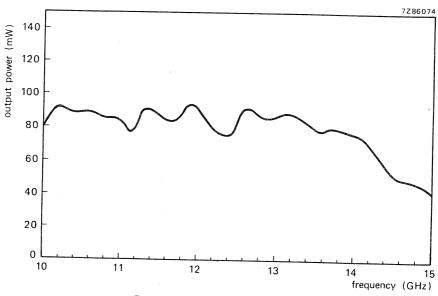


Fig. 6 Typical test curve of YG1104.



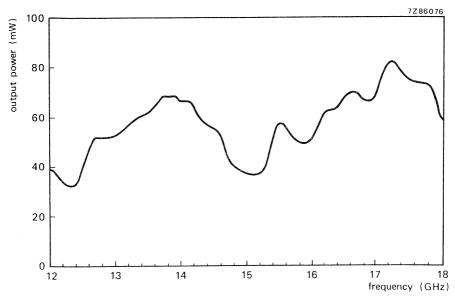


Fig. 7 Typical test curve of YG1105.

YIG TUNED-OSCILLATOR

This hermetically sealed, very linear and temperature stabilized YIG tuned-oscillator consists of a Gunn diode, a microstrip impedance transformer, a YIG sphere and electromagnetic coils. It is intended for use in wideband equipment for military applications in the frequency band from 12 to 18 GHz and features an operating temperature range from -40 to +85 °C.

QUICK REFERENCE DATA

		12 to 18	GHz
Frequency range		12 10 10	GIIZ
Frequency drift with temperature -40 to 85 °C	max.	± 25	MHz
Overall linearity, over total operating temperature range		<± 50	MHz
Output power, over total tuning range and over total temperature range	typ.	20	mW

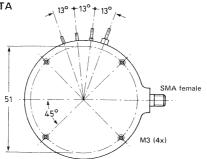
This data must be read in conjunction with GENERAL SAFETY RECOMMENDATIONS — ${\tt MICROWAVE}$ SEMICONDUCTORS.

POTENTIAL HAZARD-BERYLLIUM OXIDE

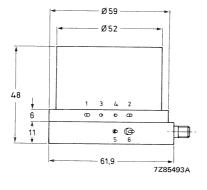
This device contains beryllium oxide, the dust of which is toxic. The device is entirely safe provided that the beryllium oxide disc is not damaged. Care should be taken to ensure that all those who may handle, use or dispose of this device are aware of its nature and of the necessary safety precautions. In particular, it should never be thrown out with general industrial or domestic waste.







Dimensions in mm



Connections:

1-2 Main coil

3-4 Fast coil

5 -V Gunn earth

6 + V Gunn

WARNING

This oscillator contains beryllium oxide the dust of which is toxic. Do not open the oscillator.

ELECTRICAL DATA

Frequency range	12	to 18	GHz
Linearity	see Figs 4	and 6	
Output power over tuning range (Fig. 5)	min.	15	mW
Power variation in band	max.	8	dB
Pulling (VSWR 1,4:1)	max.	± 5	MHz
Pushing	max.	12	MHz/V
Phase noise at 3 dBc	max.	50	kHz
Other parasitics	max.	-50	dBc
Second harmonic	max.	-15	dBc
Frequency drift as a function of temperature	see Fig. 4		
Sensitivity to external magnetic field at 50 Hz	max.	10	GHz/T
Hysteresis	typ.	15	MHz



OPERATING CONDITIONS

S. 2		4 to 10 V	
Supply voltage of Gunn diode	typ.	4 to 10 V	
Supply current of Gunn diode	typ.	1 A	
Storage temperature	_	-55 to 110 °C	

Operating temperature, measured on base plate of oscillator

--40 to 85 °C

To obtain optimum characteristics over the whole band, the supply voltage to the Gunn diode must be adjusted with the frequency at the value indicated on the test sheet supplied with the product.

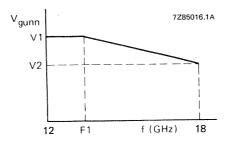


Fig. 2.

A curve giving measured data is supplied with each oscillator. The Gunn diode will be damaged if its polarity is reversed. Maximum supply voltages of the Gunn diode must not be exceeded. The oscillator must be bolted to a heatsink. To ensure good thermal contact, the oscillator has an unpainted machined flat baseplate.

/pical coil data see Fig. 3		
Main coil:	· J · -	
Tuning sensitivity up to 100 Hz	17.5	5 MHz/mA
Current (d.c.)	,	2 A
Resistance	•	Ω
Inductance at 1 kHz	170) mH
Fast coil:		
Tuning sensitivity at 3 MHz, at $I_{p-p} \leq 2.2 A$	200) MHz
Resistance	typ. 1	Ω
Inductance	• •	μΗ
Current (d.c.)	< 0.7	•

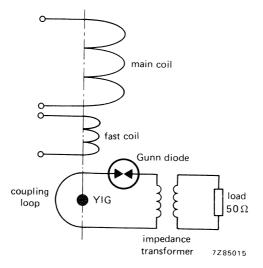


Fig. 3.



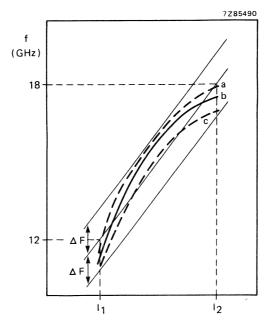


Fig. 4 Linear relation of frequency as a function of current in main coil; typical values, curve a at -40 °C; curve b at + 25 °C and curve c at + 85 °C. Deviation ΔF max. \pm 50 MHz over the whole frequency range and operating temperature range.

Frequency drift with temperature (-40 to 85 °C) at fixed current: max. ± 25 MHz.

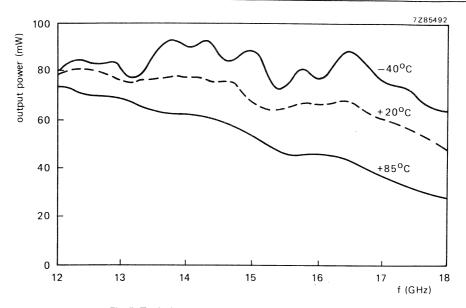
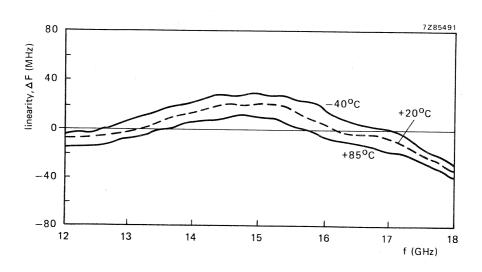


Fig. 5 Typical test curves, output power over tuning range.



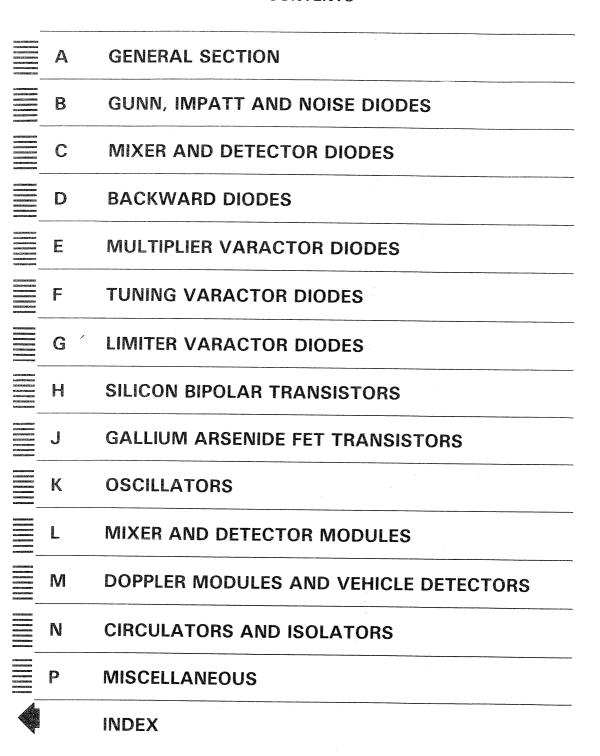


INDEX

Type number	Section	Type number	Section
ACX-01A	Р	CL7500, 20	L
AEY17	D	CL8310	Κ
AEY29, R	D	CL8630 series	κ
AEY31, A	D	CL8640R, T	К
AEY32	D	CL8690	К
AEY33	D	CL8880, 2 series	M
BAS22 to 25	С	CL8960 series	M
BAS46	С	CL9022	Р
BAT10	С	CXY10	· E
BAT11	С	CXY11A to C	В
BAT31	В	CXY12	Е
BAT38	c	CXY14A to C	В
BAT39	Č	CXY19/	В
BAT50, R	Č	CXY19A	В
BAT50, R	C	CXY19A CXY19B	В
BAIDI, N	C	CATIBD	Б
BAT52, R	С	CXY21	В
BAV22, R	С	CXY22A, B	G
BAV72	С	CXY23 series	F
BAV75	С	CXY24A, B	В
BAV96A to D	С	JA1010	Р
DAY/07	С	1841000 :	
BAV97	Ċ.	JM1000 series	L
BAW95D to G		JS1001, 2	K
BAY96	Ε	JS1101, 2	K
BFQ33	Н	JS1200 series	K
BFR49	Н	LAE4001R	Н
BXY27	E	LAE4002S	Н
BXY28	E	LAE6000Q	н
BXY29	E	LBE1004R, 1010R	Н
BXY32	Е	LCE1004R, 1010R	Н
BXY35 to 41	E	LBE2003S, 2009S	Н
DVV40	F	1.0500000 00000	
BXY48	· ·	LCE2003S, 2009S	H
BXY50	В	LKE1004R	H
BXY51	В	LKE2015T	H
BXY52	В	LKE21004R	Н
BXY53 series	F	LKE21050T	Н
BXY56, 7	E	LKE32001QC	Н
BXY60	В	LKE32002T, 4T	 Н
CAY10	E	LTE42005S	 Н
CFX13	J	LTE42008R	H
CFX21	j	PDE1001U, 1003U,	• •
		1005U, 1010U	н

Type number	Section
PEE1001U, 1003U,	
1005U, 1010U	Н
PKB20010U	Н
PKB32001U, 32003U,	
32005U	Н
PTB42001X, 42002X	Н
YG1100 series	Р
YG1301E	Р
1N415E	E
1N5152, 3	E
1N5155	E
1N5157	E

CONTENTS



Electronic components and materials for professional, industrial and consumer uses from the world-wide Philips Group of Companies

Argentina: PHILIPS ARGENTINA S.A., Div. Elcoma, Vedia 3892, 1430 BUENOS AIRES, Tel. 541-7141/7242/7343/7444/7545 Australia: PHILIPS INDUSTRIES HOLDINGS LTD., Elcoma Division, 67 Mars Road, LANE COVE, 2066, N.S.W., Tel. 427 08 88.

Austria: ÖSTERREICHISCHE PHILIPS BAUELEMENTE Industrie G.m.b.H., Triester Str. 64, A-1101 WIEN, Tel. 62 91 11.

Belgium: N.V. PHILIPS & MBLE ASSOCIATED, 9, rue du Pavillon, B-1030 BRUXELLES, Tel. (02) 242 74 00.

Brazil: IBRAPE, Caixa Postal 7383, Av. Brigadeiro Faria Lima, 1735 SAO PAULO, SP, Tel. (011) 211-2600

Canada: PHILIPS ELECTRONICS LTD., Electron Devices Div., 601 Milner Ave., SCARBOROUGH, Ontario, M1B 1M8, Tel. 292-5161.

Chile: PHILIPS CHILENA S.A., Av. Santa Maria 0760, SANTIAGO, Tel. 39-4001

Colombia: SADAPE S.A., P.O. Box 9805, Calle 13, No. 51 + 39, BOGOTA D.E. 1., Tel. 600 600 Denmark: MINIWATT A/S, Emdrupvej 115A, DK-2400 KOBENHAVN NV., Tel. (01) 69 16 22.

Finland: OY PHILIPS AB, Elcoma Division, Kaivokatu 8, SF-00100 HELSINKI 10, Tel. 17271.

France: R.T.C. LA RADIOTECHNIQUE-COMPELEC, 130 Avenue Ledru Rollin, F-75540 PARIS 11, Tel. 355-44-99

Germany: VALVO, UB Bauelemente der Philips G.m.b.H., Valvo Haus, Burchardstrasse 19, D-2 HAMBURG 1, Tel. (040) 3296-0.

Greece: PHILIPS S.A. HELLENIQUE, Elcoma Division, 52, Av. Syngrou, ATHENS, Tel. 9215111.

Hong Kong: PHILIPS HQNG KONG LTD., Elcoma Div., 15/F Philips Ind. Bldg., 24-28 Kung Yip St., KWAI CHUNG, Tel. (0)-24 51 21.

India: PEICO ELECTRONICS & ELECTRICALS LTD., Elcoma Div., Ramon House, 169 Backbay Reclamation, BOMBAY 400020, Tel. 295144.

Indonesia: P.T. PHILIPS-RALIN ELECTRONICS, Elcoma Div., Panim Bank Building, 2nd Fl., Jl. Jend. Sudirman, P.O. Box. 223, JAKARTA, Tel. 716 13 Ireland: PHILIPS ELECTRICAL (IRELAND) LTD., Newstead, Clonskeagh, DUBLIN 14, Tel. 69 33 55.

Italy: PHILIPS S.p.A., Sezione Elcoma, Piazza IV Novembre 3, I-20124 MILANO, Tel. 2-6994

Japan: NIHON PHILIPS CORP., Shuwa Shinagawa Bldg., 26-33 Takanawa 3-chome, Minato-ku, TOKYO (108), Tel. 448-5611.

(IC Products) SIGNETICS JAPAN LTD., 8-7 Sanbancho Chiyoda-ku, TOKYO 102, Tel. (03)230-1521.

Korea: PHILIPS ELECTRONICS (KOREA) LTD., Elcoma Div., Philips House, 260-199 Itaewon-dong, Yongsan-ku, C.P.O. Box 3680, SEOUL, Tel. 794-4 Malaysia: PHILIPS MALAYSIA SDN. BERHAD, Lot 2, Jalan 222, Section 14, Petaling Jaya, P.O.B. 2163. KUALA LUMPUR, Selangor, Tel. 77 44 11.

Mexico: ELECTRONICA S.A. de C.V., Varsovia No. 36, MEXICO 6, D.F., Tel. 533-11-80.

Netherlands: PHILIPS NEDERLAND, Marktgroep Elonco, Postbus 90050, 5600 PB EINDHOVEN, Tel. (040) 79 33 33,

New Zealand: PHILIPS ELECTRICAL IND. LTD., Elcoma Division, 2 Wagener Place, St. Lukes, AUCKLAND, Tel. 894-160.

Norway: NORSK A/S PHILIPS, Electronica Dept., Sandstuveien 70, OSLO 6, Tel. 68 02 00.

Peru: CADESA, Av. Alfonso Ugarte 1268, LIMA 5, Tel. 326070. Philippines: PHILIPS INDUSTRIAL DEV. INC., 2246 Pasong Tamo, P.O. Box 911, Makati Comm. Centre, MAKATI-RIZAL 3116, Tel. 86-89-51 to 59.

Portugal: PHILIPS PORTUEGESA S.A.R.L., Av. Eng. Duarte Pacheco 6, LISBOA 1, Tel. 68 31 21

Singapore: PHILIPS PROJECT DEV. (Singapore) PTE LTD., Elcoma Div., Lorong 1, Toa Payoh, SINGAPORE 1231, Tel. 25 38 811 South Africa: EDAC (Pty.) Ltd., 3rd Floor Rainer House, Upper Railway Rd. & Ove St., New Doornfontein, JOHANNESBURG 2001, Tel. 614-2362/9.

Spain: MINIWATT S.A., Balmes 22, BARCELONA 7, Tel. 30163 12

Sweden: PHILIPS KOMPONENTER A.B., Lidingövägen 50, S-11584 STOCKHOLM 27, Tel. 08/67 97 80.

Switzerland: PHILIPS A.G., Elcoma Dept., Ailmendstrasse 140-142, CH-8027 ZÜRICH, Tel. 01-488 22 11 Taiwan: PHILIPS TAIWAN LTD., 3rd Fl., San Min Building, 57-1, Chung Shan N. Rd, Section 2, P.O. Box 22978, TAIPEI, Tel. (02)-5631717.

Thailand: PHILIPS ELECTRICAL CO. OF THAILAND LTD., 283 Silom Road, P.O. Box 961, BANGKOK, Tel. 233-6330-9.

Turkey: TÜRK PHILIPS TICARET A.S., EMET Department, Inonu Cad. No. 78-80. ISTANBUL, Tel. 43 59 10

United Kingdom: MULLARD LTD., Mullard House, Torrington Place, LONDON WC1E 7HD, Tel. 01-580 6633

United States: (Active Devices & Materials) AMPEREX SALES CORP., Providence Pike, SLATERSVILLE, R.I. 02876, Tel. (401) 762-9000.

(Passive Devices) MEPCO/ELECTRA INC., Columbia Rd., MORRISTOWN, N.J. 07960, Tel. (2011539-2000

(Passive Devices & Electromechanical Devices) CENTRALAB INC., 5855 N. Glen Park Rd., MILWAUKEE, WI 53201, Tel. (414)228-7380.

(IC Products) SIGNETICS CORPORATION, 811 East Arques Avenue, SUNNYVALE, California 94086, Tel. (408) 739-7700.

Uruguay: LUZILECTRON S.A., Avda Uruguay 1287, P.O. Box 907, MONTEVIDEO, Tel. 914321

Venezuela: IND. VENEZOLANAS PHILIPS S.A., Elcoma Dept., A. Ppal de los Ruices, Edif. Centro Colgate, CARACAS, Tel. 36 05 11.

For all other countries apply to: Philips Electronic Components and Materials Division, Corporate Relations & Projects, Building BAE3, 5600 MD EINDHOVEN, THE NETHERLANDS, Tel. (040) 72 33 04, Telex 35000.

A 20

© 1982 N.V. Philips' Gloeilampenfabrieken

This information is furnished for guidance, and with no guarantees as to its accuracy or completeness; its publication conveys no licence under any patent or other right, nor does the publisher assume liability for any consequence of its use; specifications and availability of goods mentioned in it are subject to change without notice; it is not to be reproduced in any way, in whole or in part, without the written consent of the publisher